



Intel[®] 450NX PCIset

82454NX PCI Expander Bridge (PXB)

82453NX Data Path Multiplexor (MUX)

82452NX RAS/CAS Generator (RCG)

82451NX Memory & I/O Controller (MIOC)

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1.1 Overview

The Intel® 450NX PCIset provides an integrated Host-to-PCI bridge and memory controller optimized for multiprocessor systems and standard high-volume (SHV) servers based on the Pentium® II Xeon™ processor variant of the P6 family. The Intel 450NX PCIset consists of four components: 82454NX PCI Expander Bridge (PXB), 82451NX Memory and I/O Bridge Controller (MIOC), 82452NX RAS/CAS Generator (RCG), and 82453NX Data Path Multiplexor (MUX). Figure 1-1 illustrates a typical SHV server system based on the Intel 450NX PCIset. The system bus interface supports up to 4 Pentium II Xeon processors at 100 MHz. An additional bus mastering agent such as a cluster bridge can be supported at reduced frequencies. Two dedicated PCI Expander Bridges (PXBs) can be connected via the Expander

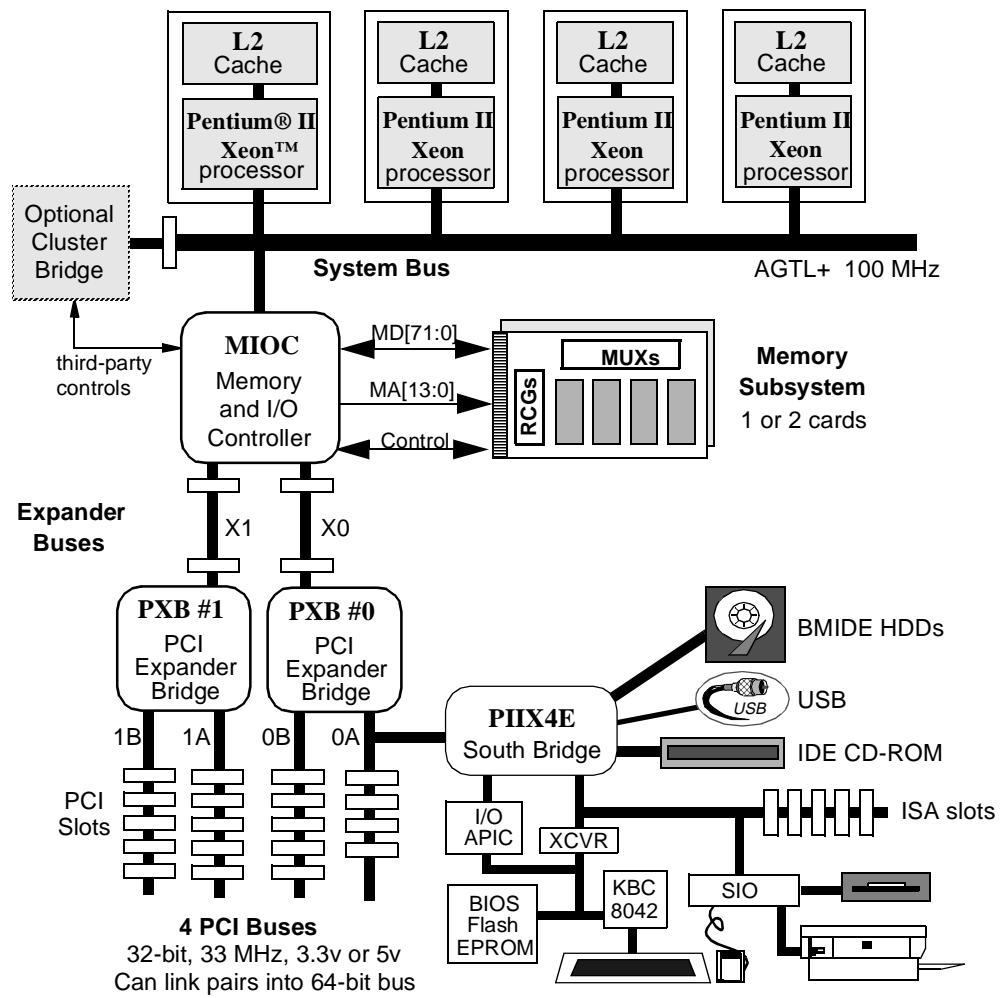


Figure 1-1: Simplified Intel® 450NX PCIset System Block Diagram

Bus. Each PXB provides two independent 32-bit, 33 MHz PCI buses, with an option to link the two buses into a single 64-bit, 33 MHz bus. The Intel 450NX PCIset memory subsystem supports one or two memory cards. Each card is comprised of an RCG, a DRAM array, and two MUXs. The MIOC issues requests to the RCG components on each card to generate RAS#, CAS#, and WE# outputs to the DRAMs. The MUX components provide the datapath for the DRAM arrays. Up to 8 GB of memory in various configurations are supported.

Other capabilities of the Intel 450NX PCIset include:

- Full Pentium® II Xeon™ processor bus interface (36-bit address, 64-bit data) at 100 MHz.
- Support for two dedicated PCI expander bridges (PXBs) attached *behind* the system bus so as not to add additional electrical load to the system bus.
- Support for both internal and external system bus and I/O bus arbitration.

Supporting Devices

The Intel 450NX PCIset is designed to support the PIIX4E south bridge. The PIIX4E is a highly integrated multi-functional component that supports the following capabilities:

- PCI Rev 2.1-compliant PCI-to-ISA Bridge with support for 33-MHz PCI operations
- Enhanced DMA controller
- 8259 Compatible Programmable Interrupt Controller
- System Timer functions
- Integrated IDE controller with Ultra DMA/33 support

1.2 Intel® 450NX PCIset Components

MIOC Memory and I/O Bridge Controller

The MIOC accepts access requests from the system bus and directs those accesses to memory or one of the PCI buses. The MIOC also accepts inbound requests from the PCI buses. The MIOC provides the data port and buffering for data transferred between the system bus, PXBs and memory. In addition, the MIOC generates the appropriate controls to the RCG and MUX components to control data transfer to and from the memory.

PXB PCI Expander Bridge

The PXB provides the interface to two independent 32-bit, 33 MHz Rev 2.1-compliant PCI buses. The PXB is both a master and target on each PCI bus.

RCG RAS/CAS Generator

The RCG is responsible for accepting memory requests from the MIOC and converting these into the specific signals and timings required by the DRAM. Each RCG controls up to four banks of memory.

MUX Data Path Multiplexor

The MUX provides the multiplexing and staging required to support memory interleaving between the DRAMs and the MIOC. Each MUX provides the data path for one-half of a Qword for each of four interleaves.

1.3 Intel® 450NX PCIset Feature Summary

System Bus Support

- Fully supports the Pentium® II Xeon™ processor bus protocol at bus frequencies up to 100 MHz.
- Functionally and electrically compatible with the original and Pentium II P6 family processor buses.
- Fully supports 4-way multiprocessing, with performance scaling to 3.5x that of a uni-processor system.
- Full 36-bit address decode and drive capability.
- Full 64-bit data bus (32-bit data bus mode is not supported).
- Parity protection on address and control signals, ECC protection on data signals.
- 8-deep in-order queue; 24-deep memory request queue; 2-deep outbound read-request queue per PCI bus; 6-deep outbound write-posting queue per PCI bus.
- AGTL+ bus driver technology.
- Intel® 450NX PCIset adds only one load to the system bus.
- Intel 450GX PCIset-compatible third-party request/grant and control signals, allowing cluster bridges to be placed on the system bus.

DRAM Interface Support

- Memory technologies supported are 16- and 64-Mbit, 60nsec and 50nsec 3.3v EDO DRAM devices.
- Supports from 32 MB to 8 GB of memory, in 64 MB increments after the initial 32 MB.
- Supports 4-way interleaved operation, with 2-way interleave supported in the first bank of card 0 to permit entry-level systems with minimal memory.
- Supports memory address bit permuting (ABP) to obtain alternate row selection bits.
- Supports card-to-card interleaving to further distribute memory accesses across multiple banks of memory.
- Staggered CAS-before-RAS refresh.
- ECC with single-bit error correction and scrub-on-error in the memory.
- Extensive Host-to-Memory and PCI-to-Memory write data buffering.

I/O Bridge Support

- Up to four independent 32-bit PCI ports (using two PXBs)
 - each supports up to 10 electrical loads (connectors count as loads).
 - each provides internal arbitration for up to 6 masters plus a south bridge on the compatibility PCI bus, or external arbitration.
- Synchronous operation to the system bus clock using a 3:1 system bus/PCI bus gearing ratio.
 - 3:1 ratio supports a 100 MHz system bus and 33.33 MHz PCI bus.
 - 3:1 ratio supports a 90 MHz system bus and 30 MHz PCI bus (or lower, depending on effect of 6th load).
- Parity protection on all PCI signals.
- Inbound read prefetches of up to 4 cache lines.
- Outbound write assembly of full/partial line writes.
- Data streaming support from PCI to DRAM.

System Management Features

- Provides controlled access to the Intel Architecture System Management Mode (SMM) memory space (SM RAM).

Test & Tuning Features

- Signal interconnectivity testing via boundary scan.
- Access to internal control and status registers via JTAG TAP port. I2C access is *not* provided in the PCIset; however, error indicators are reported to pins which can be monitored and sampled using I2C capabilities if provided elsewhere in the system.
- System bus, memory and I/O performance counters with programmable events.

Reliability/Availability/Serviceability (RAS) Features

- ECC coverage of system data bus and memory; parity coverage of system bus controls, PCI bus, and Expander bus.
- ECC bits can be corrupted via selective masking for diagnostics.
- Fault recording of the first two ECC errors. Each includes error type and syndrome. Memory ECC error logs include the effective address, allowing identification of the failing location. Error logs are not affected by reset, allowing recovery software to examine the logs.

1.4 Packaging & Power

- Table 1-1 indicates the signal count, package and power for each component in the Intel® 450NX PCIset. In a common high-end configuration, using two memory cards (each with one RCG and two MUX components), two PXBs and 3.3 V supplies, the Intel 450NX PCIset would contribute approximately 47 watts.

Table 1-1: Signals, Pins, Packaging and Power

Chip	Signals	Package	Footprint	Power ¹
MIOC	348	PLGA-540 ²	42.5 mm	13.2 W
PXB	177	PLGA-540 ²	42.5 mm	7.8 W
RCG	173	BGA-324	27.0 mm	2.5 W
MUX	207	BGA-324	27.0 mm	3.3 W

Notes:

1. Assumes 3.3 V supplies.
2. Requires heat sink.

This chapter provides a detailed description of all signals used in any component in the Intel® 450NX PCIset.

2.1 Conventions

The terms *assertion* and *deassertion* are used extensively when describing signals, to avoid confusion when working with a mix of active-high and active-low signals. The term *assert*, or *assertion*, indicates that the signal is active, independent of whether the active level is represented by a high or low voltage. The term *deassert*, or *deassertion*, indicates that the signal is inactive.

The “#” symbol at the end of a signal name indicates that the active, or asserted state occurs when the signal is at a low voltage level. When “#” is not present after the signal name the signal is asserted when at the high voltage level.

When discussing data values used inside the chip set, the *logical* value is used; i.e., a data value described as "1101b" would appear as "1101b" on an active-high bus, and as "0010b" on an active-low bus. When discussing the assertion of a value on the actual pin, the physical value is used; i.e., asserting an active-low signal produces a "0" value on the pin.

The following notations are used to describe the signal type:

I	Input pin
O	Output pin
I/O	Bidirectional (input/output) pin
OD	Open drain output pin (other than AGTL+ signals)

The signal description also includes the type of buffer used for the particular signal:

AGTL+	Open drain AGTL+ interface.
PCI	PCI-compliant 3.3 V/5 V-tolerant interface
LVTTTL	Low-voltage (3.3 V) TTL-compatible signals.
2.5V	2.5 V CMOS signals.
Analog	Typically a voltage reference or specialty power supply.

Some signals or groups of signals have multiple versions. These signal groups may represent distinct but similar ports or interfaces, or may represent identical copies of the signal used to reduce loading effects. The following conventions are used:

- RR(A,B,C)XX expands to: RRAXX, RRBXX, and RRCXX
- RR(A,...,D)XX expands to: RRAXX, RRBXX, RRCXX, and RRDXX
- RRpXX, where p=A,B,C expands to: RRAXX, RRBXX, and RRCXX

Typically, *upper case* groups (e.g., "(A,B,C)") represent functionally similar but logically distinct signals; each signal provides an independent control, and may or may not be asserted at the same time as the other signals in the grouping. In contrast, *lower case* groups (e.g., "(a,b,c)") typically represent identical duplicates of a common signal provided to reduce loading.

2.2 Summary

Figure 2-1 illustrates the partitioning of interfaces across the components in the Intel® 450NX PCIsset. The remainder of this section lists the signals and signal counts in each interface by component. The signal functions are described in subsequent sections.

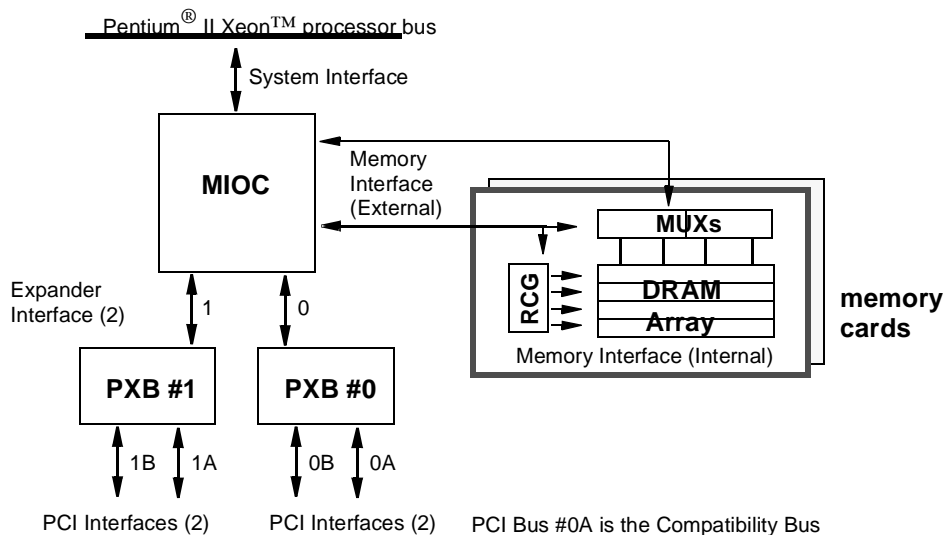


Figure 2-1: Interface Summary: Partitioning

2.2.1 Signal Summary, By Component

The following tables provide summary lists of all signals in each component, sorted alphabetically within interface type. The signals are described in a later section.

2.2.1.1 MIOC Signal List

System Interface				134
A[35:3]#	AGTL+ I/O	DEP[7:0]#	AGTL+ I/O	
ADS#	AGTL+ I/O	DRDY#	AGTL+ I/O	
AERR#	AGTL+ I/O	HIT#	AGTL+ I	
AP[1:0]#	AGTL+ I/O	HITM#	AGTL+ I	
BERR#	AGTL+ I/O	INIT#	2.5V OD	
BINIT#	AGTL+ I/O	LOCK#	AGTL+ I	
BNR#	AGTL+ I/O	REQ[4:0]#	AGTL+ I/O	
BP[1:0]#	LVTTTL I/OD	RP#	AGTL+ I/O	
BPRI#	AGTL+ I/O	RS[2:0]#	AGTL+ I/O	
BREQ[0]#	AGTL+ O	RSP#	AGTL+ I/O	
D[63:0]#	AGTL+ I/O	TRDY#	AGTL+ I/O	
DBSY#	AGTL+ I/O			
DEFER#	AGTL+ I/O			
Third-Party Agent Interface				4
IOGNT#	LVTTTL I	TPCTL[1:0]	LVTTTL I	
IOREQ#	LVTTTL O			
Memory Subsystem / External Interface				119
BANK[2:0]#	AGTL+ O	DVALID(a,b)#	AGTL+ O	
CARD[1:0]#	AGTL+ O	MA[13:0]#	AGTL+ O	
CMND[1:0]#	AGTL+ O	MD[71:0]#	AGTL+ I/O	
CSTB#	AGTL+ O	MRESET#	AGTL+ O	
DCMPLT(a,b)#	AGTL+ I/O	PHIT(a,b)#	AGTL+ I	
DOFF[1:0]#	AGTL+ O	ROW#	AGTL+ O	
DSEL[1:0]#	AGTL+ O	RCMPLT(a,b)#	AGTL+ I	
DSTBN[3:0]#	AGTL+ I/O	RHIT(a,b)#	AGTL+ I	
DSTBP[3:0]#	AGTL+ I/O	WDEVT#	AGTL+ O	
Expander Interface (two per MIOC: 0,1)				2 x 33
X(0,1)ADS#	AGTL+ I/O	X(0,1)HSTBP#	AGTL+ O	
X(0,1)BE[1:0]#	AGTL+ I/O	X(0,1)PAR#	AGTL+ I/O	
X(0,1)BLK#	AGTL+ O	X(0,1)RST#	AGTL+ O	
X(0,1)CLK	CMOS O	X(0,1)RSTB#	AGTL+ O	
X(0,1)CLKB	CMOS O	X(0,1)RSTFB#	AGTL+ I	
X(0,1)CLKFB	CMOS I	X(0,1)XRST#	AGTL+ I	
X(0,1)D[15:0]#	AGTL+ I/O	X(0,1)XSTBN#	AGTL+ I	
X(0,1)HRST#	AGTL+ O	X(0,1)XSTBP#	AGTL+ I	
X(0,1)HSTBN#	AGTL+ O			
Common Support Signals				16
CRES[1:0]	Analog I	TMS	2.5V I	
TCK	2.5V I	TRST#	2.5V I	
TDI	2.5V I	VCCA (3)	Analog I	
TDO	2.5V OD	VREF (6)	Analog I	

Component-Specific Support Signals					9
CRESET#	LVTTTL	O	PWRGD	LVTTTL	I
ERR[1:0]#	LVTTTL	I/OD	PWRGDB	LVTTTL	O
HCLKIN	2.5V	I	RESET#	AGTL+	I/O
INTREQ#	LVTTTL	O	SMIACT#	LVTTTL	O
TOTAL SIGNALS					348

2.2.1.2 PXB Signal List

PCI Bus Interface (2 per PXB: A,B)					2 x 61
P(A,B)AD[31:0]	PCI	I/O	P(A,B)PAR	PCI	I/O
P(A,B)C/BE[3:0]#	PCI	I/O	P(A,B)PERR#	PCI	I/O
P(A,B)CLKFB	LVTTTL	I	P(A,B)REQ[5:0]#	PCI	I
P(A,B)CLK	LVTTTL	O	P(A,B)RST#	PCI	O
P(A,B)DEVSEL#	PCI	I/O	P(A,B)SERR#	PCI	OD
P(A,B)FRAME#	PCI	I/O	P(A,B)STOP#	PCI	I/O
P(A,B)GNT[5:0]#	PCI	O	P(A,B)TRDY#	PCI	I/O
P(A,B)IRDY#	PCI	I/O	P(A,B)XARB#	PCI	I
P(A,B)LOCK#	PCI	I/O			
PCI Bus Interface / Non-Duplicated (one set per PXB)					6
ACK64#	PCI	I/O	PHLDA#	PCI	O
MODE64#	PCI	I	REQ64#	PCI	I/O
PHOLD#	PCI	I	WSC#	PCI	O
Expander Interface (one per PXB)					30
XADS#	AGTL+	I/O	XHSTBP#	AGTL+	I
XBE[1:0]#	AGTL+	I/O	XIB	AGTL+	O
XBLK#	AGTL+	I	XPAR#	AGTL+	I/O
XCLK	CMOS	I	XRST#	AGTL+	I
XD[15:0]#	AGTL+	I/O	XXRTS#	AGTL+	O
XHRSTS#	AGTL+	I	XXSTBN#	AGTL+	O
XHSTBN#	AGTL+	I	XXSTBP#	AGTL+	O
Common Support Signals					12
CRES[1:0]	Analog	I	TMS	2.5V	I
TCK	2.5V	I	TRST#	2.5V	I
TDI	2.5V	I	VCCA (3)	Analog	I
TDO	2.5V	OD	VREF (2)	Analog	I
Component-Specific Support Signals					8
INTRQ(A,B)#	PCI	OD	PIIXOK#	LVTTTL	I
P(A,B)MON[1:0]#	LVTTTL	I/OD	PWRGD	LVTTTL	I
TOTAL SIGNALS					177

2.2.1.3 RCG Signal List

Memory Subsystem / External Interface				27
BANK[2:0]#	AGTL+ I	MRESET#	AGTL+ I	
CARD#	AGTL+ I	PHIT#	AGTL+ O	
CMND[1:0]#	AGTL+ I	RCMPLT#	AGTL+ O	
CSTB#	AGTL+ I	RHIT#	AGTL+ O	
GRCMPLT#	AGTL+ I/O	ROW#	AGTL+ I	
MA[13:0]#	AGTL+ I			
Memory Subsystem / Internal Interface				123
ADDR(A,B,C,D)[13:0]	LVTTTL O	LRD#	AGTL+ O	
AVWP#	AGTL+ O	RAS(A,B,C,D)(a,b,c,d)[1:0]#	LVTTTL O	
CAS(A,B,C,D)(a,b,c,d)[1:0]#	LVTTTL O	WDME#	AGTL+ O	
LDSTB#	AGTL+ O	WE(A,B,C,D)(a,b)#	LVTTTL O	
Common Support Signals				10
CRES[1:0]	Analog I	TMS	2.5 V I	
TCK	2.5V I	TRST#	2.5 V I	
TDI	2.5V I	VCCA	Analog I	
TDO	2.5V OD	VREF (2)	Analog I	
Component-Specific Support Signals				4
BANKID#	LVTTTL I	DR50T#	LVTTTL I	
DR50H#	LVTTTL I	HCLKIN	2.5 V I	
TOTAL SIGNALS				173

2.2.1.4 MUX Signal List

Memory Subsystem / External Interface				48
DCMPLT#	AGTL+ I/O	DVALID#	AGTL+ I	
DOFF[1:0]#	AGTL+ I	GDCMPLT#	AGTL+ I/O	
DSEL#	AGTL+ I	MD[35:0]#	AGTL+ I/O	
DSTBP[1:0]#	AGTL+ I/O	MRESET#	AGTL+ I	
DSTBN[1:0]#	AGTL+ I/O	WDEVT#	AGTL+ I	
Memory Subsystem / Internal Interface				148
AVWP#	AGTL+ I	Q1D[35:0]	LVTTTL I/O	
LDSTB#	AGTL+ I	Q2D[35:0]	LVTTTL I/O	
LRD#	AGTL+ I	Q3D[35:0]	LVTTTL I/O	
Q0D[35:0]	LVTTTL I/O	WDME#	AGTL+ I	
Common Support Signals				10
CRES[1:0]	Analog I	TMS	2.5 V I	
TCK	2.5 V I	TRST#	2.5 V I	
TDI	2.5 V I	VCCA	Analog I	
TDO	2.5 V OD	VREF (2)	Analog I	
Component-Specific Support Signals				1
HCLKIN	2.5 V I			
TOTAL SIGNALS				207

2.3 System Interface

The MIOC provides the Intel[®] 450NX PCIset's sole connection to the system bus. This section describes the Intel 450NX PCIset-specific uses of these signals.

2.3.1 System / MIOC Interface

A[35:3]#	Address Bus A[35:3]# connect to the system address bus. During processor cycles the A[35:3]# are inputs. The MIOC drives A[35:3]# during snoop cycles on behalf of PCI initiators. The address bus is inverted on the system bus.	AGTL+ I/O
ADS#	Address Strobe The system bus owner asserts ADS# to indicate the first of two cycles of a <i>request phase</i> .	AGTL+ I/O
AERR#	Address Parity Error AERR# is asserted by any agent that detects an address parity error.	AGTL+ I/O
AP[1:0]#	Address Parity Parity protection on the address bus. AP#[1] covers A#[35:24], and AP#[0] covers A#[23:3]. They are valid on both cycles of the request.	AGTL+ I/O
BERR#	Bus Error This signal is asserted by any agent that observes an unrecoverable bus protocol violation.	AGTL+ I/O
BINIT#	Bus Initialization BINIT# is asserted to re-initialize the bus state machines. The MIOC will terminate any ongoing PCI transaction and reset its inbound and outbound queues. No configuration registers or error logging registers are affected.	AGTL+ I/O
BNR#	Block Next Request Used to block the current request bus owner from issuing a new request.	AGTL+ I/O
BP[1:0]#	Performance Monitoring In normal operation, the MIOC can be configured to drive performance monitoring data out of either of these pins, similar in function to the BP pins provided on the processors.	LVTTL I/OD
BPRI#	Priority Agent Bus Request The MIOC is the only Priority Agent on the system bus. It asserts this signal to obtain ownership of the address bus. BPRI# has priority over symmetric bus requests.	AGTL+ O
BREQ[0]#	Symmetric Agent Bus Request This signal is asserted by the MIOC when RESET# is asserted, to select the boot processor. It is deasserted 2 host clocks after RESET# is deasserted.	AGTL+ O

D[63:0]#	Data These signals are connected to the system data bus. The data signals are inverted on the system bus.	AGTL+ I/O																
DBSY#	Data Bus Busy Used by the data bus owner to hold the data bus for transfers requiring more than one cycle.	AGTL+ I/O																
DEP[7:0]#	Data Bus ECC/Parity These signals provide parity or ECC for the D#[63:0] signals. The MIOC only provides ECC.	AGTL+ I/O																
DEFER#	Defer DEFER# is driven by the addressed agent to indicate that the transaction cannot be guaranteed to be globally observed.	AGTL+ I/O																
DRDY#	Data Ready Asserted for each cycle that valid data is transferred.	AGTL+ I/O																
HIT#	Hit The MIOC never asserts HIT#; it has no cache, and never snoop stalls.	AGTL+ I																
HITM#	Hit Modified The MIOC never asserts HITM#; it has no cache, and never snoop stalls.	AGTL+ I																
INIT#	Soft Reset INIT# may be asserted to request a soft reset of the processors. During a system hard reset, the INIT# signal may be optionally asserted to cause the processors to initiate their BIST. The INIT# signal is <i>not</i> asserted during power-good reset.	2.5V OD																
LOCK#	Lock All system bus cycles sampled with the assertion of LOCK# and ADS#, until the negation of LOCK#, must be atomic; i.e., no PCI activity to DRAM is allowed and the locked cycle must be translated to PCI if targeted for the PCI bus.	AGTL+ I																
REQ[4:0]#	Request Command Asserted during both clocks of a request phase. In the first clock, the signals define the transaction type to a level which is sufficient to begin a snoop request. In the second clock, the signals carry additional information to define the complete transaction type.	AGTL+ I/O																
RP#	Request Parity Even parity protection on ADS# and REQ[4:0]#. It is valid on both cycles of the request.	AGTL+ I/O																
RS[2:0]#	Response Signals Indicate response type as shown below: <table border="0" style="margin-left: 2em;"> <tr> <td>000</td> <td>Idle state</td> <td>100</td> <td>Hard failure</td> </tr> <tr> <td>001</td> <td>Retry</td> <td>101</td> <td>No Data</td> </tr> <tr> <td>010</td> <td>Deferred</td> <td>110</td> <td>Implicit writeback</td> </tr> <tr> <td>011</td> <td><i>reserved</i></td> <td>111</td> <td>Normal Data</td> </tr> </table>	000	Idle state	100	Hard failure	001	Retry	101	No Data	010	Deferred	110	Implicit writeback	011	<i>reserved</i>	111	Normal Data	AGTL+ I/O
000	Idle state	100	Hard failure															
001	Retry	101	No Data															
010	Deferred	110	Implicit writeback															
011	<i>reserved</i>	111	Normal Data															

RSP#	Response Parity Signal Parity protection on RS[2:0]#.	AGTL+ I/O
TRDY#	Target Ready Indicates that the target of the system transaction is able to enter the data transfer phase.	AGTL+ I/O

2.3.2 Third-Party Agent / MIOC Interface

The following signals provide support for an additional non-processor, third-party agent (TPA) on the system bus. Such agents may need priority access to the system bus itself, or may need to intervene in transactions between the processors and the Intel® 450NX PCIset.

IOGNT#	I/O Grant The IOGNT# signal has two modes: Internal Arbitration Mode and External Arbitration Mode, selected by a bit in the MIOC's CONFIG register. In Internal Arbitration Mode IOGNT# is an input from another bridge device which is requesting ownership of the BPRI# signal. In external arbitration mode, this bridge requests BPRI# ownership from an external bridge arbiter. IOGNT# should be asserted by the external arbiter when this MIOC has been granted ownership of the BPRI# signal.	LVTTTL I
IOREQ#	I/O Request The IOREQ# signal has two modes: Internal Arbitration Mode and External Arbitration Mode, selected by a bit in the MIOC's CONFIG register. In Internal Arbitration Mode IOREQ# is the grant to another bridge device that is making a request for ownership of the BPRI# signal. In external arbitration mode this signal is asserted to request ownership of the BPRI# signal.	LVTTTL O
TPCTL[1:0]	Third Party Control These signals allow an agent participating in transactions between the Intel® 450NX PCIset and another bus agent as a "third-party" to control the responses generated by the Intel 450NX PCIset.	LVTTTL I
	00 Accept The MIOC will accept the request and provide the normal response.	
	01 <i>reserved</i> -	
	10 Retry The MIOC will generate a RETRY response.	
	11 Defer The MIOC will generate a DEFERRED response.	

2.4 PCI Interface

2.4.1 Primary Bus

There are two primary PCI buses per PXB, identified as the "a" bus and the "b" bus groups. Each signal name includes a "p", indicating the PCI bus port; **p = A or B**.

PpAD[31:0]	PCI Address/Data PCI Address and Data signals are multiplexed on this bus. The physical byte address is output during the address phase and the data follows in the subsequent data phase(s).	PCI I/O
PpC/BE[3:0]#	Command/Byte Enable PCI Bus Command and Byte Enable signals are multiplexed on the same pins. During the address phase of a transaction, C/BE[3:0]# define the bus command. During the data phase C/BE[3:0]# are used as byte enables.	PCI I/O
PpCLK	PCI Clock This signal is an output with a derived frequency equal to 1/3 of the system bus frequency.	LVTTL O
PpCLKFB	PCI Clock Feedback This signal is connected to the output of a low skew PCI clock buffer tree. It is used to synchronize the PCI clock driven from PpCLK to the clock used for the internal PCI logic.	LVTTL I
PpDEVSEL#	Device Select DEVSEL# is driven by the device that has decoded its address as the target of the current access.	PCI I/O
PpFRAME#	Frame The PXB asserts FRAME# to indicate the start of a bus transaction. While FRAME# is asserted, data transfers continue. When FRAME# is negated, the transaction is in the final data phase. FRAME# is an input when the PXB acts as a PCI target.	PCI I/O
PpIRDY#	Initiator Ready This signal is asserted by a master to indicate its ability to complete the current data transfer. IRDY# is an output when the PXB acts as a PCI initiator and an input when the PXB acts as a PCI target.	PCI I/O
PpPAR	Parity PAR is driven by the PXB when it acts as a PCI initiator during address and data phases for a write cycle, and during the address phase for a read cycle. PAR is driven by the PXB when it acts as a PCI target during each data phase of a PCI memory read cycle. Even parity is generated across AD[31:0] and C/BE[3:0]#.	PCI I/O
PpRST#	PCI Reset PCI Bus Reset forces the PCI interfaces of each device to a known state. The PXB generates a minimum 1 ms pulse on RST#.	PCI O
PpPERR#	PCI Parity Error Pulsed by an agent receiving data with bad parity one clock after PAR is asserted. The PXB will generate PERR# active if it detects a parity error on the PCI bus and the PERR# Enable bit in the PCICMD register is set.	PCI I/O
PpLOCK#	Lock LOCK# indicates an exclusive bus operation and may require multiple transactions to complete. It is possible for different agents to use the PCI Bus while a single initiator retains ownership of the LOCK# signal.	PCI I/O

PpTRDY#	Target Ready The assertion of TRDY# indicates the target agent's ability to complete the current data phase of the transaction. TRDY# is an input when the PXB acts as a PCI master and an output when the PXB acts as a PCI target.	PCI I/O
PpSERR#	System Error The PXB asserts this signal to indicate an error condition.	PCI OD
PpSTOP#	Stop STOP# is used for disconnect, retry, and abort sequences on the PCI Bus. It is an input when the PXB acts as a PCI initiator and an output when the PXB acts as a PCI target.	PCI I/O

2.4.2 64-bit Access Support

These signals are used only in 64-bit bus mode. There is one set per PXB.

ACK64#	64-bit Access Acknowledge This signal is driven by the accessed target to indicate its willingness to transfer 64-bit data. When the PXB is the bus target, this signal is an output. If asserted, the PXB will transfer 64-bit data; otherwise, the PXB will transfer 32-bit data. When the PXB is the bus master, this signal is an input.	PCI I/O
MODE64#	64-bit Bus Mode A strapping pin that selects whether the pair of 32-bit PCI buses are used as two independent 32-bit buses, or linked together as a single 64-bit bus. If asserted, the buses are used as a single 64-bit bus: the 32-bit data bus of the PCI "B" port becomes the high Dword of the 64-bit bus. An internal pull-up insures that the pin appears deasserted if left unconnected.	PCI I
REQ64#	64-bit Access Request This signal is driven by the bus master to indicate it's desire to transfer 64-bit data. When the PXB is the bus master, this signal is an output. The PXB will assert this signal if it can transfer 64-bit data. When the PXB is the bus target, this signal is an input.	PCI I/O

The following 64-bit extension signals are mapped from the existing "B" port signals:

AD[63:32]	from	PBAD[31:0]
C/BE[7:4]	from	PBC/BE[3:0]
PAR64	from	PBPAR

All other controls and status signals in 64-bit operation are taken from the Bus "A" signal set. Unused pins on the "B" side should be tied inactive.

2.4.3 Internal vs. External Arbitration

Each PXB supports both internal arbitration and external arbitration, independently for each PCI bus. While in internal arbitration mode, six pairs of request/grant signals are used to support up to six PCI masters on the bus (plus the PXB itself, and the PIIX4E south bridge on

the compatibility PCI bus). While in external arbitration mode, only one pair (#0) are used, and have different meanings.

Each signal name includes a “p”, indicating the PCI bus port; **p = A or B**.

PpXARB# External Arbitration Mode PCI I
 A strapping pin, sampled at the trailing edge of reset. If asserted, the PCI bus is controlled using an external arbiter. If deasserted, the PCI bus is controlled using the PXB’s internal arbiter. An internal pull-up insures that the pin appears deasserted if left unconnected.

Internal Arbitration Mode (per PCI bus, p=A,B)

PpREQ[5:0]# PCI Bus Request PCI I
 Six independent PCI bus request signals used by the internal PCI arbiter for PCI initiator arbitration. Unused signals should be strapped inactive.

PpGNT[5:0]# PCI Grant PCI O
 Six independent PCI bus grant signals used by the internal PCI arbiter for PCI initiator arbitration.

External Arbitration Mode (per PCI bus, p=A,B)

When operating in external arbitration mode, REQ[5:1]# and GNT[5:1]# signals are not used. The REQ[0]# signal is redefined as HGNT#, and the GNT[0]# signal is redefined as HREQ#.

PpHREQ# Host Request PCI O
 Generated by the PXB to the external PCI arbiter to request control of the PCI bus to perform a Host-PCI access.

PpHGNT# Host Grant PCI I
 Generated by the external PCI arbiter to grant the PCI bus to the PXB to perform a Host-PCI transfer.

2.4.4 PIIX4E Interface

The compatibility PCI bus (PCI Bus 0A) supports a PIIX4E south bridge, and requires several additional handshake signals, provided by the PXB. They are active only for Bus 0A.

NOTE

These signals, and the associated PHOLDA# and WSC# protocols, cannot be used with the PXB in external arbiter mode.

PHOLD# PCI Hold PCI I
 This signal is the PIIX4E’s request for the PCI bus.

PHLDA# PCI Hold Acknowledge PCI O
 This signal is driven by the PXB to grant PCI bus ownership to the PIIX4E.

WSC#	Write Snoop Complete	PCI O
	This signal is asserted active to indicate completion of snoop activity on the system bus on the behalf of the last PCI-DRAM write transaction, and that it is safe to send the APIC interrupt message.	

2.5 Memory Subsystem Interface

The memory subsystem is comprised of the DRAM arrays and the associated RCGs and MUXs. There is the external interface (between the MIOC and the memory subsystem), and the internal interface (between the various parts of the memory subsystem.)

2.5.1 External Interface

BANK[2:0]#	Bank Selects	AGTL+ MIOC→ RCG
	These signals indicate which memory bank will service this access. BANK[2:0]# are connected to all RCGs on both memory cards.	
CARD[1:0]#	Card Selects	AGTL+ MIOC→ RCG
	These signals indicate which memory card will service this access. Valid patterns in the Intel® 450NX PCIsset are 01b=card0 and 10b=card1, allowing CARD[0]# to be connected only to card 0 and CARD[1]# to be connected only to card 1. Each CARD signal is connected to all RCGs on the given memory card.	
CMND[1:0]#	Access Command	AGTL+ MIOC→ RCG
	These signals encode the command of the current operation. CMND[1:0]# are connected to all RCGs on both memory cards.	
CSTB#	Command Strobe	AGTL+ MIOC→ RCG
	This strobe, when activated, indicates the initiation of an access. This signal is connected to all RCGs on both memory cards.	
MA[13:0]#	Memory Address bus	AGTL+ MIOC→ RCG
	These signals define the address of the location to be accessed in the DRAM., and are driven on two successive clock cycles to provide up to 28 bits of effective memory address. The signals are connected to all RCGs on both memory cards.	
ROW#	Row Selects	AGTL+ MIOC→ RCG
	These signals indicate which row in the selected memory bank will service this access. These signals are connected to all RCGs on both memory cards.	
GRCMPLT#	Global RCMPLT#	AGTL+, I/O, all RCGs
	A “global” version of the RCMPLT(a,b)# signals, asserted coincident with RCMPLT#, and by the same agent. Whereas each RCMPLT# signal connects the RCGs on one card with the MIOC, the GRCMPLT# signal connects the	

RCGs across both cards while excluding the MIOC. This allows all RCGs to monitor each request completion without placing undue loading on the RCMPLT# signals.

MRESET#	Memory Subsystem Reset	AGTL+ MIOC→ RCG/MUX
	This signal represents a hard reset of the memory subsystem. It is asserted following PWRGD or upon the MIOC issuing a processor RESET due to software invocation.	
RCMPLTa# RCMPLTb#	Request Complete	AGTL+ RCG→ MIOC
	This signal, which is driven by the currently active RCG, indicates the completion of a request into the memory array. Typically the “a” signal connects the MIOC and all RCGs on Card #0, while the “b” signal connects the MIOC and all RCGs on Card #1.	
PHIT(a,b)# RHIT(a,b)#	Page and Row Hit Status	AGTL+ RCG→ MIOC
	These signals indicate what resource, if any, delayed the initiation of a read. Typically the “a” signal connects the MIOC and all RCGs on Card #0, while the “b” signal connects the MIOC and all RCGs on Card #1.	
DSTBP[3:0]# DSTBN[3:0]#	Data Strobes	AGTL+ MUX↔ MIOC
	This set of four signal-pairs are strobes which qualify the data transferred between the MUX and MIOC. Each strobe pair qualifies 18 bits (two bytes and two check bits), as follows:	
	DSTB[0]# qualifies MD[17:00]#.	DSTB[2]# qualifies MD[53:36]#.
	DSTB[1]# qualifies MD[35:18]#.	DSTB[3]# qualifies MD[71:54]#.
	In a 4:1 interleaved system, with 2 MUXs per card, DSTB[1:0]# strobes the low MUX and DSTB[3:2]# strobes the high MUX. In a 2:1 interleaved system, with only a single MUX per card, DSTB[1:0]# strobes the MUX, and DSTB[3:2]# is not used.	
MD[71:36]# MD[35:00]#	Memory Data	AGTL+ MUX↔ MIOC
	These signals are connected to the external datapath of the MUXs. Each MUX provides 36 bits of the 72-bit datapath to the MIOC.	
DCMPLTa# DCMPLTb#	Data Transfer Complete	AGTL+ MUX→ MIOC/MUX MIOC→MUXs
	This signal is driven by the source of the data transfer: the MIOC for writes, and the MUX for reads. DCMPLT# active indicates that the data transfer is complete. Typically the “a” signal connects the MIOC and all MUXs on Card #0, while the “b” signal connects the MIOC and all MUXs on Card #1.	
DOFF[1:0]#	Data Offset	AGTL+ MIOC→ MUX
	These two bits, when qualified by the DVALID# signal, define the initial Qword access order for the data transfer. The result is that the critical chunk is accessed first and the remaining chunks are accessed in Intel “Toggle” order.	

DSEL#	Data Card Select	AGTL+ MIOC→ MUX
	This signal, when qualified by the DVALID# signal, selects which card the memory transfer is coming from or destined towards. Each memory card uses a single DSEL# input, sent to each MUX on the card. The MIOC provides two DSEL# outputs (DSEL[1:0]#), one sent to each card.	
DVALIDa# DVALIDb#	Data Transfer Complete	AGTL+ MIOC→ MUX
	This signal indicates that the DSEL[1:0]#, DOFF[1:0]#, and WDEVT# signals are valid. Typically the “a” signal connects the MIOC and all MUXs on Card #0, while the “b” signal connects the MIOC and all MUXs on Card #1.	
GDCMPLT#	Global DCMPLT#	AGTL+, I/O, all MUXs
	A “global” version of the DCMPLT(a,b)# signals, asserted coincident with DCMPLT#, and by the same agent. Whereas each DCMPLT# signal connects the MUXs on one card with the MIOC, the GDCMPLT# signal connects the MUXs across both cards while excluding the MIOC. This allows all MUXs to monitor each data completion without placing undue loading on the DCMPLT# signals.	
WDEVT#	Write Data Event	AGTL+ MIOC→ MUX
	This signal, when qualified by the DVALID# signal, indicates the type of data transfer command. If asserted, the command represents a write data transfer. If deasserted, the command represents a read data transfer.	

2.5.2 Internal Interface

2.5.2.1 RCG / DRAM Interface

Each RCG provides four sets of signals to drive four banks in the DRAM array. In each of the following signal names, the “**B**” indicates a set of signals per bank. Each RCG controls four banks; therefore **B** = **A, B, C** or **D**.

CAS B (a,b,c,d)[1:0]#	Column Address Strobes	LVTTTL RCG→ DRAM
	These signals are used to latch the column address into the DRAMs. The “a”, “b”, “c” and “d” versions are duplicates for load reduction.	
ADDR B [13:0]	DRAM Address	LVTTTL RCG→ DRAM
	ADDR is used to provide the multiplexed row and column address to DRAM.	
RAS B (a,b,c,d)[1:0]#	Row Address Strobe	LVTTTL RCG→ DRAM
	The RAS signals are used to latch the row address into the DRAMs. Each signal is used to select one DRAM row. The 1:0 signals indicate which row within the bank. The “a”, “b”, “c” and “d” versions are duplicates for load reduction.	
WE B (a,b)#	Write Enable Signal	LVTTTL RCG→ DRAM
	WE# is asserted during writes to main memory. The “a” and “b” versions are duplicates for load reduction.	

2.5.2.2 DRAM / MUX Interface

Q0D[35:0]	Memory Data, Interleave 0 These signals are connected to the output of the DRAMs. This is one-half of a Quad-word and is connected to interleave zero.	LVTTL DRAM↔ MUX
Q1D[35:0]	Memory Data, Interleave 1 These signals are connected to the output of the DRAMs. This is one-half of a Quad-word and is connected to interleave one.	LVTTL DRAM↔ MUX
Q2D[35:0]	Memory Data, Interleave 2 These signals are connected to the output of the DRAMs. This is one-half of a Quad-word and is connected to interleave two.	LVTTL DRAM↔ MUX
Q3D[35:0]	Memory Data, Interleave 3 These signals are connected to the output of the DRAMs. This is one-half of a Quad-word and is connected to interleave three.	LVTTL DRAM↔ MUX

2.5.2.3 RCG / MUX Interface

AVWP#	Advance MUX Write Path Pointers This signal is activated by an RCG after performing a memory write.	AGTL+ RCG→ MUX
LDSTB#	Load Data Strobe This signal controls when read data is latched from the DRAM data bus.	AGTL+ RCG→ MUX
LRD#	Load Read Data This signal indicates when read data is ready to load from the DRAMs.	AGTL+ RCG→ MUX
WDME#	Write Data to Memory Enable This signal enables the MUXes to drive write data to the DRAMs.	AGTL+ RCG→ MUX

2.6 Expander Interface

The MIOC component has two Expander interfaces, one for each of the two PXBs supported by Intel® 450NX PCIset. These two high speed, low latency interfaces are identified as the **X0** bus and the **X1** bus groups.

Each signal name includes a “**p**”, indicating the Expander port. On the MIOC, **p = 0** or **1**, designating one of the two interfaces. On the PxB, **p** is not used.

XpADS#	Address / Data Strobe. Bidirectional signal asserted by the sending agent during data transmission.	AGTL+ MIOC↔ PxB
XpBE[1:0]#	Byte Enables. Bidirectional signals indicating valid bytes during the data phases of a transmission.	AGTL+ MIOC↔ PxB

XpD[15:0]#	Datapath This bidirectional datapath is used to transfer addresses and data between the MIOC and the PCI Expander.	AGTL+ MIOC↔ PXB
XpHRTS#	Host Request to Send. Request to use the bidirectional Expander bus sent from MIOC to PXB, synchronous to HCLKIN.	AGTL+ MIOC→ PXB
XpHSTBP# XpHSTBN#	Host Strobes This pair of opposite-phase strobes are used by the PXB to latch and synchronize incoming data.	AGTL+ MIOC→ PXB
XpPAR#	Bus Parity. Bidirectional signal indicating even parity across XD[15:0] and XBE[1:0].	AGTL+ MIOC↔ PXB
XpXRTS#	Expander Request to Send. Request to use the bidirectional Expander bus sent from PXB to MIOC, synchronous to HCLKIN.	AGTL+ PXB→ MIOC
XpXSTBP# XpXSTBN#	Expander Strobes This pair of opposite-phase strobes are used by the MIOC to latch and synchronize incoming data.	AGTL+ PXB→ MIOC

Support Signals

XpBLK	Block Counters. This signal is asserted when the Performance Counter Master Enable bit in the MIOC's CONFIG register is set, and is used to affect a nearly simultaneous stop/start of the performance counters across both the MIOC and all PXBs.	AGTL+ MIOC→ PXB
XpCLK	Host Clock. This is the primary clock source provided to the PXB, analogous to HCLKIN for the MIOC, RCG and MUX. Inside the PXB, it is divided by 3 to produce a PCI clock output at 33.33 MHz from an HCLKIN of 100 MHz.	CMOS MIOC→ PXB
XpCLKB	Host Clock, 2nd Version. This is a duplicate of the XpCLK signal, to be used in maintaining PLL synchronization in the MIOC. See XpCLKFB below.	CMOS MIOC→ ext
XpCLKFB	Host Clock, Feedback. This signal is a length-matched copy of the XpCLK signal sent to the PXB, used to maintain PLL synchronization in the MIOC. The XpCLKB signal is length-matched to the XpCLK's path to the PXB, then returned to the MIOC as the XpCLKFB input.	CMOS ext→ MIOC
XpIB	Driving Inbound. This active-high signal is asserted when the PXB is driving data over the Expander bus. This pin is not connected to the MIOC.	AGTL+ PXB→ ext
XpRST#	PXB Reset. This signal issues a hard reset of the PXB, including the dependent PCI buses.	AGTL+ MIOC→ PXB

XpRSTB#	PXB Reset, 2nd Version. This is a duplicate of the XpRST# signal, to be used in maintaining PLL synchronization in the MIOC. See XpRSTFB# below.	AGTL+ MIOC→ ext
XpRSTFB#	PXB Reset, Feedback. The XpRSTB# signal is length-matched to the XpRST#'s path to the PXB, then returned to the MIOC as the XpRSTFB# input.	AGTL+ ext→ MIOC

2.7 Common Support Signals

2.7.1 JTAG Interface

All four components in the Intel® 450NX PCIset have a JTAG Test Access Port (TAP) to allow access to internal registers and perform boundary scan. Each interface is identical.

TCK	Test Clock Test Clock is used to clock state information and data into and out of the device during boundary scan.	2.5V I
TDI	Test Data Input Test Input is used to serially shift data and instructions into the TAP.	2.5V I
TDO	Test Output Test Output is used to shift data out of the device.	2.5V OD
TMS	Test Mode Select Test Mode Select is used to control the state of the TAP controller.	2.5V I
TRST#	Test Reset Test Reset is used to reset the TAP controller logic.	2.5V I

2.7.2 Reference Signals

All four components have the following support signals to provide voltage references or compensation for the AGTL+ interfaces or the PLL circuitry.

CRES[1:0]	I/O Buffer Compensation Resistor Terminals For correct component operation an external 768 ohm resistor must be connected between CRES1 and CRES0. This resistor should have a minimum precision of 1%.	Analog I
VCCA (n)	PLL Analog Voltage This pin is an independent power supply for a PLL. In normal operation, this pin provides power to the PLL, and requires special decoupling (refer to Electrical Characteristics).	Analog I

VREF (n) **AGTL+ Reference Voltage** Analog I
 This is the reference voltage derived from the termination voltage to the pull-up resistors. The MIOC has 6 VREF pins, while the PXB, RCG and MUX each have 2 VREF pins.

2.8 Component-Specific Support Signals

2.8.1 MIOC

CRESET# **Clock Selection Reset.** LVTTTL O
 This is a delayed version of the RESET# signal provided to the processors. This signal is asserted asynchronously along with RESET#, but is deasserted two system bus clocks following the deassertion of RESET#.

ERR[1:0]# **Error Code** LVTTTL I/OD
 These pins reflect irrecoverable errors detectable by the Intel 450NX PCIset.

ERR	Error Type	Associated Error s Flags
00	No error	
01	PCIset Internal Error	Expander Bus Parity
10	Multi-Bit Memory Error	Multi-Bit Memory ECC error
11	System Bus Error	Address Parity, Request Parity, Protocol Violation, BERR, Multi-Bit Host ECC error

HCLKIN **Host Clock In** 2.5V I
 This pin receives a buffered system clock. This is a single trace from the clock synthesizer to minimize clock skew.

INTREQ# **Interrupt Request** LVTTTL O
 This pin is asserted by the MIOC when an internal event occurs and sets a status flag, and that flag has been configured to request an interrupt.

PWRGD **Power Good** LVTTTL I
 This pin should be connected to a 3.3 V version of the system's power good indicator, and should be asserted only after all power supplies and clocks have reached their stable references and been stable for at least 1 msec.

PWRGDB **Buffered Power Good** LVTTTL O
 A buffered (but not synchronized) version of the PWRGD input, which is used to drive the PWRGD input on each PXB in the system.

RESET# **Reset** AGTL+ I/O
 In normal operation, this signal is an output. The MIOC will reset the system bus either on power-up or when programmed through the Reset Control register.

SMIACT# **SMI Active.** LVTTL O
This signal provides a visible indicator that the system has entered System Management Mode.

2.8.2 **PXB**

INTRQ(A,B)# **Interrupt Requests** PCI OD
These pins are asserted by the PXB when an internal event occurs and sets a status flag, and that flag has been configured to request an interrupt. There is one pin for each side (A,B) of the PXB. The signals may be connected to the standard PCI bus interrupt request lines.

PAMON[1:0]#
PBMON[1:0]# **Performance Monitors** LVTTL I/OD
These pins track the two performance monitoring counters associated with each PCI bus (a,b) in the PXB. PMON[0] tracks the PMD[0] counter while PMON[1] tracks the PMD[1] counter.

PIIXOK# **PIIX Reset Complete.** LVTTL I
This signal is tied to the PIIX's CPURST output, and is used to detect when the PIIX completes its reset functions.

PWRGD **Power Good** LVTTL I
This input should be driven from the MIOC's PWRGDB output.

2.8.3 **RCG**

BANKID# **Bank Identifier** LVTTL I
This strapping pin should be tied high (deasserted), or have an external pullup.

DR50H# **50ns DRAM "Here".** LVTTL I
This strapping pin selects between 60ns and 50ns DRAM timings for this RCG.
Deasserted: 60ns timings will be used.
Asserted: 50ns timings will be used.

DR50T# **50ns DRAM "There".** LVTTL I
This strapping pin should match the DR50H# strapping pin described above.

HCLKIN **Host Clock In** 2.5V I
This pin receives a buffered system clock.

2.8.4 **MUX**

HCLKIN **Host Clock In** 2.5V I
This pin receives a buffered system clock.

The Intel® 450NX PCIset internal registers (both I/O Mapped and Configuration registers) are accessible by the processor. Each MIOC, and each PCI bus in each PXB has an independent configuration space. This chapter provides detailed descriptions of each register.

3.1 Access Restrictions

Register Attributes

Read Only	Writes to this register have no effect.
Read/Write	Data may be read from and written to this register. Selected bits in the register may be designated as "read-only"; such bits are not affected by data writes to the register.
Read/Clear	Data may be read from the register. A data write operates strictly as a clear:
Sticky	Data in this register remains valid and unchanged, during and following any reset except the <i>power-good</i> reset.

3.2 I/O Mapped Registers

The Intel® 450NX PCIset contains two registers that reside in the processor I/O address space: the Configuration Address (CONFIG_ADDRESS) Register and the Configuration Data (CONFIG_DATA) Register. The Configuration Address Register enables/disables the configuration space and determines what portion of configuration space is visible through the Configuration Data window.

3.2.1 CONFIG_ADDRESS: Configuration Address Register

I/O Address:	CF8h [Dword]	Size:	32 bits
Default Value:	00000000h	Attribute:	Read/Write

The CONFIG_ADDRESS register contains the Bus Number, Device Number, Function Number, and Register Number for which a subsequent configuration access is intended.

3.3 MIOC Configuration Space

Table 3-1: MIOC Configuration Space ¹

DID		VID		00h	DBC 01		DBC 00		80h
				04h	DBC 03		DBC 02		84h
CLASS			RID	08h	DBC 05		DBC 04		88h
HDR				0Ch	DBC 07		DBC 06		8Ch
				10h	DBC 09		DBC 08		90h
				14h	DBC 11		DBC 10		94h
				18h	DBC 13		DBC 12		98h
				1Ch	DBC 15		DBC 14		9Ch
				24h	RCGP	<i>Reserved</i>			A0h
				28h			REFRESH		A4h
				2Ch			MEA1	MEA0	A8h
				30h					ACh
				34h	MEL1		MEL0		B0h
				38h	HEL1		HEL0		B4h
				3Ch			ECCMSK	ECCCMD	B8h
CHKCON		RC	CONFIG	40h	ROUTE0		TCAP0		C0h
		ERRCMD	ERRSTS	44h			TCAP1		C4h
		BUFSIZ		48h	ROUTE1		TCAP2		C8h
CVCR		CVDR		4Ch			TCAP3		CCh
		TOM		50h	BUSNO1	SUBB0	SUBA0	BUSNO0	D0h
LXGT		LXGB		54h	DEVMAP		SUBB1	SUBA1	D4h
		HXGB		58h	PMD0				D8h
		HXGT		5Ch			PMR0	PMD0	DCh
MAR2	MAR1	MAR0	GAPEN	60h	PMD1				E0h
MAR6	MAR5	MAR4	MAR3	64h			PMR1	PMD1	E4h
IOAR		IOABASE		68h	PME1		PME0		E8h
SMRAM				6Ch					ECh
		MMBASE		70h					F0h
MMR1		MMR0		74h					F4h
MMR3		MMR2		78h					F8h
IOR		ISA		7Ch					FCh

1. The first 64 bytes are predefined in the PCI Specification. All other locations are defined specifically for the component of interest.

Table 3-1 illustrates the MIOC's Configuration Space Map. Many of these registers affect both host-initiated transactions and PCI-initiated transactions, and are therefore duplicated in both the MIOC and PXB Configuration Spaces. It is software's responsibility to ensure that both sets of registers are programmed consistently to achieve correct operation.

3.3.1 BUFSIZ: Buffer Sizes

Address Offset:	48-4Ah	Size:	24 bits
Default Value:	304310h	Attribute:	Read Only

<u>Bits</u>	<u>Description</u>
--------------------	---------------------------

- | | |
|-------|--|
| 23:18 | <p>Inbound Write Transaction Capacity.
Total number of inbound write transactions, per Expander Port, that can be accepted by the MIOC.
Value=12.</p> |
| 17:12 | <p>Inbound Read Transaction Capacity.
Total number of inbound read transactions, per Expander Port, that can be accepted by the MIOC.
Value=4.</p> |
| 11:6 | <p>Inbound Write Data Buffer Capacity.
Total number of data buffers, per Expander Port, available in the MIOC for use by inbound write transactions, in increments of 32 bytes.
Value=12.</p> |
| 5:0 | <p>Inbound Read Data Buffer Capacity.
Total number of data buffers, per Expander Port, available in the MIOC for use by inbound read transactions, in increments of 32 bytes.
Value=16.</p> |

3.3.2 BUSNO[1:0]: Lowest PCI Bus Number, per PXB

Address Offset:	D0h, D3h	Size:	8 bits each
Default Value:	00h each	Attribute:	Read/Write

The MIOC supports two Expander Ports; each can support one PXB. PXB #0 is connected to Expander Port #0, and PXB #1 is connected to Expander Port #1. Each PXB supports one or two PCI buses, connected to PCI Ports "A" and "B". The PCI bus connected to Port #0A must be the compatibility PCI bus from which a system boots.

Three registers (BUSNO, SUBA and SUBB) define the bus hierarchy for each PXB.

- | | |
|----------|--|
| BUSNO[0] | Holds the PCI-bus-number of the bus connected to PXB #0 Bus #A. This must be set to 0. |
| SUBA[0] | Holds the PCI-bus-number of the highest <i>subordinate</i> bus under PXB #0 Bus #A. The PCI bus number for PXB #0 Bus #B is SUBA[0]+1. |
| SUBB[0] | Holds the PCI-bus-number of the highest <i>subordinate</i> bus under PXB #0 Bus #B. This also represents the highest PCI-bus-number accessible from PXB #0. |
| BUSNO[1] | Holds the PCI-bus-number of the bus connected to PXB #1 Bus #A. |
| SUBA[1] | Holds the PCI-bus-number of the highest <i>subordinate</i> bus under PXB #1 Bus #A. The PCI bus number for PXB #1 Bus #b is SUBA[1]+1. |
| SUBB[1] | Holds the PCI-bus-number of the highest <i>subordinate</i> bus under PXB #1 Bus #B. This also represents the highest PCI-bus-number accessible from PXB #1 (and therefore the Intel 450NX PCIset). If PXB#1 is not in use, program this register to 0. |

If PXB *i* is operating in 64-bit bus mode, SUBB[*i*] must equal SUBA[*i*].

<u>Bits</u>	<u>Description</u>
7:0	PCI Bus Number.

NOTE

Inactive PXBs should be disabled by writing the corresponding Reset Expander Port bit in the RC register and resetting the corresponding "Device present" bit in the DEVMAP register.

3.3.3 CHKCON: Check Connection

Address Offset:	43h	Size:	8 bits
Default Value:	10h	Attribute:	Read/Write

<u>Bits</u>	<u>Description</u>
7:6	<i>reserved</i>

3. Register Descriptions

- 5 **Live Port #1 Flag.**
If set, the port is "live".
Default=0.

- 4 **Live Port #0 Flag.**
If set, the port is "live."
Default=1.

- 3:2 *reserved*

- 1 **Test Port #1 Enable.**
Setting this enable triggers the check connection protocol for port 1.
Default=0.

- 0 **Test Port #0 Enable.**
Setting this enable triggers the check connection protocol for port 0.
Default=0.

NOTE

Setting both Test Port #1 Enable and Test Port #0 Enable simultaneously is prohibited, and will have unpredictable results, up to and including system hangs requiring a full system reset. Inactive PXBs should be disabled by writing the corresponding Reset Expander Port bit in the RC register. Transactions sent to inactive PXBs can result in system hangs.

3.3.4 CLASS: Class Code Register

Address Offset: 09 - 0Bh Size: 24 bits
Default Value: 060000h Attribute: Read Only

<u>Bits</u>	<u>Description</u>
-------------	--------------------

- | | |
|-------|---|
| 23:16 | Base Class
For the MIOC, this field is hardwired to 06h. |
| 15:8 | Sub-Class
For the MIOC, this field is hardwired to 00h. |
| 7:0 | Register-Level Programming Interface
For the MIOC this field is hardwired to 00h. |

3.3.5 CONFIG: Software-Defined Configuration Register

Address Offset: 40-41h Size: 16 bits
Default Value: 1000h Attribute: Read/Write

<u>Bits</u>	<u>Description</u>
-------------	--------------------

- | | |
|-------|---------------------|
| 15:13 | <i>reserved (0)</i> |
|-------|---------------------|

- 12 **Outbound Fairness Disable.**
 When this bit is clear, Host-PCI writes and reads that receive a retry by the MIOC follow a fairness algorithm to guarantee that retried transactions receive first priority before new transactions. If set, Host-PCI writes and reads are serviced in the order first observed without regard to retry history. Default=1.
- 11 **Performance Counter Master Enable (PCME).**
 This bit provides a mechanism to (nearly) simultaneously freeze or start the performance counters across both the MIOC and PXBs.
 If this bit is cleared the MIOC's and PXB's performance counters will not increment
 If set the MIOC's and PXB's performance counters resume normal operation.
 Default = 0.
- 10 *reserved (0)*
- 9 **Third Party Support Disable**
 If set, performance optimizations are enabled that may result in coherency violations in the presence of a third party agent. This bit should be clear for systems with TPAs.
 Default = 0.
- 8 **External Arbiter Enable.**
 If set, access to the system bus is controlled by an external arbiter. If cleared, the MIOC's internal arbiter is used. Default=0.
- 7 **WC Write Post During I/O Bridge Access Enable (UWPE).**
 This bit should be cleared for normal operation. Default=0.
- 6 **Outbound I/O Write Posting Enable.**
 If set, Host-PCI I/O writes will be posted. If cleared, Host-PCI I/O writes will not be posted. In normal operation, this enable should be set. Default=0.
- 5 **Read-Around-Write Enable (RAWWE).**
 If RAWWE is set, it enables the read-around-write capability for the MIOC and memory subsystem. If cleared, read accesses will not advance past any previously posted writes. In normal operation, this enable should be set. Default=0.
- 4 **ISA Expansion Aliasing Enable.**
 If set, every I/O access with an address in the range x100-x3FFh, x500-x7FFh, x900-xBFF and xD00-xFFFh is internally aliased to the range 0100-03FFh before any other address range checking is performed. This bit only affects routing, the unmasked address is passed to the PCI bus. Default=0.
- 3 *reserved (0)*
- 2 **Card to Card Interleave Enable.**
 If set, Host or PCI accesses to memory are distributed to both memory cards on a cache line granularity. This provides a performance enhancement for systems which utilize two memory cards. When this bit is clear, C2C interleaving is disabled. Default = 0.

- 1:0 **Memory Address Bit Permuted.**
 The MIOC supports cache-line permuting across banks. This field controls the type of permuting used, as follows:
- 00b No permuting.
 - 01b 2-way Permuting.
 - 10b 4-way Permuting.
 - 11b *reserved*
- Default=0.

3.3.6 CVCR: Configuration Values Captured on Reset

Address Offset: 4E-4Fh Size: 16 bits
 Default Value: 0000h Attribute: Read-Only

This register captures the configuration values driven on A#[15:0] at the trailing edge of RESET#. This allows an external device to override the default values provided by the MIOC via its CVDR register.

Bits **Description**

- 15:13 *reserved (0)*
- 12:11 **APIC Cluster ID.**
 Captured from A#[12:11]. Represents the APIC Cluster identifier.
- 10 **Enable BINIT# Input.**
 Captured from A#[10]. If set, the MIOC will observe the assertion of the BINIT# input. Further details on BINIT# processing may be found in the ERRCMD register.
- 9 **Enable BERR# Input.**
 Captured from A#[9]. If set, the MIOC will observe the assertion of the BERR# input. Further details on BERR# processing may be found in the ERRCMD register.
- 8 **Enable AERR# Input.**
 Captured from A#[8]. If set, the MIOC will observe the assertion of the AERR# input. Further details on AERR# processing may be found in the ERRCMD register. If this enable is asserted, then the BINIT# Driver Enable in the ERRCMD register must also be asserted.
- 7 **In-Order Queue Depth 1.**
 Captured from A#[7]. If set, the MIOC will limit its In-Order Queue Depth to 1 (no pipelining support), instead of the usual 8.
- 6 **1M Power-on Reset Vector.**
 Captured from A#[6]. This bit has no meaning for the MIOC. If set, all Pentium® II Xeon™ processors on the system bus will use the 1MB-1 (000FFFFFFh) reset vector, instead of their usual 4 GB-1 (FFFFFFFFFh) vector.
- 5 **Enable FRC Mode.**
 Captured from A#[5]. This bit has no meaning for the MIOC. If set, all Pentium II Xeon processors on the system bus will enter FRC-enabled mode.
- 4:0 *reserved (0)*

Unused DBC registers should be configured as inactive, with the Bank Present bit cleared and the TOB field set to that of the previous bank, indicating that the amount of memory in that bank is zero.

<u>Bits</u>	<u>Description</u>
15	4:1 Interleave. If set, bank is a 4:1 interleave. If cleared, bank is a 2:1 interleave. Default=1.
14	Single Row. This bit is set if the bank contains only a single row. If cleared, the bank contains two rows; <i>both rows must be configured identically</i> . Default=0.
13	Bank Present. This bit is set to indicate that this memory bank is present, and refresh cycles should be issued to the bank. This bit must be cleared if this bank is not physically present. Default=1.
12:10	<i>reserved (0)</i>
9:0	Top of Bank (TOB). This field contains the effective address of the top of memory in this bank <i>and all lower banks</i> , and is used to determine which bank is selected. Each TOB field specifies the amount of memory, in 32 MB chunks, contained in this bank <i>and all lower banks</i> . Unpopulated banks must have their TOB set equal to that of the previous bank indicating that the amount of memory in that bank is zero. Default = 200h, each.

3.3.9 DEVMAP: System Bus PCI Device Map

Address Offset:	D6-D7h	Size:	16 bits
Default Value:	0005h	Attribute:	Read/Write, Read Only

This register indicates which PCI devices on the system bus have active configuration spaces. At reset, DEVMAP is initialized with all devices *not present* except the MIOC and the compatibility PCI bus.

<u>Bits</u>	<u>Description</u>
15	<i>reserved (0)</i>
14:0	PCI Bus #0, Device [30:16] Present. Each bit corresponds to a device on PCI Bus #0 (numbers 16-30). If set, the device is present in the system and is expected to respond to configuration cycles directed to it. Bit 0 is hardwired "on", and is read-only. Default=0005h (MIOC, PCI #0A present)

3.3.10 DID: Device Identification Register

Address Offset: 02 - 03h Size: 16 bits
 Default Value: 84CAh Attributes: Read Only

<u>Bits</u>	<u>Description</u>
15:0	Device Identification Number. The value 84CAh indicates the Intel® 450NX PCIset MIOC.

3.3.11 ECCCMD: ECC Command Register

Address Offset: B8h Size: 8 bits
 Default Value: 00h Attribute: Read/Write

This register controls the Intel 450NX PCIset responses to ECC errors on data retrieved from the memory subsystem or received from the system bus.

<u>Bits</u>	<u>Description</u>
7	<i>reserved (0)</i>
6	System Bus, Report Multi-Bit Errors (HRM). If set, the Intel® 450NX PCIset will log multiple-bit ECC errors on data received from the system bus in the appropriate HEL register. If the BERR# driver is enabled, BERR# will also be asserted. Default=0.
5	System Bus, Report Single-Bit Errors (HRS). If set, on detection of a single-bit ECC error on data received from the system bus the Intel 450NX PCIset will log the error in the appropriate HEL register, and assert the INTREQ# signal. Default=0.
4	System Bus, Correct Single-Bit Errors (HCS). If set, on detection of a single-bit ECC error on data received from the system bus the Intel 450NX PCIset will correct the data and generate a new ECC code before writing the data into memory. Default=0.
3	Memory, Scrub Single-Bit Errors (MSS). If set, on detection of a single-bit ECC error on data read from the memory array the Intel 450NX PCIset will perform a scrub operation to correct the location in the memory. The MCS bit in this register must be set for this feature to be effective. Default=0.
2	Memory, Report Multi-Bit Errors (MRM). If set, on detection of a multiple-bit ECC error on data read from the memory array the Intel 450NX PCIset will log the error in the appropriate MEL and MEA registers. If the BERR# driver is enabled, BERR# will also be asserted. Default=0.

- 1 **Memory, Report Single-Bit Errors (MRS).**
If set, on detection of a single-bit ECC error on data read from the memory array the Intel 450NX PCIset will log the error in the appropriate MEL and MEA registers, and assert the INTREQ# signal. Default=0.
- 0 **Memory, Correct Single-Bit Errors (MCS).**
If set, on detection of a single-bit ECC error on data read from the memory array the Intel 450NX PCIset will correct the data and generate a new ECC code before returning the data to the requestor. Default=0.

3.3.12 ECCMSK: ECC Mask Register

Address Offset: B9h Size: 8 bits
Default Value: 00h Attribute: Read/Write

This register is used to test the ECC error detection logic in the memory subsystem. The register is written with a masking function which is applied on subsequent writes to memory. All subsequent writes into memory will store a masked version of the computed ECC. Subsequent reads of the memory locations written while masked will return an invalid ECC code. To disable testing, the mask value is left at 0h (default).

Bits Description

- 7:0 **ECC Generation Mask.**
Each bit of the computed ECC is XOR'ed with the corresponding bit in this mask field before it is stored in the memory array.

3.3.13 ERRCMD: Error Command Register

Address Offset: 46h Size: 8 bits
Default Value: 00h Attribute: Read/Write

This register controls the MIOC responses to various system and data errors.

Bits Description

- 7:6 *reserved (0)*
- 5 **BERR#-to-BINIT# Enable.**
If set, on observation or assertion of BERR#, (and *Enable BERR# Input* is set) the MIOC will also assert BINIT#. Default=0.
- 4 **Fast System Bus Time-out.**
This bit controls the duration of a watchdog timer which is started at the end of the system bus response phase. If this bit is set, the timer expires in 256 host cycles. If cleared, the timer expires in 2^{17} cycles. Default=0.

- 7 *reserved (0)*
- 6 **System Bus Time-out Flag.**
This flag is set when the watchdog timer monitoring accesses on the system bus times out. See the *BINIT#-on-System-Bus-Time-outs Enable* and the *BINIT# Driver Enable* in the ERRCMD register.
- 5 **Expander Bus 1 Parity Error Flag.**
This flag is set when Expander Bus #1 reports a parity error on data inbound from the PXB. This condition is a catastrophic fail and will also assert BINIT#.
- 4 **Expander Bus 0 Parity Error Flag.**
This flag is set when Expander Bus #0 reports a parity error on data inbound from the PXB. This condition is a catastrophic fail and will also assert BINIT#.
- 3 **BERR# Error Flag.**
This flag is set when BERR# is detected asserted on the system bus.
- 2 **Address Parity Error.**
This flag is set upon detecting the assertion of AP#, indicating a parity error on the system address signals. If the *AERR# Driver Enable* is set in the ERRCMD register, AERR# is asserted. If the *BINIT# Driver Enable* is set in the ERRCMD register, BINIT# is asserted.
- 1 **Response Parity Error Flag.**
This flag is set upon detecting the assertion of RP#, indicating a parity error on the system bus response signals. If the *BINIT# Driver Enable* is set in the ERRCMD register, BINIT# is also asserted.
- 0 **Request Parity Error.**
This flag is set upon detecting the assertion of RP#, indicating an error on ADS or request signals. If the *AERR# Driver Enable* is set in the ERRCMD register, AERR# is asserted. If the *BINIT# Driver Enable* is set in the ERRCMD register, BINIT# is asserted.

3.3.15 GAPEN: Gap Enables

Address Offset: 60h Size: 8 bits
Default Value: 0Eh Attribute: Read/Write

Bits	Description
-------------	--------------------

- | | |
|---|--|
| 7 | <i>reserved (0)</i> |
| 6 | ISA Space Enable.
When set, the ISA Space address range is enabled. Memory-mapped accesses that fall within this address range are forwarded to the compatibility PCI bus. If this bit is cleared, accesses to this address range are handled normally. Default=0. |
| 5 | High Expansion Gap Enable.
When set, the High Expansion Gap (HXG) is enabled. Default=0. |

- 4 **Low Expansion Gap Enable.**
When set, the Low Expansion Gap (LXG) is enabled. Default=0.
- 3 **High BIOS Space Enable.**
If set, a 2 MByte space is opened at location (4 GB - 2 MB), and accesses into this address range will be directed to the compatibility PCI bus instead of memory. Default=1.
- 2 **High Graphics Adapter Space Enable.**
If set, a 64 KB space is opened in the upper half of the Graphics Adapter portion of the Low Compatibility Region (address range B_0000h-BFFFFh), and accesses into this address range will be directed to the compatibility PCI bus instead of memory. Default=1.
- 1 **Low Graphics Adapter Space Enable.**
If set, a 64 KB space is opened in the lower half of the Graphics Adapter portion of the Low Compatibility Region (address range A_0000h-AFFFFh), and accesses into this address will be directed to the compatibility PCI bus instead of memory. Default=1.
- 0 *reserved (0)*

3.3.16 HDR: Header Type Register

Address Offset:	0Eh	Size:	8 bits
Default Value:	00h	Attribute:	Read Only

This register identifies the header layout of the configuration space. Writes to this register have no effect.

Bits	Description
-------------	--------------------

- | | |
|-----|--|
| 7 | Multi-function Device.
The MIOC is not a multi-function device, and this bit is hardwired to 0. |
| 6:0 | Configuration Layout.
This field is hardwired to 00h, which represents the default PCI configuration layout. |

3.3.17 HEL[1:0] Host Bus Error Log

Address Offset:	B4-B7h	Size:	16 bits each
Default Value:	0000h each	Attribute:	Read/Write, Sticky

These registers are loaded on the first and second ECC errors detected on data received from the system bus. HEL[0] logs the first error, and HEL[1] logs the second. The registers hold their data until reloaded due to a new error condition, or until they are explicitly cleared by software or a *power-good* reset.

<u>Bits</u>	<u>Description</u>
15:8	Syndrome. Holds the calculated syndrome that identifies the specific bit in error.
7:2	<i>reserved (0)</i>
1	Multiple-Bit Error Logged (MBE). This flag is set if the logged error was a multiple-bit (uncorrectable) error.
0	Single-Bit Error Logged (SBE). This flag is set if the logged error was a single-bit (correctable) error.

3.3.18 HXGB: High Expansion Gap Base

Address Offset:	58-5Ah	Size:	24 bits
Default Value:	000000h	Attribute:	Read/Write

<u>Bits</u>	<u>Description</u>
23:0	Gap Base Address. This field specifies the A[43:20] portion of the gap's base address, in 1 MB increments. The A[19:0] portions of the gap's base address are zero.

3.3.19 HXGT: High Expansion Gap Top

Address Offset:	5C-5Eh	Size:	24 bits
Default Value:	000000h	Attribute:	Read/Write

<u>Bits</u>	<u>Description</u>
23:0	Gap Top Address. This field specifies the A[43:20] portion of the gap's highest address, in 1 MB increments. The A[19:0] portion of the gap's top address is FFFFh.

3.3.20 IOABASE: I/O APIC Base Address

Address Offset:	68-69h	Size:	16 bits
Default Value:	0FECh	Attribute:	Read/Write

<u>Bits</u>	<u>Description</u>
15:12	<i>reserved (0)</i>
11:0	I/O APIC Base Address. This field specifies the A[31:20] portion of the I/O APIC Space's base address, in 1 MB increments. The A[43:32] and A[19:0] portions of the address are zero.

3.3.26 MAR[6:0]: Memory Attribute Region Registers

Address Offset:	61-67h	Size:	8 bits each
Default Value:	03h for MAR[0] 00h for all others	Attribute:	Read/Write

Seven Memory Attribute Region (MAR) registers are used to program memory attributes of various sizes in the 640 Kbyte-1 MByte address range. Each MAR register controls two segments, typically 16 Kbyte in size. Each of these segments has an identical 4-bit field which specifies the memory attributes for the segment, and apply to both host-initiated accesses and PCI-initiated accesses to the segment.

Bits	Description
7:6	<i>reserved (0)</i>
5	Segment 1, Write Enable (WE). When cleared, host-initiated write accesses are directed to the compatibility PCI bus. When set, write accesses are handled normally according to the outbound access disposition.
4	Segment 1, Read Enable (RE). When cleared, host-initiated read accesses are directed to the compatibility PCI bus. When set, read accesses are handled normally according to the outbound access disposition.
3:2	<i>reserved (0)</i>
1	Segment 0, Write Enable (WE). Identical to segment 1 WE, above.
0	Segment 0, Read Enable (RE). Identical to segment 1 RE, above.

Table 3-2 summarizes the possible outcomes of the various Read Enable (RE) and Write Enable (WE) combinations:

Table 3-2: MAR-controlled Access Disposition

WE, RE	Outbound		Outbound locked		Inbound	
	Write	Read	Write	Read	Write	Read
00	PCI 0a	PCI 0a	PCI 0a	PCI 0a	unclaimed	unclaimed
01	PCI 0a	Memory ¹	PCI 0a	PCI 0a	unclaimed	Memory ²
10	Memory ¹	PCI 0a	PCI 0a	PCI 0a	Memory ²	unclaimed
11	Memory ¹	Memory ¹	Memory ¹	Memory ¹	Memory ²	Memory ²

1. Normally, the access will be directed to the DRAM. However, if this MAR region is overlapped by an enabled expansion gap, the access will instead be left unclaimed on the system bus. A third-party agent may then claim the access.
2. Normally, the access will be directed to the DRAM. However, if this MAR region is overlapped by an enabled expansion gap, the access will instead be directed up to the system bus. A third-party agent may then claim the access.

3.3.29 MMBASE: Memory-Mapped PCI Base

Address Offset:	70-71h	Size:	16 bits
Default Value:	0002h	Attribute:	Read/Write

The MMBASE register defines the starting address of the Memory-Mapped PCI Space, and each MMR register defines the highest address to be directed to a PCI bus.

If PXB 0 is operating in 64-bit bus mode, MMR[0] must equal MMBASE.

If PXB 1 is operating in 64-bit bus mode, MMR[3] must equal MMR[2].

<u>Bits</u>	<u>Description</u>
-------------	--------------------

15:12	<i>reserved (0)</i>
-------	---------------------

11:0	<p>PCI Space Base Address. This field specifies the A[31:20] portion of the PCI space's base address, in 1MB increments. The A[43:32] and A[19:0] portions of the address are zero.</p>
------	--

3.3.30 MMR[3:0]: Memory-Mapped PCI Ranges

Address Offset:	74-7Bh	Size:	16 bits each
Default Value:	0001h each	Attribute:	Read/Write

These registers define the high addresses for addresses to be directed to the PCI space.

<u>Bits</u>	<u>Description</u>
-------------	--------------------

15:12	<i>reserved (0)</i>
-------	---------------------

11:0	<p>PCI Space Top Address. This field specifies the A[31:20] portion of the PCI space's highest address, in 1 MB increments. The A[43:32] portion of this address is zero, while the A[19:0] portion of this address is FFFFFh.</p>
------	---

3.3.31 PMD[1:0]: Performance Monitoring Data Register

Address Offset:	D8-DCh, E0-E4h	Size:	40 bits each
Default Value:	0000000000h each	Attribute:	Read/Write

Two performance monitoring counters are provided in the MIOC. The PMD registers hold the performance monitoring count values. Each counter can be configured to reload the data when it, or the other counter overflows.

Event selection is controlled by the PME registers, and the action performed on event detection is controlled by the PMR registers. An additional *Performance Counter Master Enable* (PCME) in the MIOC's CONFIG register allows (nearly) simultaneous stopping/starting of all counters in the MIOC and each PXB. The counters cannot be read or written coherently while the counters are running.

Bits **Description**39:0 **Count Value.****3.3.32 PME[1:0]: Performance Monitoring Event Selection**

Address Offset: E8-E9h, EA-EBh Size: 16 bits each

Default Value: 0000h each Attribute: Read/Write

Bits **Description**15 *reserved (0)***14 Count Data Cycles**

1: Count the request length of the selected transaction.

0: Count the selected event

13 *reserved (0)***12:10 Initiating Agent Selection.**

This field qualifies the tracking of bus transactions by limiting event detection to those transactions issued by specific agents.

000	Symmetric Agent 0 (DID=0/000)	100	Any symmetric agent (DID=0/xxx)
001	Symmetric Agent 1 (DID=0/001)	101	Third party agent (DID=1/other)
010	Symmetric Agent 2 (DID=0/010)	110	Intel® 450NX PCIset agent (DID=1/001)
011	Symmetric Agent 3 (DID=0/011)	111	Any agent

9:8 Transaction Destination Selection.

This field qualifies the tracking of bus transactions by limiting event detection to those transactions directed to a specific resource.

00	Any	10	Not Third Party or Memory ¹
01	Main Memory	11	Third party

1. The usual destination in this category is a PCI Target. Also included are Internal CFC/CF8 accesses, Branch trace messages, Interrupt acknowledge, and some special transactions.

7:6 Data Length Selection.

This field qualifies the tracking of bus transactions by limiting event detection to those transactions of a specific length.

00	Any	10	Part-lines or partials
01	Lines	11	<i>reserved</i>

5:0 Event Selection.

This field specifies the basic system bus transaction, system bus signal assertion, or memory event to be monitored.

Individual Bus Transactions

00 0000	Deferred Reply	00 1000	<i>reserved</i>
00 0001	<i>reserved</i>	00 1001	<i>reserved</i>
00 0010	<i>reserved</i>	00 1010	Memory Read Invalidate
00 0011	<i>reserved</i>	00 1011	<i>reserved</i>
00 0100	I/O Read	00 1100	Memory Read Code
00 0101	I/O Write	00 1101	Memory Writeback

00 0110	<i>reserved</i>	00 1110	Memory Read
00 0111	<i>reserved</i>	00 1111	Memory Write
Generic (Grouped) Bus Transactions			
010 000	Any bus transaction	010 100	Any I/O transaction
010 001	Any memory transaction	010 101	Any I/O or memory transactions
010 010	Any memory read	010 110	Any I/O or memory read
010 011	Any memory write	010 111	Any I/O or memory write
Bus Signal Assertions			
011 000	HIT ^{1,2}	011 100	BNR ^{1,2}
011 001	HITM ^{1,2}	011 101	BPRI ²
011 010	RETRY ^{1,2}	011 110	LOCK ²
011 011	DEFER ^{1,2}	011 111	<i>reserved</i>
Memory Hits/Misses			
100 000	Bank was idle ^{1,2}	100 010	Waited for address lines ^{1,2}
100 001	Waited for Row precharge ^{1,2}	100 011	Hit open page ^{1,2}

All other encodings are reserved.

Notes:

1. Counting data cycles is undefined for this selection.
2. The Agent, Destination and Length fields cannot be applied to this selection, and should be programmed to "any".

3.3.33 PMR[1:0]: Performance Monitoring Response

Address Offset: DDh, E5h Size: 8 bits each
 Default Value: 00h each Attribute: Read/Write

The PMR register specifies how the event selected by the corresponding PME register affects the associated PMD register, the BP[1:0] pins, and the INTREQ# pin. Events defined by PME[0] can be driven out BP0 and events defined by PME[1] can be driven out BP1.

Bits **Description**

- 7:6 **Interrupt Assertion**
 Defines how selected event affects INTREQ# assertion. Whenever INTREQ# is asserted, a flag for this counter is set in the Error Status (ERRSTS) register, so that software can determine the cause of the interrupt. This flag is reset by writing the ERRSTS register.
- 0 Selected event does not assert INTREQ#
 - 1 *reserved*
 - 2 Assert INTREQ# pin when event occurs
 - 3 Assert INTREQ# pin when counter overflows
- 5:4 **Performance Monitoring pin assertion**
 Defines how the selected event affects the Performance Monitoring pin for this counter.
- 0 Selected event does not assert this counters PM pin
 - 1 *reserved*
 - 2 Assert this counter's PM pin when event occurs
 - 3 Assert this counter's PM pin when counter overflows

24 SMM Space Locked (D_LCK).

When software writes a 1 to this bit, the hardware will clear the D_OPEN bit, and both D_LCK and D_OPEN then become read only. No application software, except the SMI handler, should violate or change the contents of SMM memory. Default=0.

23:20 SMM Space Size.

This field specifies the size of the SMM RAM space, in 64 KB increments.

0h	64 KB	4h	320 KB	8h	576 KB	Ch	832 KB
1h	128 KB	5h	384 KB	9h	640 KB	Dh	896 KB
2h	192 KB	6h	448 KB	Ah	704 KB	Eh	960 KB
3h	256 KB	7h	512 KB	Bh	768 KB	Fh	1 MB

Default: 0h (64 KB).

19:16 *reserved (0)*

15:0 SMM Space Base Address.

This field specifies the A[31:16] portion of the SMM RAM space base address (A[15:0]=0000h). The space may be relocated anywhere below the 4 GB boundary and the Top of Memory (TOM); however, the base address must be aligned on the next highest power-of-2 natural boundary given the chosen size. Incorrect alignment results in indeterminate operation. Default: 000Ah.

Table 3-3: SMRAM Space Cycles

SMRAM	D_OPEN	D_CODE	D_LCK	SMMEM	Code Fetch	Data Reference	Usage
0	X	X	X	X	Normal ¹	Normal ¹	SMM RAM space is not supported.
1	0	0	X	0	PCI 0a	PCI 0A	Normal SMM usage. Accesses to the SMM RAM space from processors in SMM will access the DRAM. Accesses by processors not in SMM will be diverted to the compatibility PCI bus.
1	0	0	X	1	DRAM	DRAM	
1	0	1	X	0	PCI 0A	PCI 0A	A modification of the normal SMM usage, in which only code fetches are accepted from processors in SMM mode.
1	0	1	X	1	DRAM	PCI 0A	
X	1	1	X	X	Illegal Combination		
1	1	0	0	X	DRAM	DRAM	Full access by any agent to SMM RAM space.

1. SMRAM functions are disabled.

3.3.40 SUBA[1:0]: Bus A Subordinate Bus Number, per PXB

Address Offset: D1h, D4h

Default Value: 00h each

Size: 8 bits each

Attribute: Read/Write

See the description of BUSNO.

3.3.41 SUBB[1:0]: Bus B Subordinate Bus Number, per PXB

Address Offset: D2h, D5h Size: 8 bits each
 Default Value: 00h each Attribute: Read/Write

See the description of BUSNO.

3.3.42 TCAP[0:3]: Target Capacity, per PXB/PCI Port

Address Offset: C0-C2h, C4-C6h Size: 24 bits each
 C8-CAh, CC-CEh
 Default Value: 041082 each Attribute: Read/Write

Each of these registers is programmed by software with the maximum number of transactions and data bytes that the receiving PXB/PCI port can accept for outbound transactions.

Register	Controls outbound transactions to ... if in ...	
	dual 32-bit Bus Mode	64-bit Bus Mode
TCAP[0]	PXB #0 / PCI Bus A	PXB #0
TCAP[1]	PXB #0 / PCI Bus B	N/A
TCAP[2]	PXB #1 / PCI Bus A	PXB #0
TCAP[3]	PXB #1 / PCI Bus B	N/A

NOTE

Setting a value below the listed minimum-allowed value will have unpredictable results, up to and including potential deadlocks requiring a hard reset of the PCIset.

Bits **Description**

23:18 **Outbound Write Transaction Capacity.**
 This field specifies the total number of outbound write transactions, per PXB/PCI port, that can be forwarded and queued by the PXB.
 MIOC maximum: 12 Minimum allowed: 1, 2 or 3 Default= 1

- If no outbound locks are supported, then the minimum is 1.
- If ordinary outbound locks are supported, then the minimum is 2.
- If outbound split locks are supported, then the minimum is 3.

17:12 **Outbound Read Transaction Capacity.**
 This field specifies the total number of outbound read transactions, per PXB/PCI port, that can be forwarded and queued in the PXB.

MIOC maximum: 2 Minimum allowed: 1 Default= 1

11:6 **Outbound Write Data Buffer Capacity.**
 This field specifies the total number of data buffers, per PXB/PCI port, available in the PXB for use by outbound write transactions, in increments of 32 bytes.
 MIOC maximum: 12 Minimum allowed: 2 Default= 2

- 5:0 **Outbound Read Data Buffer Capacity.**
 This field specifies the total number of data buffers, per PXB/PCI port, available in the PXB for use by outbound read transactions, in increments of 32 bytes.
 MIOC maximum: 16 Minimum allowed: 2 Default= 2

3.3.43 TOM: Top of Memory

Address Offset: 50-52h Size: 24 bits
 Default Value: 000FFFh Attribute: Read/Write

Bits **Description**

- 23:0 **Memory Address Ceiling.**
 Represents bits A[43:20] of the highest physical address to be directed toward this node's DRAM. The lower A[19:0] bits of this address are FFFFh.
 Default=000FFFh (4 GB-1).

3.3.44 VID: Vendor Identification Register

Address Offset: 00 - 01h Size: 16 bits
 Default Value: 8086h Attributes: Read Only

Bits **Description**

- 15:0 **Vendor Identification Number.**
 This is a 16-bit value assigned to Intel. Intel VID = 8086h.

3.4 PXB Configuration Space

Each PXB supports two independent PCI buses (Bus "A" and Bus "B"), which can be configured independently. Each PCI bus therefore has its own configuration space. Both configuration spaces are identical. When operating the PXB in 64-bit Bus Mode, only the A-side configuration space is used. The B-side configuration space is not accessible while in 64-bit mode.

Table 3-4 illustrates the PXB/PCI Bus Configuration Space Map.

Table 3-4: PXB Configuration Space ¹

DID		VID		00h					80h		
PCISTS		PCICMD		04h					84h		
CLASS			RID	08h					88h		
HDR	MLT	CLS		0Ch					8Ch		
				10h					90h		
				14h						94h	
				18h							98h
				1Ch							9Ch
				24h							A0h
				28h							A4h
				2Ch							A8h
				30h							ACCh
				34h							B0h
				38h							B4h
				3Ch							B8h
				40h	MTT	CONFIG					
44h	RC	ERRCMD	ERRSTS		ROUTE	TCAP		C0h			
48h	BUFSIZ						TMODE	C4h			
4Ch								C8h			
50h	TOM							CCh			
54h	LXGT	LXGB						D0h			
58h	HXGB							D4h			
5Ch	HXGT							D8h			
60h	MAR2	MAR1	MAR0	GAPEN			PMR0	PMD0	DCh		
64h	MAR6	MAR5	MAR4	MAR3					E0h		
68h	IOABASE						PMR1	PMD1	E4h		
6Ch	SMRAM				PME1	PME0			E8h		
70h	MMBASE								ECh		
74h									F0h		
78h	MMT								F4h		
7Ch			ISA						F8h		
									FCh		

1. The first 64 bytes are predefined in the PCI Specification. All other locations are defined specifically for the component of interest.

- 8 **Outbound Write Around Retried/Partial Read Enable.**
 If set, the PXB allows outbound writes to pass retried or partially completed (i.e., disconnected) outbound reads. This enable *must* be set for Pentium® II Xeon™ processor/Intel® 450NX PCIset systems. Default=1.
- 7 **Burst Write Combining Enable (BWCE).**
 If set, back-to-back sequentially addressed outbound writes may be combined in the outbound write buffers before placement on the PCI bus. When the BWCE is cleared, all outbound write combining is disabled, and each host transaction results in a corresponding transaction on the PCI bus. Default=0.
- 6 **Re-streaming Buffer Enable.**
 If set, the data returned and buffered for a Delayed Inbound Read may be re-accessed following a disconnect. If cleared, following a disconnect, the buffer is invalidated, and a subsequent read to the next location will initiate a new read. Default=0 (Disabled).
- 5:4 **Read Prefetch Size.**
 This field configures the number of Dwords that will be prefetched on Memory Read Multiple commands. Legal values are:
- | | | | |
|----|--------------------------|----|--------------------------|
| 00 | 16 Dwords (2 x 32 bytes) | 10 | 64 Dwords (8 x 32 bytes) |
| 01 | 32 Dwords (4 x 32 bytes) | 11 | <i>reserved</i> |
- The normal selection is 32 Dwords. The 64 Dword selection provides highest performance when the PXB is in 64-bit bus mode. Default=01 (32 Dwords).
- 3 **External Arbiter Enable.**
 This is a read-only bit that selects internal or external arbitration for the PCI bus. The bit reflects the state of the P(A,B)XARB# strapping pin for this bus (A or B). Default=[P(A,B)XARB pin].
- 2 **64-bit Bus Enable.**
 This is a read-only bit that selects whether the PXB operates as two 32-bit PCI buses or a single 64-bit PCI bus. The bit reflects the state of the MODE64# strapping pin. Default=[MODE64# pin].
- 1 **Host/PCI Bus Gearing Ratio.**
 This is a read-only bit that selects the system clock to PCI clock gearing ratio. The bit reflects the state of the GEAR4# strapping pin. This bit should be cleared (i.e., GEAR4# is high, or deasserted), resulting in a system clock/ PCI clock gearing ratio of 3:1. Default=[GEAR4# pin].
- 0 *reserved*

3.4.5 DID: Device Identification Register

Address Offset:	02 - 03h	Size:	16 bits
Default Value:	84CBh	Attributes:	Read Only

<u>Bits</u>	<u>Description</u>
--------------------	---------------------------

15:0	Device Identification Number. The value 84CBh indicates the Intel® 450NX PCIset PXB.
------	--

3.4.6 ERRCMD: Error Command Register

Address Offset: 46h	Size: 8 bits
Default Value: 00h	Attribute: Read/Write

This register provides extended control over the assertion of SERR# beyond the basic controls specified in the PCI-standard PCICMD register.

<u>Bits</u>	<u>Description</u>
--------------------	---------------------------

7	<i>reserved</i>
6	Assert SERR# on Observed Parity Error. If set, the PXB asserts SERR# if PERR# is observed asserted, and the PXB was not the asserting agent.
5	Assert SERR# on Received Data with Parity Error. If set, the PXB asserts SERR# upon receiving PCI data with a parity error. This occurs regardless of whether PXB asserts its PERR# pin.
4	Assert SERR# on Address Parity Error. If set, the PXB asserts SERR# on detecting a PCI address parity error.
3	Assert PERR# on Data Parity Error. If set, and the PERRE bit is set in the PCICMD register, the PXB asserts PERR# upon receiving PCI data with parity errors.
2	Assert SERR# On Inbound Delayed Read Time-out. Each inbound read request that is accepted and serviced as a delayed read will start a watchdog timer (2 ¹⁵ cycles). If this enable is set, the PXB will assert SERR# if the data has been returned and the timer expires before the requesting master initiates its repeat request. Default=0.
1	Assert SERR# on Expander Bus Parity Error. If set, the PXB asserts SERR# upon detecting a parity error on packets arriving from the Expander bus. (Note that SERR# will be asserted on <i>both</i> PCI buses).
0	Return Hard Fail Upon Generating Master Abort. If set, the PXB will return a Hard Fail response through the MIOC to the system bus after generating a master abort time-out for an outbound transaction placed on the PCI bus. If cleared, the PXB will return a normal response (with data of all 1's for a read). In either case, an error flag is set in the PCISTS register. Default=0.

3.4.12 IOABASE: I/O APIC Base Address

Address Offset:	68-69h	Size:	16 bits
Default Value:	0FECh	Attribute:	Read/Write

This register defines the base address of the 1MB I/O APIC Space address range. IOABASE applies to both host-initiated transactions and PCI-initiated inbound transactions, and is therefore duplicated in both the MIOC and PXB Configuration Spaces. Software must ensure that both sets are programmed identically to achieve correct functioning. See the MIOC Configuration Space for a detailed description.

3.4.13 ISA: ISA Space

Address Offset:	7Ch	Size:	8 bits
Default Value:	00h	Attribute:	Read/Write

This register defines the ISA Space address range. The register applies to both host-initiated transactions and PCI-initiated inbound transactions, and is therefore duplicated in both the MIOC and PXB Configuration Spaces. Software must ensure that both sets are programmed identically to achieve correct functioning. See the MIOC Configuration Space for a detailed description.

3.4.14 LXGB: Low Expansion Gap Base

Address Offset:	54-55h	Size:	16 bits
Default Value:	0000h	Attribute:	Read/Write

This register defines the starting address of the Low Expansion Gap (LXG). LXGB register applies to both host-initiated transactions and PCI-initiated inbound transactions, and is therefore duplicated in both the MIOC and PXB Configuration Spaces. Software must ensure that both sets are programmed identically to achieve correct functioning. See the MIOC Configuration Space for a detailed description.

3.4.15 LXGT: Low Expansion Gap Top

Address Offset:	56-57h	Size:	16 bits
Default Value:	0000h	Attribute:	Read/Write

LXGT defines the highest address of the Low Expansion Gap (LXG), above. This register applies to both host-initiated transactions and PCI-initiated inbound transactions, and is therefore duplicated in both the MIOC and PXB Configuration Spaces. Software must ensure that both sets are programmed identically to achieve correct functioning. See the MIOC Configuration Space for a detailed description.

3.4.16 MAR[6:0]: Memory Attribute Region Registers

Address Offset:	61-67h	Size:	8 bits each
Default Value:	03h for MAR[0] 00h for all others	Attribute:	Read/Write

The Intel 450NX PCIset allows programmable memory attributes on 14 memory segments of various sizes in the 640 Kbyte to 1 MByte address range. Seven Memory Attribute Region (MAR) registers are used to support these features. These registers apply to both host-initiated transactions and PCI-initiated transactions, and are therefore duplicated in both the MIOC and PXB Configuration Spaces. Software must ensure that both sets are programmed identically to achieve correct functioning. See the MIOC Configuration Space for a detailed description.

3.4.17 MLT: Master Latency Timer Register

Address Offset:	0Dh	Size:	8 bits
Default Value:	00h	Attribute:	Read/Write

MLT is an 8-bit register that controls the amount of time (measured in PCI clocks) the Intel 450NX PCIset, as a bus master, can burst data on the PCI Bus. The Count Value is an 8 bit quantity; however, MLT[2:0] are reserved and assumed to be 0 when determining the Count Value. The number of clocks programmed in the MLT represents the guaranteed time slice allotted to the Intel 450NX PCIset, after which it must complete the current data transfer phase and then surrender the bus as soon as its bus grant is removed.

Bits **Description**

7:3 **Master Latency Timer Count Value.**
Counter value in 8 PCI clock units.

2:0 *reserved (0)*

3.4.18 MMBASE: Memory-Mapped PCI Base

Address Offset:	70-71h	Size:	16 bits
Default Value:	0002h	Attribute:	Read/Write

The MMBASE register specifies the starting address of this memory-mapped PCI range, and is identical to the MMBASE register in the MIOC. The MMT register specifies the highest address that will be directed to PCI Bus #1B, and corresponds identically to the MMR[3] register in the MIOC. The MMBASE register must be programmed identically to the MMBASE register in the MIOC to achieve correct functioning. See the MIOC Configuration Space for a detailed description.

- 7 **Address/Data Stepping.**
The PXB does not support address/data stepping, and this bit is hardwired to 0.
- 6 **Parity Error Response (PERRE).**
If PERRE is set, the PXB will report parity errors on data received by asserting the PERR# signal. Address parity errors are not reported using PERR#, but instead through the SERR# signal, and only if both PERRE and SERRE are set. If PERRE is cleared, then PCI parity errors are not reported by the PXB. Default=0.
- 5 *reserved (0)*
- 4 **Memory Write and Invalidate Enable.**
Selects whether the PXB, as a PCI master, can generate Memory Write and Invalidate cycles. Default=1.
- 3 **Special Cycle Enable.**
The PXB will ignore all special cycles generated on the PCI bus, and this bit is hardwired to 0.
- 2 **Bus Master Enable.**
The PXB does not permit disabling of its bus master capability, and this bit is hardwired to 1.
- 1 **Memory Access Enable.**
The PXB does not permit disabling access to main memory, and this bit is hardwired to 1.
- 0 **I/O Access Enable.**
The PXB does not respond to PCI I/O cycles, and this bit is hardwired to 0.

3.4.22 PCISTS: PCI Status Register

Address Offset: 06 - 07h Size: 16 bits
Default Value: 0280h Attribute: Read/Write Clear, Sticky

This is a PCI specification required register, with a fixed format.

Bits Description

- 15 **Parity Error (PE).**
This bit is set when the PXB detects a parity error in data or address on the PCI bus. This bit remains set until explicitly cleared by software writing a 1 to this bit. Default=0.
- 14 **Signaled System Error (SSE).**
This bit is set when the PXB asserts the SERR# signal. This bit remains set until explicitly cleared by software writing a 1 to this bit. Default=0.

- 13 **Received Master Abort (RMA).**
 This bit is set when the PXB, as bus master, terminates its transaction (except for Special Cycles) with a master abort. This bit remains set until explicitly cleared by software writing a 1 to this bit.
 Default=0.
- 12 **Received Target Abort (RTA).**
 This bit is set when the PXB, as bus master, receives a target abort for its transaction. This bit remains set until explicitly cleared by software writing a 1 to this bit.
 Default=0.
- 11 **Signaled Target Abort (STA).**
 This bit is set when the PXB, as bus target, terminates a transaction with target abort. This bit remains set until explicitly cleared by software writing a 1 to this bit.
 Default=0.
- 10:9 **DEVSEL# Timing (DEVT).**
 This 2-bit field encodes the timing of the DEVSEL# signal when the PXB responds as a target, and represents the slowest time that the PXB asserts DEVSEL# for any bus command except Configuration Reads or Writes. This field is hardwired to the value 01b (medium).
- 8 **Data Parity Error (DPE).**
 This bit is set when all of the following conditions are met:
 1. The PXB asserted PERR# or sampled PERR# asserted.
 2. The PXB was the initiator for the operation in which the error occurred.
 3. The PERRE bit in the PCICMD register is set.
 This bit remains set until explicitly cleared by software writing a 1 to this bit.
 Default=0.
- 7 **Fast Back-to-Back (FB2B).**
 The PXB supports fast back-to-back transactions, and this bit is hardwired to 1.
- 6 **UDF Supported.**
 The PXB does not support User Definable Features (UDF), and this bit is hardwired to 0.
- 5 **66 MHz Capable.**
 The PXB is not capable of running at 66 MHz, and this bit is hardwired to 0.
- 4:0 *reserved (0)*

3.4.23 PMD[1:0]: Performance Monitoring Data Register

Address Offset:	D8-DCh, E0-E4h	Size:	40 bits each
Default Value:	000000000000h each	Attribute:	Read/Write

Two performance monitoring counters, with associated event selection and control registers, are provided for each PCI bus in the PXB. The PMD registers hold the performance monitoring count values. Event selection is controlled by the PME registers, and the action performed on event detection is controlled by the PMR registers.

Bits **Description**39:0 **Count Value.****3.4.24 PME[1:0]: Performance Monitoring Event Selection**Address Offset: E8 - EBh
Default Value: 0000h eachSize: 16 bits each
Attribute: Read/Write**Bits** **Description**15 *reserved (0)***14 Count Data Cycles**1: Count the data cycles associated with the selected transactions.
0: Count the selected event**13:10 Initiating Agent Selection.**

This field qualifies the tracking of bus transactions by limiting event detection to those transactions issued by specific agents.

0000	Agent 0	1000	<i>reserved</i>
0001	Agent 1	1001	<i>reserved</i>
0010	Agent 2	1010	<i>reserved</i>
0011	Agent 3	1011	<i>reserved</i>
0100	Agent 4	1100	<i>reserved</i>
0101	Agent 5	1101	south bridge
0110	<i>reserved</i>	1110	Intel® 450NX PCIset agent (i.e., outbound)
0111	<i>reserved</i>	1111	Any agent

Note: This field is applicable only if the PCI bus is operated in internal arbiter mode. If the bus is operated using an external arbiter, this field must be set to *Any Agent* to trigger any events.**9:8 Transaction Destination Selection.**

This field qualifies the tracking of bus transactions by limiting event detection to those transactions directed to a specific resource.

00	Any	10	PCI Target
01	Main Memory	11	Third party

7:6 *reserved*

5:0 **Event Selection.**

This field specifies the basic PCI bus transaction or PCI bus signal to be monitored.

Individual Bus Transactions

00 0000	<i>reserved</i>	00 1000	<i>reserved</i>
00 0001	<i>reserved</i>	00 1001	<i>reserved</i>
00 0010	I/O Read	00 1010	<i>reserved</i>
00 0011	I/O Write	00 1011	<i>reserved</i>
00 0100	<i>reserved</i>	00 1100	Memory Read Multiple
00 0101	<i>reserved</i>	00 1101	Dual Address Cycle
00 0110	Memory Read	00 1110	Memory Read Line
00 0111	Memory Write	00 1111	Memory Write & Invalidate

Generic (Grouped) Bus Transactions

010 000	Any bus transaction	010 100	Any I/O transaction
010 001	Any memory transaction	010 101	Any I/O or memory transactions
010 010	Any memory read	010 110	Any I/O read or memory read
010 011	Any memory write	010 111	Any I/O read or memory write

Bus Signal Assertions

011 000	<i>reserved</i>	011 100	<i>reserved</i>
011 001	<i>reserved</i>	011 101	<i>reserved</i>
011 010	RETRY ¹	011 110	LOCK
011 011	<i>reserved</i>	011 111	ACK64

All other encodings are reserved.

Note:

1. Counting data cycles is undefined for this selection.

3.4.25 PMR[1:0]: Performance Monitoring Response

Address Offset: DDh, E5h Size: 8 bits each
 Default Value: 0000h each Attribute: Read/Write

There are two PMR registers for each PCI bus, one for each PMD counter. Each PMR register specifies how the event selected by the corresponding PME register affects the associated PMD register, P(A,B)MON# pins, and the INT(A,B)RQ# pins.

Bits	Description
-------------	--------------------

7:6 **Interrupt Assertion**

Defines how selected event affects INTRQ# assertion. Whenever INTRQ# is asserted, a flag for this counter is set in the Error Status Register, so that software can determine the cause of the interrupt. This flag is reset by writing the Error Status Register.

- | | |
|---|--|
| 0 | Selected event does not assert INTRQ # |
| 1 | <i>reserved</i> |
| 2 | Assert INTRQ# pin when event occurs |
| 3 | Assert INTRQ# pin when counter overflows |

5:4 **Performance Monitoring pin assertion**

Defines how the selected event affects the PMON# pin for this counter.

- | | |
|---|---|
| 0 | PMON# pin is tristated. Selected event has no effect. |
| 1 | <i>reserved</i> |

3. Register Descriptions

- 2 Assert this counter's PMON# pin when event occurs
- 3 Assert this counter's PMON# pin when counter overflows

3:2 Count Mode

Selects when the counter is updated for the detected event.

- 0 Stop counting.
- 1 Count each cycle selected event is active.
- 2 Count on each rising edge of the selected event.
- 3 Trigger. Start counting on the first rising edge of the selected event, and continue counting each clock cycle.

1:0 Reload Mode

Reload has priority over increment. That is, if a reload event and a count event happen simultaneously, the count event has no effect.

- 0 Never reload
- 1 Reload when this counter overflows.
- 2 Reload when the other counter overflows.
- 3 Reload unless the other counter increments.

3.4.26 RID: Revision Identification Register

Address Offset: 08h
Default Value: 00h

Size: 8 bits
Attribute: Read Only

<u>Bits</u>	<u>Description</u>
-------------	--------------------

7:0	Revision Identification Number.
-----	--

This is an 8-bit value that indicates the revision identification number for the PXB. These bits are read only and writes to this register have no effect.

3.4.27 RC: Reset Control Register

Address Offset: 47h
Default Value: 01h

Size: 8 bits
Attribute: Read/Write/Sticky

The RC register controls the response of the PXB to XRST#.

<u>Bits</u>	<u>Description</u>
-------------	--------------------

7:1	<i>reserved (0)</i>
-----	---------------------

0	Reset PCI clocks on XRST#
---	----------------------------------

Clearing this bit enables PCICLK A and PCICLK B to run undisturbed through reset. When set, PCI clock phase will be reset whenever XRST# is asserted. When clear, System Hard Resets, PXB Resets, Soft Resets, BINIT Resets will not disturb PCICLK A and PCICLK B. This bit is defined to be sticky so that it can only be modified by PWRGD or configuration write. Default=1.

and the Top of Memory (TOM); however, the base address must be aligned on the next highest power-of-2 natural boundary given the chosen size. Incorrect alignment results in indeterminate operation.

Default: 000Ah (representing a base address of A0000h)

3.4.30 TCAP: Target Capacity

Address Offset: C0-C2h Size: 24 bits
 Default Value: 041082h Attribute: Read/Write

This register is programmed with the maximum number of transactions and data bytes that the receiving MIOC can accept from this PXB/PCI port for inbound transactions. The MIOC space has a set of four similar TCAP registers, one per PXB/PCI bus, that is programmed with the transaction and data limits for *outbound* transactions.

If the PXB is in 32-bit bus mode, divide the MIOC BUFSIZ limits in half. If the PXB is in 64-bit bus mode, the full MIOC BUFSIZ limits can be used, except in either case, the PXB's maximum values (shown below) cannot be exceeded.

Bits Description

- 23:18 **Inbound Write Transaction Capacity.**
 This field specifies the total number of inbound write transactions that can be forwarded and enqueued in the MIOC from this PXB/PCI port.
- | | | | |
|------------|-----------------|--------------------|------------|
| 32-bit Bus | PXB maximum: 6 | Minimum allowed: 1 | Default= 1 |
| 64-bit Bus | PXB maximum: 12 | Minimum allowed: 1 | Default= 1 |
- 17:12 **Inbound Read Transaction Capacity.**
 This field specifies the total number of inbound read transactions that can be forwarded and enqueued in the MIOC from this PXB/PCI port.
- | | | | |
|------------|----------------|--------------------|------------|
| 32-bit Bus | PXB maximum: 2 | Minimum allowed: 1 | Default= 1 |
| 64-bit Bus | PXB maximum: 2 | Minimum allowed: 1 | Default= 1 |
- 11:6 **Inbound Write Data Buffer Capacity.**
 This field specifies the total number of data buffers available in the MIOC for use by inbound write transactions from this PXB/PCI port, in increments of 32 bytes.
- | | | | |
|------------|-----------------|--------------------|------------|
| 32-bit Bus | PXB maximum: 6 | Minimum allowed: 2 | Default= 2 |
| 64-bit Bus | PXB maximum: 12 | Minimum allowed: 2 | Default= 2 |
- 5:0 **Inbound Read Data Buffer Capacity.**
 This field specifies the total number of data buffers available in the MIOC for use by inbound read transactions from this PXB/PCI port, in increments of 32 bytes.
- | | | | |
|------------|-----------------|--------------------|------------|
| 32-bit Bus | PXB maximum: 8 | Minimum allowed: 2 | Default= 2 |
| 64-bit Bus | PXB maximum: 16 | Minimum allowed: 2 | Default= 2 |

3.4.31 TMODE: Timer Mode

Address Offset: C4h Size: 8 bits
 Default Value: 00h Attribute: Read/Write

This register allows nominally fixed-duration timers to be adjusted to shorter values for test purposes.

<u>Bits</u>	<u>Description</u>
-------------	--------------------

7:2	<i>reserved (0)</i>
-----	---------------------

1:0	Delayed Read Request Expiration Counter.
-----	---

This counter is strictly for test purposes. Changing it from the default value is a violation of the PCI specification.

00	normal mode (2^{15} clocks)
01	128 clocks
10	64 clocks
11	16 clocks

3.4.32 TOM: Top of Memory

Address Offset: 50-52h
Default Value: 000FFFh

Size: 24 bits
Attribute: Read/Write

This register specifies the highest physical address that could be directed to the memory. This register applies to both host-initiated transactions and PCI-initiated inbound transactions, and is therefore duplicated in both the MIOC and PXB Configuration Spaces. Software must ensure that both sets are programmed identically to achieve correct functioning. See the MIOC Configuration Space for a detailed description.

3.4.33 VID: Vendor Identification Register

Address Offset: 00 - 01h
Default Value: 8086h

Size: 16 bits
Attributes: Read Only

<u>Bits</u>	<u>Description</u>
-------------	--------------------

15:0	Vendor Identification Number.
------	--------------------------------------

This is a 16-bit value assigned to Intel. Intel VID = 8086h.

4.1 Memory Address Map

A Pentium® II Xeon™ processor system based on the Intel® 450NX PCIset supports up to 64 GBytes of addressable memory space. Within this memory address range the Intel 450NX PCIset has two structured compatibility regions, two expansion gaps, and two general purpose memory-mapped I/O spaces, as illustrated in Figure 4-1. The two compatibility regions are the 1 MB Low Compatibility Region at the bottom of the address space, and the 20 MB High Compatibility Region just below the 4 GB boundary. The two expansion gaps allow holes to be opened in the address space, where accesses can be directed to the PCI buses or to a third-party agent, instead of to memory. The two I/O spaces allow control over which addresses are forwarded to each of the four PCI buses supported by the Intel 450NX PCIset.

Spaces and Gaps

The Intel 450NX PCIset memory address map is based on *spaces* and *gaps*.

A *space* is an address range where the access is directed to a specific destination, usually (but not always) a PCI bus. Any DRAM behind the space is not reclaimed, unless it is also covered by a gap (described below). The Intel 450NX PCIset supports a variety of spaces with fixed or configurable address ranges and individual enables.

A *gap* is a memory-mapped address range where the access is specifically *not* directed to DRAM. The DRAM behind the gap is reclaimed; that is, the effective address presented to the memory has the gaps subtracted from it, presenting a contiguous address space to the memory. The gap does not control where the access is directed. Accesses may be directed through an overlapping space, or left unclaimed on the system bus for a third-party agent to claim. In typical maps, large spaces will be contained within gaps, to reclaim the DRAM that would otherwise be wasted. The Intel 450NX PCIset supports two configurable gaps.

Low Compatibility Region

The Low Compatibility Region spans the first 1 MB address range (0h to F_FFFFh). This region is divided into five subregions, some of which are further subdivided.

- The 640 KB DOS Region is split into a 512 KB DOS area (memory only) and a 128 KB ISA Window, which can be mapped to either main memory or the PCI memory.
- The 128 KB Graphics Adapter Memory is normally mapped to a video device on the PCI bus, typically a VGA controller. This region is also the default location of the configuration SMM RAM space.

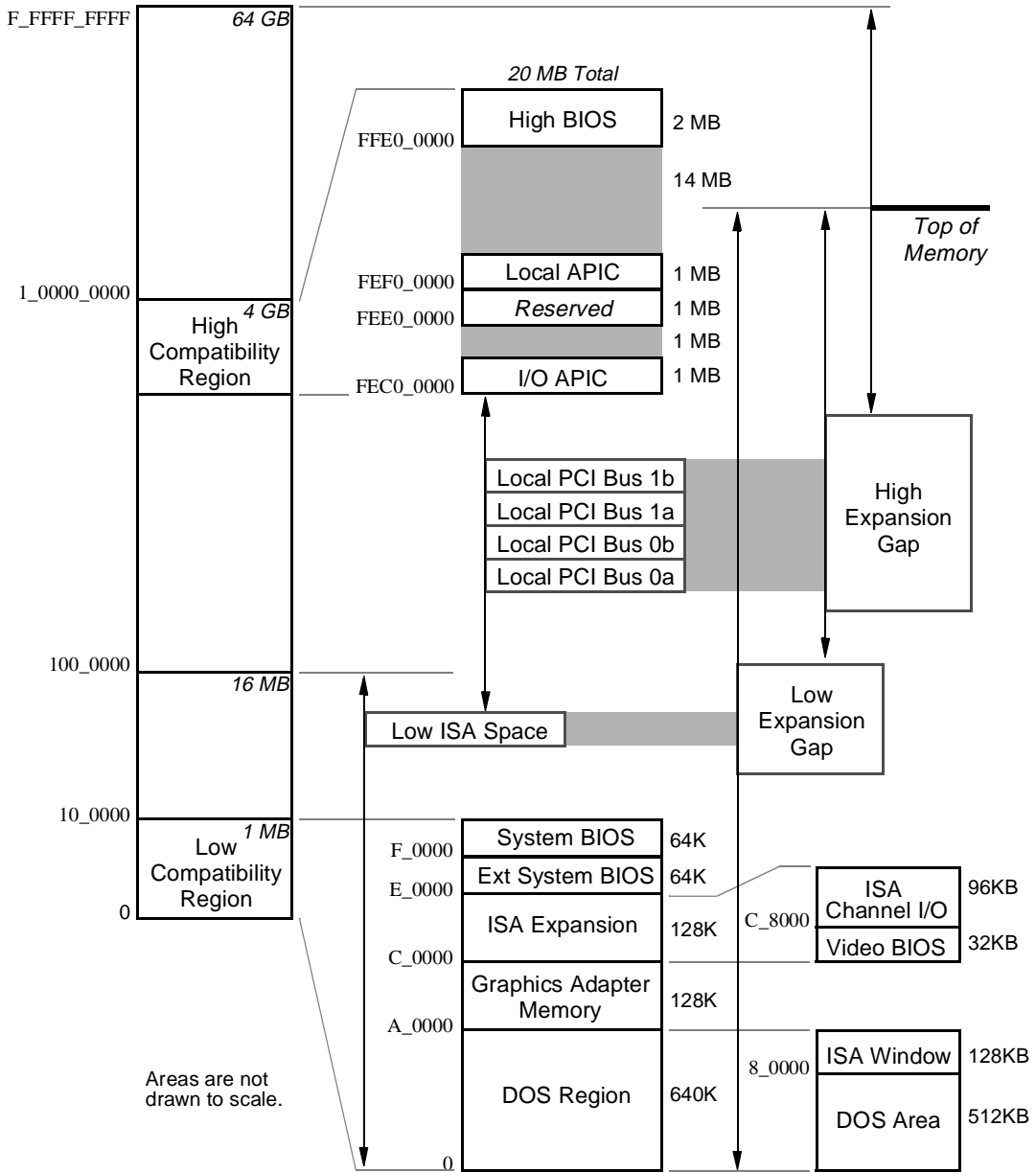


Figure 4-1: System Memory Address Space

- The 128 KB ISA Expansion Region is divided into eight 16 KB blocks that can be independently configured for read/write accessibility. Typically, these blocks are mapped through the PCI bridge to ISA space. Memory that is disabled is not remapped. Traditionally, the lower 32 KB contains the video BIOS located on a video card, and the upper 96 KB is made available to expand memory windows in 16 KB blocks depending on the requirements of other channel devices in the corresponding ISA space.
- The 64 KB Extended System BIOS Region is divided into four 16 KB blocks and may be mapped either to memory or the compatibility PCI bus. Typically, this area is used for RAM or ROM. Selecting appropriate read/write attributes for this region allows the BIOS to be “shadowed” into RAM.

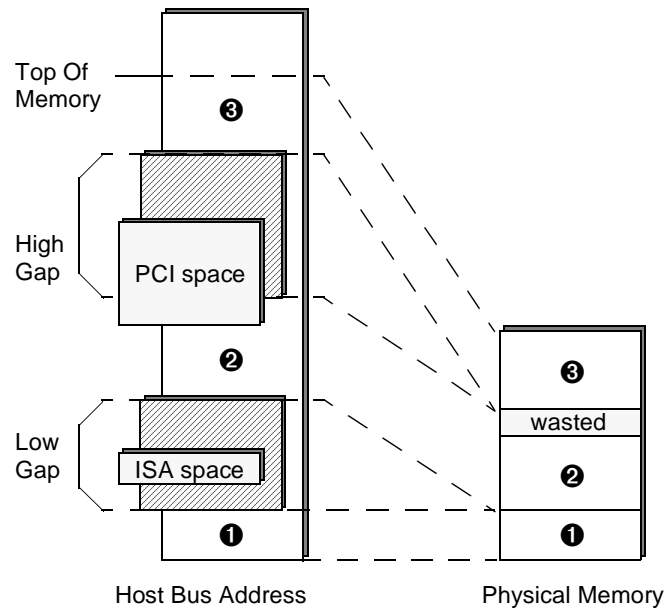


Figure 4-2: Gaps, Spaces and Reclaiming Physical Memory

- The 64 KB System BIOS Region is treated as a single block and is normally mapped to the compatibility PCI bus. Selecting appropriate read/write attributes for this region allows the BIOS to be “shadowed” into RAM. After power-on reset, the Intel® 450NX PCIset has this area configured to direct accesses to PCI memory, allowing fetches from the boot ROM during system initialization.

High Compatibility Region

The High Compatibility Region spans 20 MB immediately below the 4 GB address boundary (address range FEC0_0000h to FFFF_FFFFh). This region supports four fixed spaces with predefined functions for compatibility with PC-based systems.

- The 2 MB High BIOS Space is where the processor begins execution after reset. Following power-on, the Intel® 450NX PCIset has this space enabled; accesses will be directed to the compatibility PCI bus. If an ISA bridge is also used, this area is then aliased by the ISA bridge to the top of the ISA address range (14-16 MB). If this space is disabled, accesses will be directed to memory (unless superseded by an expansion gap.)
- The 1 MB Local APIC Space is reserved for use by the processor. In Pentium® II Xeon™ processors, this contains the default local APIC space (which can be remapped to the I/O APIC space, below). Accesses to this region will not be claimed by the Intel 450NX PCIset. *No resources should be mapped to this region.*
- The 1 MB Reserved Space is defined for future use. *No resources should be mapped to this region.*
- The 1 MB I/O APIC Configuration Space provides an area where I/O APIC units in the system can be mapped, and the I/O APICs within the processors can be remapped for consistency of access. At least one I/O APIC must be included in an Intel 450NX PCIset-based system. The I/O APIC space may be relocated anywhere in the 4 GB boundary.

Top of Memory and Expansion Gaps

A “Top of Memory” pointer identifies the highest memory-mapped address that can be serviced by this node. Accesses to addresses above this pointer will not be directed to local memory or the PCI buses, but will be allowed to sit unclaimed on the system bus. A third-party agent on the system bus may claim such accesses, either servicing them with its own local resources or forwarding them to other nodes for service (i.e., a cluster bridge). Any access that remains unclaimed will eventually timeout in the Intel 450NX PCIset; on timeout the access is claimed by the Intel 450NX PCIset and terminated.

Below the Top of Memory, there are two programmable expansion gaps: the Low Expansion Gap and the High Expansion Gap. Each gap, if enabled, opens a “hole” in the physical address space, where accesses will not be directed to memory. Instead, these accesses may be directed to one of the PCI buses, or will be allowed to sit unclaimed on the system bus where they may be claimed by a third-party agent, as above.

Both expansion gaps are defined using base and top addresses, on 1MB boundaries. The Low Expansion Gap must be located *above* the Low Compatibility Region, and *below* the High Expansion Gap, the 4 GB boundary, and the Top of Memory. The High Expansion Gap must be located *above* the enabled Low Expansion Gap, *above* 1MB, and *below* the Top of Memory. At power-on, both gaps are disabled.

4.1.1 Memory-Mapped I/O Spaces

The Intel[®] 450NX PCIset provides two programmable I/O spaces: the Low ISA Space and the PCI Space. Both spaces allow accesses to be directed to a PCI bus. Any region defined as memory-mapped I/O must have a UC (UnCacheable) memory type, set in the Pentium II Xeon processor’s MTTR registers.

Low ISA Space

The Low ISA Space is provided to support older ISA devices which cannot be relocated above the 16 MB address limit of older systems. Accesses to this space will be directed down to the compatibility PCI bus (0A). The Low ISA Space can start on any 1 MB boundary below 16 MB, and can be of size 1, 2, 4 or 8 MB.

PCI Space

The PCI Space consists of four contiguous address ranges, allowing accesses to be directed to each of the four PCI buses supported by the Intel 450NX PCIset. Each address range corresponds to a PCI bus, and is configurable on 1 MB boundaries.

4.1.2 SMM RAM Support

Intel Architecture processors include a System Management Mode (SMM) that defines a protected region of memory called SM RAM. The Intel 450NX PCIset allows an SM RAM region to be defined and enabled. When enabled, memory reads and writes to addresses that fall within the SM RAM address range are protected accesses. If the configuration enables permit access, and the requesting agent asserts SMMEM# (privileged access), the MIOC will

direct the access to DRAM. Otherwise, the access will be forwarded to the compatibility PCI bus. If SMM is not enabled in the Intel 450NX PCIset, accesses are treated normally.

4.2 I/O Space

The Intel® 450NX PCIset allows I/O accesses to be mapped to resources supported on any of the four PCI buses. The 64KB I/O address range is partitioned into sixteen 4 KB segments which may be partitioned amongst the four PCI buses, as shown in Figure 4-3. Host-initiated accesses that fall within a bus' I/O range are directed to that bus. Segment 0 always defaults to the compatibility PCI bus.

The Intel 450NX PCIset's I/O Range Register defines the mapping of I/O segments to each PCI bus. This is illustrated in Figure 4-3. Accesses that fall within an I/O address range and forwarded to the selected PCI bus, but not claimed by a device on that bus, will time-out and be terminated by the Intel 450NX PCIset.

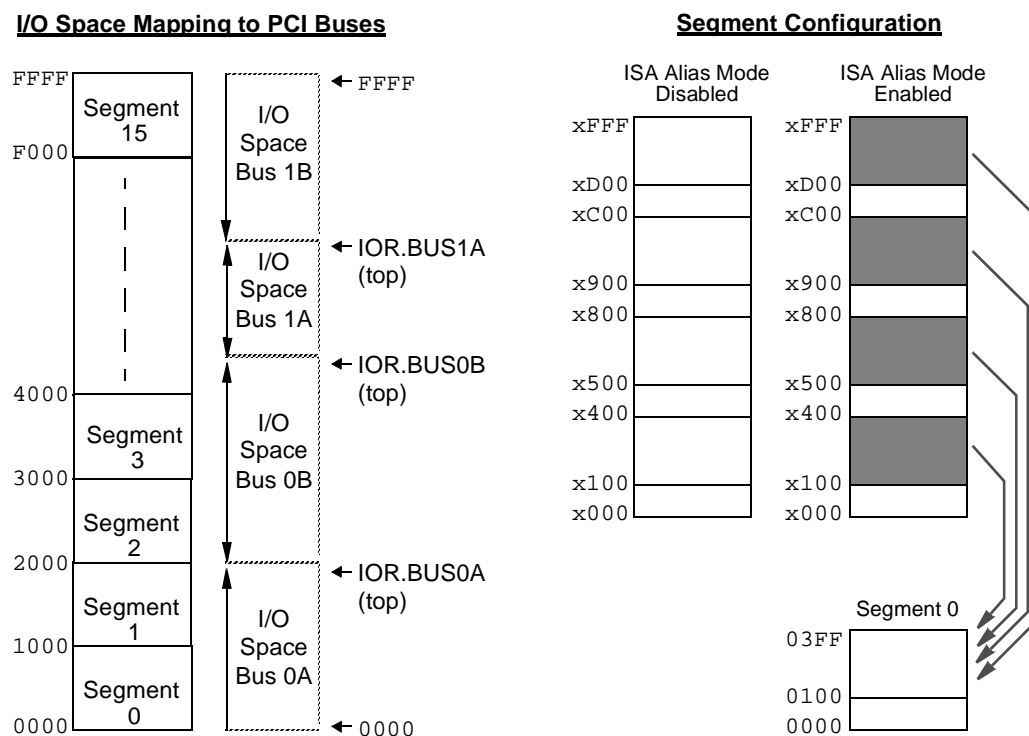


Figure 4-3: I/O Space Address Mapping

The Intel 450NX PCIset optionally supports ISA expansion aliasing, as shown in Figure 4-3. When ISA expansion aliasing is supported, the ranges designated as I/O Expansion are internally aliased to the 0100h-03FFh range in Segment 0 before the normal I/O address range checking is performed. This aliasing is only for purposes of routing to the correct PCI bus. The address that appears on the PCI bus is unaltered. ISA expansion aliasing is enabled or disabled through the ISA Aliasing Enable bit in the MIOC's CONFIG register.

Restricted-Access Addresses

By default, all Host-PCI I/O writes will be posted. However, in traditional Intel-architecture systems, there are certain I/O addresses to which posting is not desirable, due to ordering side effects. Table 4-1 lists the I/O addresses for which I/O write posting will not be supported, regardless of the posting enable in the MIOC's CONFIG register. These accesses will be deferred instead.

Table 4-1: Non-Postable I/O Addresses

Address	Function
0020h-0021h	8259A Interrupt Controller, Master, Interrupt Masks
0060h-0064h	Keyboard controller: com/status and data
0070h	NMI# Mask
0092h	A20 Gate
00A0h-00A1h	8259A Interrupt Controller, Slave, Interrupt Masks
00F0h	IGNNE#, IRQ13
0CF8h, 0CFCh	PCI configuration space access

4.3 PCI Configuration Space

The Intel® 450NX PCIsset provides a PCI-compatible configuration space for the MIOC, and two in the PXB—one for each PCI bus. I/O reads and writes issued on the system bus are normally claimed by the MIOC and forwarded through the PXBs as I/O reads and writes on the PCI bus. However, I/O accesses to the **0CF8h** and **0CFCh** addresses are defined as special configuration accesses for I/O devices.

Each configuration space is selected using a Bus Number and a Device Number within that bus. PCI buses are numbered in ascending order within hierarchical buses. PCI Bus #0 represents both the compatibility PCI bus as well as the devices in the Intel 450NX PCIsset and any third party agents attached to the system bus.

The MIOC and each PCI bus within each PXB in the system is assigned a unique Device Number on Bus #0, as shown in Table 4-2. The PXBs are numbered based on the Expander bus port used.

Table 4-2: Device Numbers for Bus Number 0^{1 2}

Device Number	Device	Device Number	Device
10h	MIOC	18h	
11h	reserved	19h	
12h	PXB 0, Bus a ³	1Ah	
13h	PXB 0, Bus b	1Bh	

Table 4-2: Device Numbers for Bus Number 0 (Continued)^{1 2}

Device Number	Device	Device Number	Device
14h	PXB 1, Bus a	1Ch	<i>Third Party Agent</i>
15h	PXB 1, Bus b	1Dh	<i>Third Party Agent</i>
16h		1Eh	<i>Third Party Agent</i>
17h		1Fh	n/a ⁴

1. Device numbers 0-15 represent devices actually on the compatibility PCI bus.
2. Shaded columns are defined for future PCIset compatibility.
3. This is the compatibility PCI bus.
4. Bus #0/Device # 31 is used (along with a Function Number of all 1's and a Register Number of all 0's) to generate a PCI Special Cycle. Therefore Bus #0/Device #31 is never mapped to a device.

5.1 System Bus

The host interface of the Intel® 450NX PCIset is targeted toward Pentium® II Xeon™ processor-based multiprocessor systems, and is specifically optimized for four processors sharing a common bus with bus clock frequencies of 100 MHz. The MIOC provides the system bus address, control and data interfaces for the Intel 450NX PCIset, and represents a single electrical load on the system bus.

The Intel 450NX PCIset recognizes and supports a large subset of the transaction types that are defined for the P6 family processor's bus interface. However, each of these transaction types have a multitude of response types, some of which are not supported by this controller. The responses that are supported by the MIOC are: *Normal without Data*, *Normal with Data*, *Retry*, *Implicit Write Back*, *Deferred Response*. Refer to the chapter on Transactions for more details on the transaction types supported by the Intel 450NX PCIset.

5.2 PCI Bus

Each PXB provides two independent 32-bit, 33 MHz Rev. 2.1-compliant PCI interfaces which support 5 volt or 3 volt PCI devices. Each bus will support up to 10 electrical loads, where the PXB and the PIIX4E south bridge each represent one load, and each connector/device pair represents two loads. The internal bus arbiter supports six PCI bus masters in addition to the PXB itself and the south bridge on the compatibility bus. The compatibility bus is always bus #0A (PXB #0, Bus A).

The PCI buses are operated synchronously with the system bus, using the system bus clock as the master clock. A system bus/PCI bus clock ratio of 3:1 supports the Intel Pentium® II Xeon™ processor at 100 MHz with 33.3 MHz PCI bus, or a degraded 90 MHz system bus with a 30 MHz PCI bus (or lower, depending on the effect of the 6th load on the system bus).

A configuration option allows the two 32-bit PCI buses (A and B) on a single PXB to be operated in combination as a single 64-bit PCI bus. Bus A data represents the low Dword, while bus B data represents the high Dword.

5.3 Expander Bus

The Expander Interface provides a bidirectional path for data and control between the PXB and MIOC components. The Expander bus consists of a 16 bit wide data bus which carries command, address, data, and transaction information. There are two additional bits that carry

Byte enable information for data fields. All 18 of these bits are protected by an even parity signal. Two synchronous arbitration signals (one in each direction) are used for each Expander bus.

5.3.1 Expander Electrical Signal and Clock Distribution

The Expander bus is designed to allow multiple high bandwidth I/O ports to be added to the Intel® 450NX PCIsset with minimal impact on signal pin count. The Expander bus also provides flexibility in server system topology by allowing the I/O subsystem to be located away from the main PCIsset. This flexibility is achieved with a signaling scheme that uses a combination of synchronous and source synchronous clocking. This is illustrated in Figure 5-1.

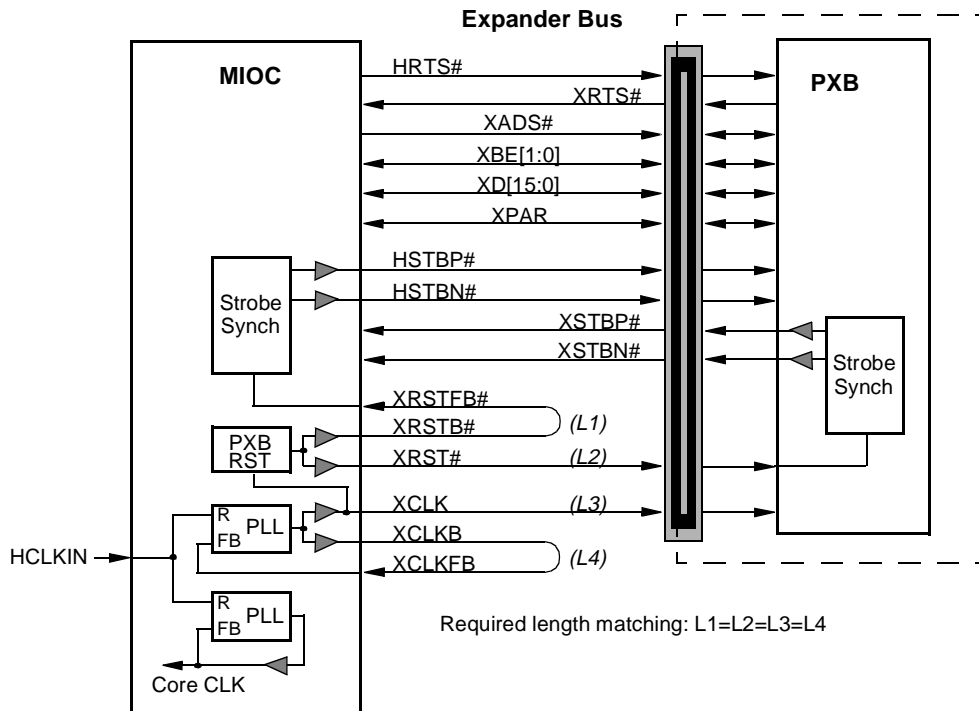


Figure 5-1: Expander Bus Clock Distribution

5.4 Third-Party Agents

In addition to the processors and the Intel® 450NX PCIsset, the Pentium® II Xeon™ processor bus allows for additional bus masters, generically referred to as *third-party agents (TPA)*. These agents may be symmetric agents, in which case they must participate in the bus arbitration algorithm used by the processors. They may also be priority agents, in which case they must negotiate with the Intel 450NX PCIsset for control of the system bus.

The Intel 450NX PCIset supports the same request/grant and third-party control signals originally provided by the Intel 450GX PCIset. These signals are used to exchange priority ownership of the bus between the TPA and the Intel 450NX PCIset. The Intel 450NX PCIset makes no assumptions about the relative priorities between the Intel 450NX PCIset and the TPA, and will grant priority ownership at the next natural transaction boundary. The Intel 450NX PCIset also makes no assumptions about the frequency of TPA requests or the duration of TPA bus ownership; it is the responsibility of the TPA to ensure that its use of the system bus is commensurate with its intended purpose and expected system performance.

5.5 Connectors

Connectors are permitted only for the memory cards and between the MIOC and PXBs. Between MIOC and PXB, some degree of “stretch” distance is possible, with specific distance dependent on the design and medium chosen. Connectors are specifically not permitted between the MIOC and the system bus.

6.1 Overview

The Intel 450NX[®] PCIset's memory subsystem consists of one or two memory cards. Each card is comprised of one RCG component, a DRAM array, and two MUX components. Table 6-1 summarizes the Intel 450NX PCIset's general memory characteristics.

Table 6-1: General Memory Characteristics

DRAM type	Extended Data Out (EDO)
Memory modules	72-bit, single and double high DIMMs
DRAM technologies	16 Mbit and 64 Mbit 50 and 60 nsec 3.3 V
Interleaves	4:1, 2:1 (in bank 0, of card 0)
Memory size	2:1 interleave: 32 MB 4:1 interleave: 64 MB to 8 GB, in 64 MB increments

6.1.1 Physical Organization

The Intel[®] 450NX PCIset supports up to 8 banks of memory, configured across one or two memory cards. Each bank can support up to 1 GB using 64 Mbit double-high DIMMs to provide a total of 8 GB of memory in 8 banks. Each bank can support one or two rows of 2 or 4 interleaves. Each row represents a set of memory devices simultaneously selected by a RAS# signal. Each interleave generates 72 bits (64 data, 8 ECC) of data per row using one DIMM. Four interleaves provide a total of 256 bits of data (32 bytes) which is one cache line for the Pentium[®] II Xeon[™] processor. Data from multiple interleaves are combined by the MUXs to exchange 72 bits of data with the MIOC at an effective rate of one cache line every 30ns (effective rate: 1.067 GB/s) for a 4-way interleaved memory. Figure 6-1 illustrates this configuration.

The RCG and MUX Components

The RCGs generate the signals to control accesses to the main memory DRAMs. The RCG initiates no activity until it receives a command from the MIOC. The maximum number of RCGs per Intel 450NX PCIset system is two. Each RCG controls up to four banks of DRAM. Each bank of memory may consist of one (for single-sided DIMMs) or two (for double-sided or double-high DIMMs) rows. Internally, each RCG component contains four RAS/CAS control units (RCCUs), each dedicated to one bank of DRAM. This is illustrated in Figure 6-2.

Each MUX component has four 36-bit data I/O connections to DRAM (one 18-bit path for each of four possible interleaved quad-words) and one 36-bit data I/O connection to the MD

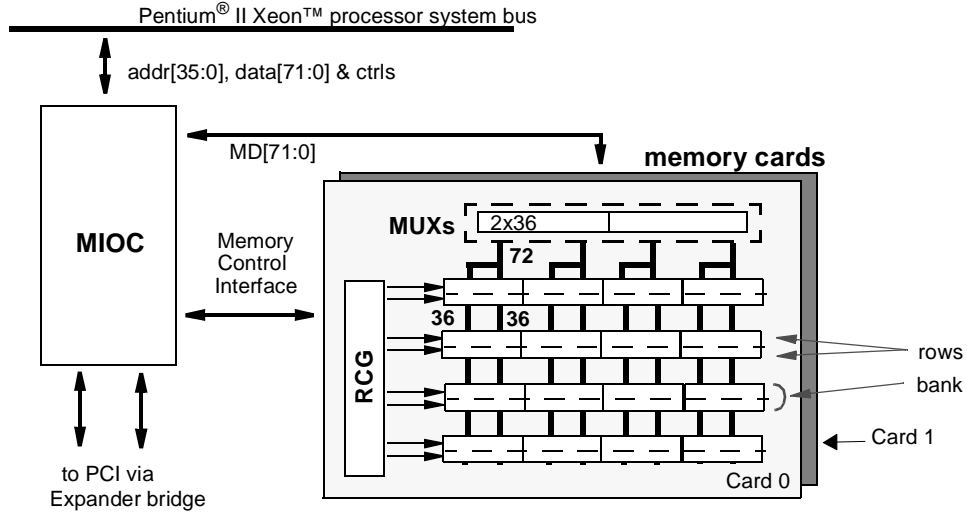


Figure 6-1: Memory Configuration Using 2 Cards

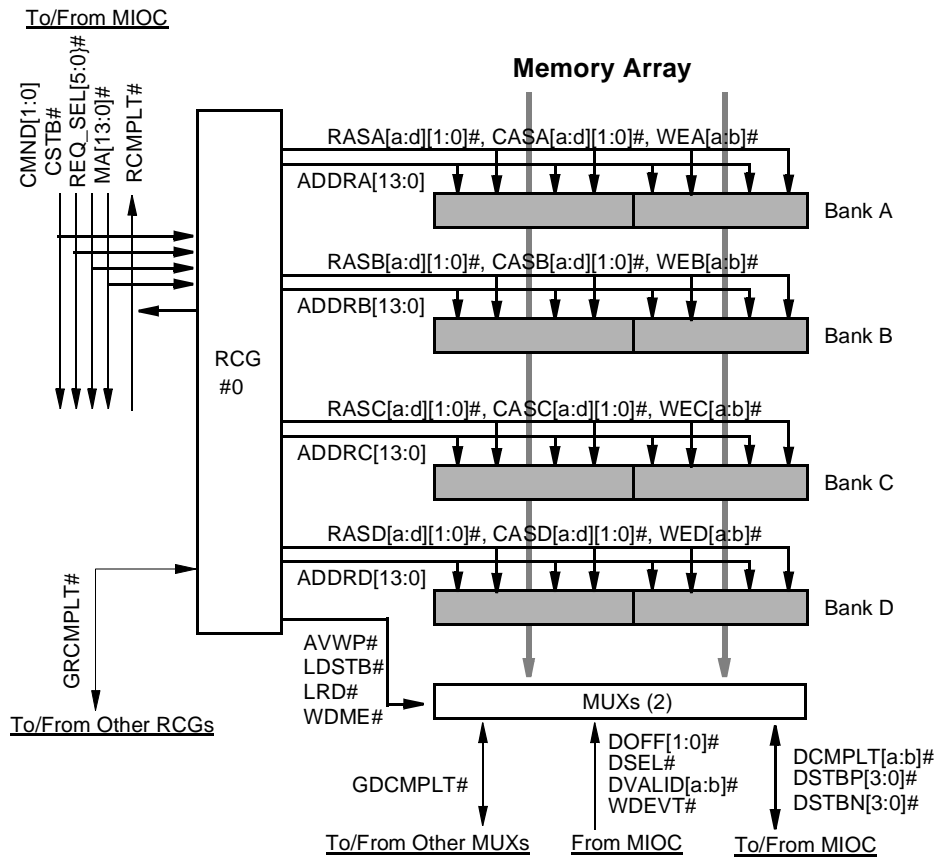


Figure 6-2: Example Showing RCG/MUX Control Signals

bus. There are two MUX components per board to provide a 72-bit data path from each of four possible interleaved quad-words to the MD bus. This is illustrated in Figure 6-3.

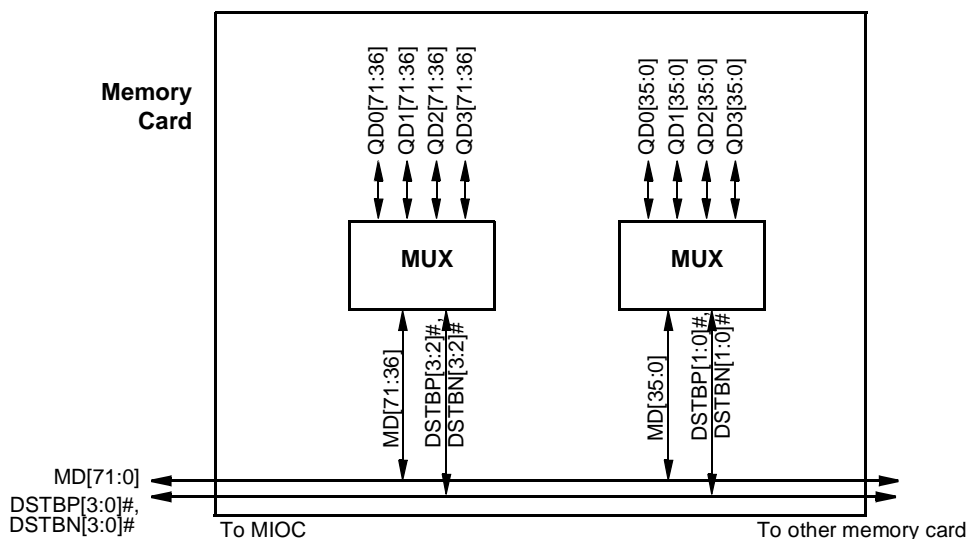


Figure 6-3: Memory Card Datapath

6.1.2 Configuration Rules and Limitations

Memory array configurations are governed by the following rules:

- Either one or two cards can be populated in a working system.
- Any number of memory rows, on either card, can be populated in a working system.
- Memory banks can be populated in any order on either card.
- Cards designed to support 4:1 interleaving will also support 2:1 interleaves (in the first bank only).
- Within any given row, the populated interleaves must have DIMMs of uniform size.
- Memory sizes (16 MB vs. 64 MB) may be mixed within a memory card, but must be the same within a bank.
- Memory speeds (60ns or faster) may be mixed, but all four banks within an RCG operate at the same speed, and must therefore be configured to the slowest DIMM in the set.

6.1.2.1 Interleaving

The Intel 450NX PCIset supports 4:1 interleaving across all banks, and 2:1 interleaving in the first bank of card #0 only. The Intel 450NX PCIset does not support non-interleaved configurations. Interleave configuration register programming must be consistent across the entire memory system. For example, if one bank is configured as 4:1 then the entire memory sub-system must be 4:1 and the associated memory bank configuration registers must be programmed as 4:1.

To support a 4:1 interleave requires two MUXs. Supporting a 2:1 interleave requires only one MUX. A two-MUX design will also support 2:1 interleaves. An entry-level card (i.e., 2:1

interleave) that may be expanded beyond the first bank must therefore be designed using two MUXs.

Table 6-2 gives a summary of the characteristics of memory configurations supported by the Intel 450NX PCIset for 4-way interleaved memory cards.

Table 6-2: Minimum and Maximum Memory Size Per Card

DRAM Technology & Config.		DIMM Size	Addressing			Memory Size for 4-way Interleave		
			Mode	Size row/col		Min (DIMMs)	Max (DIMMs)	Max (Double-high DIMMs)
16M	2M x 8	2M x 72	Asymmetric	11	10	64 MB	256 MB	512 MB
	4M x 4	4M x 72	Symmetric Asymmetric	11 12	11 10	128 MB	512 MB	1 GB
64M	8M x 8	8M x 72	Asymmetric	12	11	256 MB	1 GB	2 GB
	16M x 4	16M x 72	Symmetric Asymmetric	12 13	12 11	512 MB	2 GB	4 GB

6.1.2.2 Address Bit Permuting Rules and Limitations

The Intel 450NX PCIset supports permuting of cache lines across two or four populated banks. For a complete description of the operation of Address Bit Permuting (ABP) see Section 6.1.3.

The following rules and limitations are required for ABP to operate properly.

- All banks must be in 4:1 interleave mode.
- There must be a power of two number of banks populated.
- All banks within an ABP group (2 banks in 2 bank permuting and 4 banks in 4 bank permuting) must be the same size.
- All populated rows must be adjacent and start at bank 0.
- Both cards in a system must be configured to allow equivalent ABP settings (i.e., Card 0 and Card 1 must both be configured according to the above rules for the current setting of the ABP enable.)

6.1.2.3 Card to Card (C2C) Interleaving Rules and limitations

Card to Card Interleaving is described in detail in Section 6.1.4. All of the ABP rules defined above apply to C2C interleaving, plus the following rules:

- The memory cards must be identically populated with memory DIMMs of the same size and type.
- The DBC registers must be programmed in the alternate C2C order as defined in the C2C functional description in Section 6.1.4.

6.1.3 Address Bit Permuting

Address Bit Permuting works by increasing the likelihood that requests spaced closely together in time access different banks of memory which will already be closed and precharged.

This is achieved by distributing the addresses, on a cache line size granularity, across either two or four banks of memory. The lowest order address bits which define a cache line are used as the bank selects into the memory array so that all requests to a zero based cache line are directed at bank 0. This is illustrated in Figure 6-4.

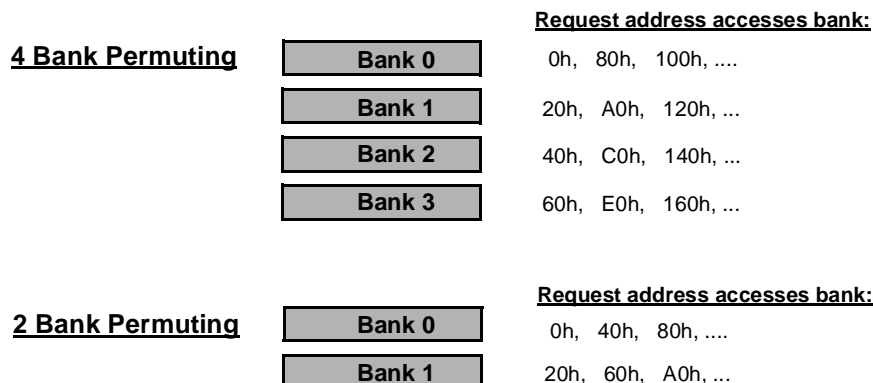


Figure 6-4: Effect of Address Bit Permuting on Bank Access Order

6.1.4 Card to Card (C2C) Interleaving

The purpose of the C2C feature is to further distribute memory accesses across multiple banks of memory as done with the ABP modes. This mode is supported in addition to the standard ABP modes so that maximum distribution of memory accesses and hence, maximum sustained bandwidth can be achieved.

The distribution of accesses to each memory card with C2C enabled is by cache line with all even cache lines sent to Card 0 and all odd cache lines sent to Card 1. The feature can be enabled, if all of the restrictions are met, by setting bit 2 of the MIOC CONFIG register.

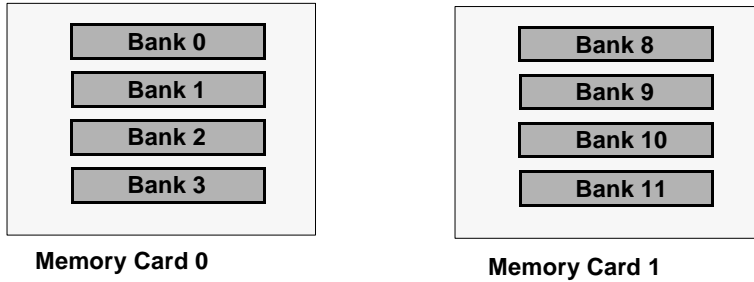
With C2C enabled the DRAM Bank Configuration Registers become mapped to the physical memory differently than with C2C disabled (default mode). Figure 6-5 shows both the C2C disabled and enabled modes mapping of DRAM Bank Configuration Registers to physical bank location.

With C2C enabled and 2 bank ABP enabled Banks 0, 1, 2 and 3 must all be the same size and type and Banks 4, 5, 6 and 7 (if present) must be the same size and type.

With C2C enabled and 4 bank ABP enabled Banks 0 through 7 must all be the same size and type.

With C2C enabled and no ABP enabled each pair of consecutive banks must be of the same size and type. For example Banks 0 and 1 must be the same size and type and Banks 2 and 3 must be the same size and type but need not match Banks 0 and 1.

C2C Disabled Bank Register Ordering



C2C Enabled Bank Register Ordering

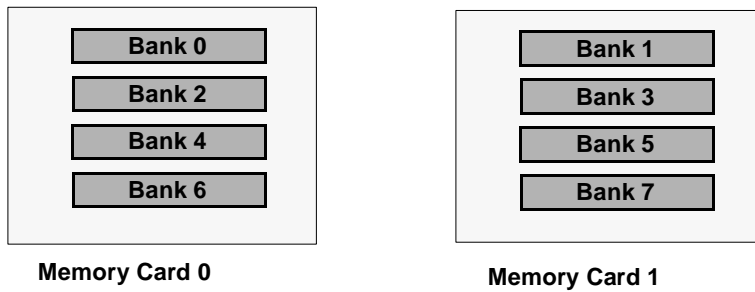


Figure 6-5: DRAM Bank Configuration Register Programming with C2C Disabled and Enabled

6.1.5 Memory Initialization

The MIOC provides an MRESET# output, which is asserted on power-good reset, system hard reset, and a BINIT reset. The MRESET# signal is sent to all RCGs and MUXs in the memory subsystem. When asserted, each RCG and MUX clears their transaction queues, data buffers and transaction state. Any transactions that may have been in-progress or pending in the memory subsystem are lost. Note that this may corrupt the contents of the DRAMs, and could leave the DRAMs themselves in an intermediate state, unable to accept a new transaction. Following MRESET# deassertion, the MIOC will re-initialize the memory subsystem by issuing eight CAS#-before-RAS# refreshes per bank (this does not affect the data held in the memory).

This chapter describes the transactions supported by the Intel® 450NX PCIset.

7.1 Host To/From Memory Transactions

7.1.1 Reads and Writes

The Read transactions supported by the Intel 450NX PCIset are: *Partial Reads, Part-line Reads, Cache Line Reads, Memory Read and Invalidate (length > 0), Memory Read and Invalidate (length = 0), Memory Read (length = 0)*.

The Write transactions supported by the Intel 450NX PCIset are: *Partial Writes, Part-line Writes, Cache Line Writes*.

7.1.2 Cache Coherency Cycles

The MIOC implements an implicit writeback response during system bus read and write transactions when a system bus agent asserts HITM# during the snoop phase. In the read case the MIOC snarfs the writeback data and updates the DRAM. The write case has two data transfers: the requesting agent's data followed by the snooping agent's writeback data.

7.1.3 Interrupt Acknowledge Cycles

A processor agent issues an Interrupt Acknowledge cycle in response to an interrupt from an 8259-compatible interrupt controller. The Interrupt Acknowledge cycle is similar to a partial read transaction, except that the address bus does not contain a valid address. The interrupt acknowledge request issued by the processor is deferred by the MIOC and forwarded to PXB #0, which performs a PCI Interrupt Acknowledge cycle on PCI bus #0A (the compatibility PCI bus).

7.1.4 Locked Cycles

The system bus specification provides a means of performing a bus lock. Any Host-PCI locked transaction will initiate a PCI locked sequence. The processor implements the bus lock

mechanism which means that no change of bus ownership can occur from the time the agent has established the locked sequence (i.e., asserts LOCK# signal on the first transaction and data is returned) until it is completed. The DRAM is locked from the PCI perspective until the host locked transaction is completed.

7.1.5 Branch Trace Cycles

An agent issues a Branch Trace Cycle for taken branches if execution tracing is enabled. The address Aa[35:3]# is reserved and can be driven to any value. D[63:32]# carries the linear address of the instruction causing the branch and D[31:0]# carries the target linear address. The MIOC will respond and retire this transaction but will not latch the value on the data lines or provide any additional support for this type of cycle.

7.1.6 Special Cycles

Special cycles are used to indicate to the system some internal processor conditions. The first address phase Aa[35:3]# is undefined and can be driven to any value. The second address phase, Ab[15:8]# defines the type of Special Cycle issued by the processor. Table 7-1 below specifies the cycle type and definition as well as the action taken by the MIOC when the corresponding cycles are identified.

Table 7-1: MIOC Actions on Special Cycles

Ab[15:8]	Cycle Type	Action Taken
0000 0000	NOP	This transaction has no side-effects.
0000 0001	Shutdown	This cycle is claimed by the MIOC. No corresponding cycle is delivered to the PCI bus. The MIOC asserts INIT# back to the agent for a minimum of 4 clocks.
0000 0010	Flush	The MIOC claims this cycle and retires it.
0000 0011	Halt	This cycle is claimed by the MIOC, forwarded to the compatibility PCI bus as a Special Halt Cycle, and retired on the system bus after it is terminated on the PCI bus via a master abort mechanism.
0000 0100	Sync	The MIOC claims this cycle and retires it.
0000 0101	Flush Acknowledge	The MIOC claims this cycle and retires it.
0000 0110	Stop Clock Acknowledge	This cycle is claimed by the MIOC and propagated to the PCI bus as a Special Stop Grant Cycle. It is completed on the system bus after it is terminated on the PCI bus via a master abort mechanism.
0000 0111	SMI Acknowledge	The MIOC's SMI ACT# signal will be asserted upon detecting an SMI Acknowledge cycle with SMMEM# asserted, and will remain asserted until detecting a subsequent SMI Acknowledge cycle with SMMEM# deasserted.
all others	<i>Reserved</i>	

7.1.7 System Management Mode Accesses

The Intel 450NX PCIset uses an SMRAM configuration register to enable, define and control access to the SMM RAM space. The SMM RAM space defaults to location A000h, with a size of 64 KB, but may be relocated and grown in increments of 64 KB. A master enable (SMRAME) and three access-control enables (Open, Closed, Locked) determine how accesses to the space are to be serviced. Table 7-2 summarizes how accesses to the SMM RAM space are serviced.

Table 7-2: SMRAM Space Cycles

SMRAME	D_OPEN	C_CODE	C_LCK	SMMEM	Code Fetch	Data Reference	Usage
0	X	X	X	X	Normal ¹	Normal ¹	SMM RAM space is not supported.
1	0	0	X	0	PCI 0a	PCI 0a	Normal SMM usage. Accesses to the SMM RAM space from processors in SMM will access the DRAM. Accesses by processors not in SMM will be diverted to the compatibility PCI bus.
1	0	0	X	1	DRAM	DRAM	
1	0	1	X	0	PCI 0a	PCI 0a	A modification of the normal SMM usage, in which only code fetches are accepted from processors in SMM mode.
1	0	1	X	1	DRAM	PCI 0a	
1	1	X	0	X	DRAM	DRAM	Full access by any agent to SMM RAM space. Typically used by the BIOS to initialize SMM RAM space.

1. SMRAM functions are disabled. The access is serviced like any other. The address is checked against the other space and gap definitions to determine its disposition -- to PCI, to memory, or to the system bus for a third party agent to claim.

7.1.8 Third-Party Intervention

The Intel 450NX PCIset supports the same third-party control sideband controls that were defined in Intel 450GX PCIset. These controls allow an external agent on the system bus to affect the way in which the MIOC responds to a system bus request to memory. This external agent is referred to as a “third-party” to the transaction. When a third-party agent intervenes in the normal transaction flow, both the MIOC and the third-party share responsibility for generating the appropriate response; however, the MIOC is always the “owner” of the transaction, and hence must be the responding bus agent.

The third-party controls how the MIOC responds by asserting a code on the sideband TPCTL[1:0] signals during the snoop phase. The MIOC samples these signals in the last cycle of the snoop phase. Table 7-3 indicates the actions possible using the TPCTL[1:0] signals.

Table 7-3: TPCTL[1:0] Operations

TPCTL [1:0]	Action
00	Accept. The MIOC accepts the request, and provides the normal response. The third-party agent is not involved in the transaction.
01	Hard Fail. Not supported by the Intel [®] 450NX PCIset.
10	Retry. The MIOC will generate a retry response. The access will be retried by the requesting agent.
11	Defer. The MIOC will issue a defer response, and the third-party agent will complete the transaction at a later time using a deferred reply.

7.2 Outbound Transactions

7.2.1 Supported Outbound Accesses

The PXB translates valid system bus commands into PCI bus requests. For all Host-PCI transactions the PXB is a non-caching agent since the Intel 450NX PCIset does not support cacheability on PCI. However, the PXB must respond appropriately to the system bus commands that are cache oriented.

7.2.2 Outbound Locked Transactions

The Intel 450NX PCIset supports memory-mapped outbound locked operations. I/O-mapped outbound locked transactions are *not* supported. Further, a locked transaction cannot be initiated with a zero-length read. These restrictions are consistent with the transactions supported by the processor.

7.2.3 Outbound Write Combining

The Intel 450NX PCIset provides its own write combining for Host-PCI write transactions. If enabled, and multiple Host-PCI writes target sequential locations in the PCI space, the data is combined and sent to the PCI bus as a single write burst. *This holds true for all memory attributes, not just WC.* There is no corresponding write-combining for the Host-DRAM path.

7.2.4 Third-Party Intervention on Outbounds

The use of the third-party control signals (TPCTL) is not supported for outbound transactions (Host-PCI). Assertion of the TPCTL signals during an outbound transaction will have

indeterminate results. Assertion of DEFER# during an outbound transaction will also have indeterminate results.

7.3 Inbound Transactions

For all inbound transactions, the Intel® 450NX MIOC will use an Agent ID of **'1001b'** (9). This is the same agent ID used by the Intel 450GX PCIset, which the Intel 450NX PCIset replaces.

Note that memory-mapped accesses across PCI buses (i.e., peer-to-peer transfers) are not supported. Also, inbound I/O transactions are not supported, either to other PCI buses or to the system bus.

7.3.1 Inbound LOCKs

Inbound (PCI-to-system bus) LOCKs are not supported in the Intel 450NX PCIset. Use of inbound locks on the Intel 450NX PCIset may result in unanticipated behavior. The Intel 450NX PCIset is NOT compatible with devices on the compatibility PCI bus which are capable of initiating inbound bus- or resource-locks. Deadlock may occur between outbound locked transactions, south bridge-initiated Secure Sideband Requests (PHOLD#), and LOCK# assertion by the offending device. Devices capable of asserting LOCK# to access memory should not be used on the compatibility PCI bus.

7.3.2 South Bridge Accesses

The PXB's Bus 'a' has sideband signals to support the PIIX4E south bridge for ISA expansion. The PXB does not support an EISA bridge.

WSC# Handshake

When the PIIX4E south bridge issues an interrupt for an ISA master, it must first check that any writes posted from ISA to memory have been observed before the interrupt is issued. This action is necessary to guarantee that an ISA write followed by an ISA interrupt is observed in that same order by a processor on the system bus.

Whenever the compatibility bus PXB receives a write from the south bridge, it will deassert the WSC# (Write Snoop complete) signal. WSC# will remain de-asserted until the write Completion for that write has returned. When the Completion returns, WSC# is again asserted. While WSC# is de-asserted the PXB must retry any additional writes from the south bridge.

The PXB will only support the WSC# Handshake when the internal arbiter is used. When operating in external arbiter mode, the PXB will always hold WSC# asserted. The WSC# mode may be disabled by a bit in the PXB's CONFIG register. If disabled, WSC# stays asserted and inbound writes from the south bridge are accepted.

Distributed DMA

Distributed DMA across the PCI bus is not supported by the Intel 450NX PCIset. This function is incompatible with the passive release mechanism portion of the PHOLD#/PHLDA# protocol used to grant PCI bus access to south bridges.

Accesses Prohibited to Third-Party Agent

The Intel 450NX PCIset only supports inbound south bridge accesses to memory. Inbound accesses from a south bridge using the PHOLD#/PHLDA# protocol, directed to a third-party agent on the system bus, are not supported. Such accesses, involving interactions with unknown and unpredictable agents, could violate the rules governing the PHOLD#/PHLDA# protocol, potentially leading to deadlocks.

7.4 Configuration Accesses

The PCI specification defines two mechanisms to access configuration space, Mechanism #1 and Mechanism #2. The Intel[®] 450NX PCIset supports only Mechanism #1.

Mechanism #1 defines two I/O-space locations: an address register (CONFIG_ADDRESS) at location **0CF8h**, and a data register (CONFIG_DATA) at location **0CFCh**. The Intel 450NX PCIset provides a PCI-compatible configuration space for the MIOC, and one for each PCI bus in the PXB.

- If the MIOC detects the I/O request is a configuration access to its own configuration space, it will service that request entirely within the MIOC. Reads result in data being returned to the system bus.
- If the MIOC detects the I/O request is a configuration access to a PXB configuration space, it will forward the request to the appropriate PXB for servicing. The request is not forwarded to a PCI bus. Reads will result in data being returned by the PXB through the MIOC to the system bus.
- If the MIOC detects the I/O request is a configuration access to a third-party agent on the system bus, it will leave the access unclaimed on the system bus. The third-party agent may claim the access, with reads resulting in data being returned by the third-party agent to the system bus.
- Otherwise, the access is forwarded on to the PXB to be placed on the PCI bus as a Configuration Read or Configuration Write cycle. Reads will result in data being returned through the PXB and MIOC back to the system bus, just as in normal Outbound Read operations.

8.1 PCI Arbitration Scheme

The PCI Specification Rev 2.1 requires that the arbiter implement a fairness algorithm to avoid deadlocks and that it assert only a single GNT# signal on any rising clock. The arbitration algorithm is fundamentally not part of the PCI Specification.

The PXB contains an internal PCI arbiter. This arbiter can be disabled either when the PXB operates with I/O bridges which include this function, or when a customized PCI arbiter solution is required. The Internal PCI Arbiter has the following features:

- Support for 6 PCI masters, Host and I/O Bridge
- 2 Level Round Robin
- Bus Lock Implementation
- Bus Parking on last agent using the bus
- 4-PCI clock grant (FRAME#) time-out
- Multi Transaction Timer (MTT) mechanism
- PCI arbitration is independent from the system bus arbitration
- PIIX4E-compatible protocol (EISA bridges are *not* supported)
- PCI Protocol Requirements

8.2 Host Arbitration Scheme

The system bus arbitration protocol supports two classes of bus agents: symmetric agents and priority agents. The processors arbitrate for the system bus as symmetric agents using their own signaling. Symmetric agents implement fair, distributed arbitration using a round-robin algorithm. The MIOC, as an I/O agent, uses a priority agent arbitration protocol to obtain the ownership of the system bus. Priority agents use the BPRI# signal to immediately obtain bus ownership.

Besides two classes of arbitration agents (symmetric and priority agents), each bus agent has two mechanisms available that act as arbitration modifiers: the bus lock (LOCK#) and the request stall (BNR#).

8.2.1 Third Party Arbitration

The Intel 450NX PCIset requests the system bus with BPRI#. If multiple bridges or a third party agent is on the system bus, an arbitration method is required to establish bus ownership among multiple requesting bridges (which bridge can drive BPRI#). This arbitration is transparent to the Pentium® II Xeon™ processors or other symmetric bus agents. Only one bridge is allowed to drive BPRI# at a time.

8.3 South Bridge Support

The Intel® 450NX PCIset is designed to work with the PIIX4E south bridge which connects the PCI bus to ISA bus and I/O APIC components. Note that the protocols described here apply only when the Intel 450NX PCIset is used in internal arbiter mode — use of the PIIX4E in external arbiter configurations is not supported.

The Intel 450NX PCIset does *not* guarantee ISA access latencies of < 2.5 usec. ISA devices which require these latencies to be met (GAT mode timing) are not supported.

8.3.1 I/O Bridge Configuration Example.

The basic I/O bridge configuration supported by the Intel 450NX PCIset is shown in Figure 8-1. The figure shows the sideband signals that connect the PXB to the PIIX4E, I/O APIC components and the external arbiter. Note that PHOLD#/PHLDA# are connected between PXB and the PIIX4E, and WSC# output from PXB is connected to the APICACK2# input of the stand-alone I/O APIC component. If the configuration does not have I/O APIC component, then WSC# pin is left unconnected.

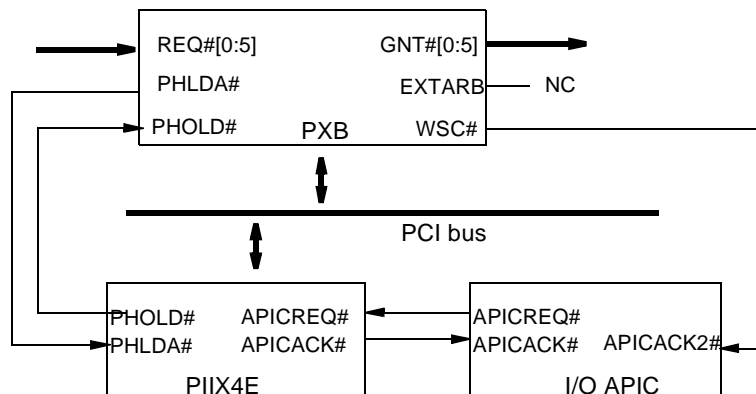


Figure 8-1: ISA Bridge with the I/O APIC (Internal Arbiter)

8.3.2 PHOLD#/PHLDA# Protocol

The PIIX4E uses only two signals to obtain the ownership of the PCI bus. The PIIX4E will assert PHOLD# to indicate that an ISA master is requesting to run a cycle (*DREQ* active) or an integrated PCI-IDE bus-mastering device is requesting the PCI bus.

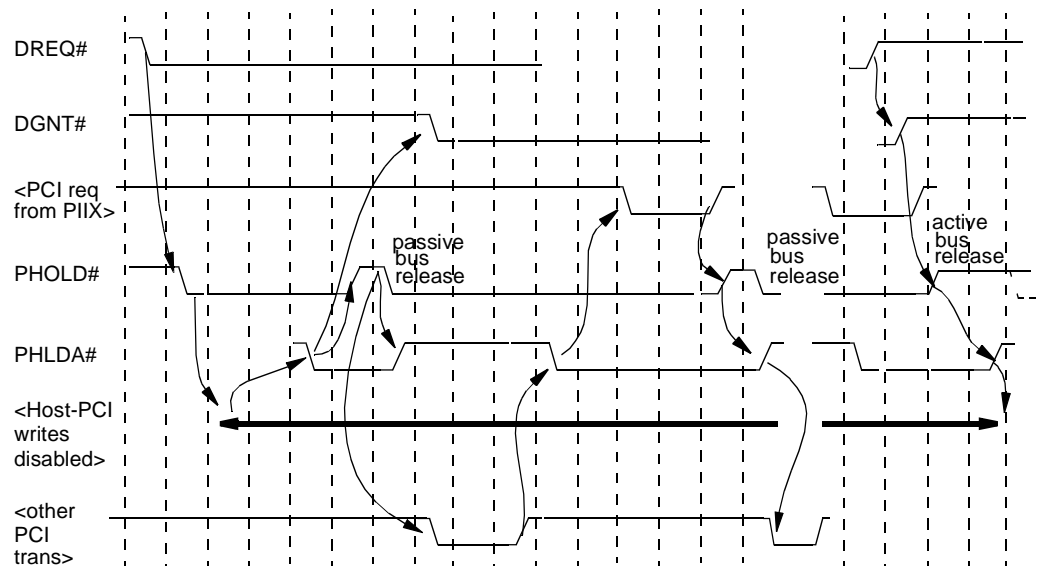


Figure 8-2: PHOLD#/PHLDA# Protocol Showing Active and Passive Bus Release

8.3.3 WSC# Protocol

The WSC# (Write Snoop Complete) is a status signal output from the Intel 450NX PCIset PXB. The WSC# assertion indicates that all necessary snoops for a previously posted PCI-DRAM write have been completed on the system bus.

The WSC# signal is primarily used by the I/O APIC device connected to the ISA bridge. The I/O APIC uses this signal to maintain data coherency and ordering of transactions in the system.

NOTE

The WSC# Handshake only applies if the PXB is in internal arbiter mode.

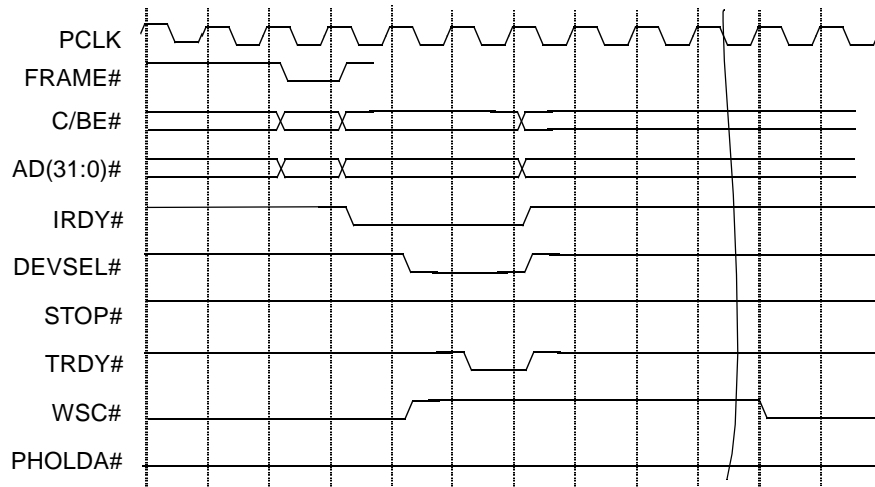


Figure 8-3: WSC# Signal Functionality

This chapter describes the data integrity support and general error detection and reporting mechanisms used in the Intel® 450NX PCIset.

9.1 DRAM Integrity

Both the system data bus and the Intel® 450NX PCIset's memory subsystem use a common Error Correcting Code which provides SEC/DED/NED coverage. The ECC used is capable of correcting single-bit errors and detecting 100% of double-bit errors over one code word.

9.1.1 ECC Generation

When enabled, the DRAM ECC mechanism allows automatic generation of an 8-bit protection code for the 64-bit (Qword) of data during DRAM write operations. Note that when ECC is intended to be enabled, the whole DRAM array *must* be first initialized by doing writes before the DRAM read operations can be performed. This will establish the correlation between 64-bit data and associated 8-bit ECC code which does not exist after power-on. This function is *not* provided by hardware.

9.1.2 ECC Checking and Correction

During DRAM read operations, a full Qword of data (8 bytes) is always transferred from the DRAM to the MIOC regardless of the size of the originally requested data. Both 64-bit data and 8-bit ECC code are transferred simultaneously from the DRAM to the MIOC. The ECC checking logic in the MIOC uses the received 72 bit Data + ECC to generate the check syndrome. If a single-bit error is detected the ECC logic corrects the identified incorrect data bit.

9.1.3 ECC Error Reporting

When ECC checking is enabled, single-bit and multiple-bit errors detected by the ECC logic are logged in the MIOC. The first two errors detected on reads-from-memory are logged, as are the first two errors detected on data received from the system bus.

For memory errors, the error type (single-bit or multi-bit), syndrome, chunk and effective address are logged. The first two memory errors (single-bit or multi-bit) will be logged in the

MEL and MEA registers. For bus errors, the error type, syndrome and chunk are logged. The first two system bus errors (single-bit or multi-bit) will be logged in the HEL registers.

All ECC error logging registers are sticky through reset, allowing software to determine the source of an error after restoring the system to functioning mode. The logging registers hold their values until explicitly cleared by software.

Error Signaling Mechanism

Single-bit correctable errors are not critical from the point-of-view of presenting the correct value of data to the system. The DRAM (if the cause of error is a DRAM array) will still contain faulty data which will cause the repetition of error detection and recovery for the subsequent accesses to the same location.

Multi-bit uncorrectable errors are fatal system errors and will cause the MIOC to assert the BERR# signal if enabled in the ERRCMD register. The uncorrected data is forwarded to its destination. For the first two multi-bit uncorrectable errors, the MIOC will log in the MEA register the row number where the error occurred. This information can be used later to point to a faulty DRAM DIMM.

The MEA/MEL registers log only the first two errors. After the first two errors have been logged, the MEA/MEL registers will not be updated. However, normal error detection still continues, the ERR[1:0]# and BERR# signals are still asserted as appropriate, and scrubbing of the memory still continues.

9.1.4 Memory Scrubbing

The Intel 450NX PCIset provides a “scrub-on-error” (demand scrubbing) mechanism, wherein corrected data for single-bit errors will be automatically written back into the memory subsystem by the MIOC. Note that this is not the same as “walk-through” scrubbing, in which every memory location is systematically accessed, checked and corrected on a regular basis. The scrub-on-error mechanism will scrub only those locations accessed during normal operation and thus complements the software controlled “walk-through” scrubbing.

9.1.5 Debug/Diagnostic Support

The MIOC supports in-system testing of ECC functions. An ECC Mask Register (ECCMSK) can be programmed with a masking function. Subsequent writes into memory will store a masked version of the computed ECC. Subsequent reads of the memory locations written while masked will return an invalid ECC code. If the mask register is left at 0h (the default), the normal computed ECC is written to memory.

9.2 System Bus Integrity

A variety of system bus error detection features are provided by the MIOC. Particularly, the system data bus is checked for ECC errors on Host-DRAM and Host-PCI writes.

Additionally, the MIOC supports parity checking on the system address and request/response signals.

9.2.1 System Bus Control & Data Integrity

The MIOC detects errors on the system data bus by checking the ECC provided with data and the parity flag provided with control signals. In turn, the MIOC will generate new ECC with data and parity with control signals so that bus errors can be detected by receiving clients.

The request control signals ADS# and REQ#[4:0] are covered with the Request Parity signal RP#, which is computed as even parity. This ensures that it is deasserted when all covered signals are deasserted.

The address signals A#[35:3] are covered by the Address Parity signal AP#[1:0], which is also configured for even parity. This ensures that each is deasserted when all covered signals are deasserted. AP#[1] covers A#[35:24] and AP#[0] covers A#[23:3].

Response signals RS#[2:0] are protected by RSP#. RSP# is computed as even parity. This ensures that it is deasserted when all covered signals are deasserted.

9.3 PCI Integrity

The PCI bus provides a single even-parity bit (PAR) that covers the AD[31:0] and C/BE#[3:0] lines. The agent that drives the AD[31:0] lines is responsible for driving PAR. Any undefined signals must still be driven to a valid logic level and included in the parity calculation.

Parity generation is not optional on the PCI bus; however, parity error detection and reporting is optional. The PXB will always detect an address parity error, even if it is not the selected target. The PXB will detect data parity errors if it is either the master or the target of a transaction, and will optionally report them to the system.

Address parity errors are reported using the SERR# signal. Data parity errors are reported using the PERR# signal. The ERRCMD (Error Command) register provides the capability to configure the PXB to propagate PERR# signaled error conditions onto the SERR# signal.

9.4 Expander Bus

Each Expander bus has a parity bit covering all data and control signals for each clock cycle. Parity is generated at the expander bus interface by the sender, and checked at the expander bus interface in the receiver. Detected parity errors are reported at the receiving component — outbound packets report parity errors in the PXB, while inbound packets report parity errors in the MIOC.

10.1 Post Reset Initialization

10.1.1 Reset Configuration Using CVDR/CVCR

All system bus devices must sample the following configuration options at reset:

- Address/request/response parity checking: Enabled or Disabled
- AERR# detection enable
- BERR# detection enable
- BINIT# detection enable
- FRC mode: Enabled or Disabled
- Power-on reset vector: 1M or 4G
- In-Order Queue depth: 1 or 8
- APIC cluster ID: 0, 1, 2, or 3
- Symmetric agent arbitration ID: 0, 1, 2, 3

The MIOC provides both the Symmetric Arbitration ID parameter and other parameters. (Refer to the CVDR register description.)

10.1.1.1 Configuration Protocol

A Pentium® II Xeon™ processor-based system is initialized and configured in the following manner.

1. The system is powered. The power-supply provides resets for the Intel® 450NX PCIset through the PWRGD signal. The MIOC and PXBs assert their resets while the PWRGD signal is not asserted. PCI reset is driven to tristate the PCI buses in order to prevent PCI output buffers from short circuiting when the PCI power rails are not within the specified tolerances.
2. All Intel 450NX PCIset components are initialized, with their internal registers defaulting to the power-on values.
3. The MIOC will drive the appropriate system bus data lines with the initial configuration values that defaulted in the *Configuration Values Driven on Reset* (CVDR) register.
4. On the rising edge of RESET#, the MIOC will continue driving the appropriate system bus lines with the configuration values. These values are driven at least one clock after the rising edge of RESET#.

5. All system bus devices will capture the system configuration parameters from the appropriate system bus lines on the rising edge of **RESET#**. The MIOC captures these values in its *Configuration Values Captured on Reset (CVCR)* register. (This allows an external device to over-ride the MIOC default parameters.)
6. All system bus devices are now ready for further programming. The MIOC will respond to BIOS code fetches.
7. If a change in the system bus system configuration is desired, the MIOC's CVDR register can be programmed with the desired values.
8. After the CVDR register is programmed, the MIOC must be programmed to do a hard reset, through the Reset Control (RC) register.
9. When the MIOC performs a hard reset, all system bus devices are again reset. This reset repeats steps 2-8, except that the CVDR register is not effected by the reset. This register is only re-initialized by the PWRGD signal.

10.1.1.2 Special Considerations for Third-Party Agents

One of the settings available in the CVDR/CVCR registers allows the Bus In-Order Queue Depth to be set to 1, instead of the usual 8. When IOQ Depth=1, there is a case where a Third-Party Agent can starve the system bus.

Therefore, any system containing a TPA must either:

- require that the TPA back-off its **BPRI#** arbitration requests sufficiently to allow the symmetric agents access to the bus, *or*
- not use IOQ depth=1.

This chapter describes the generation, distribution and interaction between the various clocks in an Intel® 450NX PCIsset-based system, as well as the various reset functionality supported by the Intel 450NX PCIsset.

11.1 Clocking

The Pentium® II Xeon™ processor uses a clock ratio scheme where the system bus clock frequency is multiplied to produce the processor's core frequency. The MIOC supports a system bus frequency optimized for 100 MHz. The Intel® 450NX PCIsset should be used at a bus frequency which provides the required clock frequency for the PCI interfaces. The external clock generator is responsible for generating the system clock. The Intel 450NX PCIsset's core clock is equal to the system bus clock rate. The Intel 450NX PCIsset is responsible for driving the signals which the processor uses to determine the core to bus clock ratio.

The MIOC receives an output of a clock generator on the HCLKIN pin, as illustrated in Figure 11-1. The MIOC uses the HCLKIN signal to drive the host and memory interfaces and the core. This clock is doubled for the MD bus and the Expander buses.

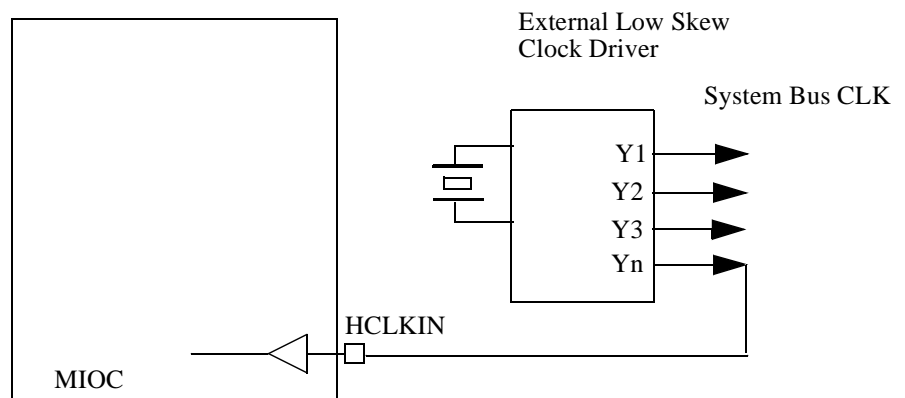


Figure 11-1: Host Clock Generation and Distribution

PCI clock distribution is illustrated in Figure 11-2. The PXB provides a PCI bus clock that is generated by dividing the internal host clock frequency by three. The PCI clock is output through the PCLK pin. Externally this PCI clock drives a low skew clock driver which in turn supplies multiple copies of the PCI clock to the PCI bus. One of the outputs of the external clock driver is fed back into the PXB. A PLL in the PXB forces the external PCI clock to phase lock to the internal PCI clock tree.

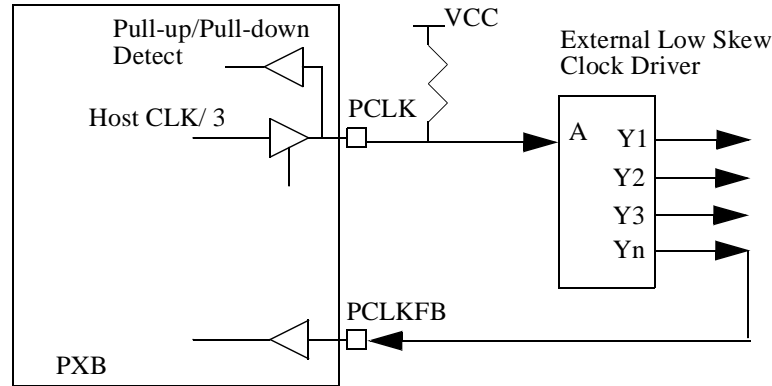


Figure 11-2: PCI Clock Generation and Distribution

11.2 System Reset

Five varieties of reset functions are supported by the Intel® 450NX PCIset.

- A *Power-Good Reset* is triggered by an externally generated signal which indicates that the power supplies and clocks are stable. This reset clears all configuration and transaction state in the Intel 450NX PCIset, as well as asserting resets to the processors, PCI buses, and PIIX, if present.
- A *System Hard Reset* is a software-initiated reset that performs nearly the same functions as the power-good reset. The key difference is that the system hard reset does not clear "sticky" error flags in the Intel 450NX PCIset, thus allowing an error handler to determine the cause of a failure that resulted in reset. Also, hard reset may optionally trigger the processor's Built-In Self-Test (BIST).
- A *Soft Reset* is another software-initiated reset which affects only the processors. This reset may also be generated by certain I/O activities.
- A *BINIT Reset* results from a catastrophic transaction error on the system bus. The memory and the MIOC's configuration space are untouched.
- A *PXB Reset* is a software-initiated reset that affects only a single PXB and its dependent PCI buses. This reset may be used in high-availability systems, where it is desirable to allow the processors and one PXB to continue operation in the event of failure of a single PXB.

11.2.1 Intel® 450NX PCIset Reset Structure

Figure 11-3 shows the recommended reset structure for an Intel 450NX PCIset-based system including the PIIX4E south bridge. Note that the primary system power-good signal is provided to the MIOC, which then distributes a variety of reset signals to the rest of the system.

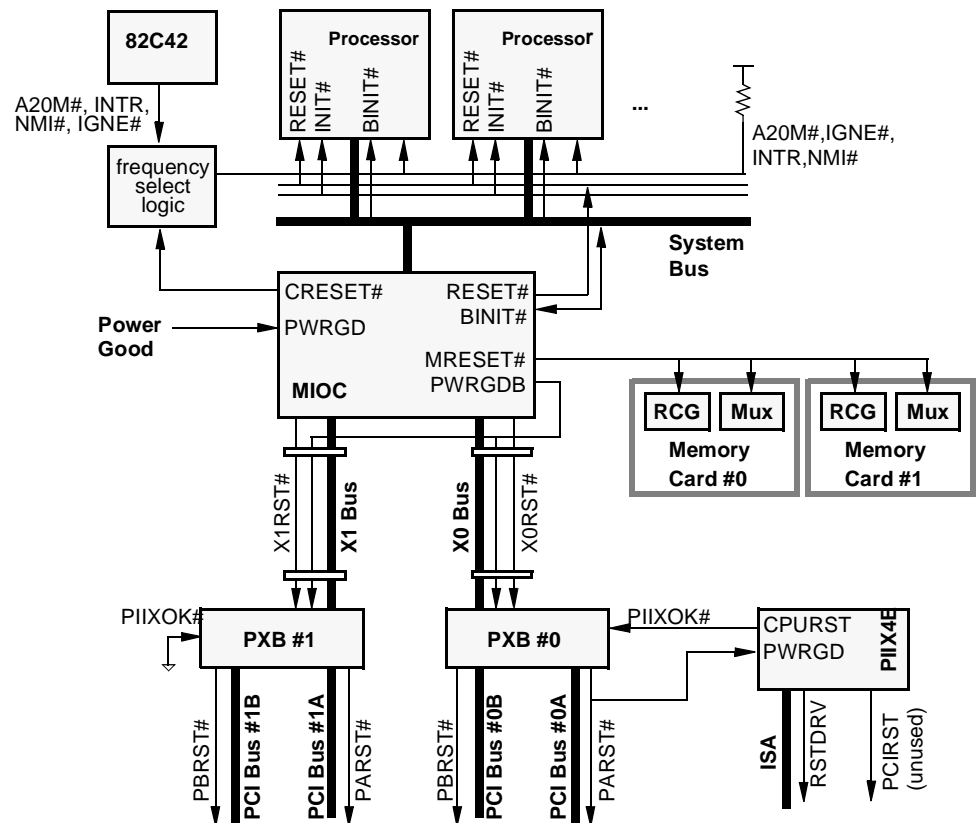


Figure 11-3: Recommended RESET Distribution for Intel® 450NX PCIsset-Based Systems Including a PIIX4E South Bridge

Power Good

The reference system shown here assumes a single "power good" signal that indicates clean power supplies and clocks to the MIOC and both PXBs. For routing convenience and drive capability, the MIOC provides a buffered version of its PWRGD input (PWRGDB), which should be connected to the PWRGD inputs of each PXB. Refer to the Electrical Characteristics for additional PWRGD requirements.

RESET#

The RESET# signal is directed to the processors. Assertion of this signal puts all processors in a known state, and invalidates their L1 and L2 caches. When this signal is deasserted, the processor begins to execute from address 00_FFFF_FFF0h. The Boot ROM must respond to this address range regardless of where it physically resides in the system.

CRESET#

The CRESET# signal tracks RESET#, but is held asserted two clocks longer than RESET#. It is provided to allow an external frequency selection mux to drive the system-bus-to-core-clock ratio onto pins LINT[1:0], IGNNE#, and A20M# of the system bus during RESET#.

MRESET#

The MRESET# signal is sent to all RCGs and MUXs in the memory subsystem. When asserted, each RCG and MUX clears their transaction state and data buffers. Any transactions that may have been in-progress or pending in the memory subsystem are lost. Upon MRESET# deassertion, the MIOC will re-initialize the memory subsystem by issuing 8 CAS-before-RAS refreshes per bank (this does not affect the data held in the memory).

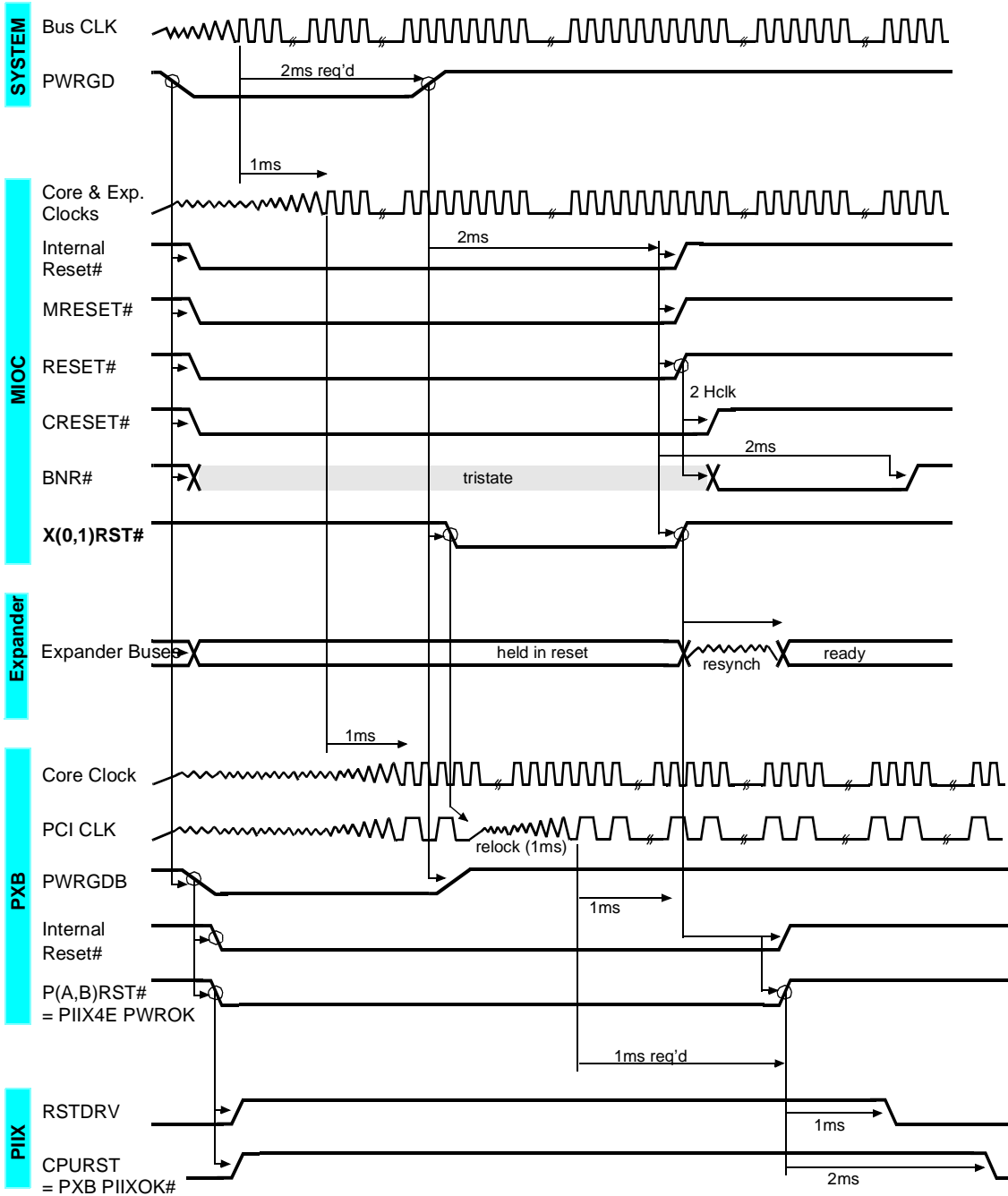


Figure 11-4: Power-Good Reset

Soft Reset

A *Soft Reset* is a reset directed to the processors on the system bus which does not affect the configuration or transaction state of the Intel 450NX PCIset or the dependent PCI buses. To support this function, the system design must externally combine the MIOC's INIT# output with the I/O port 92h and keyboard controller soft reset sources as shown in Figure 11-5.

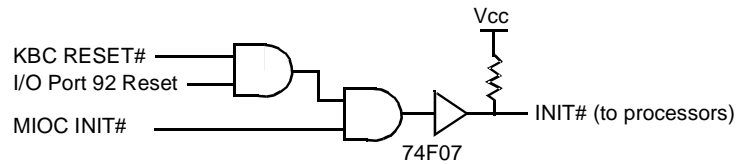


Figure 11-5: Soft Reset

PXB Reset

A *PXB Reset* is a software-initiated reset that affects only a single PXB and its dependent PCI buses. Figure 11-4 illustrates a software-initiated PXB Reset.

Reset Without Disturbing PCI Clocks

PCICLK_A and PCICLK_B must be re-phased whenever any type of reset is asserted if the Intel 450NX PCIset is to be deterministic relative to that reset. The behavior of these clocks cannot be guaranteed during this re-phasing. A bit in the PXB RC register can be cleared by a configuration write to defeat the PCI clock re-phasing, so that PCICLK_A and PCICLK_B remain well behaved through resets.

11.2.2 Output States During Reset

The following tables shows the signal states of the Intel 450NX PCIset components during a Power-Good Reset or System Hard Reset. Inputs are denoted by “-”.

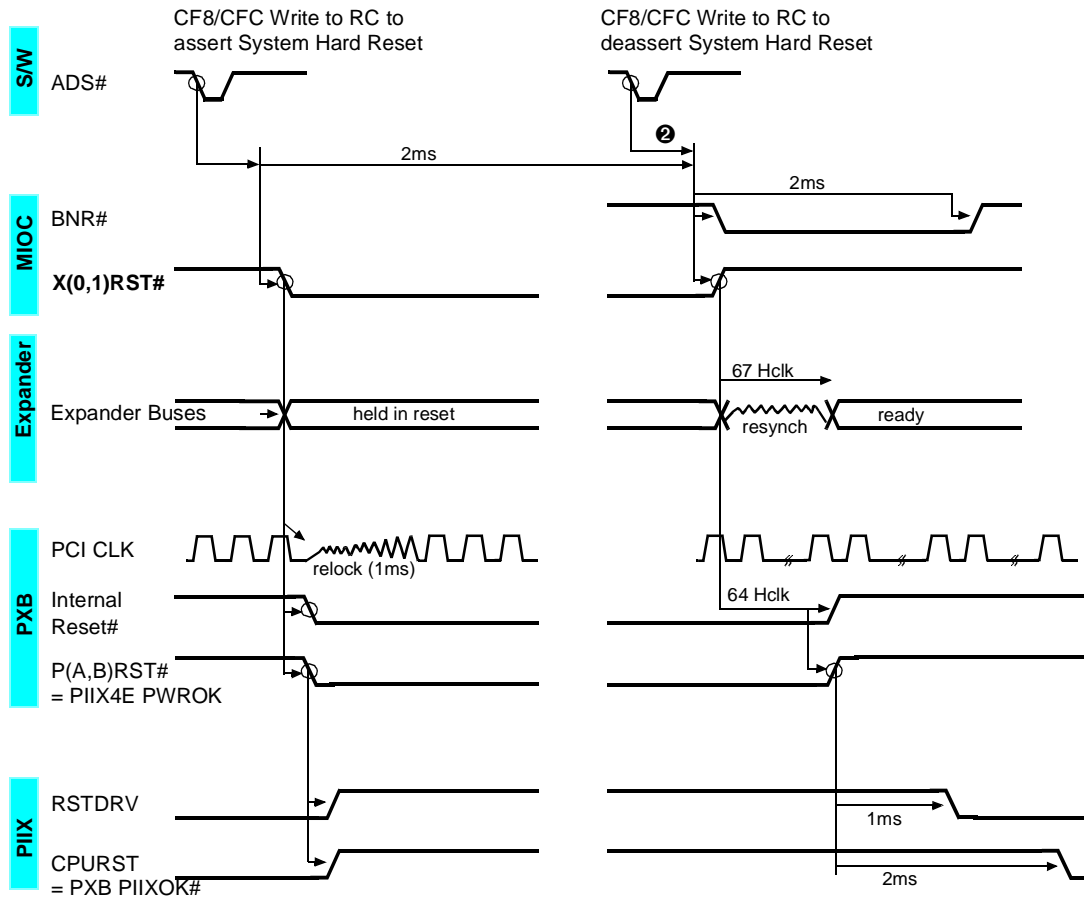


Figure 11-6: Software-Initiated PXB Reset

11.2.2.1 MIOC Reset State

Host Interface			
A[35:3]#	Tristate ¹	DEP[7:0]#	Tristate
ADS#	Tristate	DRDY#	Tristate
AERR#	Tristate	HIT#	-
AP[1:0]#	Tristate	HITM#	-
BERR#	Tristate	INIT#	Tristate ³
BINIT#	Tristate	LOCK#	-
BNR#	Tristate	REQ[4:0]#	Tristate
BP[1:0]#	Tristate	RP#	Tristate
BPRI#	Tristate	RS[2:0]#	Tristate
BREQ[0]#	Asserted ²	RSP#	Tristate
D[63:0]#	Tristate	TRDY#	Tristate
DBSY#	Tristate		
DEFER#	Tristate		

Third-Party Agent Interface			
IOGNT#	-	TPCTL[1:0]	-
IOREQ#	Tristate		
Memory Subsystem / External Interface			
BANK[2:0]#	Deasserted	DVALID(a,b)#	Deasserted
CARD[1:0]#	Deasserted	MA[13:0]#	Deasserted
CMND[1:0]#	Deasserted	MD[71:0]#	Tristate
CSTB#	Deasserted	MRESET#	Asserted
DCMPLT(a,b)#	Tristate	PHIT(a,b)#	-
DOFF[1:0]#	Deasserted	ROW#	Deasserted
DSEL[1:0]#	Deasserted	RCMPLT(a,b)#	-
DSTBN[3:0]#	Tristate	RHIT(a,b)#	-
DSTBP[3:0]#	Tristate	WDEVT#	Deasserted
Expander Interface (two per MIOC: 0,1)			
X(0,1)ADS#	Tristate	X(0,1)HSTBP#	Toggling
X(0,1)BE[1:0]#	Tristate	X(0,1)PAR#	Tristate
X(0,1)BLK#	Deasserted	X(0,1)RST#	Asserted
X(0,1)CLK	Toggling	X(0,1)RSTB#	Asserted
X(0,1)CLKB	Toggling	X(0,1)RSTFB#	-
X(0,1)CLKFB	-	X(0,1)XRTS#	-
X(0,1)D[15:0]#	Tristate	X(0,1)XSTBN#	-
X(0,1)HRTS#	Toggling	X(0,1)XSTBP#	-
X(0,1)HSTBN#	Toggling		
Common Support Signals			
CRES[1:0]	Strapped	TMS	-
TCK	-	TRST#	-
TDI	-	VCCA (3)	Reference
TDO	OD	VREF (6)	Reference
Component-Specific Support Signals			
CRESET#	Asserted	PWRGD	- ⁴
ERR[1:0]#	Tristate	PWRGDB	De/asserted ⁴
HCLKIN	Toggling	RESET#	Asserted
INTREQ#	Deasserted	SMIACT#	Deasserted

Notes:

1. The Pentium® II Xeon™ processor allows for configuring a variety of processor and bus variables during the reset sequence. During RESET# assertion, and for one clock past the trailing edge of RESET#, the Intel 450NX PCIset MIOC will drive the contents of its CVDR register onto A[15:3]#. All system bus devices (including the MIOC) are required to sample these address lines using the trailing edge of reset, and modify their internal configuration accordingly. Note the initial value of CVDR may be changed by the boot processor, and the reset process re-engaged. This allows the processors and buses to power-up in a "safe" state, yet allow re-configuration based on specific system constraints.
2. BREQ0# must stay asserted (low) for a minimum of 2 system clocks after the rising edge of RESET#. The MIOC then releases (tristates) the BREQ0# signal.
3. INIT# is not asserted during power-up. It may be optionally asserted during system hard reset through the RC register to cause the processors to initiate BIST.
4. The PWRGDB output is asserted if the PWRGD input is asserted (i.e., a power-good reset). For a system hard reset, the PWRGDB output is deasserted.

11.2.2.2 PXB Reset State

PCI Bus Interface (2 per PXB: A,B)			
P(A,B)AD[31:0]	Tristate	P(A,B)PAR	Tristate
P(A,B)C/BE[3:0]#	Tristate	P(A,B)PERR#	Tristate
P(A,B)CLKFB	-	P(A,B)REQ[5:0]#	- (see note)
P(A,B)CLK	Toggling	P(A,B)RST#	Asserted
P(A,B)DEVSEL#	Tristate	P(A,B)SERR#	Open
P(A,B)FRAME#	Tristate	P(A,B)STOP#	Tristate
P(A,B)GNT[5:0]#	Tristate	P(A,B)TRDY#	Tristate
P(A,B)IRDY#	Tristate	P(A,B)XARB#	Strapped
P(A,B)LOCK#	Tristate		
PCI Bus Interface / Non-Duplicated (one set per PXB)			
ACK64#	Tristate	PHLDA#	Tristate
MODE64#	Strapped	REQ64#	Asserted
PHOLD#	-	WSC#	Tristate
Expander Interface (one per PXB)			
XADS#	Tristate	XHSTBP#	-
XBE[1:0]#	Tristate	XIB	Deasserted
XBLK#	-	XPAR#	Tristate
XCLK	Toggling	XRST#	Asserted
XD[15:0]#	Tristate	XXRTS#	Deasserted
XHRTS#	-	XXSTBN#	Deasserted
XHSTBN#	-	XXSTBP#	Deasserted
Common Support Signals			
CRES[1:0]	Strapped	TMS	-
TCK	-	TRST#	-
TDI	-	VCCA (3)	Reference
TDO	OD	VREF (2)	Reference
Component-Specific Support Signals			
INTRQ(A,B)#	Deasserted	PIIXOK#	-
LONGXB#	Strapped	PWRGD	-
P(A,B)MON[1:0]#	Tristate		

Note:

The P(A,B)REQ[5:0]# signals are inputs to the PXB. During reset, these inputs are ignored. However, these signals become "live" immediately following reset deassertion. All unconnected REQ# inputs should be strapped deasserted. All connected REQ# inputs should have weak pullups.

11.2.2.3 RCG Reset State

Memory Subsystem / External Interface			
BANK[2:0]#	-	MRESET#	-
CARD#	-	PHIT#	Deasserted
CMND[1:0]#	-	RCMPLT#	Deasserted
CSTB#	-	RHIT#	Deasserted
GRCMPLT#	Deasserted	ROW#	-
MA[13:0]#	-		
Memory Subsystem / Internal Interface			
ADDR(A,B,C,D)[13:0]	Deasserted	LRD#	Deasserted
AVWP#	Deasserted	RAS(A,B,C,D)(a,b,c,d)[1:0]#	Deasserted
CAS(A,B,C,D)(a,b,c,d)[1:0]#	Deasserted	WDME#	Deasserted
LDSTB#	Deasserted	WE(A,B,C,D)(a,b)#	Deasserted
Common Support Signals			
CRES[1:0]	-	TMS	-
TCK	-	TRST#	-
TDI	-	VCCA	Reference
TDO	Tristate	VREF (2)	Reference
Component-Specific Support Signals			
BANKID#	Strapped	DR50T#	Strapped
DR50H#	Strapped	HCLKIN	Toggling

11.2.2.4 MUX Reset State

Memory Subsystem / External Interface			
DCMPLT#	Deasserted	DVALID#	-
DOFF[1:0]#	-	GDCMPLT#	Deasserted
DSEL#	-	MD[35:0]#	Tristate
DSTBP[1:0]#	Tristate	MRESET#	-
DSTBN[1:0]#	Tristate	WDEVT#	-
Memory Subsystem / Internal Interface			
AVWP#	-	Q1D[35:0]	Tristate
LDSTB#	-	Q2D[35:0]	Tristate
LRD#	-	Q3D[35:0]	Tristate
Q0D[35:0]	Tristate	WDME#	-
Common Support Signals			
CRES[1:0]	Strapped	TMS	-
TCK	-	TRST#	-
TDI	-	VCCA	Reference
TDO	Tristate	VREF (2)	Reference
Component-Specific Support Signals			
HCLKIN	Toggling		

12.1 Signal Specifications

12.1.1 Unused Pins

For reliable operation, always connect unused inputs to an appropriate signal level. Unused AGTL+ inputs should be connected to V_{TT} . Unused active low 3.3 V-tolerant inputs should be connected to 3.3 V. Unused active high inputs should be connected to ground (V_{SS}). When tying bidirectional signals to power or ground, a resistor must be used. When tying *any* signal to power or ground, a resistor will also allow for fully testing the processor and PCIset after board assembly. It is suggested that $\sim 10K\Omega$ resistors be used for pull-ups and $\sim 1K\Omega$ resistors be used as pull-downs.

12.1.2 Signal Groups

In order to simplify the following discussion, signals have been combined into groups of like characteristics (see below). Refer to Chapter 2 for a description of the signals and their functions.

Table 12-1: Signal Groups MIOC

Pin Group	Signals	Notes
AGTL+ Input	LOCK#, PHIT(a,b)#, RCMPLT(a,b)#, RHIT(a,b)#, X(0,1)RSTFB#, X(0,1)XRTS#, X(0,1)XSTBN#, X(0,1)XSTBP#, HIT#, HITM#	
AGTL+ Output	BR[0]#, BANK[2:0]#, BREQ[0]#, CARD[1:0]#, CMND[1:0]#, CSTB#, DOFF[1:0]#, DSEL[1:0]#, DVALID(a,b)#, MA[13:0]#, MRESET#, ROW#, X(0,1)BLK#, X(0,1)HRTS#, X(0,1)HSTBN#, X(0,1)HSTBP#, X(0,1)RST#, X(0,1)RSTB#, WDEVT#	
AGTL+ I/O	A[35:3]#, ADS#, AERR#, AP[1:0]#, BERR#, BINIT#, BNR#, BPRI#, D[63:0]#, DBSY#, DCMPLT(a,b)#, DEFER#, DEP[7:0]#, DRDY#, DSTBN[3:0]#, DSTBP[3:0]#, MD[71:0]#, REQ[4:0]#, RESET#, RP#, RS[2:0]#, RSP#, TRDY#, X(0,1)ADS#, X(0,1)BE[1:0]#, X(0,1)D[15:0]#, X(0,1)PAR#	
CMOS 14 mA 2.5 V Open Drain Output (3.3 V Tolerant)	INIT#, TDO	
CMOS Input 3.3 V	IOGNT#, TPCTL[1:0], PWRGD,	

Table 12-1: Signal Groups MIOC (Continued)

CMOS Input 2.5 V (3.3 V Tolerant)	HCLKIN, X(0,1)CLKFB, TMS, TDI, TCK, TRST#	1
CMOS I/O 14mA 2.5 V Open Drain Output (3.3 V Tolerant)	BP[1:0]#, ERR[1:0]#	
CMOS Output 10mA 3.3 V	CRESET#, INTREQ#, IOREQ#, SMIACT#, PWRGDB, X(0,1)CLK, X(0,1)CLKB	
Analog signals	CRES[1:0], VCCA[2:0], VREF[5:0]	

Note:

1. HCLKIN is equivalent to the Processor BCLK

Table 12-2: Signal Groups PXB

Pin Group	Signals	Notes
AGTL+ Input	XBLK#, XHRTS#, XHSTBN#, XHSTBP#, XRST#	
AGTL+ Output	XIB, XXRTS#, XXSTBN#, XXSTBP#	
AGTL+ I/O	XADS#, XBE[1:0], XD[15:0]#, XPAR#	
CMOS Input 2.5 V (3.3 V Tolerant)	XCLK, TMS, TDI, TCK, TRST#	
CMOS Input 3.3 V	P(A,B)CLKFB, PIIXOK#, PWRGD	
CMOS Output 10mA, 3.3 V	P(A,B)CLK	
CMOS 14mA 2.5 V Open Drain Output (3.3 V Tolerant)	TDO	
CMOS I/O 14mA, 3.3 V Open Drain Output	P(A,B)MON[1:0]#	
Analog Signals	CRES[1:0], VCCA[2:0], VREF[1:0]	
PCI Signals (Non-Duplicated)	ACK64#, MODE64#, PHOLD#, PHLDA#, REQ64#, WSC#	
PCI Signals	INTRQ(A,B)#, P(A,B)AD[31:0], P(A,B)C/BE#[3:0], P(A,B)DEVSEL#, P(A,B)FRAME#, P(A,B)GNT[5:0]#, P(A,B)IRDY#, P(A,B)LOCK#, P(A,B)PAR, P(A,B)PERR#, P(A,B)REQ(5:0)#, P(A,B)RST#, P(A,B)SERR#, P(A,B)STOP#, P(A,B)TRDY#, P(A,B)XARB#	

Table 12-3: Signal Groups MUX

Pin Group	Signals	Notes
AGTL+ Input	AVWP#, DOFF[1:0]#, DSEL#, DVALID#, LD-STB#, LRD#, WDEVT#, WDME#, MRESET#	
AGTL+ I/O	DCMPLT#, DSTBP[1:0]#, DSTBN[1:0]#, GDCMPLT#, MD[35:0]#	
CMOS Input 2.5 V (3.3 V Tolerant)	HCLKIN, TMS, TDI, TCK, TRST#	
CMOS 14mA, 2.5 V Open Drain Output (3.3 V Tolerant)	TDO	
CMOS I/O 10mA, 3.3 V	Q0D[35:0], Q1D[35:0], Q2D[35:0], Q3D[35:0]	
Analog Signals	CRES[1:0], VCCA, VREF[1:0]	

Table 12-4: Signal Groups RCG

Pin Group	Signals	Notes
AGTL+ Input	BANK[2:0]#, CARD#, CMND[1:0]#, CSTB#, MA[13:0]#, MRESET#, ROW#	
AGTL+ Output	AVWP#, LDSTB#, LRD#, PHIT#, RCMPLT#, RHIT#, WDME#	
AGTL+ I/O	GRCMPLT#	
CMOS Input 3.3 V	BANKID#, DR50H#, DR50T#	
CMOS Input 2.5 V (3.3 V Tolerant)	HCLKIN, TMS, TDI, TCK, TRST#	
CMOS 14mA, 2.5 V Open Drain Output (3.3 V Tolerant)	TDO	
CMOS Output 10mA, 3.3 V	ADDR(A,B,C,D)[13:0]#, WE(A,B,C,D)(a,b)#, CAS(A,B,C,D)(a,b,c,d)[1:0]#, RAS(A,B,C,D)(a,b,c,d)[1:0]#	
Analog Signals	CRES[1:0], VCCA, VREF[1:0]	

12.1.3 The Power Good Signal: PWRGD

PWRGD is a 3.3 V-tolerant input to the PCI Bridge and memory controller components. It is expected that this signal will be a *clean* indication that the clocks and the 3.3 V, VCC_PCI supplies are within their specifications. ‘Clean’ implies that PWRGD will remain low, (capable of sinking leakage current) without glitches, from the time that the power supplies are turned on until they become valid. The signal will then have a single low to high transition to a high (3. V) state with a minimum of 100ns slew rate. Figure 12-1 illustrates the relationship of PWRGD to HCLKIN and system reset signals.

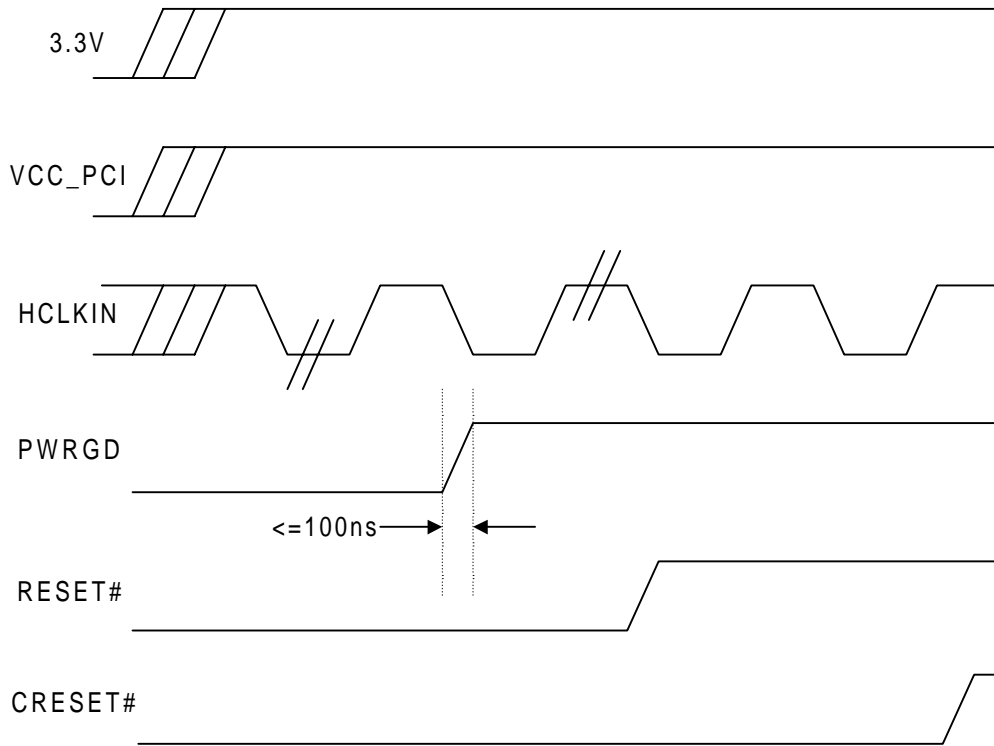


Figure 12-1: PWRGD Relationship

The PWRGD inputs to the Intel® 450NX PCIset and to the Pentium® II Xeon™ processor(s) should be driven with an “AND” of ‘Power-Good’ signals from the 5 V, 3.3 V and V_{CCcoreP} supplies. The output of this logic should be a 3.3 V level and should have a pull-down resistor at the output to cover the period when this logic is not receiving power.

12.1.4 LDSTB# Usage

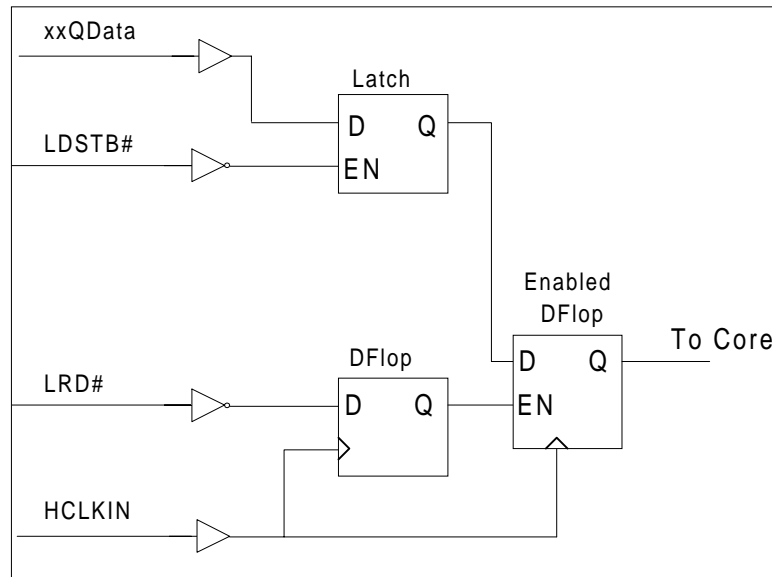


Figure 12-2: LDSTB# Usage

LDSTB# opens a flow-through latch to enable fine tuning of the read data timing. By adjusting the trace length of the LDSTB# signal it is possible to match the CAS# or RAS# timings (whichever is last) for optimal timing margin on DRAM read cycles.

12.1.5 VCCA Pins

The VCCA inputs provide the analog supply voltage used by the internal PLLs. To ensure PLL stability, a filter circuit must be used from the board VCC. Figure 12-3 shows a recommended circuit. It is important to note that a separate filter for each VCCA pin is necessary to avoid feeding noise from one analog circuit to another.

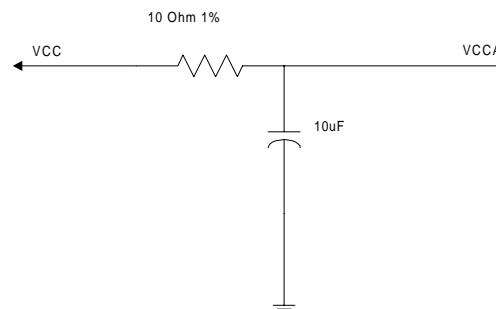


Figure 12-3: VCCA filter

12.2 Maximum Ratings

Table 12-5 contains stress ratings for the Intel® 450NX PCIset. Functional operation at the absolute maximum and minimum ratings is neither implied nor guaranteed. The Intel 450NX PCIset **should not receive a clock while subjected to these conditions**. Functional operating conditions are given in the AC and DC tables. Extended exposure to the maximum ratings may affect device reliability. Furthermore, although the Intel 450NX PCIset contains protective circuitry to resist damage from static discharge, care should always be taken to avoid high static voltages or electric fields.

Table 12-5: Absolute Maximum Ratings

Symbol	Parameter	Min	Max	Unit	Notes
V _{CC3}	3.3 V Supply Voltage with respect to V _{SS}	-0.5	4.3	V	
V _{IN}	AGTL+ Buffer DC Input Voltage with respect to V _{SS}	-0.5	V _{tt} + 0.5 (not to exceed 3.0)	V	1
V _{IN3}	3.3 V Tolerant DC Input Voltage with respect to V _{SS}	-0.5	V _{CC3} + 0.9 (not to exceed 4.3)	V	2
V _{IN5}	5 V Tolerant DC Input Voltage with respect to V _{SS}	-0.5	V _{CC-PCI} + 0.5	V	3
T _{STOR}	Storage Temperature	-65	150	°C	

Notes:

1. Parameter applies to the AGTL+ signal groups only.
2. Parameter applies to 3.3 V-tolerant and JTAG signal groups only.
3. Parameter applies to 5 V-tolerant signal groups and PCI signals only. V_{CC-PCI} is the voltage level on the PCI Bus.

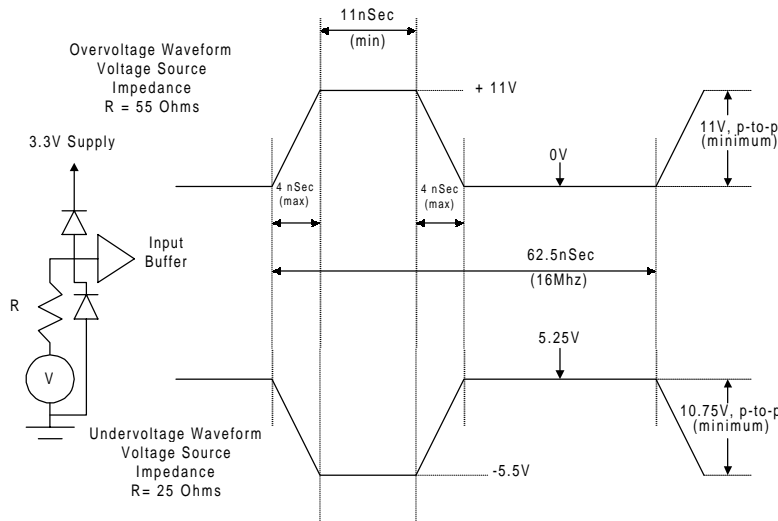


Figure 12-4: Maximum AC Waveforms for 5 V Signaling (PCI Signals)

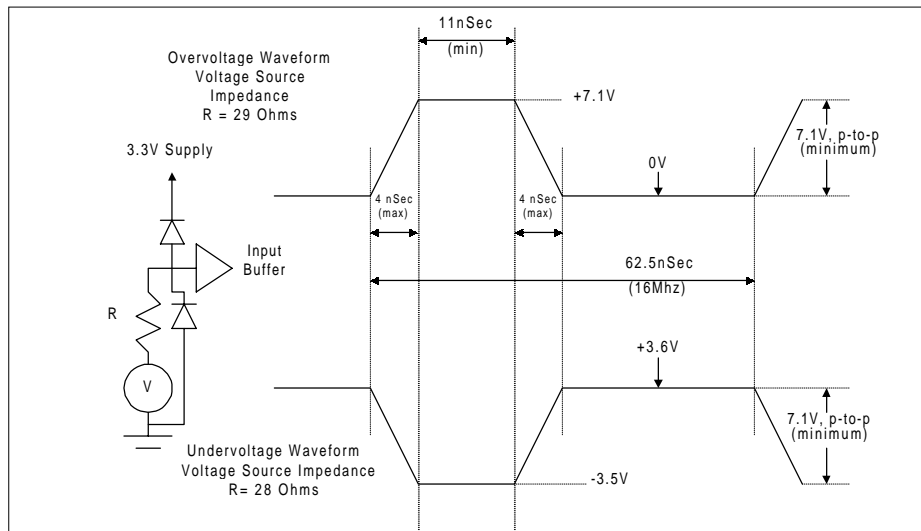


Figure 12-5: Maximum AC Waveforms for 3.3 V Signaling (PCI Signals)

12.3 DC Specifications

Table 12-6 through Table 12-10 list the DC specifications associated with the Intel[®] 450NX PCIset. Care should be taken to read any notes associated with each parameter listed.

Table 12-6: Intel[®] 450NX PCIset Power Parameters

Symbol	Parameter	Min	Typ	Max	Unit	Notes
V _{CC3}	Device V _{CC}	3.13	3.3	3.46	V	1
V _{CC-PCI (3.3)}	PCI V _{CC} for 3.3 V PCI Operation	3.0	3.3	3.6	V	2, 4
V _{CC-PCI (5)}	PCI V _{CC} for 5.0 V PCI Operation	4.5	5.0	5.5	V	2, 4, 5
I _{CC-PCI}	Clamping Diode Leakage Current			2	mA	3
T _C	Operating Case Temperature	0		85	°C	

Notes:

- 3.3 V +/-5%.
- The Intel[®] 450NX PCIset PXB will support either a 5 V or 3.3 V PCI Bus.
- At 33 MHz.
- From PCI Specification Rev 2.1.
- Pin List VCC (A-N).

Table 12-7: Intel® 450NX PCIsset Power Specifications

Symbol	Parameter	Max	Unit	Notes
P_{MAX}	Max Power Dissipation PXB	7.8	W	1, 2, 5
	MIOC	13.2	W	1, 2, 5
	MUX	3.3	W	1, 2, 5
	RCG	2.5	W	1, 5
I_{CC3}	Max Power Supply Current PXB	2.2	A	1, 4
	MIOC	3.3	A	1, 4
	MUX	0.87	A	1, 4
	RCG	0.7	A	1
I_{SS}	Max Power Supply Current PXB	3.3	A	1, 3
	MIOC	18.1	A	1, 3
	MUX	2.5	A	1, 3
	RCG	0.8	A	1, 3

Notes:

1. Frequency = 100 MHz.
2. This specification is a combination of core power (I_{CC3}), and power dissipated in the AGTL+ outputs and I/O.
3. I_{SS} is the maximum supply current consumption when all AGTL+ signals are low.
4. The I_{CC} Specification does not include the AGTL+ output current to GND.

Table 12-8 lists the nominal specifications for the AGTL+ termination voltage (V_{TT}) and the AGTL+ reference voltage (V_{REF}).

Table 12-8: Intel® 450NX PCIsset AGTL+ Bus DC Specifications

Symbol	Parameter	Min	Typ	Max	Unit	Notes
V_{TT}	Bus Termination Voltage		1.5		V	1
V_{REF}	Input Reference Voltage	$2/3 V_{TT} - 2\%$	$2/3 V_{TT}$	$2/3 V_{TT} + 2\%$	V	2, 3

Notes:

1. +/-9% during maximum di/dt and +/- 3% steady state, as measured at component V_{TT} pins.
2. Where V_{TT} tolerance can range from - 9% to +9%, as noted above.
3. V_{REF} should be created from V_{TT} by a voltage divider of 1% resistors.

Some of the signals on the MIOC, PXB, MUX and RCG are in the AGTL+ signal group. These signals are specified to be terminated to 1.5V. The DC specifications for these signals are shown in Table 12-9.

Table 12-9: Intel® 450NX PCIset DC Specifications (AGTL+ Signal Groups) $V_{CC3} = 3.3 \text{ V}$ (5%, $T_{CASE} = 0 \text{ to } 85 \text{ }^\circ\text{C}$)

Symbol	Parameter	Min	Max	Unit	Notes
V_{IL}	Input Low Voltage	-0.3	$V_{REF} - 0.2$	V	1
V_{IH}	Input High Voltage	$V_{REF} + 0.2$	2.185	V	1
V_{OL}	Output Low Voltage		0.6	V	2
V_{OH}	Output High Voltage	1.2	--	V	3
I_{OH}	Output High Current	2	20	mA	
I_{OL}	Output Low Current	38	55	mA	2
I_{LI}	Input Leakage Current		+/- 15	uA	4
I_{REF}	Reference Voltage Current		+/- 15	uA	5
I_{LO}	Output Leakage Current		+/- 15	uA	6
C_{IN}	Input Capacitance		10	pF	7
C_O	Output Capacitance		10	pF	7
$C_{I/O}$	I/O Capacitance		10	pF	7

Notes:

- V_{REF} worst case. Noise on V_{REF} should be accounted for. Refer to the *Pentium® Pro Family Developer's Manual* for more information on V_{REF} .
- Parameter measured into a $25 \text{ } \Omega$ resistor to V_{TT} (1.5 V).
- A high level is maintained by the external pull-up resistors. AGTL+ is an open drain bus. Refer to the *Pentium® Pro Family Developer's Manual* for information on V_{TT} .
- $(0 \leq V_{IN} \leq V_{CC3})$
- Total current for all V_{REF} pins.
- $(0 \leq V_{OUT} \leq V_{CC3})$
- Total of I/O buffer and package parasitics.

Table 12-10: Intel® 450NX PCIset DC Specifications (Non AGTL+ Groups) $V_{CC3} = 3.3 \text{ V}$ (5%, $T_{CASE} = 0 \text{ to } 85 \text{ }^\circ\text{C}$)

Symbol	Pin Group	Parameter	Min	Max	Unit	Notes/Test Conditions
C_{IN}	All	Input Capacitance		10	pF	1
C_O	All	Output Capacitance		10	pF	
$C_{I/O}$	All	I/O Capacitance		10	pF	
C_{CLK}	HCLKIN	HCLKIN Input Capacitance		10	pF	
C_{TCK}	TCK	TCK Input Capacitance		8	pF	
I_{OL-14}	CMOS 2.5 V OD 14mA	Output Low Current	14.0		mA	
I_{OL-10}	CMOS 10mA	Output Low Current	10.0		mA	2
V_{OL}	CMOS 10mA	Output Low Voltage		0.45	V	

Table 12-10: Intel® 450NX PCIset DC Specifications (Non AGTL+ Groups) (Continued) $V_{CC3} = 3.3\text{ V}$ (5%, $T_{CASE} = 0\text{ to }85\text{ }^{\circ}\text{C}$)

Symbol	Pin Group	Parameter	Min	Max	Unit	Notes/Test Conditions
V_{OL}	CMOS 2.5 V OD 14mA	Output Low Voltage		0.45	V	11
V_{OH}	CMOS 10mA	Output High Voltage	2.4		V	9
V_{OH}	CMOS 2.5 V OD 14mA	Output High Voltage	--			8, 11
I_{LO}	CMOS 10mA	Output Leakage Current		+/-10	uA	3
I_{LI}	CMOS Input	Input Leakage Current		+/-10	uA	4, 5
V_{IL}	CMOS Input	Input Low Voltage	-0.5	0.8	V	
V_{IH}	CMOS Input	Input High Voltage	2.0	3.6	V	
V_{IL}	CMOS 2.5 V Input	Input Low Voltage	-0.5	0.7	V	11
V_{IH}	CMOS 2.5 V Input	Input High Voltage	1.7	3.6	V	11
V_{IL-PCI}	PCI	Input Low Voltage	- 0.5	0.8	V	6
V_{IH-PCI}	PCI	Input High Voltage	2.0	V_{CC-PCI} +0.5	V	6, 7
V_{OL-PCI}	PCI	Output Low Voltage		0.55	V	6
V_{OH-PCI}	PCI	Output High Voltage	2.4		V	6
I_{OL-PCI}	PCI	Output Low Current	6.0		mA	6
I_{LI-PCI}	PCI	Input Leakage Current		+/-70	uA	6
I_{LO-PCI}	PCI	Output Leakage Current		+/-10	uA	6

Notes:

1. Except HCLK, TCK
2. $V_{OL} = 0.4\text{V}$
3. ($0 \leq V_{OUT} \leq V_{CC3}$)
4. ($0 \leq V_{IN} \leq V_{CC3}$)
5. -100uA for pins with 50K pullups, +100uA for pins with 50K pulldowns.
6. 5 V-tolerant 3.3V I/O buffer.
7. $V_{CC-PCI} = \text{PCI Bus Voltage}$.
8. Determined by 2.5 V connected through a 150 ohm resistor.
9. Measured with 10ma load.
10. Specifications for PCI are from PCI Specification Rev 2.1.
11. 3.3 V-tolerant 2.5 V Input or Output buffer.

12.4 AC Specifications

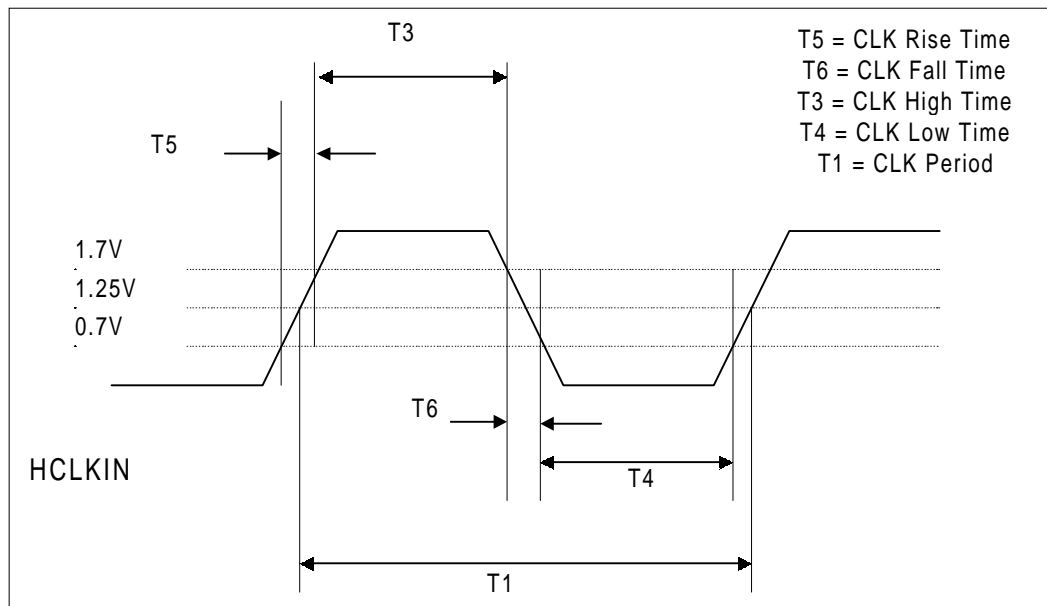


Figure 12-6: CLK Waveform

Table 12-11: Intel® 450NX PCIset Clock Specifications

$V_{CC3} = 3.3\text{ V (5\%, } T_{CASE} = 0\text{ to }85\text{ }^{\circ}\text{C)}$

Symbol	Parameter	Min	Max	Unit	Notes
	Host Interface:				
	Bus Frequency	90	100	MHz	
T1	CLK Period	10	11.11	ns	1
T2	CLK Period Stability		+/-100	ps	1
T3	CLK High Time	3		ns	1
T4	CLK Low Time	3		ns	1
T5	CLK Rise Time	0.5	1.5	ns	1
T6	CLK Fall Time	0.5	1.5	ns	1
T9	TCK Frequency		16.67	MHz	
T72	TCK Hightime	25		ns	
T73	TCK Lowtime	25		ns	
T74	TCK rise time		5	ns	
T75	TCK fall time		5	ns	

Note:

1. These specifications apply to all clock inputs for all four Intel® 450NX PCIset components.

Table 12-12: Intel® 450NX PCIset MIOC AC Specifications

V_{CC3} = 3.3V (5%, T_{CASE} = 0 to 85 °C)

Symbol	Parameter	Setup Min	Hold Min	Delay Min	Delay Max	Unit	Notes
	Host Interface:						
T10A	A[35:3]#, ADS#, AERR#, AP[1:0]#, BERR#, BINIT#, BNR#, BPRI#, D[63:0]#, DBSY#, DEFER#, DEP[7:0]#, DRDY#, REQ[4:0]#, RP#, RS[2:0]#, RSP#, TRDY#	1.58	0.63	-0.15	2.65	ns	8
T17	BP[1:0]	2.0	0.5	1.0	5.0	ns	10
T11	BR0#			-0.15	2.65	ns	8
T13A	HIT#, HITM#, LOCK#	1.58	0.63			ns	
T12	INIT#			1.0	5.0	ns	9
	Third-Party Agent Interface:						
T14	IOREQ#			0.0	3.5	ns	3
T15	IOGNT#	2.0	0.5			ns	
T16	TPCTL[1:0]	2.0	0.5			ns	
	Memory Interface:						
T11	BANK[2:0]#, CARD[1:0]#, CMND[1:0]#, CSTB#, DOFF[1:0], DSEL[1:0]#, DVALID(a,b)#, MA[13:0]#, ROW#, WDEVT#			-0.15	2.65	ns	8
T11	MRESET#			-0.15	2.65	ns	7, 8
T10	DCMPLT(a,b)#	1.88	0.63	-0.15	2.65	ns	8
T13	PHIT(a,b)#, RCM-PLT(a,b)#, RHIT(a,b)#	1.88	0.63			ns	
	MD(71:0)#, DST-BP(3:0)#, DST-BN(3:0)#						11
							11
							11

Table 12-12: Intel® 450NX PCIset MIOC AC Specifications (Continued)V_{CC3} = 3.3V (5%, T_{CASE} = 0 to 85 °C)

Symbol	Parameter	Setup Min	Hold Min	Delay Min	Delay Max	Unit	Notes
	Expander Interface (two per MIOC:0,1)						
T21	X(0,1)RST#, X(0,1)RSTB#			-0.1	3.25	ns	7, 8
T23	X(0,1)RSTFB#, X(0,1)XRSTB#	1.88	0.63			ns	
T11	X(0,1)HRTS#			-0.15	2.65	ns	8
	Other						
T39	CRESET#			1.0	4.1	ns	3
T25	ERR[1:0]#	2.0	0.5	1.0	5.0	ns	10
T70	INTREQ#, SMI- ACT#			0.0	3.5	ns	3
T71	PWRGD	4.0	1.0			ns	1, 6
T70	PWRGDB			0.0	3.5	ns	3, 5, 13
T21	RESET#			-0.1	3.25	ns	7, 8, 12
	Testability Signals:						
T26	TRST#					ns	4, 6
T27	TMS	5.0	14.0			ns	2
T27	TDI	5.0	14.0			ns	2
T28	TDO			1.0	10.0	ns	2, 3
T29	TDO on/off delay				25.0	ns	2, 3

Notes:

1. The power supply must wait until all voltages are stable for at least 1ms, and then assert the PWRGD signal.
2. 3.3 V-tolerant signals. Inputs are referenced to TCK rising, outputs are referenced to TCK falling.
3. Min and Max timings are measured with 0pF load.
4. TRST# requires a pulse width of 40 ns.
5. This output is asynchronous.
6. This input is asynchronous.
7. Asynchronous assertion with synchronous deassertion.
8. Min and Max timings are measured with 0pf and 25 Ohms to V_{tt}.
9. Min and Max timings are measured with 0pf and 150 Ohms to 2.5 V.
10. Min and Max timings are measured with 0pf and 230 Ohm to 3.3 V.
11. See Table 12-16 for source synchronous timings.
12. Minimum pulse width 1.0ms.
13. PWRGDB is the buffered output of PWRGD, and has no relation to HCLKIN.

Table 12-13: Intel® 450NX PCIset PXB AC Specifications

V_{CC3} = 3.3 V (5%, T_{CASE} = 0 to 85 °C)

Symbol	Parameter	Setup Min	Hold Min	Delay Min	Delay Max	Unit	Notes
	PCI Interface						
T30	P(A,B)AD[31:0], P(A,B)C/BE[3:0]#, P(A,B)TRDY#, P(A,B)STOP#, P(A,B)LOCK#, P(A,B)DEVSEL#, P(A,B)PAR, P(A,B)IRDY#, P(A,B)FRAME#, P(A,B)PERR#, P(A,B)XARB#	7.0	0.0	2.0	11.0	ns	1, 3
T31	P(A,B)REQ[5:0]#	12.0	0.0			ns	1, 3
T32	P(A,B)GNT[5:0]#			2.0	12.0	ns	1, 3
T34	INTRQ(A,B)#, P(A,B)RST#, P(A,B)SERR#			2.0	11.0	ns	1, 3
T33	ACK64#	7.0	0.0	2.0	11.0	ns	1, 3
T35	PHOLD#	7.0	0.0			ns	1
T36	PHLDA#			2.0	12.0	ns	1, 3
T37	REQ64#	7.0	0.0	2.0	11.0	ns	1, 3
T38	WSC#			2.0	12.0	ns	1, 3
	Expander Interface (one per PXB)						
T40	XRST#	2.8	0.0			ns	6
T11	XXRTS#			-0.15	2.65	ns	8
T13	XHRTS#	1.88	0.63			ns	
	OTHER						
T47	P(A,B)MON[1:0]#	4.0	0.5	1.0	6.0	ns	4
T46	PIIXOK#	7.0	0.0			ns	1
	Testability Signals:						
T26	TRST#					ns	5, 7
T27	TMS	5.0	14.0			ns	2
T27	TDI	5.0	14.0			ns	2
T28	TDO			1.0	10.0	ns	2, 4
T29	TDO on/off delay				25.0	ns	2, 4

Notes:

1. 5 V-tolerant.
2. 3.3 V-tolerant signals. Inputs are referenced to TCK rising, outputs are referenced to TCK falling.
3. Min timings are measured with 0pF load, Max timings are measured with 50pF load.
4. Min and Max timings are measured with 0pF load.
5. TRST# requires a pulse width of 40 ns.
6. This signal has an asynchronous assertion and a synchronous deassertion.
7. This input is asynchronous.

PCI Bus Signal Waveforms: All PCI Bus signals are referenced to the PCLK Rising edge. For more information on the PCI Bus signals and waveforms, please refer to the *PCI Specification*.

Table 12-14: Intel® 450NX PCIset RCG AC Specifications

$V_{CC3} = 3.3 \text{ V}$ (5%, $T_{CASE} = 0 \text{ to } 85 \text{ }^{\circ}\text{C}$)

Symbol	Parameter	Setup Min	Hold Min	Delay Min	Delay Max	Unit	Notes
	Memory Subsystem/ External Interface						
T50	BANK[2:0]#, CARD#, CMND[1:0]#, CSTB#, MA[13:0]#, ROW#	2.80	0.0			ns	
T51	GRCMPLT#	2.80	0.0	-0.15	2.65	ns	6
T52	PHIT#, RCMPLT#, RHIT#			-0.15	2.65	ns	6
	Memory Subsystem/Internal Interface						
T52	AVWP#, LRD#, WDME#, LD-STB#			-0.15	2.65	ns	6
T53	CAS(A,B,C,D)(a,b,c,d)[1:0]#			0.0	3.5	ns	3
T54	ADDR(A,B,C,D)[13:0]#			1.0	5.5	ns	3
T53	RAS(A,B,C,D)(a,b,c,d)[1:0]#			0.0	3.5	ns	3
T53	WE(A,B,C,D)(a,b)#			0.0	3.5	ns	3
	Other						
T50	MRESET#	2.8	0.0			ns	5
T26	TRST#					ns	4, 7
T27	TMS	5.0	14.0			ns	2
T27	TDI	5.0	14.0			ns	2
T28	TDO			1.0	10.0	ns	2, 3
T29	TDO on/off delay				25.0	ns	2, 3

Notes:

1. The power supply must wait until all voltages are stable for at least 1ms, and then assert the PWRGD signal.
2. 3.3- tolerant signals. Inputs are referenced to TCK rising, outputs are referenced to TCK falling.
3. Min and Max timings are measured with 0pF load.
4. TRST# requires a pulse width of 40 ns.
5. Max delay timing requirement from MIOC to RCGs and MUXs is two clock cycles. Asynchronous assertion and synchronous deassertion.
6. Min and Max timings are measured with 0pF and 25Ω to V_{tt} (1.5 V).
7. This input is asynchronous.

Table 12-15: Intel® 450NX PCIset MUX AC Specifications $V_{CC3} = 3.3\text{ V}$ (5%, $T_{CASE} = 0$ to 85°C)

Symbol	Parameter	Setup Min	Hold Min	Delay Min	Delay Max	Unit	Notes
	Memory Subsystem/ External Interface						
T60	DCMPLT#	2.8	0.0	-0.15	2.65	ns	6
T61	DOFF[1:0]#, DSEL#, DVALID#, WDEVT#	2.8	0.0			ns	8
T60	GDCMPLT#	2.8	0.0	-0.15	2.65	ns	6
T67	LDSTB#	3.0	1.0			ns	
	Memory Subsystem/ Internal Interface						
T62	AVWP#, WDME#	3.5	0.0			ns	
T62	LRD#	3.5	0.0			ns	
T68	Q0D[35:0], Q1D[35:0], Q2D[35:0], Q3D[35:0]	1.0	4.0	0.0	3.5	ns	2, 4
	Other						
T69	MRESET#	2.8	0.0			ns	5
	Testability Signals:						
T26	TRST#					ns	3, 7
T27	TMS, TDI	5.0	14.0			ns	1
T28	TDO			1.0	10.0	ns	1, 2
T29	TDO on/off delay				25.0	ns	1, 2

Notes:

- 3.3 V-tolerant signals. Inputs are referenced to TCK rising, outputs are referenced to TCK falling.
- Min and Max timings are measured with 0pF load.
- TRST# requires a pulse width of 40 ns.
- Input timings are referenced from LDSTB# rising edge. Output timings are referenced from HCLKIN.
- Max delay timing requirement from MIOC to RCGs and MUXs is two clock cycles. Asynchronous assertion and synchronous deassertion.
- Min and Max timings are measured with 0pF and 25Ω to V_{tt} (1.5 V).
- This input is asynchronous.
- DOFF[1:0]#, DSEL#, WDEVT# max delay timing requirement from MIOC to MUX is two clock cycles.

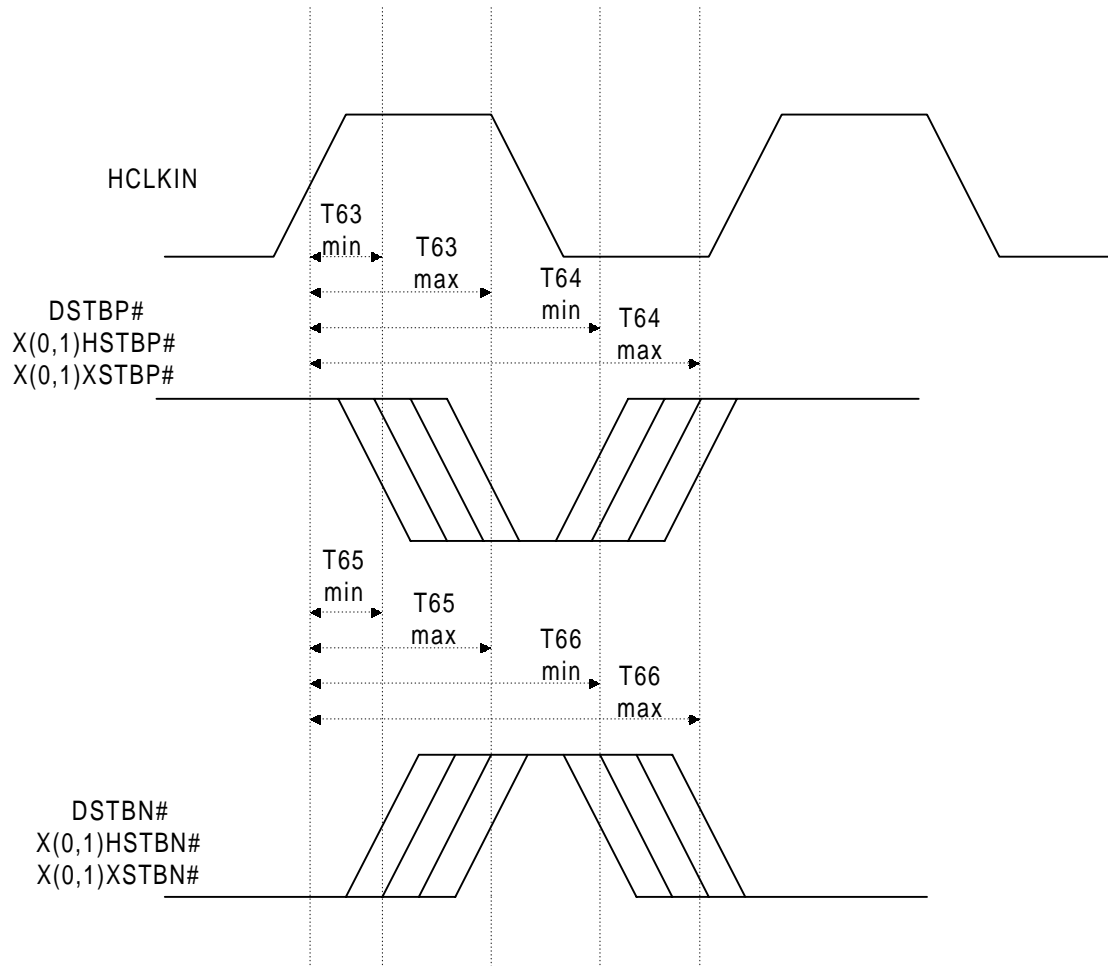


Figure 12-7: Source Synchronous Strobe Timing

Table 12-16: 100 MHz Source Synchronous Timing

Symbol	Parameter	Delay Min	Delay Max	Skew	Unit	Notes
T63	DSTBP(3:0)#, X(0,1)HSTBP#, X(0,1)XSTBP# Falling Edge	2.35	5.15		ns	1, 2, 4
T64	DSTBP(3:0)#, X(0,1)HSTBP#, X(0,1)XSTBP# Rising Edge	7.35	10.15		ns	1, 3, 4
T65	DSTBN(3:0)#, X(0,1)HSTBN#, X(0,1)XSTBN# Rising Edge	2.35	5.15		ns	1, 2, 4
T66	DSTBN(3:0)#, X(0,1)HSTBN#, X(0,1)XSTBN# Falling Edge	7.35	10.15		ns	1, 3, 4

Notes:

1. Relative to HCLKIN Rising edge.
2. Strobe timings are generated from an internal clock which is a multiple of HCLKIN. This enables the strobes to track system timings staying centered within the data window. Numbers given are for 100 MHz operation. Timings for other frequencies can be calculated by $\text{Strobe_Min_Time} = [-0.15 + (1/\text{Bus_Freq})1/4]$ ns and $\text{Strobe_Max_Time} = [2.65 + (1/\text{Bus_Freq})1/4]$ ns.
3. Strobe timings are generated from an internal clock which is a multiple of HCLKIN. This enables the strobes to track system timings staying centered within the data window. Numbers given are for 100 MHz operation. Timings for other frequencies can be calculated by $\text{Strobe_Min_Time} = [-0.15 + (1/\text{Bus_Freq})3/4]$ ns and $\text{Strobe_Max_Time} = [2.65 + (1/\text{Bus_Freq})3/4]$ ns.
4. Min and Max timings are measured with 0pF and 25Ω to Vtt (1.5 V).

Table 12-17: Source Synchronous Signal to Strobe Timings (at source)

Symbol	Parameter	Setup Min	Setup Max	Hold Min	Hold Max	Notes
T80	MD(71:0)#, X(0,1)D[15:0]#, X(0,1)ADS#, X(0,1)BE[1:0]#, X(0,1)BLK#, X(0,1)PAR#	2.0	2.75			1-5
T81	MD(71:0)#, X(0,1)D[15:0]#, X(0,1)ADS#, X(0,1)BE[1:0]#, X(0,1)BLK#, X(0,1)PAR#			2.0	2.75	1-5

Notes:

1. MD(71:0)# strobes are single-ended, and the falling edge of the strobe is used to capture data; Expander strobes are differential.
2. Values are guaranteed by design.
3. Setup Max and Hold Max are specified at frequency= 100 MHz.
4. Timings for other frequencies can be calculated as follows: T80 Setup_Max = $[(1/\text{Bus_Freq})1/4 + .250]$ ns, T81 Hold_Max = $[(1/\text{Bus_Freq})1/4 + .250]$ ns, where .250ns represents the error margin around strobe placement.
5. Data delay times relative to HCLK for any bus frequency can be calculated as follows... For First Data: Data_Min_Time = $[-0.15]$ ns and Data_Max_Time = $[2.65]$ ns; For Second Data: Data_Min_Time = $[-0.15 + (1/\text{Bus_Freq})/2]$ ns and Data_Max_Time = $[2.65 + (1/\text{Bus_Freq})/2]$ ns.

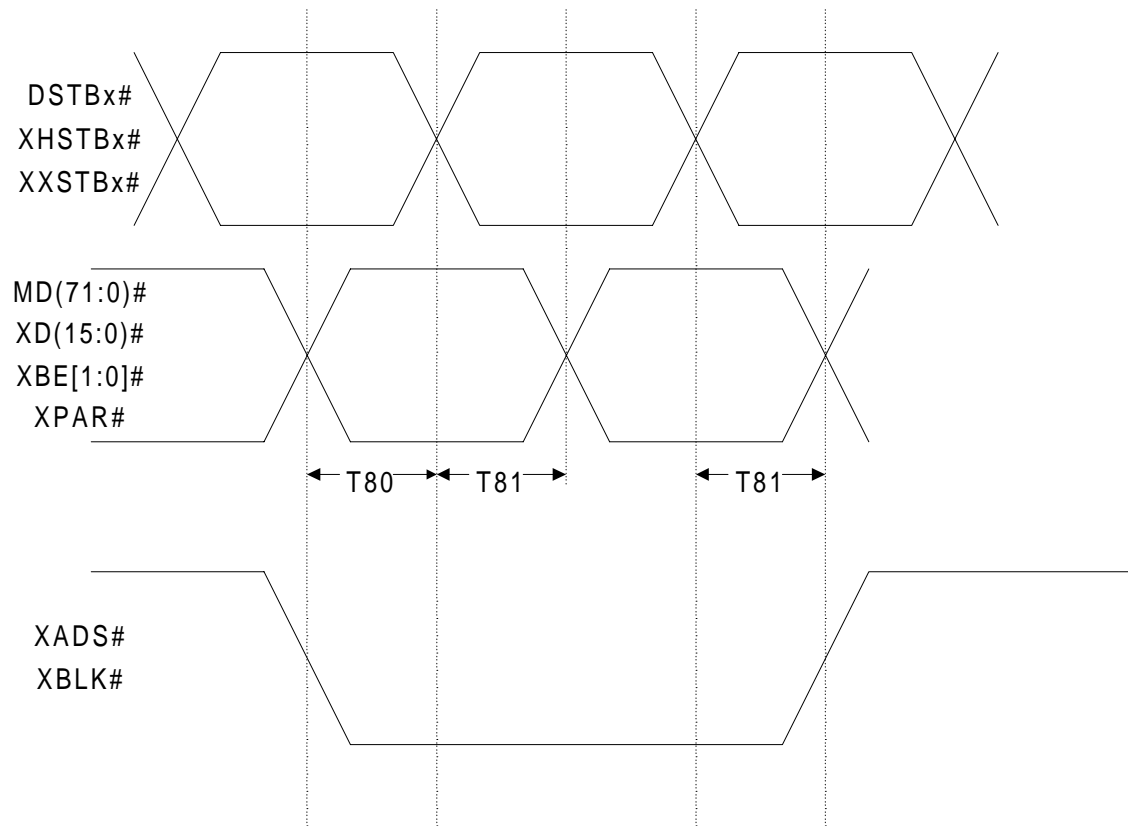


Figure 12-8: Source Synchronous Signal to Strobe Timings (at source)

Table 12-18: 100 MHz Source Synchronous Timing (at destination)

Symbol	Parameter	Setup Min	Hold Min	Unit	Notes
T20	DSTBN(3:0)#, DSTBP(3:0)# X(0,1)XSTBN# X(0,1)XSTBP#	7.0		ns	1,4
T24	MD(71:0)#	1.5	1.5	ns	2
T22	X(0,1)D[15:0]#, X(0,1)ADS#, X(0,1)BE[1:0]#, X(0,1)BLK#, X(0,1)D[15:0]#, X(0,1)PAR#	1.75	1.0	ns	3

Notes:

1. Setup in relation to “capture” HCLKIN.
2. With respect to the DSTBs.
3. With respect to the HSTBs.
4. Applies to Expander bus source synchronous signals. For synchronous signals (RTS#) the maximum clock skew between MIOC and PXB plus the flight time must not exceed 4.97nS.

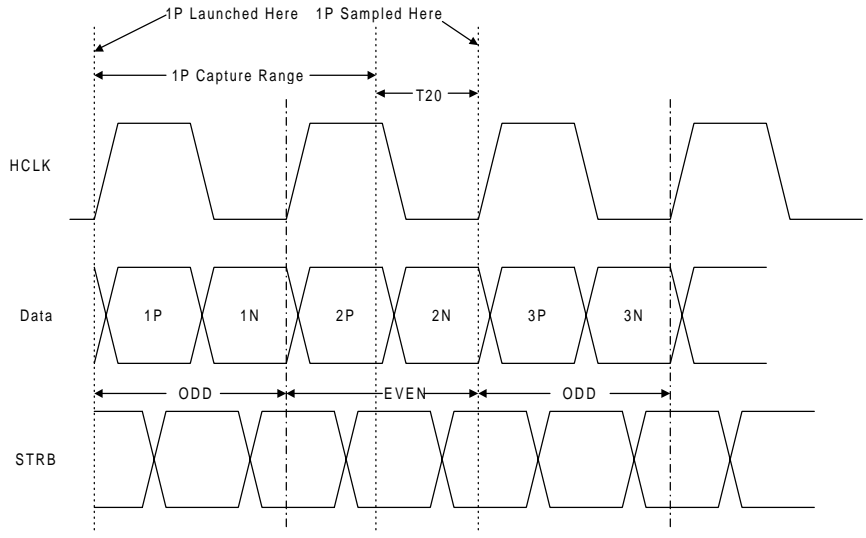


Figure 12-9: Source Synchronous Data Transfer

12.5 Source Synchronous Data Transfers

A Source Synchronous packet has a two clock period delivery time, and is divided into positive and negative phases of even and odd cycles. During this two clock window, packets are launched synchronously and sampled synchronously. Signals launched with a positive phase “even” clock are sampled on a positive phase of next “even” clock. Between launch and sample, signals are captured with source synchronous strobes.

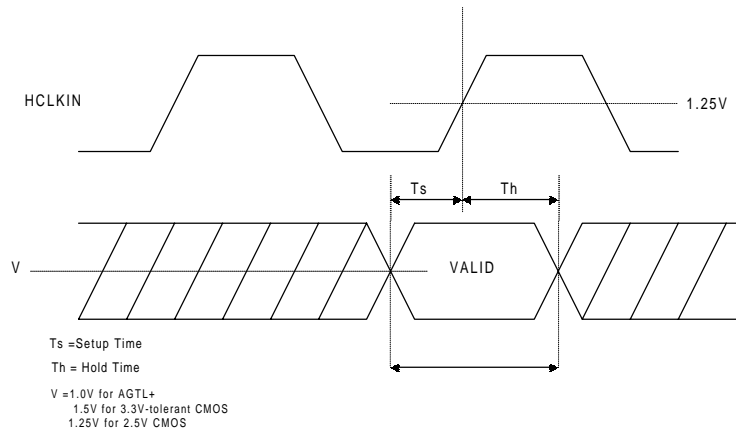


Figure 12-10: Setup and Hold Timings

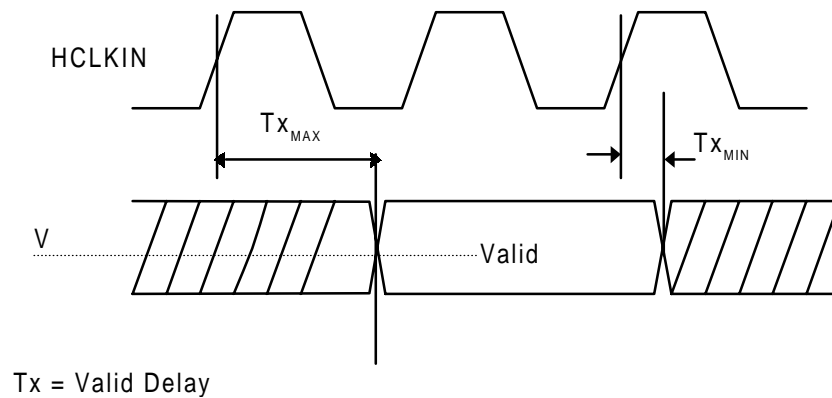


Figure 12-11: Valid Delay Timing

12.6 I/O Signal Simulations: Ensuring I/O Timings

It is highly recommended that system designers run extensive simulations on their Pentium® II Xeon™ processor/Intel® 450NX PCIset-based designs. These simulations should include the memory subsystem design as well. Please refer to the *Pentium® Pro Family Developer's Manual* for more information.

12.7 Signal Quality Specifications

Signals driven by any component on the Pentium® II Xeon™ processor bus must meet signal quality specifications to guarantee that the components read data properly, and to ensure that incoming signals do not affect the long term reliability of the components. There are three signal quality parameters defined: Overshoot/Undershoot, Ringback, and Settling Limit, which are discussed in the next sections.

12.7.1 Intel® 450NX PCIset Ringback Specification

This section discusses the ringback specification for the parameters in the AGTL+ signal groups on the Intel® 450NX PCIset.

Case A requires less time than Case B from the V_{REF} crossing until the ringback into the "overdrive" region. The longer time from V_{REF} crossing until the ringback into the "overdrive" region required in Case B allows the ringback to be closer to V_{REF} for a defined period.

Table 12-19: Intel® 450NX PCIset AGTL+ Signal Groups Ringback Tolerance: Case A

Parameter	Min	Unit	Figure	Notes
α Overshoot	100	mV	12 & 13	1
τ Minimum Time at High or Low	2.25	ns	12 & 13	1
ρ Amplitude of Ringback	-100	mV	12 & 13	1
δ Duration of Squarewave Ringback	N/A	ns	12 & 13	1
ϕ Final Settling Voltage	100	mV	12 & 13	1

Note:

1. Specified for an edge rate of 0.8-1.3 V/ns. See the *Pentium® Pro Family Developer's Manual* for the definition of these terms. See Figure 12-12 and Figure 12-13 for the generic waveforms. All values are determined by design/characterization.

Table 12-20: Intel® 450NX PCIset AGTL+ Signal Groups Ringback Tolerance: Case B

Parameter	Min	Unit	Figure	Notes
α Overshoot	100	mV	12 & 13	1
τ Minimum Time at High or Low	2.7	ns	12	1
τ Minimum Time at Low	3.7	ns	13	1
ρ Amplitude of Ringback	-0	mV	12 & 13	1
δ Duration of Squarewave Ringback	2	ns	12 & 13	1
ϕ Final Settling Voltage	100	mV	12 & 13	1

Note:

1. Specified for an edge rate of 0.8-1.3 V/ns. See the *Pentium® Pro Family Developer's Manual* for the definition of these terms. See the figures below for the generic waveforms. All values are determined by design/characterization.

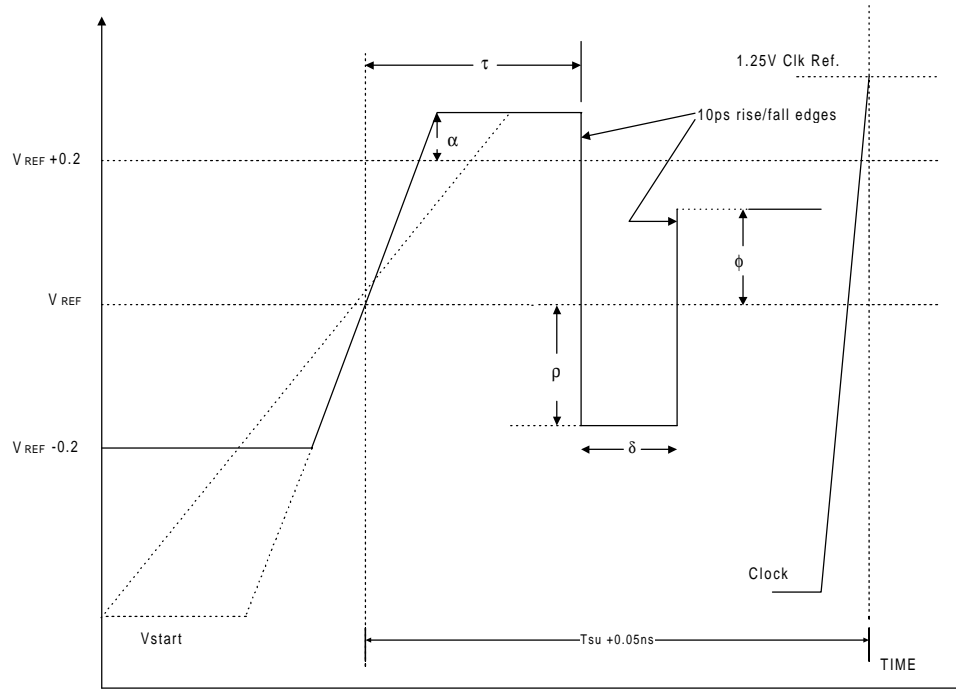


Figure 12-12: Standard Input Lo-to-Hi Waveform for Characterizing Receiver Ringback Tolerance

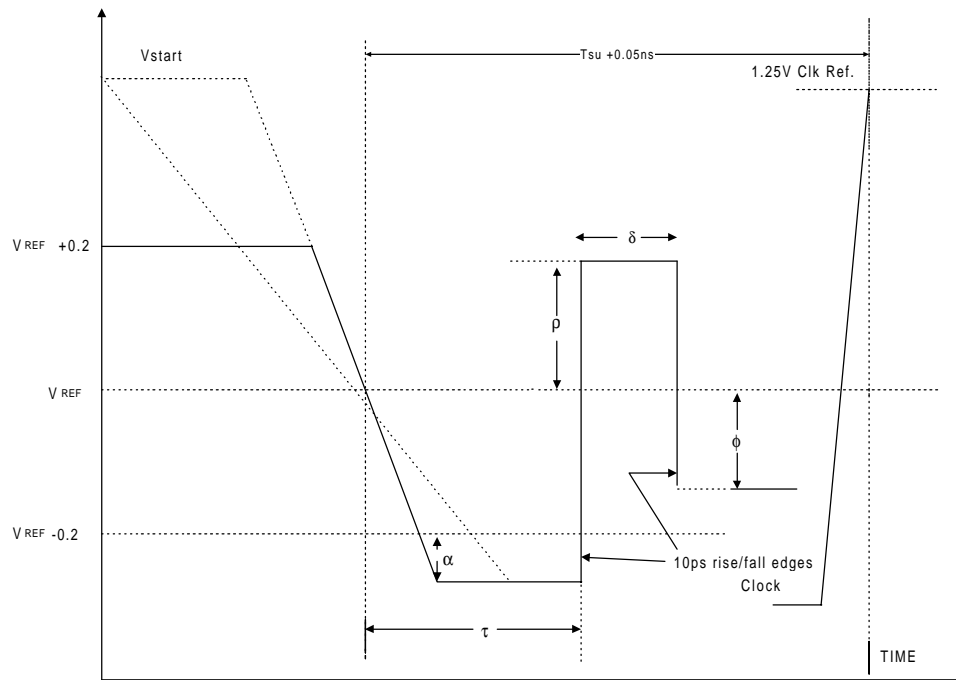


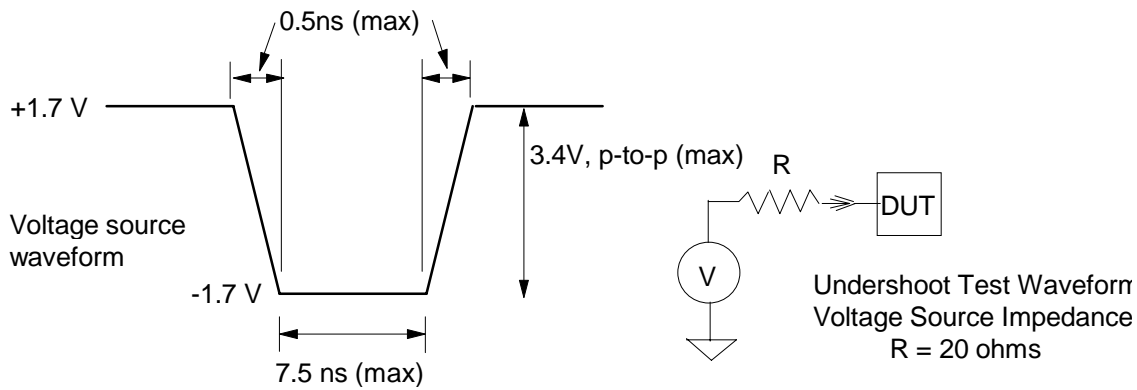
Figure 12-13: Standard Input Hi-to-Lo Waveform for Characterizing Receiver Ringback Tolerance

12.7.2 Intel® 450NX PCIset Undershoot Specification

The undershoot specification for the Intel 450NX PCIset components (and Pentium II Xeon processor) is as follows:

The Pentium II Xeon processor bus signals AERR#, BERR#, BINIT#, BNR#, HIT#, and HITM# (only) are capable of sinking an 85mA current pulse at a 2.4% average time duty cycle. This is equivalent to -1.7V applied to a 20Ω source in series with the device pin for 5.38 ns at 100 MHz with a utilization of 5%.

This test covers the AC operating conditions only



Average duty cycle of 2.4%.

Figure 12-14: Undershoot Test Setup

12.7.3 Skew Requirements

The skew requirement for XpRST# versus XpRSTFB#, and XpCLK versus XpCLKFB is +/- 125ps.

The electrical length (delay) from the XpCLK# signal pin on the MIOC to the clock input of the PXB must match the delay to the XpCLKFB# pin on the MIOC by that amount. The same is true with XpRST# and XpRSTFB#.

12.8 Intel® 450NX PCIset Thermal Specifications

12.8.1 Thermal Solution Performance

The system's thermal solution must adequately control the package temperatures below the maximum and above the minimum specified. The performance of any thermal solution is defined as the thermal resistance between the package and the ambient air around the part (package to ambient). The lower the thermal resistance between the package and the ambient air, the more efficient the thermal solution is. The required θ package to ambient is dependent upon the maximum allowed package temperature (T_{Package}), the local ambient temperature (TLA), and the package power (P_{Package}).

$$\text{Package to ambient} = (T_{\text{Package}} - T_{\text{LA}}) / P_{\text{Package}}$$

TLA is a function of the system design. Table 12-21 and Table 12-22 provide the resulting thermal solution performance required for an Intel® 450NX PCIset at different ambient air temperatures around the parts.

Table 12-21: Example Thermal Solution Performance for MIOC at Package Power of 13.2 Watts

Local Ambient Temperature (TLA)			
	35° C	40° C	45° C
θ Package to ambient °C/(Watt)	3.79	3.41	3.03

Table 12-22: Example Thermal Solution Performance for PXB at Package Power of 7.8 Watts

Local Ambient Temperature (TLA)			
	35° C	40° C	45° C
θ Package to ambient °C/(Watt)	6.41	5.76	5.13

The θ package to ambient value is made up of two primary components: the thermal resistance between the package and heatsink (θ package to heatsink) and the thermal resistance between the heatsink and the ambient air around the part (θ heatsink to air). A critical but controllable factor to decrease the value of θ package to heatsink is management of the thermal interface between the package and heatsink. The other controllable factor (θ heatsink to air) is determined by the design of the heatsink and airflow around the heatsink.

12.9 Mechanical Specifications

12.9.1 Pin Lists Sorted by Pin Number:

Table 12-23: MIOC Pin List Sorted by Pin

Pin #	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
A01	GND		Power		
A02	GND		Power		
A03	GND		Power		
A04	DBSY#	I/O	AGTL+	55ma	
A05	A07#	I/O	AGTL+	55ma	
A06	GND		Power		
A07	A13#	I/O	AGTL+	55ma	
A08	VTT		Power		
A09	A20#	I/O	AGTL+	55ma	
A10	GND		Power		
A11	GND		Power		
A12	A29#	I/O	AGTL+	55ma	
A13	A34#	I/O	AGTL+		
A14	GND		Power		
A15	D01#	I/O	AGTL+	55ma	
A16	GND		Power		
A17	CRES1	I	Analog		
A18	D12#	I/O	AGTL+	55ma	
A19	GND		Power		
A20	D19#	I/O	AGTL+	55ma	
A21	D22#	I/O	AGTL+	55ma	
A22	GND		Power		
A23	GND		Power		
A24	D32#	I/O	AGTL+	55ma	
A25	VTT		Power		
A26	D38#	I/O	AGTL+	55ma	
A27	GND		Power		
A28	D46#	I/O	AGTL+	55ma	
A29	D49#	I/O	AGTL+	55ma	
A30	VCC		Power		
A31	VCC		Power		
A32	VCC		Power		
B01	GND		Power		

Table 12-23: MIOC Pin List Sorted by Pin (Continued)

Pin #	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
B02	GND		Power		
B03	RS0#	I/O	AGTL+	55ma	
B04	A03#	I/O	AGTL+	55ma	
B05	GND		Power		
B06	A10#	I/O	AGTL+	55ma	
B07	A14#	I/O	AGTL+	55ma	
B08	VTT		Power		
B09	A21#	I/O	AGTL+	55ma	
B10	A24#	I/O	AGTL+	55ma	
B11	A27#	I/O	AGTL+	55ma	
B12	A30#	I/O	AGTL+	55ma	
B13	A35#	I/O	AGTL+	55ma	
B14	DRDY#	I/O	AGTL+	55ma	
B15	D02#	I/O	AGTL+	55ma	
B16	D06#	I/O	AGTL+	55ma	
B17	D09#	I/O	AGTL+	55ma	
B18	D13#	I/O	AGTL+	55ma	
B19	D17#	I/O	AGTL+	55ma	
B20	D20#	I/O	AGTL+	55ma	
B21	D23#	I/O	AGTL+	55ma	
B22	D27#	I/O	AGTL+	55ma	
B23	D29#	I/O	AGTL+	55ma	
B24	D33#	I/O	AGTL+	55ma	
B25	VTT		Power		
B26	D39#	I/O	AGTL+	55ma	
B27	D43#	I/O	AGTL+	55ma	
B28	GND		Power		
B29	D50#	I/O	AGTL+	55ma	
B30	D54#	I/O	AGTL+	55ma	
B31	VCC		Power		
B32	VCC		Power		
C01	GND		Power		
C02	BNR#	I/O	AGTL+	55ma	
C03	RS1#	I/O	AGTL+	55ma	
C04	A04#	I/O	AGTL+	55ma	
C05	A08#	I/O	AGTL+	55ma	
C06	A11#	I/O	AGTL+	55ma	
C07	A15#	I/O	AGTL+	55ma	

Table 12-23: MIOC Pin List Sorted by Pin (Continued)

Pin #	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
C08	A18#	I/O	AGTL+	55ma	
C09	A22#	I/O	AGTL+	55ma	
C10	VCC		Power		
C11	CRES0	I	Analog		
C12	A31#	I/O	AGTL+	55ma	
C13	VCC		Power		
C14	VCC		Power		
C15	D03#	I/O	AGTL+	55ma	
C16	VTT		Power		
C17	VTT		Power		
C18	D14#	I/O	AGTL+	55ma	
C19	VCC		Power		
C20	VCC		Power		
C21	D24#	I/O	AGTL+	55ma	
C22	VCC		Power		
C23	N/C				
C24	D34#	I/O	AGTL+	55ma	
C25	D36#	I/O	AGTL+	55ma	
C26	D40#	I/O	AGTL+	55ma	
C27	D44#	I/O	AGTL+	55ma	
C28	D47#	I/O	AGTL+	55ma	
C29	D51#	I/O	AGTL+	55ma	
C30	D55#	I/O	AGTL+	55ma	
C31	D57#	I/O	AGTL+	55ma	
C32	VCC		Power		
D01	BPRI#	I/O	AGTL+	55ma	
D02	TRDY#	I/O	AGTL+	55ma	
D03	VTT		Power		
D04	A05#	I/O	AGTL+	55ma	
D05	VTT		Power		
D06	A12#	I/O	AGTL+	55ma	
D07	A16#	I/O	AGTL+	55ma	
D08	GND		Power		
D09	A23#	I/O	AGTL+	55ma	
D10	A25#	I/O	AGTL+	55ma	
D11	A28#	I/O	AGTL+	55ma	
D12	A32#	I/O	AGTL+	55ma	
D13	BERR#	I/O	AGTL+	55ma	

Table 12-23: MIOC Pin List Sorted by Pin (Continued)

Pin #	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
D14	D00#	I/O	AGTL+	55ma	
D15	D04#	I/O	AGTL+	55ma	
D16	D07#	I/O	AGTL+	55ma	
D17	D10#	I/O	AGTL+	55ma	
D18	D15#	I/O	AGTL+	55ma	
D19	D18#	I/O	AGTL+	55ma	
D20	D21#	I/O	AGTL+	55ma	
D21	D25#	I/O	AGTL+	55ma	
D22	D28#	I/O	AGTL+	55ma	
D23	D30#	I/O	AGTL+	55ma	
D24	D35#	I/O	AGTL+	55ma	
D25	GND		Power		
D26	D41#	I/O	AGTL+	55ma	
D27	D45#	I/O	AGTL+	55ma	
D28	VTT		Power		
D29	D52#	I/O	AGTL+	55ma	
D30	VTT		Power		
D31	D58#	I/O	AGTL+	55ma	
D32	D60#	I/O	AGTL+	55ma	
E01	REQ0#	I/O	AGTL+	55ma	
E02	RSP#	I/O	AGTL+	55ma	
E03	RS2#	I/O	AGTL+	55ma	
E04	A06#	I/O	AGTL+	55ma	
E05	A09#	I/O	AGTL+	55ma	
E06	VCC		Power		
E07	A17#	I/O	AGTL+	55ma	
E08	A19#	I/O	AGTL+	55ma	
E09	GND		Power		
E10	A26#	I/O	AGTL+	55ma	
E11	VTT		Power		
E12	A33#	I/O	AGTL+	55ma	
E13	GND		Power		
E14	GND		Power		
E15	D05#	I/O	AGTL+	55ma	
E16	D08#	I/O	AGTL+	55ma	
E17	D11#	I/O	AGTL+	55ma	
E18	D16#	I/O	AGTL+	55ma	
E19	GND		Power		

Table 12-23: MIOC Pin List Sorted by Pin (Continued)

Pin #	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
E20	GND		Power		
E21	D26#	I/O	AGTL+	55ma	
E22	VTT		Power		
E23	D31#	I/O	AGTL+	55ma	
E24	GND		Power		
E25	D37#	I/O	AGTL+	55ma	
E26	D42#	I/O	AGTL+	55ma	
E27	VCC		Power		
E28	D48#	I/O	AGTL+	55ma	
E29	D53#	I/O	AGTL+	55ma	
E30	D56#	I/O	AGTL+	55ma	
E31	D59#	I/O	AGTL+	55ma	
E32	D61#	I/O	AGTL+	55ma	
F01	GND		Power		
F02	REQ4#	I/O	AGTL+	55ma	
F03	LOCK#	I	AGTL+		
F04	REQ1#	I/O	AGTL+	55ma	
F05	VCC		Power		
F28	VCC		Power		
F29	D62#	I/O	AGTL+	55ma	
F30	D63#	I/O	AGTL+	55ma	
F31	DEP7#	I/O	AGTL+	55ma	
F32	GND		Power		
G01	GND		Power		
G02	HIT#	I	AGTL+		
G03	VTT		Power		
G04	REQ2#	I/O	AGTL+	55ma	
G05	DEFER#	I/O	AGTL+	55ma	
G28	DEP6#	I/O	AGTL+	55ma	
G29	DEP5#	I/O	AGTL+	55ma	
G30	VTT		Power		
G31	DEP4#	I/O	AGTL+	55ma	
G32	DEP3#	I/O	AGTL+	55ma	
H01	AP0#	I/O	AGTL+	55ma	
H02	HITM#	I	AGTL+		
H03	VTT		Power		
H04	REQ3#	I/O	AGTL+	55ma	
H05	GND		Power		

Table 12-23: MIOC Pin List Sorted by Pin (Continued)

Pin #	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
H28	GND		Power		
H29	CRESET#	O	LVTTL	10ma	
H30	DEP2#	I/O	AGTL+	55ma	
H31	DEP1#	I/O	AGTL+	55ma	
H32	DEP0#	I/O	AGTL+	55ma	
J01	AP1#	I/O	AGTL+	55ma	
J02	BR0#	O	AGTL+	55ma	
J03	ADS#	I/O	AGTL+	55ma	
J04	RP#	I/O	AGTL+	55ma	
J05	GND		Power		
J28	X0CLKFB	I	LVTTL		
J29	BINIT#	I/O	AGTL+	55ma	
J30	BP0#	I/O	OD	14ma	
J31	BP1#	I/O	OD	14ma	
J32	GND		Power		
K01	ERR0#	I/O	OD	14ma	
K02	ERR1#	I/O	OD	14ma	
K03	VCC		Power		
K04	VREF	I	Analog		
K05	AERR#	I/O	AGTL+	55ma	
K28	VCC		Power		
K29	N/C				
K30	VCCA0		Power		
K31	VCCA1		Power		
K32	VCCA2		Power		
L01	GND		Power		
L02	TRST#	I	LVTTL		
L03	TCK	I	LVTTL		
L04	INTREQ#	O	LVTTL	10ma	
L05	TMS	I	LVTTL		
L28	X0CLK	O	LVTTL	10ma	
L29	X0CLKB	O	LVTTL	10ma	
L30	VCC		Power		
L31	PWRGD	I	LVTTL		
L32	GND		Power		
M01	TPCTL0	I	LVTTL		
M02	VCC		Power		
M03	TDO	O	OD	14ma	

Table 12-23: MIOC Pin List Sorted by Pin (Continued)

Pin #	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
M04	TDI	I	LVTTTL		
M05	GND		Power		
M28	GND		Power		
M29	RESET#	I/O	AGTL+	55ma	
M30	X1CLK	O	LVTTTL	10ma	
M31	X1CLKB	O	LVTTTL	10ma	
M32	X0RSTFB#	I	AGTL+		
N01	VCC		Power		
N02	TPCTL1	I	LVTTTL		
N03	VTT		Power		
N04	IOREQ#	O	LVTTTL	10ma	
N05	IOGNT#	I	LVTTTL		
N28	X1CLKFB	I	LVTTTL		
N29	INIT#	OD	2.5V	14ma	
N30	X0RSTB#	O	AGTL+	55ma	
N31	VREF	I	Analog		
N32	VCC		Power		
P01	VCC		Power		
P02	MD00#	I/O	AGTL+	55ma	
P03	MD01#	I/O	AGTL+	55ma	
P04	MD02#	I/O	AGTL+	55ma	
P05	VCC		Power		
P28	PWRGDB	O	LVTTTL	10ma	
P29	X0RST#	O	AGTL+	55ma	
P30	X0BE1#	I/O	AGTL+	55ma	
P31	X0BE0#	I/O	AGTL+	55ma	
P32	VCC		Power		
R01	GND		Power		
R02	MD03#	I/O	AGTL+	55ma	
R03	MD04#	I/O	AGTL+	55ma	
R04	VCC		Power		
R05	VCC		Power		
R28	HCLKIN	I	2.5V		
R29	GND		Power		
R30	X0ADS#	I/O	AGTL+	55ma	
R31	X0PAR#	I/O	AGTL+	55ma	
R32	X0BLK#	O	AGTL+	55ma	
T01	MD05#	I/O	AGTL+	55ma	

Table 12-23: MIOC Pin List Sorted by Pin (Continued)

Pin #	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
T02	MD06#	I/O	AGTL+	55ma	
T03	MD07#	I/O	AGTL+	55ma	
T04	MD08#	I/O	AGTL+	55ma	
T05	VCC		Power		
T28	GND		Power		
T29	X0D03#	I/O	AGTL+	55ma	
T30	X0D02#	I/O	AGTL+	55ma	
T31	X0D01#	I/O	AGTL+	55ma	
T32	X0D00#	I/O	AGTL+	55ma	
U01	DSTBP0#	I/O	AGTL+	55ma	
U02	DSTBN0#	I/O	AGTL+	55ma	
U03	MD09#	I/O	AGTL+	55ma	
U04	GND		Power		
U05	GND		Power		
U28	N/C				
U29	X0D04#	I/O	AGTL+	55ma	
U30	VREF	I	Analog		
U31	X0D05#	I/O	AGTL+	55ma	
U32	GND		Power		
V01	VCC		Power		
V02	MD10#	I/O	AGTL+	55ma	
V03	MD11#	I/O	AGTL+	55ma	
V04	GND		Power		
V05	GND		Power		
V28	VCC		Power		
V29	VCC		Power		
V30	X0XSTBN#	I	AGTL+		
V31	X0XSTBP#	I	AGTL+		
V32	GND		Power		
W01	MD12#	I/O	AGTL+	55ma	
W02	MD13#	I/O	AGTL+	55ma	
W03	MD14#	I/O	AGTL+	55ma	
W04	MD15#	I/O	AGTL+	55ma	
W05	GND		Power		
W28	VCC		Power		
W29	X0XRTS#	I	AGTL+		
W30	X0HRTS#	O	AGTL+	55ma	
W31	X0HSTBN#	O	AGTL+	55ma	

Table 12-23: MIOC Pin List Sorted by Pin (Continued)

Pin #	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
W32	X0HSTBP#	O	AGTL+	55ma	
Y01	VCC		Power		
Y02	MD16#	I/O	AGTL+	55ma	
Y03	VTT		Power		
Y04	MD17#	I/O	AGTL+	55ma	
Y05	MD18#	I/O	AGTL+	55ma	
Y28	GND		Power		
Y29	X0D07#	I/O	AGTL+	55ma	
Y30	VTT		Power		
Y31	X0D06#	I/O	AGTL+	55ma	
Y32	VCC		Power		
AA01	MD19#	I/O	AGTL+	55ma	
AA02	MD20#	I/O	AGTL+	55ma	
AA03	MD21#	I/O	AGTL+	55ma	
AA04	MD22#	I/O	AGTL+	55ma	
AA05	GND		Power		
AA28	GND		Power		
AA29	X0D11#	I/O	AGTL+	55ma	
AA30	X0D10#	I/O	AGTL+	55ma	
AA31	X0D09#	I/O	AGTL+	55ma	
AA32	X0D08#	I/O	AGTL+	55ma	
AB01	GND		Power		
AB02	MD23#	I/O	AGTL+	55ma	
AB03	VCC		Power		
AB04	MD24#	I/O	AGTL+	55ma	
AB05	MD25#	I/O	AGTL+	55ma	
AB28	X0D14#	I/O	AGTL+	55ma	
AB29	X0D13#	I/O	AGTL+	55ma	
AB30	VCC		Power		
AB31	X0D12#	I/O	AGTL+	55ma	
AB32	GND		Power		
AC01	GND		Power		
AC02	MD26#	I/O	AGTL+	55ma	
AC03	VREF	I	Analog		
AC04	DSTBP1#	I/O	AGTL+	55ma	
AC05	GND		Power		
AC28	GND		Power		
AC29	X1RST#	O	AGTL+	55ma	

Table 12-23: MIOC Pin List Sorted by Pin (Continued)

Pin #	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AC30	VCC		Power		
AC31	X0D15#	I/O	AGTL+	55ma	
AC32	VCC		Power		
AD01	DSTBN1#	I/O	AGTL+	55ma	
AD02	MD27#	I/O	AGTL+	55ma	
AD03	MD28#	I/O	AGTL+	55ma	
AD04	MD29#	I/O	AGTL+	55ma	
AD05	GND		Power		
AD28	GND		Power		
AD29	X1BE1#	I/O	AGTL+	55ma	
AD30	X1BE0#	I/O	AGTL+	55ma	
AD31	X1RSTB#	O	AGTL+	55ma	
AD32	X1ADS#	I/O	AGTL+	55ma	
AE01	GND		Power		
AE02	MD30#	I/O	AGTL+	55ma	
AE03	VTT		Power		
AE04	MD31#	I/O	AGTL+	55ma	
AE05	MD32#	I/O	AGTL+	55ma	
AE28	X1BLK#	O	AGTL+	55ma	
AE29	X1D1#	I/O	AGTL+	55ma	
AE30	VTT		Power		
AE31	X1D00#	I/O	AGTL+	55ma	
AE32	GND		Power		
AF01	GND		Power		
AF02	MD33#	I/O	AGTL+	55ma	
AF03	VTT		Power		
AF04	MD34#	I/O	AGTL+	55ma	
AF05	MD35#	I/O	AGTL+	55ma	
AF28	VCC		Power		
AF29	X1D03#	I/O	AGTL+	55ma	
AF30	VTT		Power		
AF31	X1D02#	I/O	AGTL+	55ma	
AF32	GND		Power		
AG01	MD36#	I/O	AGTL+	55ma	
AG02	MD37#	I/O	AGTL+	55ma	
AG03	MD38#	I/O	AGTL+	55ma	
AG04	MD39#	I/O	AGTL+	55ma	
AG05	VCC		Power		

Table 12-23: MIOC Pin List Sorted by Pin (Continued)

Pin #	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AG28	VCC		Power		
AG29	VREF	I	Analog		
AG30	X1D05#	I/O	AGTL+	55ma	
AG31	X1D04#	I/O	AGTL+	55ma	
AG32	X1RSTFB#	I	AGTL+		
AH01	MD40#	I/O	AGTL+	55ma	
AH02	MD41#	I/O	AGTL+	55ma	
AH03	MD42#	I/O	AGTL+	55ma	
AH04	MD43#	I/O	AGTL+	55ma	
AH05	MD44#	I/O	AGTL+	55ma	
AH06	VCC		Power		
AH07	MD57#	I/O	AGTL+	55ma	
AH08	MD62#	I/O	AGTL+	55ma	
AH09	DSTBN3#	I/O	AGTL+	55ma	
AH10	VCC		Power		
AH11	VCC		Power		
AH12	DOFF0#	O	AGTL+	55ma	
AH13	GND		Power		
AH14	GND		Power		
AH15	DCMPLTB#	I/O	AGTL+	55ma	
AH16	ROW#	O	AGTL+	55ma	
AH17	VCC		Power		
AH18	BANK1#	O	AGTL+	55ma	
AH19	GND		Power		
AH20	GND		Power		
AH21	MA07#	O	AGTL+	55ma	
AH22	VTT		Power		
AH23	MA12#	O	AGTL+	55ma	
AH24	GND		Power		
AH25	GND		Power		
AH26	X1D14#	I/O	AGTL+	55ma	
AH27	VCC		Power		
AH28	X1HSTBN#	O	AGTL+	55ma	
AH29	X1HSTBP#	O	AGTL+	55ma	
AH30	X1XSTBN#	I	AGTL+		
AH31	X1XSTBP#	I	AGTL+		
AH32	GND		Power		
AJ01	DSTBP2#	I/O	AGTL+	55ma	

Table 12-23: MIOC Pin List Sorted by Pin (Continued)

Pin #	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AJ02	DSTBN2#	I/O	AGTL+	55ma	
AJ03	VTT		Power		
AJ04	MD45#	I/O	AGTL+	55ma	
AJ05	VTT		Power		
AJ06	MD54#	I/O	AGTL+	55ma	
AJ07	MD58#	I/O	AGTL+	55ma	
AJ08	GND		Power		
AJ09	MD63#	I/O	AGTL+	55ma	
AJ10	MD67#	I/O	AGTL+	55ma	
AJ11	MD71#	I/O	AGTL+	55ma	
AJ12	CMND1#	O	AGTL+	55ma	
AJ13	DSEL0#	O	AGTL+	55ma	
AJ14	WDEVT#	O	AGTL+	55ma	
AJ15	RCMPLTB#	I	AGTL+		
AJ16	DCMPLTA#	I/O	AGTL+	55ma	
AJ17	BANK0#	O	AGTL+	55ma	
AJ18	CARD1#	O	AGTL+	55ma	
AJ19	GND		Power		
AJ20	MA02#	O	AGTL+	55ma	
AJ21	MA06#	O	AGTL+	55ma	
AJ22	MA09#	O	AGTL+	55ma	
AJ23	MA11#	O	AGTL+	55ma	
AJ24	GND		Power		
AJ25	GND		Power		
AJ26	GND		Power		
AJ27	X1D13#	I/O	AGTL+	55ma	
AJ28	VTT		Power		
AJ29	X1D06#	I/O	AGTL+	55ma	
AJ30	VTT		Power		
AJ31	X1XRTS#	I	AGTL+		
AJ32	X1HRTS#	O	AGTL+	55ma	
AK01	VCC		Power		
AK02	MD46#	I/O	AGTL+	55ma	
AK03	MD47#	I/O	AGTL+	55ma	
AK04	MD48#	I/O	AGTL+	55ma	
AK05	MD49#	I/O	AGTL+	55ma	
AK06	MD55#	I/O	AGTL+	55ma	
AK07	MD59#	I/O	AGTL+	55ma	

Table 12-23: MIOC Pin List Sorted by Pin (Continued)

Pin #	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AK08	DSTBP3#	I/O	AGTL+	55ma	
AK09	MD64#	I/O	AGTL+	55ma	
AK10	MD68#	I/O	AGTL+	55ma	
AK11	VCC		Power		
AK12	VCC		Power		
AK13	PHITA#	I	AGTL+		
AK14	VCC		Power		
AK15	DVALIDA#	O	AGTL+	55ma	
AK16	VTT		Power		
AK17	VTT		Power		
AK18	VCC		Power		
AK19	VCC		Power		
AK20	VCC		Power		
AK21	MA5#	O	AGTL+	55ma	
AK22	VCC		Power		
AK23	VCC		Power		
AK24	GND		Power		
AK25	GND		Power		
AK26	X1D15#	I/O	AGTL+	55ma	
AK27	GND		Power		
AK28	X1D10#	I/O	AGTL+	55ma	
AK29	X1D09#	I/O	AGTL+	55ma	
AK30	X1D08#	I/O	AGTL+	55ma	
AK31	X1D07#	I/O	AGTL+	55ma	
AK32	GND		Power		
AL01	VCC		Power		
AL02	VCC		Power		
AL03	MD50#	I/O	AGTL+	55ma	
AL04	MD51#	I/O	AGTL+	55ma	
AL05	GND		Power		
AL06	MD56#	I/O	AGTL+	55ma	
AL07	MD60#	I/O	AGTL+	55ma	
AL08	VTT		Power		
AL09	MD65#	I/O	AGTL+	55ma	
AL10	MD69#	I/O	AGTL+	55ma	
AL11	CMND0#	O	AGTL+	55ma	
AL12	RHITA#	I	AGTL+		
AL13	MRESET#	O	AGTL+	55ma	

Table 12-23: MIOC Pin List Sorted by Pin (Continued)

Pin #	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AL14	DSEL1#	O	AGTL+	55ma	
AL15	VREF	I	Analog		
AL16	DVALIDB#	O	AGTL+	55ma	
AL17	PHITB#	I	AGTL+	55ma	
AL18	CARD0#	O	AGTL+	55ma	
AL19	SMIACT#	O	LVTTTL	10ma	
AL20	MA01#	O	AGTL+	55ma	
AL21	MA04#	O	AGTL+	55ma	
AL22	MA08#	O	AGTL+	55ma	
AL23	MA10#	O	AGTL+	55ma	
AL24	VCC		Power		
AL25	VTT		Power		
AL26	VTT		Power		
AL27	GND		Power		
AL28	GND		Power		
AL29	X1D12#	I/O	AGTL+	55ma	
AL30	X1D11#	I/O	AGTL+	55ma	
AL31	GND		Power		
AL32	GND		Power		
AM01	VCC		Power		
AM02	VCC		Power		
AM03	VCC		Power		
AM04	MD52#	I/O	AGTL+	55ma	
AM05	MD53#	I/O	AGTL+	55ma	
AM06	GND		Power		
AM07	MD61#	I/O	AGTL+	55ma	
AM08	VTT		Power		
AM09	MD66#	I/O	AGTL+	55ma	
AM10	MD70#	I/O	AGTL+	55ma	
AM11	GND		Power		
AM12	CSTB#	O	AGTL+	55ma	
AM13	DOFF1#	O	AGTL+	55ma	
AM14	GND		Power		
AM15	RCMPLTA#	I	AGTL+		
AM16	GND		Power		
AM17	RHITB#	I	AGTL+		
AM18	BANK2#	O	AGTL+	55ma	
AM19	GND		Power		

Table 12-23: MIOC Pin List Sorted by Pin (Continued)

Pin #	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AM20	MA00#	O	AGTL+	55ma	
AM21	MA03#	O	AGTL+	55ma	
AM22	GND		Power		
AM23	GND		Power		
AM24	MA13#	O	AGTL+	55ma	
AM25	VTT		Power		
AM26	VTT		Power		
AM27	GND		Power		
AM28	GND		Power		
AM29	X1PAR#	I/O	AGTL+	55ma	
AM30	GND		Power		
AM31	GND		Power		
AM32	GND		Power		

Table 12-24: PXB Pinlist Sorted by Pin

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
A01	N/C				
A02	N/C				
A03	VCC		Power		
A04	VCC		Power		
A05	VCC		Power		
A06	VCC		Power		
A07	VCC		Power		
A08	VCC		Power		
A09	VCC		Power		
A10	VCC		Power		
A11	N/C				
A12	VREF	I	Analog		
A13	N/C				
A14	VCC		Power		
A15	XD[10]#	I/O	AGTL+	55ma	
A16	VCC		Power		
A17	XHSTBN#	I	AGTL+		
A18	VCC		Power		
A19	XD[04]#	I/O	AGTL+	55ma	
A20	VCC		Power		
A21	XBLK#	I	AGTL+		
A22	VCC		Power		

Table 12-24: PXB Pinlist Sorted by Pin (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
A23	N/C				
A24	VREF	I	Analog		
A25	N/C				
A26	VCC		Power		
A27	VCCA0		Power		
A28	VCC		Power		
A29	VCC		Power		
A30	N/C				
A31	N/C				
A32	N/C				
B01	N/C				
B02	VCC		Power		
B03	VCC		Power		
B04	VCC		Power		
B05	N/C				
B06	N/C				
B07	N/C				
B08	N/C				
B09	N/C				
B10	N/C				
B11	N/C				
B12	N/C				
B13	N/C				
B14	XD[15]#	I/O	AGTL+	55ma	
B15	XD[11]#	I/O	AGTL+	55ma	
B16	XD[08]#	I/O	AGTL+	55ma	
B17	N/C				
B18	XHRTS#	I	AGTL+		
B19	XD[05]#	I/O	AGTL+	55ma	
B20	XD[02]#	I/O	AGTL+	55ma	
B21	XPAR#	I/O	AGTL+	55ma	
B22	XBE[01]#	I/O	AGTL+	55ma	
B23	N/C				
B24	N/C				
B25	N/C				
B26	N/C				
B27	N/C				
B28	VCC		Power		

Table 12-24: PXB Pinlist Sorted by Pin (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
B29	VCC		Power		
B30	VCC		Power		
B31	VCC		Power		
B32	N/C				
C01	N/C				
C02	N/C				
C03	N/C				
C04	N/C				
C05	N/C				
C06	GND		Power		
C07	GND		Power		
C08	GND		Power		
C09	N/C				
C10	GND		Power		
C11	N/C				
C12	GND		Power		
C13	N/C				
C14	GND		Power		
C15	XD[12]#	I/O	AGTL+	55ma	
C16	GND		Power		
C17	XHSTBP#	I	AGTL+		
C18	GND		Power		
C19	XXSTBN#	O	AGTL+	55ma	
C20	GND		Power		
C21	XADS#	I/O	AGTL+	55ma	
C22	GND		Power		
C23	N/C				
C24	GND		Power		
C25	XCLK	I	LVTTTL		
C26	GND		Power		
C27	VCCA1		Power		
C28	N/C				
C29	N/C				
C30	N/C				
C31	N/C				
C32	N/C				
D01	N/C				
D02	GND		Power		

Table 12-24: PXB Pinlist Sorted by Pin (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
D03	N/C				
D04	VTT		Power		
D05	N/C				
D06	N/C				
D07	N/C				
D08	N/C				
D09	CRES1	I	Analog		
D10	N/C				
D11	N/C				
D12	N/C				
D13	N/C				
D14	N/C				
D15	XD[13]#	I/O	AGTL+	55ma	
D16	XD[09]#	I/O	AGTL+	55ma	
D17	XD[06]#	I/O	AGTL+	55ma	
D18	XXRTS#	O	AGTL+	55ma	
D19	N/C				
D20	XD[03]#	I/O	AGTL+	55ma	
D21	XD[00]#	I/O	AGTL+	55ma	
D22	XRST#	I	AGTL+		
D23	N/C				
D24	N/C				
D25	N/C				
D26	N/C				
D27	VCC		Power		
D28	VTT		Power		
D29	PWRGD	I	LVTTL		
D30	N/C				
D31	GND		Power		
D32	N/C				
E01	N/C				
E02	N/C				
E03	N/C				
E04	N/C				
E05	N/C				
E06	VTT		Power		
E07	N/C				
E08	VTT		Power		

Table 12-24: PXB Pinlist Sorted by Pin (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
E09	CRES0	I	Analog		
E10	VTT		Power		
E11	N/C				
E12	VTT		Power		
E13	XIB	O	AGTL+	55ma	
E14	VTT		Power		
E15	XD[14]#	I/O	AGTL+	55ma	
E16	VTT		Power		
E17	XD[07]#	I/O	AGTL+	55ma	
E18	VTT		Power		
E19	XXSTBP#	O	AGTL+	55ma	
E20	VTT		Power		
E21	XD[01]#	I/O	AGTL+	55ma	
E22	VTT		Power		
E23	XBE[00]#	I/O	AGTL+	55ma	
E24	VTT		Power		
E25	N/C				
E26	VTT		Power		
E27	VCCA2		Power		
E28	N/C				
E29	N/C				
E30	N/C				
E31	N/C				
E32	N/C				
F01	GND		Power		
F02	N/C				
F03	VCC		Power		
F04	N/C				
F05	GND		Power		
F28	GND		Power		
F29	PIIXOK#	I	LVTTL		
F30	N/C				
F31	N/C				
F32	N/C				
G01	N/C				
G02	N/C				
G03	N/C				
G04	N/C				

Table 12-24: PXB Pinlist Sorted by Pin (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
G05	N/C				
G28	N/C				
G29	N/C				
G30	VCC		Power		
G31	VCC		Power		
G32	N/C				
H01	VCC		Power		
H02	N/C				
H03	GND		Power		
H04	N/C				
H05	VCC		Power		
H28	N/C				
H29	N/C				
H30	GND		Power		
H31	N/C				
H32	N/C				
J01	N/C				
J02	N/C				
J03	N/C				
J04	N/C				
J05	N/C				
J28	N/C				
J29	N/C				
J30	PBCLKFB	I	LVTTL		
J31	N/C				
J32	PACLKFB	I	LVTTL		
K01	GND		Power		
K02	N/C				
K03	VCC		Power		
K04	N/C				
K05	GND		Power		
K28	GND		Power		
K29	N/C				
K30	VCC		Power		
K31	N/C				
K32	GND		Power		
L01	GND		Power		
L02	GND		Power		

Table 12-24: PXB Pinlist Sorted by Pin (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
L03	GND		Power		
L04	GND		Power		
L05	GND		Power		
L28	N/C				
L29	N/C				
L30	PBCLK	O	LVTTL	10ma	
L31	N/C				
L32	PACLK	O	LVTTL	10ma	
M01	VCC		Power		
M02	N/C				
M03	GND		Power		
M04	TCK	I	2.5V		
M05	VCC		Power		
M28	VCC		Power		
M29	N/C				
M30	GND		Power		
M31	N/C				
M32	VCC		Power		
N01	TDI	I	2.5V		
N02	TDO	O	OD	14ma	
N03	VCC		Power		
N04	TMS	I	2.5V		
N05	TRST#	I	2.5V		
N28	N/C				
N29	N/C				
N30	N/C				
N31	N/C				
N32	N/C				
P01	VCC		Power		
P02	N/C				
P03	GND		Power		
P04	N/C				
P05	VCC		Power		
P28	GND		Power		
P29	N/C				
P30	VCC		Power		
P31	N/C				
P32	GND		Power		

Table 12-24: PXB Pinlist Sorted by Pin (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
R01	VCC		Power		
R02	N/C				
R03	GND		Power		
R04	N/C				
R05	VCC		Power		
R28	GND		Power		
R29	N/C				
R30	VCC		Power		
R31	N/C				
R32	GND		Power		
T01	VCC		Power		
T02	N/C				
T03	GND		Power		
T04	N/C				
T05	VCC		Power		
T28	GND		Power		
T29	N/C				
T30	VCC		Power		
T31	N/C				
T32	GND		Power		
U01	N/C				
U02	N/C				
U03	N/C				
U04	N/C				
U05	N/C				
U28	N/C				
U29	N/C				
U30	VCC		Power		
U31	N/C				
U32	GND		Power		
V01	GND		Power		
V02	N/C				
V03	VCC5A	I	Power (PCI)		
V04	N/C				
V05	GND		Power		
V28	VCC		Power		
V29	N/C				
V30	VCC5N		Power (PCI)		

Table 12-24: PXB Pinlist Sorted by Pin (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
V31	N/C				
V32	GND		Power		
W01	PBAD[31]	I/O	PCI		
W02	PBAD[30]	I/O	PCI		
W03	PBAD[29]	I/O	PCI		
W04	PBAD[28]	I/O	PCI		
W05	GND		Power		
W28	VCC		Power		
W29	PAAD[28]	I/O	PCI		
W30	PAAD[29]	I/O	PCI		
W31	PAAD[30]	I/O	PCI		
W32	PAAD[31]	I/O	PCI		
Y01	VCC		Power		
Y02	PBAD[27]	I/O	PCI		
Y03	GND		Power		
Y04	PBAD[26]	I/O	PCI		
Y05	VCC		Power		
Y28	VCC		Power		
Y29	PAAD[26]	I/O	PCI		
Y30	GND		Power		
Y31	PAAD[27]	I/O	PCI		
Y32	VCC		Power		
AA1	PBAD[25]	I/O	PCI		
AA2	PBAD[24]	I/O	PCI		
AA3	PBAD[23]	I/O	PCI		
AA4	PBAD[22]	I/O	PCI		
AA5	PBAD[21]	I/O	PCI		
AA28	PAAD[21]	I/O	PCI		
AA29	PAAD[22]	I/O	PCI		
AA30	PAAD[23]	I/O	PCI		
AA31	PAAD[24]	I/O	PCI		
AA32	PAAD[25]	I/O	PCI		
AB01	GND		Power		
AB02	PBAD[20]	I/O	PCI		
AB03	VCC5B		Power (PCI)		
AB04	PBAD[19]	I/O	PCI		
AB05	GND		Power		
AB28	GND		Power		

Table 12-24: PXB Pinlist Sorted by Pin (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AB29	PAAD[19]	I/O	PCI		
AB30	VCC5M		Power (PCI)		
AB31	PAAD[20]	I/O	PCI		
AB32	GND		Power		
AC01	PBAD[18]	I/O	PCI		
AC02	PBAD[17]	I/O	PCI		
AC03	PBAD[16]	I/O	PCI		
AC04	PBAD[15]	I/O	PCI		
AC05	PBAD[14]	I/O	PCI		
AC28	PAAD[14]	I/O	PCI		
AC29	PAAD[15]	I/O	PCI		
AC30	PAAD[16]	I/O	PCI		
AC31	PAAD[17]	I/O	PCI		
AC32	PAAD[18]	I/O	PCI		
AD01	VCC		Power		
AD02	PBAD[13]	I/O	PCI		
AD03	GND		Power		
AD04	PBAD[12]	I/O	PCI		
AD05	VCC		Power		
AD28	VCC		Power		
AD29	PAAD[12]	I/O	PCI		
AD30	GND		Power		
AD31	PAAD[13]	I/O	PCI		
AD32	VCC		Power		
AE01	PBAD[11]	I/O	PCI		
AE02	PBAD[10]	I/O	PCI		
AE03	PBAD[09]	I/O	PCI		
AE04	PBAD[08]	I/O	PCI		
AE05	PBAD[07]	I/O	PCI		
AE28	PAAD[07]	I/O	PCI		
AE29	PAAD[08]	I/O	PCI		
AE30	PAAD[09]	I/O	PCI		
AE31	PAAD[10]	I/O	PCI		
AE32	PAAD[11]	I/O	PCI		
AF01	GND		Power		
AF02	PBAD[06]	I/O	PCI		
AF03	VCC5C		Power (PCI)		
AF04	PBAD[05]	I/O	PCI		

Table 12-24: PXB Pinlist Sorted by Pin (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AF05	GND		Power		
AF28	GND		Power		
AF29	PAAD[05]	I/O	PCI		
AF30	VCC5L		Power (PCI)		
AF31	PAAD[06]	I/O	PCI		
AF32	GND		Power		
AG01	PBAD[04]	I/O	PCI		
AG02	PBAD[03]	I/O	PCI		
AG03	PBAD[02]	I/O	PCI		
AG04	PBAD[01]	I/O	PCI		
AG05	PBAD[00]	I/O	PCI		
AG28	PAAD[00]	I/O	PCI		
AG29	PAAD[01]	I/O	PCI		
AG30	PAAD[02]	I/O	PCI		
AG31	PAAD[03]	I/O	PCI		
AG32	PAAD[04]	I/O	PCI		
AH01	N/C				
AH02	N/C				
AH03	VCC5D		Power (PCI)		
AH04	VCC		Power		
AH05	N/C				
AH06	N/C				
AH07	GND		Power		
AH08	PBMON[01]#	I/O	LVTTTL	10ma	
AH09	VCC		Power		
AH10	PBGNT[02]#	O	PCI		
AH11	GND		Power		
AH12	PBREQ[01]#	I	PCI		
AH13	VCC		Power		
AH14	PBDEVSEL#	I/O	PCI		
AH15	GND		Power		
AH16	PBCBE[00]#	I/O	PCI		
AH17	VCC		Power		
AH18	PACBE[00]#	I/O	PCI		
AH19	GND		Power		
AH20	PADEVSEL#	I/O	PCI		
AH21	VCC		Power		
AH22	PAREQ[01]#	I	PCI		

Table 12-24: PXB Pinlist Sorted by Pin (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AH23	GND		Power		
AH24	PAGNT[02]#	O	PCI		
AH25	VCC		Power		
AH26	PAMON[01]#	I/O	LVTTTL	10ma	
AH27	GND		Power		
AH28	N/C				
AH29	VCC		Power		
AH30	VCC5K		Power (PCI)		
AH31	N/C				
AH32	N/C				
AJ01	N/C				
AJ02	N/C				
AJ03	N/C				
AJ04	VCC		Power		
AJ05	N/C				
AJ06	N/C				
AJ07	PBXARB#	I	PCI		
AJ08	N/C				
AJ09	PBRST#	O	PCI		
AJ10	PBGNT[03]#	O	PCI		
AJ11	PBGNT[00]#	O	PCI		
AJ12	PBREQ[02]#	I	PCI		
AJ13	PBCBE[03]#	I/O	PCI		
AJ14	PBTRDY#	I/O	PCI		
AJ15	PBLOCK#	I/O	PCI		
AJ16	PBCBE[01]#	I/O	PCI		
AJ17	REQ64#	I/O	PCI		
AJ18	PACBE[01]#	I/O	PCI		
AJ19	PALOCK#	I/O	PCI		
AJ20	PATRDY#	I/O	PCI		
AJ21	PACBE[03]#	I/O	PCI		
AJ22	PAREQ[02]#	I	PCI		
AJ23	PAGNT[00]#	O	PCI		
AJ24	PAGNT[03]#	O	PCI		
AJ25	PARST#	O	PCI		
AJ26	MODE64#	I	PCI		
AJ27	PAXARB#	I	PCI		
AJ28	N/C				

Table 12-24: PXB Pinlist Sorted by Pin (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AJ29	VCC		Power		
AJ30	N/C				
AJ31	N/C				
AJ32	N/C				
AK01	N/C				
AK02	GND		Power		
AK03	N/C				
AK04	VCC5E		Power (PCI)		
AK05	N/C				
AK06	N/C				
AK07	VCC		Power		
AK08	N/C				
AK09	GND		Power		
AK10	PBGNT[04]#	O	PCI		
AK11	VCC5F		Power (PCI)		
AK12	PBREQ[03]#	I	PCI		
AK13	GND		Power		
AK14	PBIRDY#	I/O	PCI		
AK15	VCC5G		Power (PCI)		
AK16	PBPAR	I/O	PCI		
AK17	GND		Power		
AK18	PAPAR	I/O	PCI		
AK19	VCC5H		Power (PCI)		
AK20	PAIRDY#	I/O	PCI		
AK21	GND		Power		
AK22	PAREQ[03]#	I	PCI		
AK23	VCC5I		Power (PCI)		
AK24	PAGNT[04]#	O	PCI		
AK25	GND		Power		
AK26	PHOLD#	I	PCI		
AK27	VCC		Power		
AK28	N/C				
AK29	VCC5J		Power (PCI)		
AK30	N/C				
AK31	GND		Power		
AK32	N/C				
AL01	N/C				
AL02	N/C				

Table 12-24: PXB Pinlist Sorted by Pin (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AL03	N/C				
AL04	N/C				
AL05	N/C				
AL06	N/C				
AL07	INTRQB#	OD	PCI		
AL08	N/C				
AL09	PBMON[00]#	I/O	PCI		
AL10	PBGNT[05]#	O	PCI		
AL11	PBGNT[01]#	O	PCI		
AL12	PBREQ[04]#	I	PCI		
AL13	PBREQ[00]#	I	PCI		
AL14	PBFRAME#	I/O	PCI		
AL15	PBSTOP#	I/O	PCI		
AL16	PBSERR#	OD	PCI		
AL17	ACK64#	I/O	PCI		
AL18	PASERR#	OD	PCI		
AL19	PASTOP#	I/O	PCI		
AL20	PAFRAME#	I/O	PCI		
AL21	PAREQ[00]#	I	PCI		
AL22	PAREQ[04]#	I	PCI		
AL23	PAGNT[01]#	O	PCI		
AL24	PAGNT[05]#	O	PCI		
AL25	PAMON[00]#	I/O	PCI		
AL26	PHLDA#	O	PCI		
AL27	INTRQA#	OD	PCI		
AL28	N/C				
AL29	N/C				
AL30	N/C				
AL31	N/C				
AL32	N/C				
AM01	N/C				
AM02	N/C				
AM03	GND		Power		
AM04	GND		Power		
AM05	GND		Power		
AM06	N/C				
AM07	GND		Power		
AM08	N/C				

Table 12-24: PXB Pinlist Sorted by Pin (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AM09	VCC		Power		
AM10	N/C				
AM11	GND		Power		
AM12	PBREQ[05]#	I	PCI		
AM13	VCC		Power		
AM14	PBCBE[02]#	I/O	PCI		
AM15	GND		Power		
AM16	PBPERR#	I/O	PCI		
AM17	VCC		Power		
AM18	PAPERR#	I/O	PCI		
AM19	GND		Power		
AM20	PACBE[02]#	I/O	PCI		
AM21	VCC		Power		
AM22	PAREQ[05]#	I	PCI		
AM23	GND		Power		
AM24	N/C				
AM25	VCC		Power		
AM26	WSC#	O	PCI		
AM27	GND		Power		
AM28	GND		Power		
AM29	GND		Power		
AM30	GND		Power		
AM31	N/C				
AM32	GND		Power		

Table 12-25: MUX Pin List Sorted by Pin

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
A01	GND		Power		
A02	Q2D23	I/O	LVTTTL	10ma	
A03	Q1D22	I/O	LVTTTL	10ma	
A04	Q3D21	I/O	LVTTTL	10ma	
A05	Q3D20	I/O	LVTTTL	10ma	
A06	GND		Power		
A07	Q3D19	I/O	LVTTTL	10ma	
A08	VCC		Power		
A09	Q3D18	I/O	LVTTTL	10ma	
A10	TDO	O	OD	14ma	
A11	VCC		Power		

Table 12-25: MUX Pin List Sorted by Pin (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
A12	Q3D17	I/O	LVTTL	10ma	
A13	VCC		Power		
A14	Q1D16	I/O	LVTTL	10ma	
A15	GND		Power		
A16	Q1D15	I/O	LVTTL	10ma	
A17	Q3D14	I/O	LVTTL	10ma	
A18	Q3D13	I/O	LVTTL	10ma	
A19	Q1D13	I/O	LVTTL	10ma	
A20	GND		Power		
B01	Q1D25	I/O	LVTTL	10ma	
B02	GND		Power		
B03	Q1D23	I/O	LVTTL	10ma	
B04	VCC		Power		
B05	Q2D21	I/O	LVTTL	10ma	
B06	GND		Power		
B07	Q2D19	I/O	LVTTL	10ma	
B08	VCC		Power		
B09	Q2D18	I/O	LVTTL	10ma	
B10	GND		Power		
B11	GND		Power		
B12	Q2D17	I/O	LVTTL	10ma	
B13	VCC		Power		
B14	Q0D16	I/O	LVTTL	10ma	
B15	GND		Power		
B16	Q2D14	I/O	LVTTL	10ma	
B17	VCC		Power		
B18	Q0D13	I/O	LVTTL	10ma	
B19	GND		Power		
B20	Q2D11	I/O	LVTTL	10ma	
C01	Q3D25	I/O	LVTTL	10ma	
C02	Q0D25	I/O	LVTTL	10ma	
C03	Q0D24	I/O	LVTTL	10ma	
C04	Q0D23	I/O	LVTTL	10ma	
C05	Q0D22	I/O	LVTTL	10ma	
C06	Q1D21	I/O	LVTTL	10ma	
C07	Q1D20	I/O	LVTTL	10ma	
C08	Q1D19	I/O	LVTTL	10ma	
C09	Q1D18	I/O	LVTTL	10ma	

Table 12-25: MUX Pin List Sorted by Pin (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
C10	TDI	I	LVTTTL		
C11	TCK	I	LVTTTL		
C12	Q1D17	I/O	LVTTTL	10ma	
C13	Q3D16	I/O	LVTTTL	10ma	
C14	Q3D15	I/O	LVTTTL	10ma	
C15	Q1D14	I/O	LVTTTL	10ma	
C16	Q2D13	I/O	LVTTTL	10ma	
C17	Q3D12	I/O	LVTTTL	10ma	
C18	Q0D12	I/O	LVTTTL	10ma	
C19	Q1D11	I/O	LVTTTL	10ma	
C20	Q1D10	I/O	LVTTTL	10ma	
D01	Q3D26	I/O	LVTTTL	10ma	
D02	VCC		Power		
D03	Q3D24	I/O	LVTTTL	10ma	
D04	GND		Power		
D05	Q3D22	I/O	LVTTTL	10ma	
D06	VCC		Power		
D07	Q2D20	I/O	LVTTTL	10ma	
D08	GND		Power		
D09	Q0D18	I/O	LVTTTL	10ma	
D10	VCC		Power		
D11	VCC		Power		
D12	Q0D17	I/O	LVTTTL	10ma	
D13	GND		Power		
D14	Q0D15	I/O	LVTTTL	10ma	
D15	VCC		Power		
D16	Q2D12	I/O	LVTTTL	10ma	
D17	GND		Power		
D18	Q0D11	I/O	LVTTTL	10ma	
D19	VCC		Power		
D20	Q3D09	I/O	LVTTTL	10ma	
E01	Q1D27	I/O	LVTTTL	10ma	
E02	Q2D26	I/O	LVTTTL	10ma	
E03	Q2D25	I/O	LVTTTL	10ma	
E04	Q2D24	I/O	LVTTTL	10ma	
E05	Q3D23	I/O	LVTTTL	10ma	
E06	Q2D22	I/O	LVTTTL	10ma	
E07	Q0D21	I/O	LVTTTL	10ma	

Table 12-25: MUX Pin List Sorted by Pin (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
E08	Q0D20	I/O	LVTTL	10ma	
E09	Q0D19	I/O	LVTTL	10ma	
E10	TMS	I	LVTTL		
E11	TRST#	I	LVTTL		
E12	Q2D16	I/O	LVTTL	10ma	
E13	Q2D15	I/O	LVTTL	10ma	
E14	Q0D14	I/O	LVTTL	10ma	
E15	Q1D12	I/O	LVTTL	10ma	
E16	Q3D11	I/O	LVTTL	10ma	
E17	Q3D10	I/O	LVTTL	10ma	
E18	Q0D10	I/O	LVTTL	10ma	
E19	Q2D09	I/O	LVTTL	10ma	
E20	Q3D08	I/O	LVTTL	10ma	
F01	Q0D28	I/O	LVTTL	10ma	
F02	GND		Power		
F03	Q1D26	I/O	LVTTL	10ma	
F04	VCC		Power		
F05	Q1D24	I/O	LVTTL	10ma	
F06	VCC		Power		
F14	VCC		Power		
F15	VCC		Power		
F16	Q2D10	I/O	LVTTL	10ma	
F17	VCC		Power		
F18	Q1D09	I/O	LVTTL	10ma	
F19	GND		Power		
F20	Q1D08	I/O	LVTTL	10ma	
G01	Q2D28	I/O	LVTTL	10ma	
G02	Q1D28	I/O	LVTTL	10ma	
G03	Q3D27	I/O	LVTTL	10ma	
G04	Q0D27	I/O	LVTTL	10ma	
G05	Q0D26	I/O	LVTTL	10ma	
G06	VCC		Power		
G16	Q0D09	I/O	LVTTL	10ma	
G17	Q2D08	I/O	LVTTL	10ma	
G18	Q0D08	I/O	LVTTL	10ma	
G19	Q1D07	I/O	LVTTL	10ma	
G20	Q2D07	I/O	LVTTL	10ma	
H01	VCC		Power		

Table 12-25: MUX Pin List Sorted by Pin (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
H02	VCC		Power		
H03	Q0D29	I/O	LVTTL	10ma	
H04	GND		Power		
H05	Q2D27	I/O	LVTTL	10ma	
H16	Q3D07	I/O	LVTTL	10ma	
H17	GND		Power		
H18	Q0D07	I/O	LVTTL	10ma	
H19	VCC		Power		
H20	VCC		Power		
J01	Q0D30	I/O	LVTTL	10ma	
J02	Q3D29	I/O	LVTTL	10ma	
J03	Q2D29	I/O	LVTTL	10ma	
J04	Q1D29	I/O	LVTTL	10ma	
J05	Q3D28	I/O	LVTTL	10ma	
J09	GND		Power		
J10	GND		Power		
J11	GND		Power		
J12	GND		Power		
J16	Q3D06	I/O	LVTTL	10ma	
J17	Q3D05	I/O	LVTTL	10ma	
J18	Q0D06	I/O	LVTTL	10ma	
J19	Q1D06	I/O	LVTTL	10ma	
J20	Q2D06	I/O	LVTTL	10ma	
K01	Q3D30	I/O	LVTTL	10ma	
K02	GND		Power		
K03	Q2D30	I/O	LVTTL	10ma	
K04	VCC		Power		
K05	Q1D30	I/O	LVTTL	10ma	
K09	GND		Power		
K10	GND		Power		
K11	GND		Power		
K12	GND		Power		
K16	Q0D05	I/O	LVTTL	10ma	
K17	VCC		Power		
K18	Q1D05	I/O	LVTTL	10ma	
K19	GND		Power		
K20	Q2D05	I/O	LVTTL	10ma	
L01	Q2D31	I/O	LVTTL	10ma	

Table 12-25: MUX Pin List Sorted by Pin (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
L02	GND		Power		
L03	Q1D31	I/O	LVTTTL	10ma	
L04	VCC		Power		
L05	Q0D31	I/O	LVTTTL	10ma	
L09	GND		Power		
L10	GND		Power		
L11	GND		Power		
L12	GND		Power		
L16	Q1D04	I/O	LVTTTL	10ma	
L17	VCC		Power		
L18	Q2D04	I/O	LVTTTL	10ma	
L19	GND		Power		
L20	Q3D04	I/O	LVTTTL	10ma	
M01	Q2D32	I/O	LVTTTL	10ma	
M02	Q1D32	I/O	LVTTTL	10ma	
M03	Q0D32	I/O	LVTTTL	10ma	
M04	Q3D31	I/O	LVTTTL	10ma	
M05	Q3D32	I/O	LVTTTL	10ma	
M09	GND		Power		
M10	GND		Power		
M11	GND		Power		
M12	GND		Power		
M16	Q3D02	I/O	LVTTTL	10ma	
M17	Q1D03	I/O	LVTTTL	10ma	
M18	Q2D03	I/O	LVTTTL	10ma	
M19	Q3D03	I/O	LVTTTL	10ma	
M20	Q0D04	I/O	LVTTTL	10ma	
N01	VCC		Power		
N02	VCC		Power		
N03	Q0D33	I/O	LVTTTL	10ma	
N04	GND		Power		
N05	Q3D33	I/O	LVTTTL	10ma	
N16	Q3D01	I/O	LVTTTL	10ma	
N17	GND		Power		
N18	Q0D03	I/O	LVTTTL	10ma	
N19	VCC		Power		
N20	VCC		Power		
P01	Q2D33	I/O	LVTTTL	10ma	

Table 12-25: MUX Pin List Sorted by Pin (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
P02	Q1D33	I/O	LVTTTL	10ma	
P03	Q0D34	I/O	LVTTTL	10ma	
P04	Q1D34	I/O	LVTTTL	10ma	
P05	Q3D34	I/O	LVTTTL	10ma	
P15	VCC		Power		
P16	Q1D00	I/O	LVTTTL	10ma	
P17	Q1D01	I/O	LVTTTL	10ma	
P18	Q0D02	I/O	LVTTTL	10ma	
P19	Q1D02	I/O	LVTTTL	10ma	
P20	Q2D02	I/O	LVTTTL	10ma	
R01	GND		Power		
R02	GND		Power		
R03	Q0D35	I/O	LVTTTL	10ma	
R04	VCC		Power		
R05	MD31#	I/O	AGTL+	55ma	
R06	VCC		Power		
R07	VCC		Power		
R15	VCC		Power		
R16	MD00#	I/O	AGTL+	55ma	
R17	VCC		Power		
R18	Q2D00	I/O	LVTTTL	10ma	
R19	GND		Power		
R20	GND		Power		
T01	Q2D34	I/O	LVTTTL	10ma	
T02	Q1D35	I/O	LVTTTL	10ma	
T03	Q3D35	I/O	LVTTTL	10ma	
T04	MD32#	I/O	AGTL+	55ma	
T05	MD29#	I/O	AGTL+	55ma	
T06	DSTBP1#	I/O	AGTL+	55ma	
T07	MD23#	I/O	AGTL+	55ma	
T08	MD19#	I/O	AGTL+	55ma	
T09	N/C				
T10	VCCA		Power		
T11	WDME#	I	AGTL+	55ma	
T12	CRES0	I	Analog		
T13	MD15#	I/O	AGTL+	55ma	
T14	MD09#	I/O	AGTL+	55ma	
T15	MD07#	I/O	AGTL+	55ma	

Table 12-25: MUX Pin List Sorted by Pin (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
T16	MD05#	I/O	AGTL+	55ma	
T17	MD01#	I/O	AGTL+	55ma	
T18	Q0D00	I/O	LVTTTL	10ma	
T19	Q3D00	I/O	LVTTTL	10ma	
T20	Q2D01	I/O	LVTTTL	10ma	
U01	Q2D35	I/O	LVTTTL	10ma	
U02	VCC		Power		
U03	MD33#	I/O	AGTL+	55ma	
U04	GND		Power		
U05	VTT		Power		
U06	VCC		Power		
U07	MD21#	I/O	AGTL+	55ma	
U08	GND		Power		
U09	VTT		Power		
U10	VCC		Power		
U11	VCC		Power		
U12	VTT		Power		
U13	GND		Power		
U14	MD13#	I/O	AGTL+	55ma	
U15	VCC		Power		
U16	VTT		Power		
U17	GND		Power		
U18	MD02#	I/O	AGTL+	55ma	
U19	VCC		Power		
U20	Q0D01	I/O	LVTTTL	10ma	
V01	N/C				
V02	MD34#	I/O	AGTL+	55ma	
V03	MD30#	I/O	AGTL+	55ma	
V04	MD27#	I/O	AGTL+	55ma	
V05	VREF	I	Analog		
V06	MD24#	I/O	AGTL+	55ma	
V07	MD20#	I/O	AGTL+	55ma	
V08	DOFF1#	I	AGTL+	55ma	
V09	DOFF0#	I	AGTL+	55ma	
V10	HCLKIN	I	2.5V		
V11	DVALID#	I	AGTL+	55ma	
V12	LRD#	I	AGTL+	55ma	
V13	CRES1	I	Analog		

Table 12-25: MUX Pin List Sorted by Pin (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
V14	MD16#	I/O	AGTL+	55ma	
V15	MD10#	I/O	AGTL+	55ma	
V16	VREF	I	Analog		
V17	MD08#	I/O	AGTL+	55ma	
V18	MD06#	I/O	AGTL+	55ma	
V19	MD03#	I/O	AGTL+	55ma	
V20	N/C				
W01	MD35#	I/O	AGTL+	55ma	
W02	GND		Power		
W03	VTT		Power		
W04	VCC		Power		
W05	MD25#	I/O	AGTL+	55ma	
W06	GND		Power		
W07	VTT		Power		
W08	VCC		Power		
W09	DSEL#	I	AGTL+	55ma	
W10	GND		Power		
W11	GND		Power		
W12	GDCMPLT#	I/O	AGTL+	55ma	
W13	VCC		Power		
W14	VTT		Power		
W15	GND		Power		
W16	MD11#	I/O	AGTL+	55ma	
W17	VCC		Power		
W18	VTT		Power		
W19	GND		Power		
W20	MD04#	I/O	AGTL+	55ma	
Y01	GND		Power		
Y02	MD28#	I/O	AGTL+	55ma	
Y03	DSTBN1#	I/O	AGTL+	55ma	
Y04	MD26#	I/O	AGTL+	55ma	
Y05	MD22#	I/O	AGTL+	55ma	
Y06	GND		Power		
Y07	MD18#	I/O	AGTL+	55ma	
Y08	LDSTB#	I	AGTL+	55ma	
Y09	MRESET#	I	AGTL+	55ma	
Y10	VCC		Power		
Y11	WDEVT#	I	AGTL+	55ma	

Table 12-25: MUX Pin List Sorted by Pin (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
Y12	AVWP#	I	AGTL+	55ma	
Y13	DCMPLT#	I/O	AGTL+	55ma	
Y14	MD17#	I/O	AGTL+	55ma	
Y15	GND		Power		
Y16	MD14#	I/O	AGTL+	55ma	
Y17	MD12#	I/O	AGTL+	55ma	
Y18	DSTBP0#	I/O	AGTL+	55ma	
Y19	DSTBN0#	I/O	AGTL+	55ma	
Y20	GND		Power		

Table 12-26: RCG Pin List Sorted by Pin

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
A01	GND		Power		
A02	RASCA0#	O	LVTTTL	10ma	
A03	CASCA0#	O	LVTTTL	10ma	
A04	RASCB0#	O	LVTTTL	10ma	
A05	CASCB1#	O	LVTTTL	10ma	
A06	GND		Power		
A07	WECA#	O	LVTTTL	10ma	
A08	VCC		Power		
A09	WECB#	O	LVTTTL	10ma	
A10	ADDRD13	O	LVTTTL	10ma	
A11	ADDRD08	O	LVTTTL	10ma	
A12	ADDRD03	O	LVTTTL	10ma	
A13	VCC		Power		
A14	ADDRD01	O	LVTTTL	10ma	
A15	GND		Power		
A16	RASDD1#	O	LVTTTL	10ma	
A17	RASDD0#	O	LVTTTL	10ma	
A18	CASDC0#	O	LVTTTL	10ma	
A19	CASDA1#	O	LVTTTL	10ma	
A20	GND		Power		
B01	RASCA1#	O	LVTTTL	10ma	
B02	GND		Power		
B03	RASCB1#	O	LVTTTL	10ma	
B04	VCC		Power		
B05	CASCC0#	O	LVTTTL	10ma	
B06	GND		Power		

Table 12-26: RCG Pin List Sorted by Pin (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
B07	CASCD1#	O	LVTTTL	10ma	
B08	VCC		Power		
B09	CASCC1#	O	LVTTTL	10ma	
B10	GND		Power		
B11	GND		Power		
B12	ADDRD04	O	LVTTTL	10ma	
B13	VCC		Power		
B14	RASDC1#	O	LVTTTL	10ma	
B15	GND		Power		
B16	RASDC0#	O	LVTTTL	10ma	
B17	VCC		Power		
B18	CASDD1#	O	LVTTTL	10ma	
B19	GND		Power		
B20	CASDC1#	O	LVTTTL	10ma	
C01	ADDRC05	O	LVTTTL	10ma	
C02	ADDRC03	O	LVTTTL	10ma	
C03	ADDRC00	O	LVTTTL	10ma	
C04	RASCC1#	O	LVTTTL	10ma	
C05	RASCC0#	O	LVTTTL	10ma	
C06	RASCD0#	O	LVTTTL	10ma	
C07	CASCB0#	O	LVTTTL	10ma	
C08	CASCD0#	O	LVTTTL	10ma	
C09	N/C				
C10	ADDRD12	O	LVTTTL	10ma	
C11	ADDRD09	O	LVTTTL	10ma	
C12	ADDRD05	O	LVTTTL	10ma	
C13	ADDRD02	O	LVTTTL	10ma	
C14	ADDRD00	O	LVTTTL	10ma	
C15	RASDA0#	O	LVTTTL	10ma	
C16	RASDB0#	O	LVTTTL	10ma	
C17	WEDA#	O	LVTTTL	10ma	
C18	CASDB0#	O	LVTTTL	10ma	
C19	CASDD0#	O	LVTTTL	10ma	
C20	WEDB#	O	LVTTTL	10ma	
D01	ADDRC08	O	LVTTTL	10ma	
D02	VCC		Power		
D03	ADDRC02	O	LVTTTL	10ma	
D04	GND		Power		

Table 12-26: RCG Pin List Sorted by Pin (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
D05	RASCD1#	O	LVTTTL	10ma	
D06	VCC		Power		
D07	CASCA1#	O	LVTTTL	10ma	
D08	GND		Power		
D09	N/C				
D10	VCC		Power		
D11	VCC		Power		
D12	ADDRD06	O	LVTTTL	10ma	
D13	GND		Power		
D14	RASDB1#	O	LVTTTL	10ma	
D15	VCC		Power		
D16	CASDA0#	O	LVTTTL	10ma	
D17	GND		Power		
D18	CASDB1#	O	LVTTTL	10ma	
D19	VCC		Power		
D20	N/C				
E01	ADDRC10	O	LVTTTL	10ma	
E02	ADDRC07	O	LVTTTL	10ma	
E03	ADDRC04	O	LVTTTL	10ma	
E04	ADDRC01	O	LVTTTL	10ma	
E05	N/C				
E06	N/C				
E07	N/C				
E08	N/C				
E09	N/C				
E10	ADDRD11	O	LVTTTL	10ma	
E11	ADDRD10	O	LVTTTL	10ma	
E12	ADDRD07	O	LVTTTL	10ma	
E13	RASDA1#	O	LVTTTL	10ma	
E14	N/C				
E15	N/C				
E16	N/C				
E17	N/C				
E18	N/C				
E19	N/C				
E20	ADDRB12	O	LVTTTL	10ma	
F01	ADDRC13		LVTTTL	10ma	
F02	GND	O	Power		

Table 12-26: RCG Pin List Sorted by Pin (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
F03	ADDRC06		LVTTTL	10ma	
F04	VCC	O	LVTTTL	10ma	
F05	N/C				
F06	VCC		Power		
F14	VCC		Power		
F15	VCC		Power		
F16	N/C				
F17	VCC		Power		
F18	ADDRB13	O	LVTTTL	10ma	
F19	GND		Power		
F20	ADDRB09	O	LVTTTL	10ma	
G01	N/C				
G02	ADDRC12	O	LVTTTL	10ma	
G03	ADDRC11	O	LVTTTL	10ma	
G04	ADDRC09	O	LVTTTL	10ma	
G05	N/C				
G06	VCC		Power		
G16	N/C				
G17	ADDRB11	O	LVTTTL	10ma	
G18	ADDRB10	O	LVTTTL	10ma	
G19	ADDRB06	O	LVTTTL	10ma	
G20	ADDRB05	O	LVTTTL	10ma	
H01	VCC		Power		
H02	VCC		Power		
H03	CASAC0#	O	LVTTTL	10ma	
H04	GND		Power		
H05	CASAA1#	O	LVTTTL	10ma	
H16	ADDRB08	O	LVTTTL	10ma	
H17	GND		Power		
H18	ADDRB07	O	LVTTTL	10ma	
H19	VCC		Power		
H20	VCC		Power		
J01	WEAA#	O	LVTTTL	10ma	
J02	CASAB1#	O	LVTTTL	10ma	
J03	CASAD1#	O	LVTTTL	10ma	
J04	WEAB#	O	LVTTTL	10ma	
J05	CASAC1#	O	LVTTTL	10ma	
J09	GND		Power		

Table 12-26: RCG Pin List Sorted by Pin (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
J10	GND		Power		
J11	GND		Power		
J12	GND		Power		
J16	ADDRB04	O	LVTTTL	10ma	
J17	ADDRB03	O	LVTTTL	10ma	
J18	ADDRB02	O	LVTTTL	10ma	
J19	ADDRB01	O	LVTTTL	10ma	
J20	ADDRB00	O	LVTTTL	10ma	
K01	CASAA0#	O	LVTTTL	10ma	
K02	GND		Power		
K03	CASAB0#	O	LVTTTL	10ma	
K04	VCC		Power		
K05	CASAD0#	O	LVTTTL	10ma	
K09	GND		Power		
K10	GND		Power		
K11	GND		Power		
K12	GND		Power		
K16	RASBB1#	O	LVTTTL	10ma	
K17	VCC		Power		
K18	RASBC1#	O	LVTTTL	10ma	
K19	GND		Power		
K20	RASBD1#	O	LVTTTL	10ma	
L01	RASAA0#	O	LVTTTL	10ma	
L02	GND		Power		
L03	RASAC0#	O	LVTTTL	10ma	
L04	VCC		Power		
L05	RASAD0#	O	LVTTTL	10ma	
L09	GND		Power		
L10	GND		Power		
L11	GND		Power		
L12	GND		Power		
L16	RASBA1#	O	LVTTTL	10ma	
L17	VCC		Power		
L18	RASBA0#	O	LVTTTL	10ma	
L19	GND		Power		
L20	RASBC0#	O	LVTTTL	10ma	
M01	RASAB0#	O	LVTTTL	10ma	
M02	RASAA1#	O	LVTTTL	10ma	

Table 12-26: RCG Pin List Sorted by Pin (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
M03	RASAB1#	O	LVTTL	10ma	
M04	RASAC1#	O	LVTTL	10ma	
M05	RASAD1#	O	LVTTL	10ma	
M09	GND		Power		
M10	GND		Power		
M11	GND		Power		
M12	GND		Power		
M16	CASBA0#	O	LVTTL	10ma	
M17	CASBB1#	O	LVTTL	10ma	
M18	RASBB0#	O	LVTTL	10ma	
M19	CASBB0#	O	LVTTL	10ma	
M20	RASBD0#	O	LVTTL	10ma	
N01	VCC		Power		
N02	VCC		Power		
N03	ADDRA01	O	LVTTL	10ma	
N04	GND		Power		
N05	ADDRA00	O	LVTTL	10ma	
N16	N/C				
N17	GND		Power		
N18	CASBA1#	O	LVTTL	10ma	
N19	VCC		Power		
N20	VCC		Power		
P01	ADDRA03	O	LVTTL	10ma	
P02	ADDRA02	O	LVTTL	10ma	
P03	ADDRA05	O	LVTTL	10ma	
P04	ADDRA04	O	LVTTL	10ma	
P05	N/C				
P15	VCC		Power		
P16	N/C				
P17	WEBA#	O	LVTTL	10ma	
P18	CASBC0#	O	LVTTL	10ma	
P19	CASBD0#	O	LVTTL	10ma	
P20	WEBB#	O	LVTTL	10ma	
R01	GND		Power		
R02	GND		Power		
R03	ADDRA06	O	LVTTL	10ma	
R04	VCC		Power		
R05	N/C				

Table 12-26: RCG Pin List Sorted by Pin (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
R06	VCC		Power		
R07	VCC		Power		
R15	VCC		Power		
R16	N/C				
R17	VCC		Power		
R18	CASBD1#	O	LVTTTL	10ma	
R19	GND		Power		
R20	GND		Power		
T01	ADDRA08	O	LVTTTL	10ma	
T02	ADDRA07	O	LVTTTL	10ma	
T03	ADDRA10	O	LVTTTL	10ma	
T04	ADDRA09	O	LVTTTL	10ma	
T05	N/C				
T06	N/C				
T07	MA05#	I	LVTTTL	10ma	
T08	MA02#	I	LVTTTL	10ma	
T09	N/C				
T10	VCCA		Power		
T11	CMND1#	I	AGTL+		
T12	BANK0#	I	AGTL+		
T13	N/C				
T14	WDME#	O	AGTL+	55ma	
T15	LRD#	O	AGTL+	55ma	
T16	N/C				
T17	VCC		Power		
T18	BANKID#	I	LVTTTL		Requires external pull-up
T19	DR50T#	I	LVTTTL		
T20	CASBC1#	O	LVTTTL	10ma	
U01	ADDRA11	O	LVTTTL	10ma	
U02	VCC		Power		
U03	N/C				
U04	GND		Power		
U05	VTT		Power		
U06	VCC		Power		
U07	MA06#	I	LVTTTL	10ma	
U08	GND		Power		
U09	VTT		Power		
U10	VCC		Power		

Table 12-26: RCG Pin List Sorted by Pin (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
U11	VCC		Power		
U12	VTT		Power		
U13	GND		Power		
U14	RHIT#	O	AGTL+	55ma	
U15	VCC		Power		
U16	VTT		Power		
U17	GND		Power		
U18	DR50H#	I	LVTTL		
U19	VCC		Power		
U20	VCC		Power		
V01	ADDRA13	O	LVTTL	10ma	
V02	ADDRA12	O	LVTTL	10ma	
V03	CRES1	I	Analog		
V04	CRES0	I	Analog		
V05	VREF	I	Analog		
V06	MA09#	I	AGTL+		
V07	MA07#	I	AGTL+		
V08	MA03#	I	AGTL+		
V09	MA00#	I	AGTL+		
V10	HCLKIN	I	2.5V		
V11	CSTB#	I	AGTL+		
V12	BANK1#	I	AGTL+		
V13	RCMPLT#	O	AGTL+	55ma	
V14	PHIT#	O	AGTL+	55ma	
V15	AVWP#	O	AGTL+	55ma	
V16	VREF	I	Analog		
V17	TRST#	I	LVTTL		
V18	TCK	I	LVTTL		
V19	TDO	O	OD	14ma	
V20	TDI	I	LVTTL		
W01	N/C				
W02	GND		Power		
W03	VTT		Power		
W04	VCC		Power		
W05	MA10#	I	AGTL+		
W06	GND		Power		
W07	VTT		Power		
W08	VCC		Power		

Table 12-26: RCG Pin List Sorted by Pin (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
W09	MA01#	I	AGTL+		
W10	GND		Power		
W11	GND		Power		
W12	BANK2#	I	AGTL+		
W13	VCC		Power		
W14	VTT		Power		
W15	GND		Power		
W16	N/C				
W17	VCC		Power		
W18	VTT		Power		
W19	GND		Power		
W20	N/C				
Y01	GND		Power		
Y02	N/C				
Y03	MA13#	I	AGTL+		
Y04	MA12#	I	AGTL+		
Y05	MA11#	I	AGTL+		
Y06	GND		Power		
Y07	MA08#	I	AGTL+		
Y08	MA04#	I	AGTL+		
Y09	MRESET#	I	AGTL+		
Y10	VCC		Power		
Y11	ROW#	I	AGTL+		
Y12	CMND0#	I	AGTL+		
Y13	CARD#	I	AGTL+		
Y14	GRCMPLT#	I/O	AGTL+	55ma	
Y15	GND		Power		
Y16	LDSTB#	O	AGTL+	55ma	
Y17	N/C				
Y18	TMS	I	LVTTTL		
Y19	N/C				
Y20	GND		Power		

12.9.2 Pin Lists Sorted by Signal

Table 12-27: MIOC Pin List Sorted by Signal

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
B04	A03#	I/O	AGTL+	55ma	
C04	A04#	I/O	AGTL+	55ma	
D04	A05#	I/O	AGTL+	55ma	
E04	A06#	I/O	AGTL+	55ma	
A05	A07#	I/O	AGTL+	55ma	
C05	A08#	I/O	AGTL+	55ma	
E05	A09#	I/O	AGTL+	55ma	
B06	A10#	I/O	AGTL+	55ma	
C06	A11#	I/O	AGTL+	55ma	
D06	A12#	I/O	AGTL+	55ma	
A07	A13#	I/O	AGTL+	55ma	
B07	A14#	I/O	AGTL+	55ma	
C07	A15#	I/O	AGTL+	55ma	
D07	A16#	I/O	AGTL+	55ma	
E07	A17#	I/O	AGTL+	55ma	
C08	A18#	I/O	AGTL+	55ma	
E08	A19#	I/O	AGTL+	55ma	
A09	A20#	I/O	AGTL+	55ma	
B09	A21#	I/O	AGTL+	55ma	
C09	A22#	I/O	AGTL+	55ma	
D09	A23#	I/O	AGTL+	55ma	
B10	A24#	I/O	AGTL+	55ma	
D10	A25#	I/O	AGTL+	55ma	
E10	A26#	I/O	AGTL+	55ma	
B11	A27#	I/O	AGTL+	55ma	
D11	A28#	I/O	AGTL+	55ma	
A12	A29#	I/O	AGTL+	55ma	
B12	A30#	I/O	AGTL+	55ma	
C12	A31#	I/O	AGTL+	55ma	
D12	A32#	I/O	AGTL+	55ma	
E12	A33#	I/O	AGTL+	55ma	
A13	A34#	I/O	AGTL+	55ma	
B13	A35#	I/O	AGTL+	55ma	
J03	ADS#	I/O	AGTL+	55ma	
K05	AERR#	I/O	AGTL+	55ma	
H01	AP0#	I/O	AGTL+	55ma	

Table 12-27: MIOC Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
J01	AP1#	I/O	AGTL+	55ma	
AJ17	BANK0#	O	AGTL+	55ma	
AH18	BANK1#	O	AGTL+	55ma	
AM18	BANK2#	O	AGTL+	55ma	
D13	BERR#	I/O	AGTL+	55ma	
J29	BINIT#	I/O	AGTL+	55ma	
C02	BNR#	I/O	AGTL+	55ma	
J30	BP0#	I/O	OD	14ma	
J31	BP1#	I/O	OD	14ma	
D01	BPRI#	I/O	AGTL+	55ma	
J02	BR0#	O	AGTL+	55ma	
AL18	CARD0#	O	AGTL+	55ma	
AJ18	CARD1#	O	AGTL+	55ma	
AL11	CMND0#	O	AGTL+	55ma	
AJ12	CMND1#	O	AGTL+	55ma	
C11	CRES0	I	Analog		
A17	CRES1	I	Analog		
H29	CRESET#	O	LVTTTL	10ma	
AM12	CSTB#	O	AGTL+	55ma	
D14	D00#	I/O	AGTL+	55ma	
A15	D01#	I/O	AGTL+	55ma	
B15	D02#	I/O	AGTL+	55ma	
C15	D03#	I/O	AGTL+	55ma	
D15	D04#	I/O	AGTL+	55ma	
E15	D05#	I/O	AGTL+	55ma	
B16	D06#	I/O	AGTL+	55ma	
D16	D07#	I/O	AGTL+	55ma	
E16	D08#	I/O	AGTL+	55ma	
B17	D09#	I/O	AGTL+	55ma	
D17	D10#	I/O	AGTL+	55ma	
E17	D11#	I/O	AGTL+	55ma	
A18	D12#	I/O	AGTL+	55ma	
B18	D13#	I/O	AGTL+	55ma	
C18	D14#	I/O	AGTL+	55ma	
D18	D15#	I/O	AGTL+	55ma	
E18	D16#	I/O	AGTL+	55ma	
B19	D17#	I/O	AGTL+	55ma	
D19	D18#	I/O	AGTL+	55ma	

Table 12-27: MIOC Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
A20	D19#	I/O	AGTL+	55ma	
B20	D20#	I/O	AGTL+	55ma	
D20	D21#	I/O	AGTL+	55ma	
A21	D22#	I/O	AGTL+	55ma	
B21	D23#	I/O	AGTL+	55ma	
C21	D24#	I/O	AGTL+	55ma	
D21	D25#	I/O	AGTL+	55ma	
E21	D26#	I/O	AGTL+	55ma	
B22	D27#	I/O	AGTL+	55ma	
D22	D28#	I/O	AGTL+	55ma	
B23	D29#	I/O	AGTL+	55ma	
D23	D30#	I/O	AGTL+	55ma	
E23	D31#	I/O	AGTL+	55ma	
A24	D32#	I/O	AGTL+	55ma	
B24	D33#	I/O	AGTL+	55ma	
C24	D34#	I/O	AGTL+	55ma	
D24	D35#	I/O	AGTL+	55ma	
C25	D36#	I/O	AGTL+	55ma	
E25	D37#	I/O	AGTL+	55ma	
A26	D38#	I/O	AGTL+	55ma	
B26	D39#	I/O	AGTL+	55ma	
C26	D40#	I/O	AGTL+	55ma	
D26	D41#	I/O	AGTL+	55ma	
E26	D42#	I/O	AGTL+	55ma	
B27	D43#	I/O	AGTL+	55ma	
C27	D44#	I/O	AGTL+	55ma	
D27	D45#	I/O	AGTL+	55ma	
A28	D46#	I/O	AGTL+	55ma	
C28	D47#	I/O	AGTL+	55ma	
E28	D48#	I/O	AGTL+	55ma	
A29	D49#	I/O	AGTL+	55ma	
B29	D50#	I/O	AGTL+	55ma	
C29	D51#	I/O	AGTL+	55ma	
D29	D52#	I/O	AGTL+	55ma	
E29	D53#	I/O	AGTL+	55ma	
B30	D54#	I/O	AGTL+	55ma	
C30	D55#	I/O	AGTL+	55ma	
E30	D56#	I/O	AGTL+	55ma	

Table 12-27: MIOC Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
C31	D57#	I/O	AGTL+	55ma	
D31	D58#	I/O	AGTL+	55ma	
E31	D59#	I/O	AGTL+	55ma	
D32	D60#	I/O	AGTL+	55ma	
E32	D61#	I/O	AGTL+	55ma	
F29	D62#	I/O	AGTL+	55ma	
F30	D63#	I/O	AGTL+	55ma	
A04	DBSY#	I/O	AGTL+	55ma	
AJ16	DCMPLTA#	I/O	AGTL+	55ma	
AH15	DCMPLTB#	I/O	AGTL+	55ma	
G05	DEFER#	I/O	AGTL+	55ma	
H32	DEP0#	I/O	AGTL+	55ma	
H31	DEP1#	I/O	AGTL+	55ma	
H30	DEP2#	I/O	AGTL+	55ma	
G32	DEP3#	I/O	AGTL+	55ma	
G31	DEP4#	I/O	AGTL+	55ma	
G29	DEP5#	I/O	AGTL+	55ma	
G28	DEP6#	I/O	AGTL+	55ma	
F31	DEP7#	I/O	AGTL+	55ma	
AH12	DOFF0#	O	AGTL+	55ma	
AM13	DOFF1#	O	AGTL+	55ma	
B14	DRDY#	I/O	AGTL+	55ma	
AJ13	DSEL0#	O	AGTL+	55ma	
AL14	DSEL1#	O	AGTL+	55ma	
U02	DSTBN0#	I/O	AGTL+	55ma	
AD01	DSTBN1#	I/O	AGTL+	55ma	
AJ02	DSTBN2#	I/O	AGTL+	55ma	
AH09	DSTBN3#	I/O	AGTL+	55ma	
U01	DSTBP0#	I/O	AGTL+	55ma	
AC04	DSTBP1#	I/O	AGTL+	55ma	
AJ01	DSTBP2#	I/O	AGTL+	55ma	
AK08	DSTBP3#	I/O	AGTL+	55ma	
AK15	DVALIDA#	O	AGTL+	55ma	
AL16	DVALIDB#	O	AGTL+	55ma	
K01	ERR0#	I/O	OD	14ma	
K02	ERR1#	I/O	OD	14ma	
A01	GND		Power		
A02	GND		Power		

Table 12-27: MIOC Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
A03	GND		Power		
A06	GND		Power		
A10	GND		Power		
A11	GND		Power		
A14	GND		Power		
A16	GND		Power		
A19	GND		Power		
A22	GND		Power		
A23	GND		Power		
A27	GND		Power		
B01	GND		Power		
B02	GND		Power		
B05	GND		Power		
B28	GND		Power		
C01	GND		Power		
D08	GND		Power		
D25	GND		Power		
E09	GND		Power		
E13	GND		Power		
E14	GND		Power		
E19	GND		Power		
E20	GND		Power		
E24	GND		Power		
F01	GND		Power		
F32	GND		Power		
G01	GND		Power		
H05	GND		Power		
H28	GND		Power		
J05	GND		Power		
J32	GND		Power		
L01	GND		Power		
L32	GND		Power		
M05	GND		Power		
M28	GND		Power		
R01	GND		Power		
R29	GND		Power		
T28	GND		Power		
U04	GND		Power		

Table 12-27: MIOC Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
U05	GND		Power		
U32	GND		Power		
V04	GND		Power		
V05	GND		Power		
V32	GND		Power		
W05	GND		Power		
Y28	GND		Power		
AA05	GND		Power		
AA28	GND		Power		
AB01	GND		Power		
AB32	GND		Power		
AC01	GND		Power		
AC05	GND		Power		
AC28	GND		Power		
AD05	GND		Power		
AD28	GND		Power		
AE01	GND		Power		
AE32	GND		Power		
AF01	GND		Power		
AF32	GND		Power		
AH13	GND		Power		
AH14	GND		Power		
AH19	GND		Power		
AH20	GND		Power		
AH24	GND		Power		
AH25	GND		Power		
AH32	GND		Power		
AJ08	GND		Power		
AJ19	GND		Power		
AJ24	GND		Power		
AJ25	GND		Power		
AJ26	GND		Power		
AK24	GND		Power		
AK25	GND		Power		
AK27	GND		Power		
AK32	GND		Power		
AL05	GND		Power		
AL27	GND		Power		

Table 12-27: MIOC Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AL28	GND		Power		
AL31	GND		Power		
AL32	GND		Power		
AM06	GND		Power		
AM11	GND		Power		
AM14	GND		Power		
AM16	GND		Power		
AM19	GND		Power		
AM22	GND		Power		
AM23	GND		Power		
AM27	GND		Power		
AM28	GND		Power		
AM30	GND		Power		
AM31	GND		Power		
AM32	GND		Power		
R28	HCLKIN	I	2.5V		
G02	HIT#	I	AGTL+		
H02	HITM#		AGTL+		
N29	INIT#	OD	2.5V	14ma	
L04	INTREQ#	O	LVTTL	10ma	
N05	IOGNT#	I	LVTTL		
N04	IOREQ#	O	LVTTL	10ma	
F03	LOCK#	I	AGTL+		
AM20	MA00#	O	AGTL+	55ma	
AL20	MA01#	O	AGTL+	55ma	
AJ20	MA02#	O	AGTL+	55ma	
AM21	MA03#	O	AGTL+	55ma	
AL21	MA04#	O	AGTL+	55ma	
AK21	MA05#	O	AGTL+	55ma	
AJ21	MA06#	O	AGTL+	55ma	
AH21	MA07#	O	AGTL+	55ma	
AL22	MA08#	O	AGTL+	55ma	
AJ22	MA09#	O	AGTL+	55ma	
AL23	MA10#	O	AGTL+	55ma	
AJ23	MA11#	O	AGTL+	55ma	
AH23	MA12#	O	AGTL+	55ma	
AM24	MA13#	O	AGTL+	55ma	
P02	MD00#	I/O	AGTL+	55ma	

Table 12-27: MIOC Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
P03	MD01#	I/O	AGTL+	55ma	
P04	MD02#	I/O	AGTL+	55ma	
R02	MD03#	I/O	AGTL+	55ma	
R03	MD04#	I/O	AGTL+	55ma	
T01	MD05#	I/O	AGTL+	55ma	
T02	MD06#	I/O	AGTL+	55ma	
T03	MD07#	I/O	AGTL+	55ma	
T04	MD08#	I/O	AGTL+	55ma	
U03	MD09#	I/O	AGTL+	55ma	
V02	MD10#	I/O	AGTL+	55ma	
V03	MD11#	I/O	AGTL+	55ma	
W01	MD12#	I/O	AGTL+	55ma	
W02	MD13#	I/O	AGTL+	55ma	
W03	MD14#	I/O	AGTL+	55ma	
W04	MD15#	I/O	AGTL+	55ma	
Y02	MD16#	I/O	AGTL+	55ma	
Y04	MD17#	I/O	AGTL+	55ma	
Y05	MD18#	I/O	AGTL+	55ma	
AA01	MD19#	I/O	AGTL+	55ma	
AA02	MD20#	I/O	AGTL+	55ma	
AA03	MD21#	I/O	AGTL+	55ma	
AA04	MD22#	I/O	AGTL+	55ma	
AB02	MD23#	I/O	AGTL+	55ma	
AB04	MD24#	I/O	AGTL+	55ma	
AB05	MD25#	I/O	AGTL+	55ma	
AC02	MD26#	I/O	AGTL+	55ma	
AD02	MD27#	I/O	AGTL+	55ma	
AD03	MD28#	I/O	AGTL+	55ma	
AD04	MD29#	I/O	AGTL+	55ma	
AE02	MD30#	I/O	AGTL+	55ma	
AE04	MD31#	I/O	AGTL+	55ma	
AE05	MD32#	I/O	AGTL+	55ma	
AF02	MD33#	I/O	AGTL+	55ma	
AF04	MD34#	I/O	AGTL+	55ma	
AF05	MD35#	I/O	AGTL+	55ma	
AG01	MD36#	I/O	AGTL+	55ma	
AG02	MD37#	I/O	AGTL+	55ma	
AG03	MD38#	I/O	AGTL+	55ma	

Table 12-27: MIOC Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AG04	MD39#	I/O	AGTL+	55ma	
AH01	MD40#	I/O	AGTL+	55ma	
AH02	MD41#	I/O	AGTL+	55ma	
AH03	MD42#	I/O	AGTL+	55ma	
AH04	MD43#	I/O	AGTL+	55ma	
AH05	MD44#	I/O	AGTL+	55ma	
AJ04	MD45#	I/O	AGTL+	55ma	
AK02	MD46#	I/O	AGTL+	55ma	
AK03	MD47#	I/O	AGTL+	55ma	
AK04	MD48#	I/O	AGTL+	55ma	
AK05	MD49#	I/O	AGTL+	55ma	
AL03	MD50#	I/O	AGTL+	55ma	
AL04	MD51#	I/O	AGTL+	55ma	
AM04	MD52#	I/O	AGTL+	55ma	
AM05	MD53#	I/O	AGTL+	55ma	
AJ06	MD54#	I/O	AGTL+	55ma	
AK06	MD55#	I/O	AGTL+	55ma	
AL06	MD56#	I/O	AGTL+	55ma	
AH07	MD57#	I/O	AGTL+	55ma	
AJ07	MD58#	I/O	AGTL+	55ma	
AK07	MD59#	I/O	AGTL+	55ma	
AL07	MD60#	I/O	AGTL+	55ma	
AM07	MD61#	I/O	AGTL+	55ma	
AH08	MD62#	I/O	AGTL+	55ma	
AJ09	MD63#	I/O	AGTL+	55ma	
AK09	MD64#	I/O	AGTL+	55ma	
AL09	MD65#	I/O	AGTL+	55ma	
AM09	MD66#	I/O	AGTL+	55ma	
AJ10	MD67#	I/O	AGTL+	55ma	
AK10	MD68#	I/O	AGTL+	55ma	
AL10	MD69#	I/O	AGTL+	55ma	
AM10	MD70#	I/O	AGTL+	55ma	
AJ11	MD71#	I/O	AGTL+	55ma	
AL13	MRESET#	O	AGTL+	55ma	
C23	N/C				
K29	N/C				
U28	N/C				
AC32	VCC		Power		

Table 12-27: MIOC Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AK13	PHITA#	I	AGTL+		
AL17	PHITB#	I	AGTL+		
L31	PWRGD	I	LVTTTL		
P28	PWRGDB	O	LVTTTL	10ma	
AM15	RCMPLTA#	I	AGTL+		
AJ15	RCMPLTB#	I	AGTL+		
E01	REQ0#	I/O	AGTL+	55ma	
F04	REQ1#	I/O	AGTL+	55ma	
G04	REQ2#	I/O	AGTL+	55ma	
H04	REQ3#	I/O	AGTL+	55ma	
F02	REQ4#	I/O	AGTL+	55ma	
M29	RESET#	I/O	AGTL+	55ma	
AL12	RHITA#	I	AGTL+		
AM17	RHITB#	I	AGTL+		
AH16	ROW#	O	AGTL+	55ma	
J04	RP#	I/O	AGTL+	55ma	
B03	RS0#	I/O	AGTL+	55ma	
C03	RS1#	I/O	AGTL+	55ma	
E03	RS2#	I/O	AGTL+	55ma	
E02	RSP#	I/O	AGTL+	55ma	
AL19	SMIACT#	O	LVTTTL	10ma	
L03	TCK	I	LVTTTL		
M04	TDI	I	LVTTTL		
M03	TDO	O	OD	14ma	
L05	TMS	I	LVTTTL		
M01	TPCTL0	I	LVTTTL		
N02	TPCTL1	I	LVTTTL		
D02	TRDY#	I/O	AGTL+	55ma	
L02	TRST#	I	LVTTTL		
A30	VCC		Power		
A31	VCC		Power		
A32	VCC		Power		
B31	VCC		Power		
B32	VCC		Power		
C10	VCC		Power		
C13	VCC		Power		
C14	VCC		Power		
C19	VCC		Power		

Table 12-27: MIOC Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
C20	VCC		Power		
C22	VCC		Power		
C32	VCC		Power		
E06	VCC		Power		
E27	VCC		Power		
F05	VCC		Power		
F28	VCC		Power		
K03	VCC		Power		
K28	VCC		Power		
L30	VCC		Power		
M02	VCC		Power		
N01	VCC		Power		
N32	VCC		Power		
P01	VCC		Power		
P05	VCC		Power		
P32	VCC		Power		
R04	VCC		Power		
R05	VCC		Power		
T05	VCC		Power		
V01	VCC		Power		
V28	VCC		Power		
V29	VCC		Power		
W28	VCC		Power		
Y01	VCC		Power		
Y32	VCC		Power		
AB03	VCC		Power		
AB30	VCC		Power		
AC30	VCC		Power		
AF28	VCC		Power		
AG05	VCC		Power		
AG28	VCC		Power		
AH06	VCC		Power		
AH10	VCC		Power		
AH11	VCC		Power		
AH17	VCC		Power		
AH27	VCC		Power		
AK01	VCC		Power		
AK11	VCC		Power		

Table 12-27: MIOC Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AK12	VCC		Power		
AK14	VCC		Power		
AK18	VCC		Power		
AK19	VCC		Power		
AK20	VCC		Power		
AK22	VCC		Power		
AK23	VCC		Power		
AL01	VCC		Power		
AL02	VCC		Power		
AL24	VCC		Power		
AM01	VCC		Power		
AM02	VCC		Power		
AM03	VCC		Power		
K30	VCCA0		Power		
K31	VCCA1		Power		
K32	VCCA2		Power		
K04	VREF	I	Analog		
N31	VREF	I	Analog		
U30	VREF	I	Analog		
AC03	VREF	I	Analog		
AG29	VREF	I	Analog		
AL15	VREF	I	Analog		
A08	VTT		Power		
A25	VTT		Power		
B08	VTT		Power		
B25	VTT		Power		
C16	VTT		Power		
C17	VTT		Power		
D03	VTT		Power		
D05	VTT		Power		
D28	VTT		Power		
D30	VTT		Power		
E11	VTT		Power		
E22	VTT		Power		
G03	VTT		Power		
G30	VTT		Power		
H03	VTT		Power		
N03	VTT		Power		

Table 12-27: MIOC Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
Y03	VTT		Power		
Y30	VTT		Power		
AE03	VTT		Power		
AE30	VTT		Power		
AF03	VTT		Power		
AF30	VTT		Power		
AH22	VTT		Power		
AJ03	VTT		Power		
AJ05	VTT		Power		
AJ28	VTT		Power		
AJ30	VTT		Power		
AK16	VTT		Power		
AK17	VTT		Power		
AL08	VTT		Power		
AL25	VTT		Power		
AL26	VTT		Power		
AM08	VTT		Power		
AM25	VTT		Power		
AM26	VTT		Power		
AJ14	WDEVT#	O	AGTL+	55ma	
R30	X0ADS#	I/O	AGTL+	55ma	
P31	X0BE0#	I/O	AGTL+	55ma	
P30	X0BE1#	I/O	AGTL+	55ma	
R32	X0BLK#	O	AGTL+	55ma	
L28	X0CLK	O	LVTTL	10ma	
L29	X0CLKB	O	LVTTL	10ma	
J28	X0CLKFB	I	LVTTL		
T32	X0D00#	I/O	AGTL+	55ma	
T31	X0D01#	I/O	AGTL+	55ma	
T30	X0D02#	I/O	AGTL+	55ma	
T29	X0D03#	I/O	AGTL+	55ma	
U29	X0D04#	I/O	AGTL+	55ma	
U31	X0D05#	I/O	AGTL+	55ma	
Y31	X0D06#	I/O	AGTL+	55ma	
Y29	X0D07#	I/O	AGTL+	55ma	
AA32	X0D08#	I/O	AGTL+	55ma	
AA31	X0D09#	I/O	AGTL+	55ma	
AA30	X0D10#	I/O	AGTL+	55ma	

Table 12-27: MIOC Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AA29	X0D11#	I/O	AGTL+	55ma	
AB31	X0D12#	I/O	AGTL+	55ma	
AB29	X0D13#	I/O	AGTL+	55ma	
AB28	X0D14#	I/O	AGTL+	55ma	
AC31	X0D15#	I/O	AGTL+	55ma	
W30	X0HRTS#	O	AGTL+	55ma	
W31	X0HSTBN#	O	AGTL+	55ma	
W32	X0HSTBP#	O	AGTL+	55ma	
R31	X0PAR#	I/O	AGTL+	55ma	
P29	X0RST#	O	AGTL+	55ma	
N30	X0RSTB#	O	AGTL+	55ma	
M32	X0RSTFB#	I	AGTL+		
W29	X0XRTS#	I	AGTL+		
V30	X0XSTBN#	I	AGTL+		
V31	X0XSTBP#	I	AGTL+		
AD32	X1ADS#	I/O	AGTL+	55ma	
AD30	X1BE0#	I/O	AGTL+	55ma	
AD29	X1BE1#	I/O	AGTL+	55ma	
AE28	X1BLK#	O	AGTL+	55ma	
M30	X1CLK	O	LVTTL	10ma	
M31	X1CLKB	O	LVTTL	10ma	
N28	X1CLKFB	I	LVTTL		
AE31	X1D00#	I/O	AGTL+	55ma	
AE29	X1D01#	I/O	AGTL+	55ma	
AF31	X1D02#	I/O	AGTL+	55ma	
AF29	X1D03#	I/O	AGTL+	55ma	
AG31	X1D04#	I/O	AGTL+	55ma	
AG30	X1D05#	I/O	AGTL+	55ma	
AJ29	X1D06#	I/O	AGTL+	55ma	
AK31	X1D07#	I/O	AGTL+	55ma	
AK30	X1D08#	I/O	AGTL+	55ma	
AK29	X1D09#	I/O	AGTL+	55ma	
AK28	X1D10#	I/O	AGTL+	55ma	
AL30	X1D11#	I/O	AGTL+	55ma	
AL29	X1D12#	I/O	AGTL+	55ma	
AJ27	X1D13#	I/O	AGTL+	55ma	
AH26	X1D14#	I/O	AGTL+	55ma	
AK26	X1D15#	I/O	AGTL+	55ma	

Table 12-27: MIOC Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AJ32	X1HRYS#	O	AGTL+	55ma	
AH28	X1HSTBN#	O	AGTL+	55ma	
AH29	X1HSTBP#	O	AGTL+	55ma	
AM29	X1PAR#	I/O	AGTL+	55ma	
AC29	X1RST#	O	AGTL+	55ma	
AD31	X1RSTB#	O	AGTL+	55ma	
AG32	X1RSTFB#	I	AGTL+		
AJ31	X1XRTS#	I	AGTL+		
AH30	X1XSTBN#	I	AGTL+		
AH31	X1XSTBP#	I	AGTL+		

Table 12-28: PXB Pin List Sorted by Signal

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AL17	ACK64#	I/O	PCI		
E09	CRES0	I	Analog		
D09	CRES1	I	Analog		
AL27	INTRQA#	OD	PCI		
AL7	INTRQB#	OD	PCI		
AJ26	MODE64#	I	PCI		
A01	N/C				
A02	N/C				
A11	N/C				
A13	N/C				
A23	N/C				
A25	N/C				
A30	N/C				
A31	N/C				
A32	N/C				
B01	N/C				
B05	N/C				
B06	N/C				
B07	N/C				
B08	N/C				
B09	N/C				
B10	N/C				
B11	N/C				
B12	N/C				
B13	N/C				

Table 12-28: PXB Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
B17	N/C				
B23	N/C				
B24	N/C				
B25	N/C				
B26	N/C				
B27	N/C				
B32	N/C				
C01	N/C				
C02	N/C				
C03	N/C				
C04	N/C				
C05	N/C				
C09	N/C				
C11	N/C				
C13	N/C				
C23	N/C				
C28	N/C				
C29	N/C				
C30	N/C				
C31	N/C				
C32	N/C				
D01	N/C				
D03	N/C				
D05	N/C				
D06	N/C				
D07	N/C				
D08	N/C				
D10	N/C				
D11	N/C				
D12	N/C				
D13	N/C				
D14	N/C				
D19	N/C				
D23	N/C				
D24	N/C				
D25	N/C				
D26	N/C				
D30	N/C				

Table 12-28: PXB Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
D32	N/C				
E01	N/C				
E02	N/C				
E03	N/C				
E04	N/C				
E05	N/C				
E07	N/C				
E11	N/C				
E25	N/C				
E28	N/C				
E29	N/C				
E30	N/C				
E31	N/C				
E32	N/C				
F02	N/C				
F04	N/C				
F30	N/C				
F32	N/C				
G01	N/C				
G02	N/C				
G03	N/C				
G04	N/C				
G05	N/C				
G28	N/C				
G29	N/C				
G32	N/C				
H02	N/C				
H04	N/C				
H28	N/C				
H29	N/C				
H31	N/C				
H32	N/C				
J01	N/C				
J02	N/C				
J03	N/C				
J04	N/C				
J05	N/C				
J28	N/C				

Table 12-28: PXB Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
J29	N/C				
J31	N/C				
K02	N/C				
K04	N/C				
K31	N/C				
L28	N/C				
L29	N/C				
L31	N/C				
M02	N/C				
M31	N/C				
N28	N/C				
N29	N/C				
N30	N/C				
N31	N/C				
N32	N/C				
P02	N/C				
P04	N/C				
P29	N/C				
P31	N/C				
R02	N/C				
R04	N/C				
R29	N/C				
R31	N/C				
T02	N/C				
T04	N/C				
T29	N/C				
T31	N/C				
U01	N/C				
U02	N/C				
U03	N/C				
U04	N/C				
U05	N/C				
U28	N/C				
U29	N/C				
U31	N/C				
V02	N/C				
V04	N/C				
V29	N/C				

Table 12-28: PxB Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
V31	N/C				
AH01	N/C				
AH02	N/C				
AH05	N/C				
AH06	N/C				
AH28	N/C				
AH31	N/C				
AH32	N/C				
AJ01	N/C				
AJ02	N/C				
AJ03	N/C				
AJ05	N/C				
AJ06	N/C				
AJ08	N/C				
AJ28	N/C				
AJ30	N/C				
AJ31	N/C				
AJ32	N/C				
AK01	N/C				
AK03	N/C				
AK05	N/C				
AK06	N/C				
AK08	N/C				
AK28	N/C				
AK30	N/C				
AK32	N/C				
AL01	N/C				
AL02	N/C				
AL03	N/C				
AL04	N/C				
AL05	N/C				
AL06	N/C				
AL08	N/C				
AL28	N/C				
AL29	N/C				
AL30	N/C				
AL31	N/C				
AL32	N/C				

Table 12-28: PXB Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AM01	N/C				
AM02	N/C				
AM06	N/C				
AM08	N/C				
AM10	N/C				
AM24	N/C				
AM31	N/C				
K29	N/C				
M29	N/C				
F31	N/C				
AG28	PAAD[00]	I/O	PCI		
AG29	PAAD[01]	I/O	PCI		
AG30	PAAD[02]	I/O	PCI		
AG31	PAAD[03]	I/O	PCI		
AG32	PAAD[04]	I/O	PCI		
AF29	PAAD[05]	I/O	PCI		
AF31	PAAD[06]	I/O	PCI		
AE28	PAAD[07]	I/O	PCI		
AE29	PAAD[08]	I/O	PCI		
AE30	PAAD[09]	I/O	PCI		
AE31	PAAD[10]	I/O	PCI		
AE32	PAAD[11]	I/O	PCI		
AD29	PAAD[12]	I/O	PCI		
AD31	PAAD[13]	I/O	PCI		
AC28	PAAD[14]	I/O	PCI		
AC29	PAAD[15]	I/O	PCI		
AC30	PAAD[16]	I/O	PCI		
AC31	PAAD[17]	I/O	PCI		
AC32	PAAD[18]	I/O	PCI		
AB29	PAAD[19]	I/O	PCI		
AB31	PAAD[20]	I/O	PCI		
AA28	PAAD[21]	I/O	PCI		
AA29	PAAD[22]	I/O	PCI		
AA30	PAAD[23]	I/O	PCI		
AA31	PAAD[24]	I/O	PCI		
AA32	PAAD[25]	I/O	PCI		
Y29	PAAD[26]	I/O	PCI		
Y31	PAAD[27]	I/O	PCI		

Table 12-28: PXB Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
W29	PAAD[28]	I/O	PCI		
W30	PAAD[29]	I/O	PCI		
W31	PAAD[30]	I/O	PCI		
W32	PAAD[31]	I/O	PCI		
AH18	PACBE[0]#	I/O	PCI		
AJ18	PACBE[1]#	I/O	PCI		
AM20	PACBE[2]#	I/O	PCI		
AJ21	PACBE[3]#	I/O	PCI		
L32	PACLK	O	LVTTTL	10ma	
J32	PACLKFB	I	LVTTTL		
AH20	PADEVSEL#	I/O	PCI		
AL20	PAFRAME#	I/O	PCI		
AJ23	PAGNT[0]#	O	PCI		
AL23	PAGNT[1]#	O	PCI		
AH24	PAGNT[2]#	O	PCI		
AJ24	PAGNT[3]#	O	PCI		
AK24	PAGNT[4]#	O	PCI		
AL24	PAGNT[5]#	O	PCI		
AK20	PAIRDY#	I/O	PCI		
AJ19	PALOCK#	I/O	PCI		
AL25	PAMON[0]#	I/O	LVTTTL	10ma	
AH26	PAMON[1]#	I/O	LVTTTL	10ma	
AK18	PAPAR	I/O	PCI		
AM18	PAPERR#	I/O	PCI		
AL21	PAREQ[0]#	I	PCI		
AH22	PAREQ[1]#	I	PCI		
AJ22	PAREQ[2]#	I	PCI		
AK22	PAREQ[3]#	I	PCI		
AL22	PAREQ[4]#	I	PCI		
AM22	PAREQ[5]#	I	PCI		
AJ25	PARST#	O	PCI		
AL18	PASERR#	OD	PCI		
AL19	PASTOP#	I/O	PCI		
AJ20	PATRDY#	I/O	PCI		
AJ27	PAXARB#	I	PCI		
AG05	PBAD[00]	I/O	PCI		
AG04	PBAD[01]	I/O	PCI		
AG03	PBAD[02]	I/O	PCI		

Table 12-28: PXB Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AG02	PBAD[03]	I/O	PCI		
AG01	PBAD[04]	I/O	PCI		
AF04	PBAD[05]	I/O	PCI		
AF02	PBAD[06]	I/O	PCI		
AE05	PBAD[07]	I/O	PCI		
AE04	PBAD[08]	I/O	PCI		
AE03	PBAD[09]	I/O	PCI		
AE02	PBAD[10]	I/O	PCI		
AE01	PBAD[11]	I/O	PCI		
AD04	PBAD[12]	I/O	PCI		
AD02	PBAD[13]	I/O	PCI		
AC05	PBAD[14]	I/O	PCI		
AC04	PBAD[15]	I/O	PCI		
AC03	PBAD[16]	I/O	PCI		
AC02	PBAD[17]	I/O	PCI		
AC01	PBAD[18]	I/O	PCI		
AB04	PBAD[19]	I/O	PCI		
AB02	PBAD[20]	I/O	PCI		
AA05	PBAD[21]	I/O	PCI		
AA04	PBAD[22]	I/O	PCI		
AA03	PBAD[23]	I/O	PCI		
AA02	PBAD[24]	I/O	PCI		
AA01	PBAD[25]	I/O	PCI		
Y04	PBAD[26]	I/O	PCI		
Y02	PBAD[27]	I/O	PCI		
W04	PBAD[28]	I/O	PCI		
W03	PBAD[29]	I/O	PCI		
W02	PBAD[30]	I/O	PCI		
W01	PBAD[31]	I/O	PCI		
AH16	PBCBE[0]#	I/O	PCI		
AJ16	PBCBE[1]#	I/O	PCI		
AM14	PBCBE[2]#	I/O	PCI		
AJ13	PBCBE[3]#	I/O	PCI		
L30	PBCLK	O	LVTTL	10ma	
J30	PBCLKFB	I	LVTTL		
AH14	PBDEVSEL#	I/O	PCI		
AL14	PBFRAME#	I/O	PCI		
AJ11	PBGNT[0]#	O	PCI		

Table 12-28: PXB Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AL11	PBGNT[1]#	O	PCI		
AH10	PBGNT[2]#	O	PCI		
AJ10	PBGNT[3]#	O	PCI		
AK10	PBGNT[4]#	O	PCI		
AL10	PBGNT[5]#	O	PCI		
AK14	PBIRDY#	I/O	PCI		
AJ15	PBLOCK#	I/O	PCI		
AL09	PBMON[0]#	I/O	PCI		
AH08	PBMON[1]#	I/O	PCI		
AK16	PBPAR	I/O	PCI		
AM16	PBPERR#	I/O	PCI		
AL13	PBREQ[0]#	I	PCI		
AH12	PBREQ[1]#	I	PCI		
AJ12	PBREQ[2]#	I	PCI		
AK12	PBREQ[3]#	I	PCI		
AL12	PBREQ[4]#	I	PCI		
AM12	PBREQ[5]#	I	PCI		
AJ09	PBRST#	O	PCI		
AL16	PBSERR#	OD	PCI		
AL15	PBSTOP#	I/O	PCI		
AJ14	PBTRDY#	I/O	PCI		
AJ07	PBXARB#	I	PCI		
AL26	PHLDA#	O	PCI		
AK26	PHOLD#	I	PCI		
F29	PIIXOK#	I	LVTTTL		
D29	PWRGD	I	LVTTTL		
AJ17	REQ64#	I/O	PCI		
M04	TCK	I	2.5V		
N01	TDI	I	2.5V		
N02	TDO	O	OD	14ma	
N04	TMS	I	2.5V		
N05	TRST#	I	2.5V		
A03	VCC		Power		
A04	VCC		Power		
A05	VCC		Power		
A06	VCC		Power		
A07	VCC		Power		
A08	VCC		Power		

Table 12-28: PXB Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
A09	VCC		Power		
A10	VCC		Power		
A14	VCC		Power		
A16	VCC		Power		
A18	VCC		Power		
A20	VCC		Power		
A22	VCC		Power		
A26	VCC		Power		
A28	VCC		Power		
A29	VCC		Power		
B02	VCC		Power		
B03	VCC		Power		
B04	VCC		Power		
B28	VCC		Power		
B29	VCC		Power		
B30	VCC		Power		
B31	VCC		Power		
D27	VCC		Power		
F03	VCC		Power		
G30	VCC		Power		
G31	VCC		Power		
H01	VCC		Power		
H05	VCC		Power		
K03	VCC		Power		
K30	VCC		Power		
M01	VCC		Power		
M05	VCC		Power		
M28	VCC		Power		
M32	VCC		Power		
N03	VCC		Power		
P01	VCC		Power		
P30	VCC		Power		
R01	VCC		Power		
R30	VCC		Power		
T01	VCC		Power		
T30	VCC		Power		
U030	VCC		Power		
Y1	VCC		Power		

Table 12-28: PXB Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
Y05	VCC		Power		
Y28	VCC		Power		
Y32	VCC		Power		
AD01	VCC		Power		
AD05	VCC		Power		
AD28	VCC		Power		
AD32	VCC		Power		
AH04	VCC		Power		
AH09	VCC		Power		
AH13	VCC		Power		
AH17	VCC		Power		
AH21	VCC		Power		
AH25	VCC		Power		
AH29	VCC		Power		
AJ04	VCC		Power		
AJ29	VCC		Power		
AK07	VCC		Power		
AK27	VCC		Power		
AM09	VCC		Power		
AM13	VCC		Power		
AM17	VCC		Power		
AM21	VCC		Power		
AM25	VCC		Power		
P05	VCC		Power		
R05	VCC		Power		
T05	VCC		Power		
V28	VCC		Power		
W28	VCC		Power		
V03	VCC5A		Power (PCI)		
AB03	VCC5B		Power (PCI)		
AF03	VCC5C		Power (PCI)		
AH03	VCC5D		Power (PCI)		
AK04	VCC5E		Power (PCI)		
AK11	VCC5F		Power (PCI)		
AK15	VCC5G		Power (PCI)		
AK19	VCC5H		Power (PCI)		
AK23	VCC5I		Power (PCI)		
AK29	VCC5J		Power (PCI)		

Table 12-28: PXB Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AH30	VCC5K		Power (PCI)		
AF30	VCC5L		Power (PCI)		
AB30	VCC5M		Power (PCI)		
V30	VCC5N		Power (PCI)		
A27	VCCA0		Power		
C27	VCCA1		Power		
E27	VCCA2		Power		
A12	VREF	I	Analog		
A24	VREF	I	Analog		
C06	GND		Power		
C07	GND		Power		
C08	GND		Power		
C10	GND		Power		
C12	GND		Power		
C14	GND		Power		
C16	GND		Power		
C18	GND		Power		
C20	GND		Power		
C22	GND		Power		
C24	GND		Power		
C26	GND		Power		
D02	GND		Power		
D31	GND		Power		
F01	GND		Power		
F05	GND		Power		
F28	GND		Power		
H03	GND		Power		
H30	GND		Power		
K01	GND		Power		
K05	GND		Power		
K28	GND		Power		
K32	GND		Power		
L01	GND		Power		
L02	GND		Power		
L03	GND		Power		
L04	GND		Power		
L05	GND		Power		
M03	GND		Power		

Table 12-28: PXB Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
M30	GND		Power		
P03	GND		Power		
P32	GND		Power		
R03	GND		Power		
R32	GND		Power		
T03	GND		Power		
T32	GND		Power		
U32	GND		Power		
V01	GND		Power		
V32	GND		Power		
Y03	GND		Power		
Y30	GND		Power		
AB01	GND		Power		
AB05	GND		Power		
AB28	GND		Power		
AB32	GND		Power		
AD03	GND		Power		
AD30	GND		Power		
AF01	GND		Power		
AF05	GND		Power		
AF28	GND		Power		
AF32	GND		Power		
AH07	GND		Power		
AH11	GND		Power		
AH15	GND		Power		
AH19	GND		Power		
AH23	GND		Power		
AH27	GND		Power		
AK02	GND		Power		
AK09	GND		Power		
AK13	GND		Power		
AK17	GND		Power		
AK21	GND		Power		
AK25	GND		Power		
AK31	GND		Power		
AM03	GND		Power		
AM04	GND		Power		
AM05	GND		Power		

Table 12-28: PXB Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
AM07	GND		Power		
AM11	GND		Power		
AM15	GND		Power		
AM19	GND		Power		
AM23	GND		Power		
AM27	GND		Power		
AM28	GND		Power		
AM29	GND		Power		
AM30	GND		Power		
AM32	GND		Power		
P28	GND		Power		
R28	GND		Power		
T28	GND		Power		
V05	GND		Power		
W05	GND		Power		
D04	VTT		Power		
D28	VTT		Power		
E06	VTT		Power		
E08	VTT		Power		
E10	VTT		Power		
E12	VTT		Power		
E14	VTT		Power		
E16	VTT		Power		
E18	VTT		Power		
E20	VTT		Power		
E22	VTT		Power		
E24	VTT		Power		
E26	VTT		Power		
AM26	WSC#	O	PCI		
C21	XADS#	I/O	AGTL+	55ma	
E23	XBE[0]#	I/O	AGTL+	55ma	
B22	XBE[1]#	I/O	AGTL+	55ma	
A21	XBLK#	I	AGTL+		
C25	XCLK	I	LVTTL		
D21	XD[00]#	I/O	AGTL+	55ma	
E21	XD[01]#	I/O	AGTL+	55ma	
B20	XD[02]#	I/O	AGTL+	55ma	
D20	XD[03]#	I/O	AGTL+	55ma	

Table 12-28: PXB Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
A19	XD[04]#	I/O	AGTL+	55ma	
B19	XD[05]#	I/O	AGTL+	55ma	
D17	XD[06]#	I/O	AGTL+	55ma	
E17	XD[07]#	I/O	AGTL+	55ma	
B16	XD[08]#	I/O	AGTL+	55ma	
D16	XD[09]#	I/O	AGTL+	55ma	
A15	XD[10]#	I/O	AGTL+	55ma	
B15	XD[11]#	I/O	AGTL+	55ma	
C15	XD[12]#	I/O	AGTL+	55ma	
D15	XD[13]#	I/O	AGTL+	55ma	
E15	XD[14]#	I/O	AGTL+	55ma	
B14	XD[15]#	I/O	AGTL+	55ma	
B18	XHRTS#	I	AGTL+		
A17	XHSTBN#	I	AGTL+		
C17	XHSTBP#	I	AGTL+		
E13	XIB	O	AGTL+	55ma	
B21	XPAR#	I/O	AGTL+	55ma	
D22	XRST#	I	AGTL+		
D18	XXRTS#	O	AGTL+	55ma	
C19	XXSTBN#	O	AGTL+	55ma	
E19	XXSTBP#	O	AGTL+	55ma	

Table 12-29: MUX Pin List Sorted by Signal

PIN#	Signal	I/O	Driver Type	Driver Strength	Input Pullup/Pulldown
Y12	AVWP#	I	AGTL+		
T12	CRES0	I	Analog		
V13	CRES1	I	Analog		
Y13	DCMPLT#	I/O	AGTL+	55ma	
V09	DOFF0#	I	AGTL+		
V08	DOFF1#	I	AGTL+		
W09	DSEL#	I	AGTL+		
Y19	DSTBN0#	I/O	AGTL+	55ma	
Y03	DSTBN1#	I/O	AGTL+	55ma	
Y18	DSTBP0#	I/O	AGTL+	55ma	
T06	DSTBP1#	I/O	AGTL+	55ma	
V11	DVALID#	I	AGTL+		
T09	N/C				

Table 12-29: MUX Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Input Pullup/Pulldown
W12	GDCMPLT#	I/O	AGTL+	55ma	
A01	GND		Power		
A06	GND		Power		
A15	GND		Power		
A20	GND		Power		
B02	GND		Power		
B06	GND		Power		
B10	GND		Power		
B11	GND		Power		
B15	GND		Power		
B19	GND		Power		
F02	GND		Power		
F19	GND		Power		
H04	GND		Power		
H17	GND		Power		
J09	GND		Power		
J10	GND		Power		
J11	GND		Power		
J12	GND		Power		
N04	GND		Power		
N17	GND		Power		
R01	GND		Power		
R02	GND		Power		
R19	GND		Power		
R20	GND		Power		
W06	GND		Power		
W10	GND		Power		
W11	GND		Power		
W15	GND		Power		
W19	GND		Power		
Y01	GND		Power		
Y06	GND		Power		
Y15	GND		Power		
Y20	GND		Power		
D04	GND		Power		
D08	GND		Power		
D13	GND		Power		
D17	GND		Power		

Table 12-29: MUX Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Input Pullup/Pulldown
K02	GND		Power		
K09	GND		Power		
K10	GND		Power		
K11	GND		Power		
K12	GND		Power		
K19	GND		Power		
L02	GND		Power		
L09	GND		Power		
L10	GND		Power		
L11	GND		Power		
L12	GND		Power		
L19	GND		Power		
M09	GND		Power		
M10	GND		Power		
M11	GND		Power		
M12	GND		Power		
U04	GND		Power		
U08	GND		Power		
U13	GND		Power		
U17	GND		Power		
W02	GND		Power		
V10	HCLKIN	I	2.5V		
Y08	LDSTB#	O	AGTL+	55ma	
V12	LRD#	I	AGTL+		
R16	MD00#	I/O	AGTL+	55ma	
T17	MD01#	I/O	AGTL+	55ma	
U18	MD02#	I/O	AGTL+	55ma	
V19	MD03#	I/O	AGTL+	55ma	
W20	MD04#	I/O	AGTL+	55ma	
T16	MD05#	I/O	AGTL+	55ma	
V18	MD06#	I/O	AGTL+	55ma	
T15	MD07#	I/O	AGTL+	55ma	
V17	MD08#	I/O	AGTL+	55ma	
T14	MD09#	I/O	AGTL+	55ma	
V15	MD10#	I/O	AGTL+	55ma	
W16	MD11#	I/O	AGTL+	55ma	
Y17	MD12#	I/O	AGTL+	55ma	
U14	MD13#	I/O	AGTL+	55ma	

Table 12-29: MUX Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Input Pullup/Pulldown
Y16	MD14#	I/O	AGTL+	55ma	
T13	MD15#	I/O	AGTL+	55ma	
V14	MD16#	I/O	AGTL+	55ma	
Y14	MD17#	I/O	AGTL+	55ma	
Y07	MD18#	I/O	AGTL+	55ma	
T08	MD19#	I/O	AGTL+	55ma	
V07	MD20#	I/O	AGTL+	55ma	
U07	MD21#	I/O	AGTL+	55ma	
Y05	MD22#	I/O	AGTL+	55ma	
T07	MD23#	I/O	AGTL+	55ma	
V06	MD24#	I/O	AGTL+	55ma	
W05	MD25#	I/O	AGTL+	55ma	
Y04	MD26#	I/O	AGTL+	55ma	
V04	MD27#	I/O	AGTL+	55ma	
Y02	MD28#	I/O	AGTL+	55ma	
T05	MD29#	I/O	AGTL+	55ma	
V03	MD30#	I/O	AGTL+	55ma	
R05	MD31#	I/O	AGTL+	55ma	
T04	MD32#	I/O	AGTL+	55ma	
U03	MD33#	I/O	AGTL+	55ma	
V02	MD34#	I/O	AGTL+	55ma	
W01	MD35#	I/O	AGTL+	55ma	
Y09	MRESET#	I	AGTL+		
Y10	VCC		Power		
V20	N/C				
V01	N/C				
T18	Q0D00	I/O	LVTTTL	10ma	
U20	Q0D01	I/O	LVTTTL	10ma	
P18	Q0D02	I/O	LVTTTL	10ma	
N18	Q0D03	I/O	LVTTTL	10ma	
M20	Q0D04	I/O	LVTTTL	10ma	
K16	Q0D05	I/O	LVTTTL	10ma	
J18	Q0D06	I/O	LVTTTL	10ma	
H18	Q0D07	I/O	LVTTTL	10ma	
G18	Q0D08	I/O	LVTTTL	10ma	
G16	Q0D09	I/O	LVTTTL	10ma	
E18	Q0D10	I/O	LVTTTL	10ma	
D18	Q0D11	I/O	LVTTTL	10ma	

Table 12-29: MUX Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Input Pullup/Pulldown
C18	Q0D12	I/O	LVTTL	10ma	
B18	Q0D13	I/O	LVTTL	10ma	
E14	Q0D14	I/O	LVTTL	10ma	
D14	Q0D15	I/O	LVTTL	10ma	
B14	Q0D16	I/O	LVTTL	10ma	
D12	Q0D17	I/O	LVTTL	10ma	
D09	Q0D18	I/O	LVTTL	10ma	
E09	Q0D19	I/O	LVTTL	10ma	
E08	Q0D20	I/O	LVTTL	10ma	
E07	Q0D21	I/O	LVTTL	10ma	
C05	Q0D22	I/O	LVTTL	10ma	
C04	Q0D23	I/O	LVTTL	10ma	
C03	Q0D24	I/O	LVTTL	10ma	
C02	Q0D25	I/O	LVTTL	10ma	
G05	Q0D26	I/O	LVTTL	10ma	
G04	Q0D27	I/O	LVTTL	10ma	
F01	Q0D28	I/O	LVTTL	10ma	
H03	Q0D29	I/O	LVTTL	10ma	
J01	Q0D30	I/O	LVTTL	10ma	
L05	Q0D31	I/O	LVTTL	10ma	
M03	Q0D32	I/O	LVTTL	10ma	
N03	Q0D33	I/O	LVTTL	10ma	
P03	Q0D34	I/O	LVTTL	10ma	
R03	Q0D35	I/O	LVTTL	10ma	
P16	Q1D00	I/O	LVTTL	10ma	
P17	Q1D01	I/O	LVTTL	10ma	
P19	Q1D02	I/O	LVTTL	10ma	
M17	Q1D03	I/O	LVTTL	10ma	
L16	Q1D04	I/O	LVTTL	10ma	
K18	Q1D05	I/O	LVTTL	10ma	
J19	Q1D06	I/O	LVTTL	10ma	
G19	Q1D07	I/O	LVTTL	10ma	
F20	Q1D08	I/O	LVTTL	10ma	
F18	Q1D09	I/O	LVTTL	10ma	
C20	Q1D10	I/O	LVTTL	10ma	
C19	Q1D11	I/O	LVTTL	10ma	
E15	Q1D12	I/O	LVTTL	10ma	
A19	Q1D13	I/O	LVTTL	10ma	

Table 12-29: MUX Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Input Pullup/Pulldown
C15	Q1D14	I/O	LVTTL	10ma	
A16	Q1D15	I/O	LVTTL	10ma	
A14	Q1D16	I/O	LVTTL	10ma	
C12	Q1D17	I/O	LVTTL	10ma	
C09	Q1D18	I/O	LVTTL	10ma	
C08	Q1D19	I/O	LVTTL	10ma	
C07	Q1D20	I/O	LVTTL	10ma	
C06	Q1D21	I/O	LVTTL	10ma	
A03	Q1D22	I/O	LVTTL	10ma	
B03	Q1D23	I/O	LVTTL	10ma	
F05	Q1D24	I/O	LVTTL	10ma	
B01	Q1D25	I/O	LVTTL	10ma	
F03	Q1D26	I/O	LVTTL	10ma	
E01	Q1D27	I/O	LVTTL	10ma	
G02	Q1D28	I/O	LVTTL	10ma	
J04	Q1D29	I/O	LVTTL	10ma	
K05	Q1D30	I/O	LVTTL	10ma	
L03	Q1D31	I/O	LVTTL	10ma	
M02	Q1D32	I/O	LVTTL	10ma	
P02	Q1D33	I/O	LVTTL	10ma	
P04	Q1D34	I/O	LVTTL	10ma	
T02	Q1D35	I/O	LVTTL	10ma	
R18	Q2D00	I/O	LVTTL	10ma	
T20	Q2D01	I/O	LVTTL	10ma	
P20	Q2D02	I/O	LVTTL	10ma	
M18	Q2D03	I/O	LVTTL	10ma	
L18	Q2D04	I/O	LVTTL	10ma	
K20	Q2D05	I/O	LVTTL	10ma	
J20	Q2D06	I/O	LVTTL	10ma	
G20	Q2D07	I/O	LVTTL	10ma	
G17	Q2D08	I/O	LVTTL	10ma	
E19	Q2D09	I/O	LVTTL	10ma	
F16	Q2D10	I/O	LVTTL	10ma	
B20	Q2D11	I/O	LVTTL	10ma	
D16	Q2D12	I/O	LVTTL	10ma	
C16	Q2D13	I/O	LVTTL	10ma	
B16	Q2D14	I/O	LVTTL	10ma	
E13	Q2D15	I/O	LVTTL	10ma	

Table 12-29: MUX Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Input Pullup/Pulldown
E12	Q2D16	I/O	LVTTL	10ma	
B12	Q2D17	I/O	LVTTL	10ma	
B09	Q2D18	I/O	LVTTL	10ma	
B07	Q2D19	I/O	LVTTL	10ma	
D07	Q2D20	I/O	LVTTL	10ma	
B05	Q2D21	I/O	LVTTL	10ma	
E06	Q2D22	I/O	LVTTL	10ma	
A02	Q2D23	I/O	LVTTL	10ma	
E04	Q2D24	I/O	LVTTL	10ma	
E03	Q2D25	I/O	LVTTL	10ma	
E02	Q2D26	I/O	LVTTL	10ma	
H05	Q2D27	I/O	LVTTL	10ma	
G01	Q2D28	I/O	LVTTL	10ma	
J03	Q2D29	I/O	LVTTL	10ma	
K03	Q2D30	I/O	LVTTL	10ma	
L01	Q2D31	I/O	LVTTL	10ma	
M01	Q2D32	I/O	LVTTL	10ma	
P01	Q2D33	I/O	LVTTL	10ma	
T01	Q2D34	I/O	LVTTL	10ma	
U01	Q2D35	I/O	LVTTL	10ma	
T19	Q3D00	I/O	LVTTL	10ma	
N16	Q3D01	I/O	LVTTL	10ma	
M16	Q3D02	I/O	LVTTL	10ma	
M19	Q3D03	I/O	LVTTL	10ma	
L20	Q3D04	I/O	LVTTL	10ma	
J17	Q3D05	I/O	LVTTL	10ma	
J16	Q3D06	I/O	LVTTL	10ma	
H16	Q3D07	I/O	LVTTL	10ma	
E20	Q3D08	I/O	LVTTL	10ma	
D20	Q3D09	I/O	LVTTL	10ma	
E17	Q3D10	I/O	LVTTL	10ma	
E16	Q3D11	I/O	LVTTL	10ma	
C17	Q3D12	I/O	LVTTL	10ma	
A18	Q3D13	I/O	LVTTL	10ma	
A17	Q3D14	I/O	LVTTL	10ma	
C14	Q3D15	I/O	LVTTL	10ma	
C13	Q3D16	I/O	LVTTL	10ma	
A12	Q3D17	I/O	LVTTL	10ma	

Table 12-29: MUX Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Input Pullup/Pulldown
A09	Q3D18	I/O	LVTTL	10ma	
A07	Q3D19	I/O	LVTTL	10ma	
A05	Q3D20	I/O	LVTTL	10ma	
A04	Q3D21	I/O	LVTTL	10ma	
D05	Q3D22	I/O	LVTTL	10ma	
E05	Q3D23	I/O	LVTTL	10ma	
D03	Q3D24	I/O	LVTTL	10ma	
C01	Q3D25	I/O	LVTTL	10ma	
D01	Q3D26	I/O	LVTTL	10ma	
G03	Q3D27	I/O	LVTTL	10ma	
J05	Q3D28	I/O	LVTTL	10ma	
J02	Q3D29	I/O	LVTTL	10ma	
K01	Q3D30	I/O	LVTTL	10ma	
M04	Q3D31	I/O	LVTTL	10ma	
M05	Q3D32	I/O	LVTTL	10ma	
N05	Q3D33	I/O	LVTTL	10ma	
P05	Q3D34	I/O	LVTTL	10ma	
T03	Q3D35	I/O	LVTTL	10ma	
C11	TCK	I	LVTTL		
C10	TDI	I	LVTTL		
A10	TDO	O	OD	14ma	
E10	TMS	I	LVTTL		
E11	TRST#	I	LVTTL		
A08	VCC		Power		
A11	VCC		Power		
A13	VCC		Power		
B04	VCC		Power		
B08	VCC		Power		
B13	VCC		Power		
B17	VCC		Power		
F04	VCC		Power		
F06	VCC		Power		
F14	VCC		Power		
F15	VCC		Power		
F17	VCC		Power		
G06	VCC		Power		
H01	VCC		Power		
H02	VCC		Power		

Table 12-29: MUX Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Input Pullup/Pulldown
H19	VCC		Power		
H20	VCC		Power		
N19	VCC		Power		
N20	VCC		Power		
P15	VCC		Power		
R04	VCC		Power		
R06	VCC		Power		
R07	VCC		Power		
R15	VCC		Power		
R17	VCC		Power		
W08	VCC		Power		
W13	VCC		Power		
W17	VCC		Power		
D02	VCC		Power		
D06	VCC		Power		
D10	VCC		Power		
D11	VCC		Power		
D15	VCC		Power		
D19	VCC		Power		
K04	VCC		Power		
K17	VCC		Power		
L04	VCC		Power		
L17	VCC		Power		
N01	VCC		Power		
N02	VCC		Power		
U02	VCC		Power		
U06	VCC		Power		
U10	VCC		Power		
U11	VCC		Power		
U15	VCC		Power		
U19	VCC		Power		
W04	VCC		Power		
T10	VCCA		Power		
V05	VREF	I	Analog		
V16	VREF	I	Analog		
W07	VTT		Power		
W14	VTT		Power		
W18	VTT		Power		

Table 12-29: MUX Pin List Sorted by Signal (Continued)

PIN#	Signal	I/O	Driver Type	Driver Strength	Input Pullup/Pulldown
U05	VTT		Power		
U09	VTT		Power		
U12	VTT		Power		
U16	VTT		Power		
W03	VTT		Power		
Y11	WDEVT#	I	AGTL+		
T11	WDME#	I	AGTL+		

Table 12-30: RCG Pin List Sorted by Signal

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
N05	ADDRA00	O	LVTTTL	10ma	
N03	ADDRA01	O	LVTTTL	10ma	
P02	ADDRA02	O	LVTTTL	10ma	
P01	ADDRA03	O	LVTTTL	10ma	
P04	ADDRA04	O	LVTTTL	10ma	
P03	ADDRA05	O	LVTTTL	10ma	
R03	ADDRA06	O	LVTTTL	10ma	
T02	ADDRA07	O	LVTTTL	10ma	
T01	ADDRA08	O	LVTTTL	10ma	
T04	ADDRA09	O	LVTTTL	10ma	
T03	ADDRA10	O	LVTTTL	10ma	
U01	ADDRA11	O	LVTTTL	10ma	
V02	ADDRA12	O	LVTTTL	10ma	
V01	ADDRA13	O	LVTTTL	10ma	
J20	ADDRB00	O	LVTTTL	10ma	
J19	ADDRB01	O	LVTTTL	10ma	
J18	ADDRB02	O	LVTTTL	10ma	
J17	ADDRB03	O	LVTTTL	10ma	
J16	ADDRB04	O	LVTTTL	10ma	
G20	ADDRB05	O	LVTTTL	10ma	
G19	ADDRB06	O	LVTTTL	10ma	
H18	ADDRB07	O	LVTTTL	10ma	
H16	ADDRB08	O	LVTTTL	10ma	
F20	ADDRB09	O	LVTTTL	10ma	
G18	ADDRB10	O	LVTTTL	10ma	
G17	ADDRB11	O	LVTTTL	10ma	
E20	ADDRB12	O	LVTTTL	10ma	
F18	ADDRB13	O	LVTTTL	10ma	

Table 12-30: RCG Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
C03	ADDRRC00	O	LVTTTL	10ma	
E04	ADDRRC01	O	LVTTTL	10ma	
D03	ADDRRC02	O	LVTTTL	10ma	
C02	ADDRRC03	O	LVTTTL	10ma	
E03	ADDRRC04	O	LVTTTL	10ma	
C01	ADDRRC05	O	LVTTTL	10ma	
F03	ADDRRC06	O	LVTTTL	10ma	
E02	ADDRRC07	O	LVTTTL	10ma	
D01	ADDRRC08	O	LVTTTL	10ma	
G04	ADDRRC09	O	LVTTTL	10ma	
E01	ADDRRC10	O	LVTTTL	10ma	
G03	ADDRRC11	O	LVTTTL	10ma	
G02	ADDRRC12	O	LVTTTL	10ma	
F01	ADDRRC13	O	LVTTTL	10ma	
C14	ADDRRD00	O	LVTTTL	10ma	
A14	ADDRRD01	O	LVTTTL	10ma	
C13	ADDRRD02	O	LVTTTL	10ma	
A12	ADDRRD03	O	LVTTTL	10ma	
B12	ADDRRD04	O	LVTTTL	10ma	
C12	ADDRRD05	O	LVTTTL	10ma	
D12	ADDRRD06	O	LVTTTL	10ma	
E12	ADDRRD07	O	LVTTTL	10ma	
A11	ADDRRD08	O	LVTTTL	10ma	
C11	ADDRRD09	O	LVTTTL	10ma	
E11	ADDRRD10	O	LVTTTL	10ma	
E10	ADDRRD11	O	LVTTTL	10ma	
C10	ADDRRD12	O	LVTTTL	10ma	
A10	ADDRRD13	O	LVTTTL	10ma	
V15	AVWP#	O	AGTL+	55ma	
T12	BANK0#	I	AGTL+		
V12	BANK1#	I	AGTL+		
W12	BANK2#	I	AGTL+		
T18	BANKID#	I	LVTTTL		Requires external pull-up
Y13	CARD#	I	AGTL+		
K01	CASAA0#	O	LVTTTL	10ma	
H05	CASAA1#	O	LVTTTL	10ma	
K03	CASAB0#	O	LVTTTL	10ma	
J02	CASAB1#	O	LVTTTL	10ma	

Table 12-30: RCG Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
H03	CASAC0#	O	LVTTTL	10ma	
J05	CASAC1#	O	LVTTTL	10ma	
K05	CASAD0#	O	LVTTTL	10ma	
J03	CASAD1#	O	LVTTTL	10ma	
M16	CASBA0#	O	LVTTTL	10ma	
N18	CASBA1#	O	LVTTTL	10ma	
M19	CASBB0#	O	LVTTTL	10ma	
M17	CASBB1#	O	LVTTTL	10ma	
P18	CASBC0#	O	LVTTTL	10ma	
T20	CASBC1#	O	LVTTTL	10ma	
P19	CASBD0#	O	LVTTTL	10ma	
R18	CASBD1#	O	LVTTTL	10ma	
A03	CASCA0#	O	LVTTTL	10ma	
D07	CASCA1#	O	LVTTTL	10ma	
C07	CASCB0#	O	LVTTTL	10ma	
A05	CASCB1#	O	LVTTTL	10ma	
B05	CASCC0#	O	LVTTTL	10ma	
B09	CASCC1#	O	LVTTTL	10ma	
C08	CASCD0#	O	LVTTTL	10ma	
B07	CASCD1#	O	LVTTTL	10ma	
D16	CASDA0#	O	LVTTTL	10ma	
A19	CASDA1#	O	LVTTTL	10ma	
C18	CASDB0#	O	LVTTTL	10ma	
D18	CASDB1#	O	LVTTTL	10ma	
A18	CASDC0#	O	LVTTTL	10ma	
B20	CASDC1#	O	LVTTTL	10ma	
C19	CASDD0#	O	LVTTTL	10ma	
B18	CASDD1#	O	LVTTTL	10ma	
Y12	CMND0#	I	AGTL+		
T11	CMND1#	I	AGTL+		
V04	CRES0	I	Analog		
V03	CRES1	I	Analog		
V11	CSTB#	I	AGTL+		
U18	DR50H#	I	LVTTTL		
T19	DR50T#	I	LVTTTL		
A01	GND		Power		
A06	GND		Power		
A15	GND		Power		

Table 12-30: RCG Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
A20	GND		Power		
B02	GND		Power		
B06	GND		Power		
B10	GND		Power		
B11	GND		Power		
B15	GND		Power		
B19	GND		Power		
F02	GND		Power		
F19	GND		Power		
H04	GND		Power		
H17	GND		Power		
J09	GND		Power		
J10	GND		Power		
J11	GND		Power		
J12	GND		Power		
N04	GND		Power		
N17	GND		Power		
R01	GND		Power		
R02	GND		Power		
R19	GND		Power		
R20	GND		Power		
W06	GND		Power		
W10	GND		Power		
W11	GND		Power		
W15	GND		Power		
W19	GND		Power		
Y01	GND		Power		
Y06	GND		Power		
Y15	GND		Power		
Y20	GND		Power		
D04	GND		Power		
D08	GND		Power		
D13	GND		Power		
D17	GND		Power		
K02	GND		Power		
K09	GND		Power		
K10	GND		Power		
K11	GND		Power		

Table 12-30: RCG Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
K12	GND		Power		
K19	GND		Power		
L02	GND		Power		
L09	GND		Power		
L10	GND		Power		
L11	GND		Power		
L12	GND		Power		
L19	GND		Power		
M09	GND		Power		
M10	GND		Power		
M11	GND		Power		
M12	GND		Power		
U04	GND		Power		
U08	GND		Power		
U13	GND		Power		
U17	GND		Power		
W02	GND		Power		
Y14	GRCMPLT#	I/O	AGTL+	55ma	
V10	HCLKIN	I	2.5V		
Y16	LDSTB#	O	AGTL+	55ma	
T15	LRD#	O	AGTL+	55ma	
V09	MA00#	I	AGTL+		
W09	MA01#	I	AGTL+		
T08	MA02#	I	AGTL+		
V08	MA03#	I	AGTL+		
Y08	MA04#	I	AGTL+		
T07	MA05#	I	AGTL+		
U07	MA06#	I	AGTL+		
V07	MA07#	I	AGTL+		
Y07	MA08#	I	AGTL+		
V06	MA09#	I	AGTL+		
W05	MA10#	I	AGTL+		
Y05	MA11#	I	AGTL+		
Y04	MA12#	I	AGTL+		
Y03	MA13#	I	AGTL+		
Y09	MRESET#	I	AGTL+		
T17	VCC		Power		
P16	N/C				

Table 12-30: RCG Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
R05	N/C				
R16	N/C				
T05	N/C				
T06	N/C				
T09	N/C				
T13	N/C				
T16	N/C				
E05	N/C				
E06	N/C				
E07	N/C				
E08	N/C				
E09	N/C				
E14	N/C				
E15	N/C				
E16	N/C				
F05	N/C				
F16	N/C				
G05	N/C				
G16	N/C				
N16	N/C				
P05	N/C				
Y10	VCC		Power		
C09	N/C				
D09	N/C				
D20	N/C				
E17	N/C				
E18	N/C				
E19	N/C				
G01	N/C				
W1	N/C				
W16	N/C				
W20	N/C				
Y02	N/C				
U03	N/C				
Y17	N/C				
Y19	N/C				
V14	PHIT#	O	AGTL+	55ma	
L01	RASAA0#	O	LVTTL	10ma	

Table 12-30: RCG Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
M02	RASAA1#	O	LVTTTL	10ma	
M01	RASAB0#	O	LVTTTL	10ma	
M03	RASAB1#	O	LVTTTL	10ma	
L03	RASAC0#	O	LVTTTL	10ma	
M04	RASAC1#	O	LVTTTL	10ma	
L05	RASAD0#	O	LVTTTL	10ma	
M05	RASAD1#	O	LVTTTL	10ma	
L18	RASBA0#	O	LVTTTL	10ma	
L16	RASBA1#	O	LVTTTL	10ma	
M18	RASBB0#	O	LVTTTL	10ma	
K16	RASBB1#	O	LVTTTL	10ma	
L20	RASBC0#	O	LVTTTL	10ma	
K18	RASBC1#	O	LVTTTL	10ma	
M20	RASBD0#	O	LVTTTL	10ma	
K20	RASBD1#	O	LVTTTL	10ma	
A02	RASCA0#	O	LVTTTL	10ma	
B01	RASCA1#	O	LVTTTL	10ma	
A04	RASCB0#	O	LVTTTL	10ma	
B03	RASCB1#	O	LVTTTL	10ma	
C05	RASCC0#	O	LVTTTL	10ma	
C04	RASCC1#	O	LVTTTL	10ma	
C06	RASCD0#	O	LVTTTL	10ma	
D05	RASCD1#	O	LVTTTL	10ma	
C15	RASDA0#	O	LVTTTL	10ma	
E13	RASDA1#	O	LVTTTL	10ma	
C16	RASDB0#	O	LVTTTL	10ma	
D14	RASDB1#	O	LVTTTL	10ma	
B16	RASDC0#	O	LVTTTL	10ma	
B14	RASDC1#	O	LVTTTL	10ma	
A17	RASDD0#	O	LVTTTL	10ma	
A16	RASDD1#	O	LVTTTL	10ma	
V13	RCMPLT#	O	AGTL+	55ma	
U14	RHIT#	O	AGTL+	55ma	
Y11	ROW#	I	AGTL+		
V18	TCK	I	LVTTTL		
V20	TDI	I	LVTTTL		
V19	TDO	O	OD	14ma	
Y18	TMS	I	LVTTTL		

Table 12-30: RCG Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
V17	TRST#	I	LVTTL		
D11	VCC		Power		
D15	VCC		Power		
D19	VCC		Power		
K04	VCC		Power		
K17	VCC		Power		
L04	VCC		Power		
L17	VCC		Power		
N01	VCC		Power		
N02	VCC		Power		
U02	VCC		Power		
U06	VCC		Power		
U10	VCC		Power		
U11	VCC		Power		
U15	VCC		Power		
U19	VCC		Power		
U20	VCC		Power		
W04	VCC		Power		
A08	VCC		Power		
A13	VCC		Power		
B04	VCC		Power		
B08	VCC		Power		
B13	VCC		Power		
B17	VCC		Power		
F04	VCC		Power		
F06	VCC		Power		
F14	VCC		Power		
F15	VCC		Power		
F17	VCC		Power		
G06	VCC		Power		
H01	VCC		Power		
H02	VCC		Power		
H19	VCC		Power		
H20	VCC		Power		
N19	VCC		Power		
N20	VCC		Power		
P15	VCC		Power		
R04	VCC		Power		

Table 12-30: RCG Pin List Sorted by Signal (Continued)

Pin#	Signal	I/O	Driver Type	Driver Strength	Internal Pullup/Pulldown
R06	VCC		Power		
R07	VCC		Power		
R15	VCC		Power		
R17	VCC		Power		
W08	VCC		Power		
W13	VCC		Power		
W17	VCC		Power		
D02	VCC		Power		
D06	VCC		Power		
D10	VCC		Power		
T10	VCCA		Power		
V05	VREF	I	Analog		
V16	VREF	I	Analog		
W07	VTT		Power		
W14	VTT		Power		
W18	VTT		Power		
U05	VTT		Power		
U09	VTT		Power		
U12	VTT		Power		
U16	VTT		Power		
W03	VTT		Power		
T14	WDME#	O	AGTL+	55ma	
J01	WEAA#	O	LVTTL	10ma	
J04	WEAB#	O	LVTTL	10ma	
P17	WEBA#	O	LVTTL	10ma	
P20	WEBB#	O	LVTTL	10ma	
A07	WECA#	O	LVTTL	10ma	
A09	WECB#	O	LVTTL	10ma	
C17	WEDA#	O	LVTTL	10ma	
C20	WEDB#	O	LVTTL	10ma	

12.9.3 Package information

12.9.3.1 324 BGA Package Information

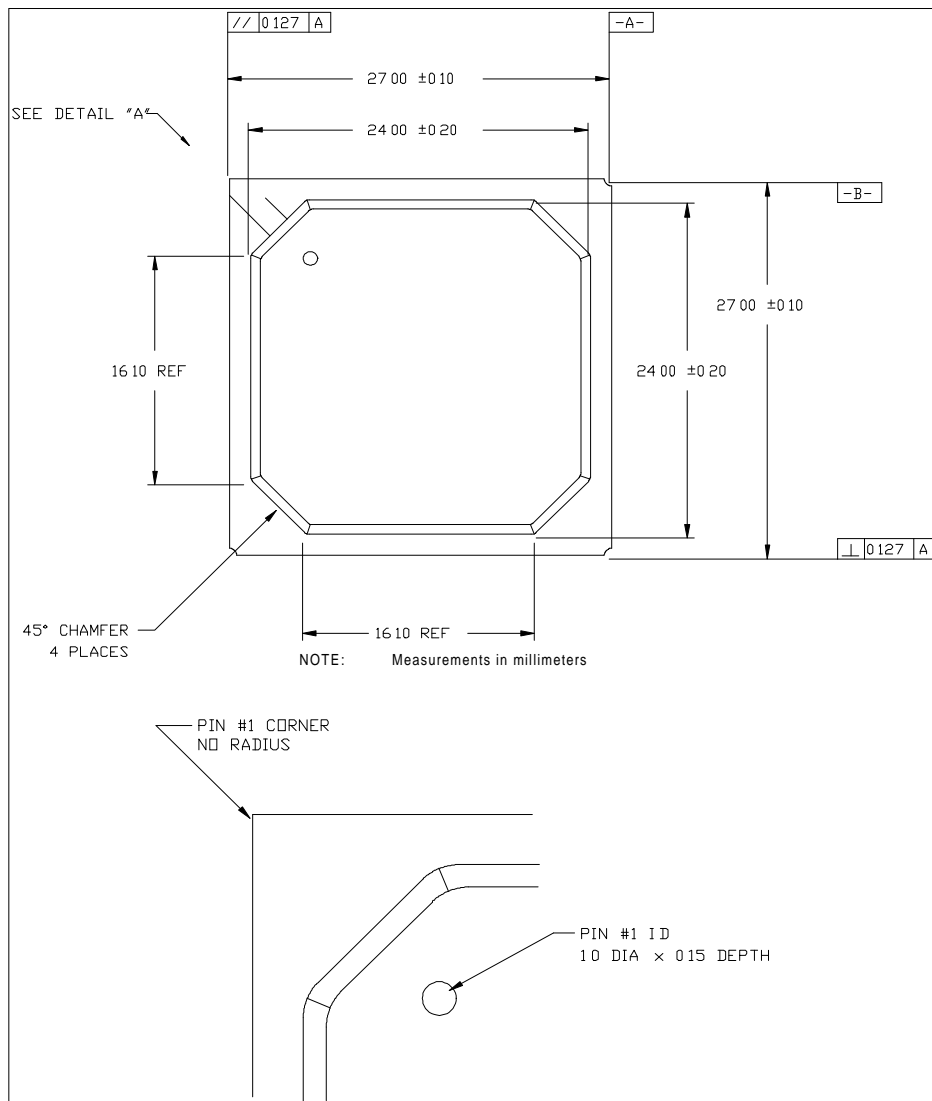


Figure 12-15: 324 BGA Dimension Top View

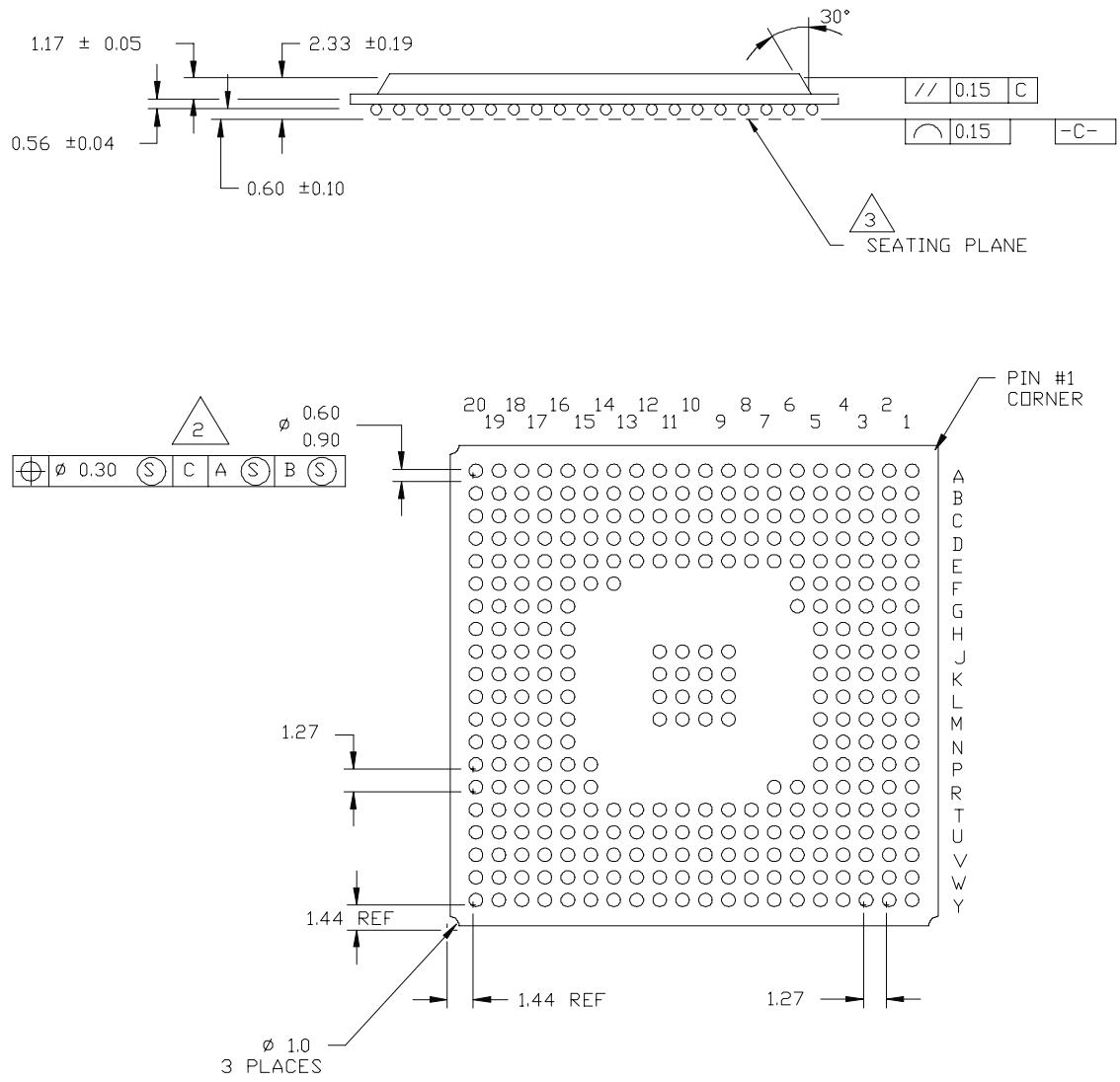
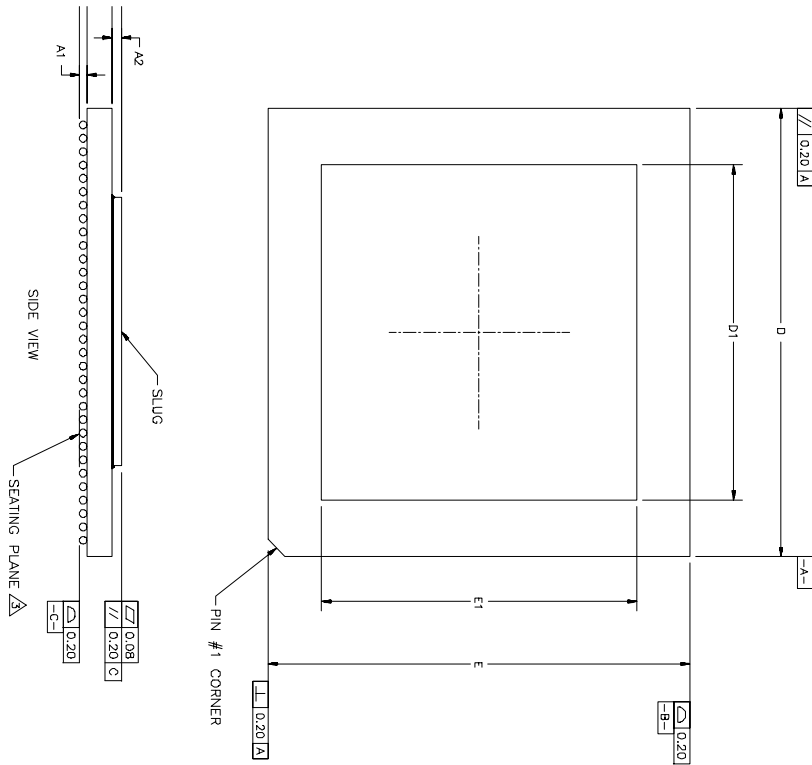


Figure 12-16: 324 BGA Dimensions Bottom View

12.9.3.2 540 PBGA Package Information



- NOTES:
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1982.
 2. DIMENSIONS IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO PRIMARY DATUM [C].
 3. PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 4. ALL DIMENSIONS ARE IN MILLIMETERS

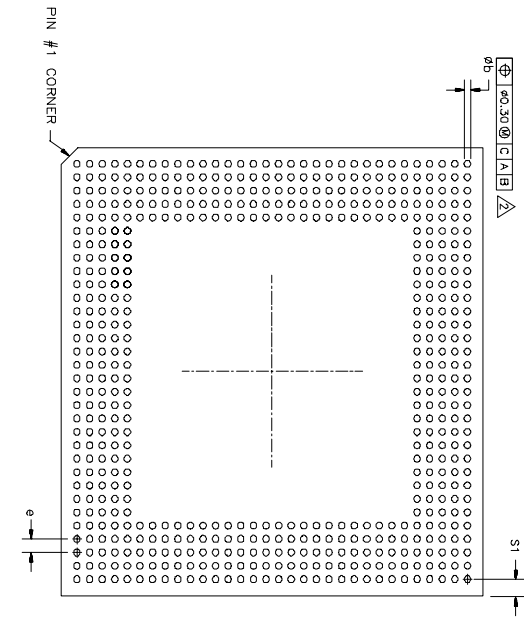


Table 12-31: 540 PBGA dimensions

Package Dimensions		
Packages		
540 LD		
Symbol	Min	Max
A	3.59	4.10
A ₁	0.40	0.70
A ₂	0.95	1.10
b	0.60	0.90
c	2.00	2.30
D	42.30	42.70
D ₁	-	27.70
E	42.30	42.70
E ₁	-	27.70
e	1.27	
N	540	
S ₁	1.56 REF	

NOTE: Measurement in millimeters

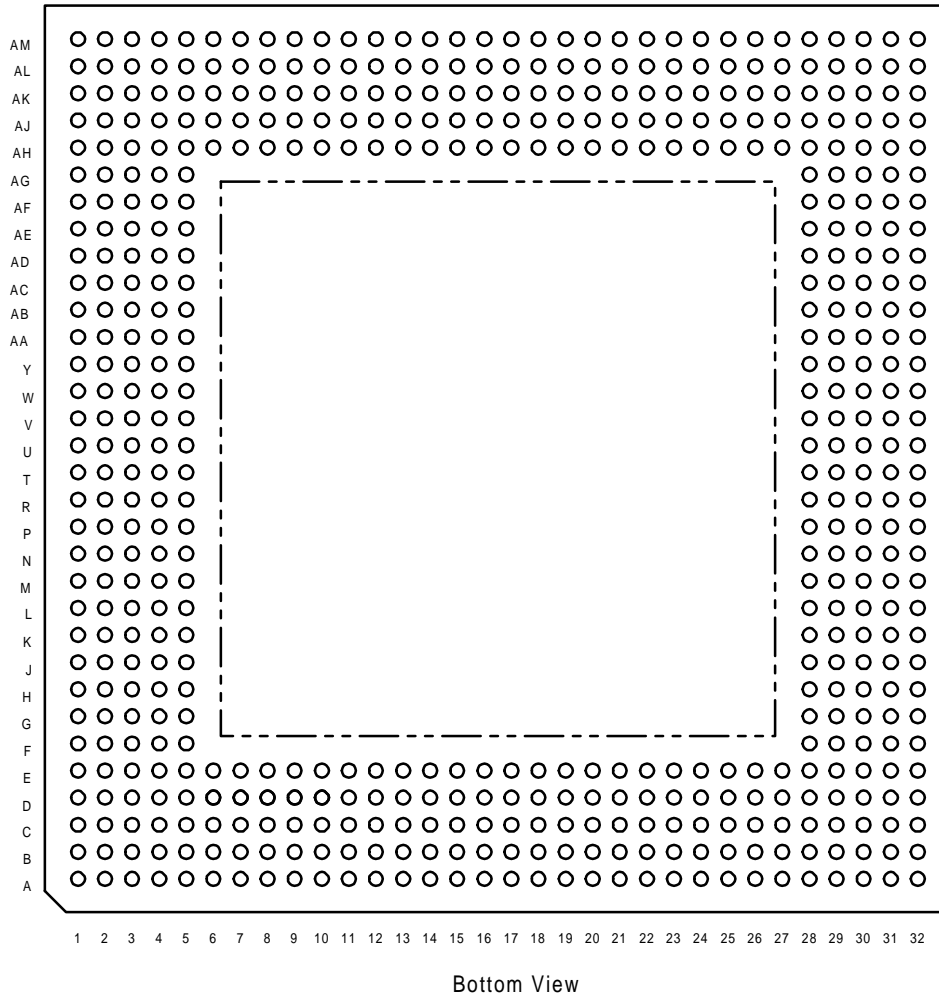


Figure 12-17: 540 PBGA Pin Grid



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